

# Field Engineering Maintenance Manual

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### Preface

This manual contains maintenance and service information for the IBM 2025 Processing Unit and integrated attachment circuitry.

The manual assumes knowledge of the System/360 as described in <u>IBM System/360</u> <u>Principles of Operation</u>, Form A22-6821, and the following appropriate FE Theory of Operation Manuals:

Form No.	Subject
¥24-3527	CPU
¥24-3531	Channel Attachment
¥24-3532	2540 Attachment
¥24-3533	1403 Attachment
¥24 <del>-</del> 3534	2311 Attachment
¥24 <del>-</del> 3535	2560 Attachment
Y24-3536	Integrated Communications
	Attachment

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Additional maintenance information can be found in the Symptom Index and Service Aids distributed by FE Technical Operations. Installation instructions, part 5870298, are included in the basic shipping group for each machine.

This manual contains references to diagrams in the <u>Field Engineering</u> <u>Maintenance Diagrams Manual, 2025</u> <u>Processing Unit</u>, Form Y24-3529. These references use only the initials of the Maintenance Diagrams Manual followed by the diagram section and number; e.g., MDM X-XX.

#### Second Edition (July 1969)

This edition, Y24-3528-1, is a major revision of and obsoletes Y24-3528-0. It also obsoletes FE Supplements Y24-0096 and Y24-0100. This publication has been revised completely with additions, deletions, and reformatting of existing material. For this reason, the reader should review this edition in its entirety.

Significant changes or additions to the specifications contained in this publication are continually being made. Any such changes will be reported in subsequent revisions or FE Supplements.

This publication has been prepared by the IBM Systems Development Division, Product Publications, Dept. 171, P.O. Box 6, Endicott, N.Y. 13760. A form has been provided at the back of this publication for readers' comments. If the form has been removed, address comments regarding this publication to this address.

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<ul> <li>2.25 Errors</li> <li>2.26 Logout</li> <li>2.27 Suggested Restart Procedures for</li> <li>2.27.1 Command Reject (Sense Bit</li> <li>2.27.2 Intervention Required (Sense</li> <li>2.27.3 Bus-Out Check (Sense Bit 2)</li> <li>2.27.4 Equipment Check (Sense Bit</li> <li>2.27.5 Sense Bits 4, 5, 6, and 7</li> <li>2.28 External to CPU Facilities (1052</li> <li>2.28.1 TI (1052 Data In)</li> <li>2.28.2 TR (1052 Tilt/Rotate Regist</li> <li>2.28.3 TD (1052 Diagnostic Branch</li> <li>2.28.4 TT (1052 Diagnostic Branch</li> <li>2.28.5 TU (1052 Diagnostic Branch</li> </ul>	r Inte 0) . e Bi t 3) t 3)	egrate t 1)		PR	KB	· · · · · · · · · · · · · · · · · · ·	2-12 2-13 2-13 2-13 2-13 2-13 2-13 2-14 2-14 2-14 2-14 2-14 2-14 2-14 2-14
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<ul> <li>2.25 Errors</li> <li>2.26 Logout</li> <li>2.27 Suggested Restart Procedures for</li> <li>2.27.1 Command Reject (Sense Bit</li> <li>2.27.2 Intervention Required (Sense</li> <li>2.27.3 Bus-Out Check (Sense Bit 2)</li> <li>2.27.4 Equipment Check (Sense Bit 2)</li> <li>2.27.5 Sense Bits 4, 5, 6, and 7</li> <li>2.28 External to CPU Facilities (1052</li> <li>2.28.1 TI (1052 Data In)</li> <li>2.28.2 TR (1052 Tilt/Rotate Regist</li> <li>2.28.3 TD (1052 Diagnostic Branch</li> <li>2.28.4 TT (1052 Branch Conditions</li> <li>2.28.5 TU (1052 Diagnostic Branch</li> <li>2.29 CPU to External Facilities (1052</li> <li>2.29.1 TA</li> <li>2.29.2 TE (1052 Data Out)</li> <li>SECTION 1B. 1403 PROCEDURES</li> </ul>	r Int 0) . e Bi t 3) () Cor () Cor () () () ()	egrat t 1)	ed 1	PR	KB	· · · · · · · · · · · · · · · · · · ·	2-12 2-13 2-13 2-13 2-13 2-13 2-14 2-14 2-14 2-14 2-14 2-14 2-14 2-14
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th	$\begin{array}{cccccccccccccccccccccccccccccccccccc$	3       SECTION 1. BASIC UNIT         4.1 CPU Timing.       4.1         4.1.1 Specifications       4.1         4.1.1 Specifications       4.1         4.1.1 Cooling.       4.1         4.1.1 Specifications       4.1         4.1.1 Specification       4.1         4.1.1 Specification       4.1         4.1.1 Specification       4.1         4.2.1 Specifications       4.1         4.2.2.1 Heating       4.1         4.2.2.2 Heater Adjustment       4.2         4.2.2.1 Specifications       4.2         4.2.2.2 Heater Adjustment       4.2         4.3.3 Schmoo Curve (Main Storage)       4.3         4.3.1 Example of Schmoo Curve Procedure       4.3.3 Service Checks         5.4.3.3 Service Checks       4.3.4         5.4.3.4 Worst-Case Patterns       4.3.4         5.4.3.5 Four-Point Strobe Schmoo Procedure       4.3.6         4.3.6 Checkout Procedures       4.3.6         4.3.7 Two-Point Schmoo Procedure       4.3.7         4.3.7 Two-Point Schmoo Procedure       4.3.7         4.4.1 Removing the 0.32K Unit       4.4.1         4.4.2 Removing the 0.32K Unit       4.4.2         4.4.4 Changing Diodes       4.4.4		· · · · · · · · · · · · · · · · · · ·	$\begin{array}{c} 4-1 \\ 4-1 \\ 4-1 \\ 4-1 \\ 4-1 \\ 4-1 \\ 4-1 \\ 4-1 \\ 4-1 \\ 4-3 \\ 4-4 \\ 4-4 \\ 4-4 \\ 4-4 \\ 4-4 \\ 4-5 \\ 4-5 \\ 4-5 \\ 4-5 \\ 4-5 \\ 4-5 \\ 4-6 \\ 4-6 \\ 4-6 \end{array}$
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# Abbreviations

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A	AND (logic block)	cyc	cycle
ac	alternating current	C0	carry zero
acv	active		
addr	address	D	displacement (field)
ALD	automated logic diagram	DAC	disk attachment control
alq	algebraic	DAR	data address register
ALŠ	arithmetic and logic section	dbl	double
AMWP	bits 12-15 of PSW 1	dc	direct current
AND	AND circuit (logic)	DDC	direct data channel
arith	arithmetic	DE	device end
AS	auxiliary storage	dec	decimal
	American Standard Code for		deconditioned
ASCII		decond	
- •	Information Interchange	decr	decrement
atn	attention	Diag	diagnostic
Aux	auxiliary	DIR	direct in register
		div	divide
		dly	delay, delayed
В	base address (field)	DM	diagnostic monitor
BCD	binary coded decimal	DOR	direct out register
B-cycle	base address cycle	Dply	display
BSM	basic storage module	DR	driver (logic block)
BTU	British Thermal Unit	Dsply	display
		dvd	dividend
CAR	channel address register	dvr	divisor
CAW	channel address word		4111001
CB	circuit breaker	EA	effective address
CBA	channel background activity	EA-cycle	effective address cycle
C-bit	carry bit	EBCDIC	extended binary coded decimal
CC	chain command; condition code	EDCDIC	interchange code
		FC	3
000	compute clock	EC	engineering change
CCC	channel control check	ECAD	error check analysis diagram
CCW	channel command word	ef	effective
C-cycle	control cycle	End Ex	end execute
CD	chain data	EOB	end of block
CDR	channel data register	EPO	emergency power off
CE	channel end; customer engineer	E-phase	execute phase
chan	channel	Eq	equal
char	character	EXOR	exclusive OR
chk	check	excpn	exception
chnl	channel	exec	execute
CI	command immediate	exp	exponent
CLA	carry look-ahead	ext	external
CLI	compare logical immediate	extn	extension
clk	clock		
clr	clear	FEMDM	Field Engineering Maintenance
CLT	circuit level test		Diagram Manual
cmnd	command	FEMM	Field Engineering Maintenance
cmpt	compute		Manual
COAR	command address register	FETOM	Field Engineering Theory of
com	common	12200	Operation Manual
comm	communications	FF	flip-flop (logic block)
comp	compare	FL	flip latch (logic block)
compl	complement	fltq	floating
-	condition	FP	floating point
cond	correction		
corrn		FPA	floating point arithmetic
CP	main clock pulse	FPR	floating point register
CPU	central processing unit	ann -	
CSL	control storage load	GPR	general purpose register
CSU	core storage unit	1	h
ct	count	hex	hexadecimal
ctr	counter	HI	high
CU	control unit	hsmpx	high-speed multiplex channel

Ulater	have a star	0.0	$(\mathbf{D})$ since $(1, \dots, n)$
H/stop	hard stop	OR	OR circuit (logic)
HW	hardware (funnel)	OS	operating system
Hz	Hertz (cycles per second)	OSC	oscillator (logic)
*		<b>.</b>	
IB	interrupt buffer	P	parity bit
IC	instruction counter	PC	parity check
ICC	interface control check	Pch	punch
I-cycle	instruction cycle	PCI	program controlled interrupt
IF	interface	PFR	punch feed read
I-fetch	instruction fetch	PG	parity generation
IL	incorrect length	PIW	priority interrupt wait
ILC	instruction length code	PLB	print line buffer
			-
incr	increment	pos	positive
info	information	poss	possible
inh	inhibit	prgm	program
insn	instruction	prgm chk	program check
int	interrupt	pri	priority
intch	interchange	priv	privileged
intv	interval	PR-KB	printer-keyboard
intvn	intervention		protection
		prot	<b>~</b>
inv	invert	Prt	printer
I/0	input/output	PS	power supply (number)
IPL	initial program loading	PSA	protected storage address
IR	interrupt request	PSW	program status word
ISA	invalid storage address	pt	point
I-time	instruction time	pty	parity
	Ine of de of our of me	Pwr	power
ИD	haveboard		
KB	keyboard	PZR	possible zero remainder
kva	kilovolt ampere	<b></b>	
		QB	quotient bit
LCW	line control word	quot	quotient
LO	lcw		
log	logical	RC	read clock
LS	local storage	Rdr	reader
lth	latch	recomp	recomplement
LUA	load unit address (switches)	-	register
TON	TOAU MITT AUGTESS (SWITCHES)	reg	-
_		req	request
mA	milliamperes	reqd	required
Man	manual	res	reset
MAP	maintenance analysis procedure	rgen	regenerate
MAS	microprogram automation system	rmdr	remainder
max	maximum	rms	root mean square
MC	machine check	RPQ	request for price quotation
MDM	Maintenance Diagrams Manual	RR	register-to-register operation
MFCM	Multi-Function Card Machine	RS	register-to-storage operation
MHz	megacycle	Rst	reset
min	minimum	rt	right
MMSK	Trap (Mask) Priority Register	Rtn	return, routine
mp ed	multiplicand	R-W	read-write
mplr	multiplier		
Mplx	multiplexer	S	sign bit
mply	multiply	SAR	storage address register
mpx	multiplexer	SC	shift counter
MS	main storage	SC	scratch (register)
ms	millisecond	SCR	silicon controlled rectifier
		SCT	system configuration table
N	inverter (logic block)	SCh	subchannel
neg	negative	SDR	storage data register
-	number	SDSD	
no No-Op			single disk storage drive
No-Op	no operation	sel	select
norm	normalize	seq	sequence
ns	nanosecond	serv	service
		sgnf	significance, significant
OE	exclusive OR (logic block)	SI	storage immediate operation
oflo	overflow	SL	shift left
0/L	overload (console)	SLD	simplified logic diagram
op	operation	SLI	suppress incorrect length
	=		
opnd	operand		indication

SLT	solid logic technology	$\mathbf{TP}$	test point
SMS	standard modular system	T/R	tilt/rotate
spl	special	T/XC	true/criss-cross
SR	shift right		
SRETL	screened resistor etched		
	transistor logic	UCW	unit control word
SRP	serial reader punch	UDT	unit definition table
SS	storage-to-storage operation,	uflo	underflow
	singleshot	un	unnormalized
st	start	unobt	unobtainable
STP0	storage protect register	usec	microsecond
STP1	storage protect local storage		
STP	storage protect	WC	write clock
subt	subtract	wđ	word
SVC	supervisor call	WLR	wrong length record
SW	switch		
sys	system	Х	index (field)
		X-cycle	index cycle
TB	terminal board		
<b>T-cycle</b>	timer cycle		llowing symbols are used with
TD	time delay (logic)	microword	statements:
Temp	temperature	\$ OR	
TH	thermal (console)	- Minus	
TIC	transfer in channel	+ Add	
tmr	timer	*- Complei	
tgr	trigger	🛛 Exclusi	ive OR.

-

## Safety

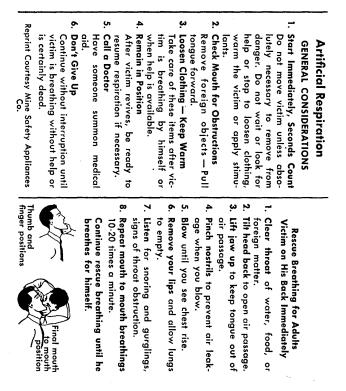
#### **CE SAFETY PRACTICES**

All Customer Engineers are expected to take every safety precaution possible and observe the following safety practices while maintaining IBM equipment:

- You should not work alone under hazardous conditions or around equipment with dangerous voltage. Always advise your manager if you MUST work alone.
- Remove all power AC and DC when removing or assembling major components, working in immediate area of
  power supplies, performing mechanical inspection of power
  supplies and installing changes in machine circuitry.
- Wall box power switch when turned off should be locked or tagged in off position. "Do not Operate" tags, form 229-1266, affixed when applicable. Pull power supply cord whenever possible.
- 4. When it is absolutely necessary to work on equipment having exposed operating mechanical parts or exposed live electrical circuitry anywhere in the machine, the following precautions must be followed:
  - a. Another person familiar with power off controls must be in immediate vicinity.
  - b. Rings, wrist watches, chains, bracelets, metal cuff links, shall not be worn.
  - c. Only insulated pliers and screwdrivers shall be used.
  - d. Keep one hand in pocket.
  - e. When using test instruments be certain controls are set correctly and proper capacity, insulated probes are used.
     f. Avoid contacting ground potential (metal floor strips,
- machine frames, etc. use suitable rubber mats purchased locally if necessary).
- 5. Safety Glasses must be worn when:
  - a. Using a hammer to drive pins, riveting, staking, etc.
  - b. Power hand drilling, reaming, grinding, etc.
  - c. Using spring hooks, attaching springs.
  - d. Soldering, wire cutting, removing steel bands.
  - e. Parts cleaning, using solvents, sprays, cleaners, chemicals, etc.
  - f. All other conditions that may be hazardous to your eyes. REMEMBER, THEY ARE YOUR EYES.
- Special safety instructions such as handling Cathode Ray Tubes and extreme high voltages, must be followed as outlined in CEM's and Safety Section of the Maintenance Manuals.
- 7. Do not use solvents, chemicals, greases or oils that have not been approved by IBM.
- 8. Avoid using tools or test equipment that have not been approved by IBM.
- 9. Replace worn or broken tools and test equipment.
- 10. Lift by standing or pushing up with stronger leg muscles this takes strain off back muscles. Do not lift any equipment or parts weighing over 60 pounds.
- 11. All safety devices such as guards, shields, signs, ground wires, etc. shall be restored after maintenance.

KNOWING SAFETY RULES IS NOT ENOUGH AN UNSAFE ACT WILL INEVITABLY LEAD TO AN ACCIDENT USE GOOD JUDGMENT – ELIMINATE UNSAFE ACTS 229-1264-1

- 12. Each Customer Engineer is responsible to be certain that no action on his part renders product unsafe or exposes hazards to customer personnel.
- Place removed machine covers in a safe out-of-the-way place where no one can trip over them.
- All machine covers must be in place before machine is returned to customer.
- Always place CE tool kit away from walk areas where no one can trip over it (i.e., under desk or table).
- Avoid touching mechanical moving parts (i.e., when lubricating, checking for play, etc.).
- When using stroboscope do not touch ANYTHING it may be moving.
- Avoid wearing loose clothing that may be caught in machinery. Shirt sleeves must be left buttoned or rolled above the elbow.
- Ties must be tucked in shirt or have a tie clasp (preferably nonconductive) approximately 3 inches from end. Tie chains are not recommended.
- Before starting equipment, make certain fellow CE's and customer personnel are not in a hazardous position.
- Maintain good housekeeping in area of machines while performing and after completing maintenance.



# Chapter 1. Reference Data and Diagnostic Techniques

#### Section 1. Reference Data

This section contains charts, listings, and diagrams giving general information for diagnosing system failures.

16K	Systems

Addrs	Usage	Aux Stor	Array
7FFF 4000	Control Storage	2048 Bytes	32K
 3FFF 0000	Program Storage	(see text)	

1.1 CORE STORAGE (FIGURES 1-1 THROUGH 1-17)

Hex	Decimal Address	Length	Purpose
Address	Autress	Length	
o	0	Doubleword	Initial program-loading PSW
8	8	Doubleword	Initial program-loading CCW1
10	16	Doubleword	Initial program-loading CCW2
18	24	Doubleword	External old PSW
20	32	Doubleword	Supervisor-call old PSW
28	40	Doubleword	Program old PSW
30	48	Doubleword	Machine-check old PSW
38	56	Doubleword	Input/output old PSW
40	64	Doubleword	Channel-status word
48	72	Word	Channel-address word
4C	76	Word	Not used
50	80	Word	Timer
54	84	Word	Not used
58	88	Doubleword	External new PSW
60	96	Doubleword	Supervisor-call new PSW
68	104	Doubleword	Program new PSW
70	112	Doubleword	Machine-check new PSW
78	120	Doubleword	Input/output new PSW
80-9F	128-159		Diagnostic scan-out area, beginning at address
			128.

Figure 1-1. Permanent Storage Assignments

24K Systems

Addrs	Usage	Aux Stor	Array	
BFFF	Control	2560	16K	
8000	Storage	Bytes		
5FFF	Program	(see	24K	
0000	Storage	text)		

Note: Addresses 6000-7FFF are not available in the 24K M2-I storage array.

32K Systems

02100,	0.01110		
Addrs	Usage	Aux Stor	Array
BFFF 8000	Control Storage	3072 Bytes	16K
7FFF 0000	Program Storage	(see text)	32K

48K Systems								
Addrs	Usage	Aux Stor	Array					
FFFF C000 BFFF	Control Storage Program	4096 Bytes (see	32K					
8000	Storage (High)	text)						
7FFF 4000	Program Storage (Mid)		32K					
3FFF 0000	Program Storage (Low)							

Figure 1-2. Addressing Ranges for Program Storage, Control Storage, and Auxiliary Storage

Program Storage			Control	Storage		Auxiliary Storage		
Array Size	Bytes	Addrs Range (Decimal/Hex)	Array Size	Bytes	Addrs Range (Decimal/Hex)	Bytes	Addrs Range (Decimal/Hex)	
32K Low half	16,384	0-16, 383 0000 - 3FFF	32K High half	16,384	16,384 - 32,767 4000 - 7FFF	2,048	0x 00-7xFF	
24K All	24,576	0-24, 575 0000-5FFF	16K All	16,384	32,768 - 49,151 8000 - BFFF	2,560	0x00-5xFF and 8x00-BxFF	
32K All	32,768	0-32, 767 0000-7FFF	16K All	16,384	32,768-49,151 8000-BFFF	3,072	0x00-BxFF	
32K(1) All Plus 32K(2) Low half	49,152	0-49, 151 0000-BFFF	32K(2) High half	16,384	49,152-65,535 C000 FFFF	4,096	0x00-FxFF	
	Array Size 32K Low half 24K All 32K All 32K(1) All Plus 32K(2) Low	Array Size         Bytes           32K         16,384           Low         -           half         -           24K         24,576           AII         -           32K         32,768           AII         -           32K(1)         49,152           AII         -           Plus         -           32K(2)         -           Low         -	Array Size         Bytes         Addrs Range (Decimal/Hex)           32K         16,384         0-16, 383 0000 - 3FFF           half         24K         24,576           24K         24,576         0-24, 575 0000-5FFF           32K         32,768         0-32, 767 0000-7FFF           32K(1)         49,152         0-49, 151 0000-BFFF           32K(2)         Low         0000-BFFF	Array Size         Bytes         Addrs Range (Decimal/Hex)         Array Size           32K         16,384         0-16,383 0000 - 3FFF         32K High half           24K         24,576         0-24,575 0000-5FFF         16K All           32K         32,768         0-32,767 0000-7FFF         16K All           32K         32,768         0-32,767 0000-7FFF         16K All           32K(1)         49,152         0-49,151 0000-BFFF         32K(2) High half           All         32K(2) Low         0000-BFFF         High half	Array Size         Bytes         Addrs Range (Decimal/Hex)         Array Size         Bytes           32K         16,384         0-16, 383 0000 - 3FFF         32K         16,384           Low half         24K         24,576         0-24, 575 0000-5FFF         16K         16,384           32K         24,576         0-24, 575 0000-5FFF         16K         16,384           All         0000-5FFF         All         16,384           32K         32,768         0-32,767 0000-7FFF         16K         16,384           All         0000-8FFF         All         16,384         16,384           32K(1)         49,152         0-49, 151 0000-BFFF         32K(2)         16,384           All         0000-BFFF         High half         High half         16,384	Array Size         Bytes         Addrs Range (Decimal/Hex)         Array Size         Bytes         Addrs Range (Decimal/Hex)           32K         16,384         0-16, 383 0000 - 3FFF         32K High half         16,384         16,384 - 32,767 4000 - 7FFF           24K         24,576         0-24, 575 0000-5FFF         16K All         16,384         32,768 - 49,151 8000 - BFFF           32K         32,768         0-32,767 0000-7FFF         16K All         16,384         32,768 - 49,151 8000 - BFFF           32K         32,768         0-32,767 0000-7FFF         16K All         16,384         32,768-49,151 8000-BFFF           32K(1)         49,152         0-49, 151 0000-BFFF         32K(2) High half         16,384         49,152-65,535 C000-FFFF           All         9152         0-49, 151 0000-BFFF         32K(2) High half         16,384         49,152-65,535 C000-FFFF	Array Size         Bytes         Addrs Range (Decimal/Hex)         Array Size         Bytes         Addrs Range (Decimal/Hex)         Bytes           32K         16,384         0-16,383 0000 - 3FFF         32K High half         16,384         16,384 - 32,767 4000 - 7FFF         2,048           24K         24,576         0-24,575         16K 0000-5FFF         16,384         32,768 - 49,151 8000 - 8FFF         2,560           32K         32,768         0-32,767         16K 0000-7FFF         16,384         32,768-49,151 8000 - 8FFF         3,072           32K         32,768         0-32,767         16K 0000 - 7FFF         16,384         32,768-49,151 8000 - 8FFF         3,072           32K         32,768         0-32,767         16K 0000 - 8FFF         16,384         49,152-65,535         4,096           All         0000 - 8FFF         High half         16,384         49,152-65,535         4,096           All         0000 - 8FFF         High half         High half         49,152         4,096	

2. Control storage is always the high-order 16K bytes of the composite core-storage array(s).

3. The notation 0x00-7xFF, etc. in the AUX STOR ADDRS RANGE column is defined in section 1.2.

Figure 1-3. Core-Storage Allocations and Addressing Scheme

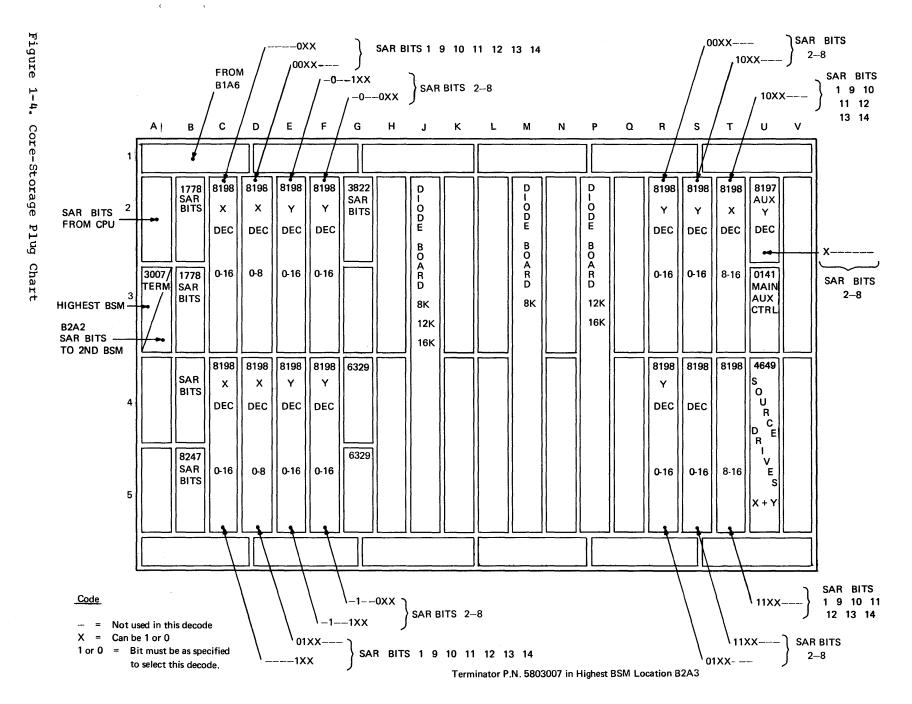
#### 1.1.1 TRAP ADDRESSES

When a microprogram trap occurs, the control-storage address of the routine is forced into the storage address assembler. The trap microprograms are located at the following fixed locations. The trap addresses given are relative to control-storage address 0000, and this location is 4000 for 16K systems, 8000 for 24K or 32K systems, or C000 for 48K systems.

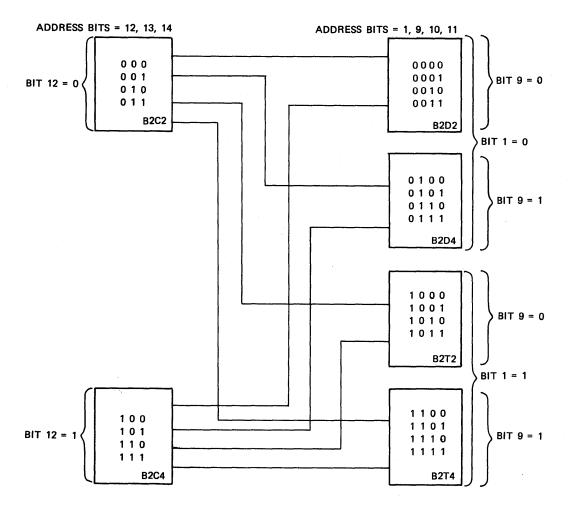
Trap <u>Addr.ess</u> 0010 0240 0220 0280 0210	Trap Routine CSL System reset or IPL Machine check FE trap Storage-wrap error, or storage protect violation
0170	Channel high priority
0140	File chaining
0180	Channel low priority
01B0	2540 reader
0110	2540 punch
01E0	Communications channel bit service
0120	Communications channel character service

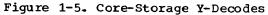
#### 1.1.1.1 Address Stop/Match

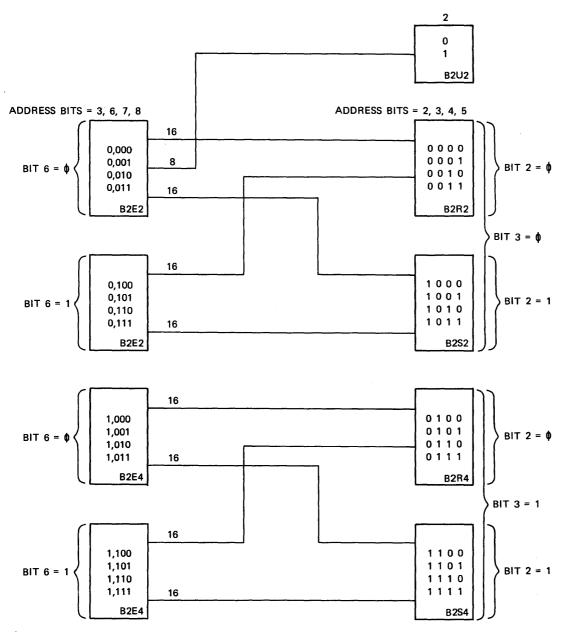
It is not possible to address stop at the first word of a trap because trap addresses are forced directly to the storage address lines, and the address match function refers to the contents of the M-register. To address match on a trap, make the match on the address of the second word of the The address of the second word of a trap. trap is normally the trap address +2. exception is the storage-wrap and An storage-protect violation trap, where the first word can be a direct branch. The appropriate MAS listing should be used, in this case, to determine the address to be matched.

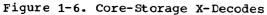


# 2025 FEMM (7/69) 1-3









#### 1.2\_AUXILIARY STORAGE MAPS (FIGURES 1-7 THROUGH 1-17)

Depending on the program-storage capacity of the system, there are from eight to sixteen 256-byte modules of auxiliary storage. Module 0 is used for CPU functions (general registers, etc.) and for storage of addresses and information relative to the integrated I/O attachment features. Module 2 is used for multiplexer-channel unit-control words. Modules 1 and 3-7 are used for operations involving the integrated attachment features. Modules 8-15 are reserved for special features. The 24K system (modules 6 and 7) is an exception (Figure 1-7).

Note: Three hexadecimal digits in the first, third and fourth positions of the storage address register are used to address auxiliary storage (the second hex character is not relevant).

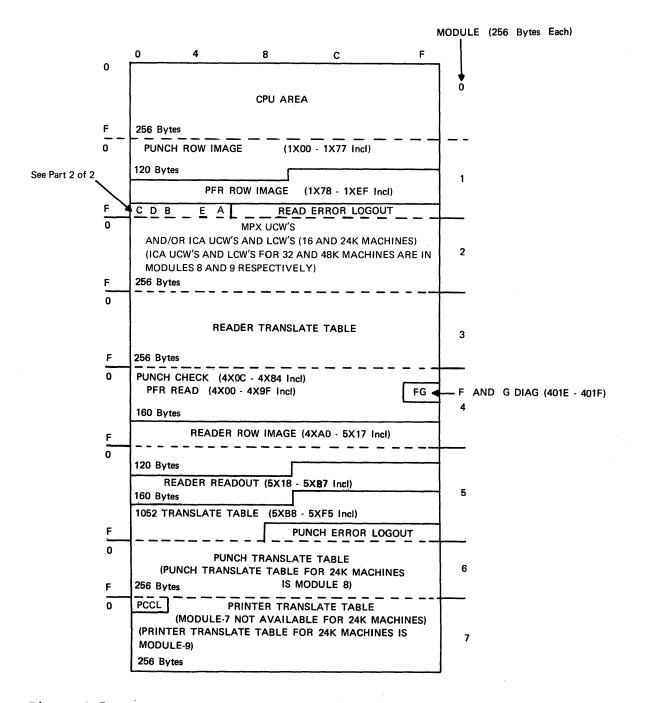


Figure 1-7. Auxiliary Storage Map (Part 1 of 2) 1-6 (7/69)

			BIT SIGNIFICANCE							
CODE	ROUTINES USING	0	1	2	3	4	5	6	7	USED FOR
A	ETRP-S	CMD REJ	NOT READY		EQUIP CHECK	VAL CHECK		UN- USUAL CMD		PUNCH SENSE
В	ETRP-S, ECOL-R		STACK SEL 1, 2, 3	STACK SEL 1, 2, 3						STACK SEL
с	EXFR-R	CDA	STACK SEL 1, 2, 3	STACK SEL 1, 2, 3		READ	CT STOR	FEED	WLR	READER INDICATOR
D	EXFR-R	CMD REJ	NOT READY		EQUIP CHECK	VAL CHECK		UN- USUAL CMĐ		READER SENSE
E	EPCH-R	CDA	STACK SEL 1, 2, 3	STACK SEL 1, 2, 3		PFR READ	CT STOR	PFR COUNT	WLR	PUNCH INDICATOR

.

Note: PCCL byte for 1403 translate table is kept in auxiliary storage 7x00 (9x00 for 24K machines).

Figure 1	1-7.	Auxiliary	Storage	Мар	(Part	2	of	2)	
----------	------	-----------	---------	-----	-------	---	----	----	--

c	) 1 2 3	4 5	6	7	89	АВ	с р	E	F
0X	G.P. REG 0				FLOA	TING POIN	T REG. 0		] ox
1X	G.P. REG 1	23	11		Н				
2X	G.P. REG 2				FLOA	TING POIN	T REG. 2		2X
зх	G.P. REG 3					J			] 3X
4X	G.P. REG 4				FLOA	TING POIN	T REG. 4		4X
5X	G.P. REG 5	1	052			к			5X
6X	G.P. REG 6	ALTER/	DISPL	AY	FLOA	TING POIN	T REG. 6		6X
7X	G.P. REG 7	MES	SAGE			L			] 7×
8X	G.P. REG 8	-	R-		К0	К1	K2	КЗ	8X
9X	G.P. REG 9	-	R–		К4	К5	К6	K7	9Х
АХ	G.P. REG A				к8	К9	КА	КВ	AX
вх	G.P. REG B	AB	l C	I D	кс	KD	KE	KF	вх
сх	G.P. REG C	P	м			1403	UCW		сх
DX	G.P. REG D		м			2540 RD	R UCW		DX
EX	G.P. REG E		м			2540 PCI	HUCW		EX
FX	G.P. REG F	E N	м	G		1052	UCW		FX
i c	0 1 2 3	4 5	6	7	89	A B	C D	E	F
A1403 UNIT ADDRESS       HMULT/DVD TABLE (X1) AND         BREADER UNIT ADDRESS       ALT/DIS REGS BACKUP         CPUNCH UNIT ADDRESS       JMULT/DVD TABLE (X4) AND         D1052 UNIT ADDRESS       JMULT/DVD TABLE (X4) AND         D1052 UNIT ADDRESS       ALT/DIS BACKUP + FLPT SAVE         EH1 SAVE       KMULT/DVD TABLE (X16)         G1052 SENSE       LMULT/DVD TABLE (X64), FLPT SAVE         N2311 ADDRESS       MNATIVE KEY KKKK0000         PCOMMU. Q-EXIT POINTER       RBURST CHANNEL BUFFERED         DEVICE ADDRESSES.       DEVICE ADDRESSES.									
		K-AD	DRESS	ABLE	AREA				
KI-8/ K2-8 K3-8	<ul> <li>8- CHANNEL 1 IN</li> <li>4- STANDARD IN</li> <li>C- CHANNEL UNI</li> <li>E- STATUS/ACTIV</li> <li>8- 2311 NEXT CCV</li> </ul>	TERRUPT TERFACE, T ADDRES /E BYTE F	BUFFE NEXT S BUF OR 23	ER CCW FER	ADDRESS	1			

- K4-98- 2311 NEXT CCW ADDRESS
- K5-9A- 2311 SENSE OR PREVIOUS OP AND MASK
- K6-9C- 2311 SENSE OR FILE ADDRESS
- K7-9E DIAGNOSTICS, ALTER/DISPLAY BAL BACKUP
- K8-A8- SYSTEM MASK -A9- CPU KEY AND AMWP
- K9-AA- EXECUTE INSTRUCTION COUNTER---- I REGISTER BACKUP
- KA-AC- U REGISTER BACKUP Q FLPT SAVE DURING INSTRUCTIONS
- **KB-AE- G REGISTER BACKUP**
- KC-B8- P REGISTER BACKUP
- KD-BA- CHANNEL 0 INTERRUPT BUFFER
- KE-BC- ADDRESS OF STRAIGHT MULT/DVD, FLPT SAVE 2540 REGS BACKUP
- KF-BE- ADDRESS OF SKEWED MULT/DVD, FLPT SAVE OR CAW KEY 2540 REGS BACKUP

Figure 1-8. Auxiliary Storage Module 0 (Part 1 of 2)

#### STANDARD DEVICE ADDRESSES

INTEGRATED	LOC	BURST CHANNEL	LOC
14030E	B4	1443 or 1445 0B	84
2540 RDR0C	B5	2540 RDR0C	85
2540 PCH0D	B6	2540 PCH0D	86
10521F	B7	1403 0E	87
23119X	F5	1404 or 2ND 14030F	94
Note:		252015	95
The text preceding the	-BCPL- Routine	contains information on punching cards to	recon-
figurate the system to o			

Figure 1-8.	Auxiliarv	Storage	Module	0	(Part	2	of	2)	í.
-------------	-----------	---------	--------	---	-------	---	----	----	----

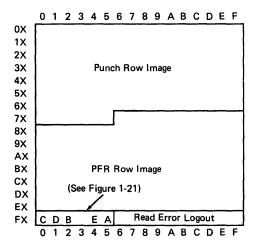


Figure 1-9. Auxiliary Storage Module 1

	x0	x2 x4	x6	x8 xA xC xE
0x	UCW	0, Addrs 000		UCW 16, Addrs 010
		or 080*		
1x	UCW	1, Addrs 001		UCW 17, Addrs 011
2x	UCW	or 090* 2. Addrs 002		UCW 18, Addrs 012
20	0011	or 0A0*		001110, Addis 012
3x	UCW	3, Addrs 003		UCW 19, Addrs 013
		or 080*		
4x	UCW	4, Addrs 004		UCW 20, Addrs 014
		or 0C0*		
5x	UCW	5, Addrs 005		UCW 21, Addrs 015
6x	UCW	or 0D0* 6, Addrs 006	1	UCW 22, Addrs 016
	000	or 0E0*		00W 22, Addis 010
7x	UCW	7, Addrs 007		UCW 23, Addrs 017
		or 0F0*		
8x	UCW	8, Addrs 008		UCW 24, Addrs 018
9x	UCW	9, Addrs 009		UCW 25, Addrs 019
Ax	UCW	10, Addrs 00A		UCW 26, Addrs 01A
Вx	UCW	11, Addrs 00B		UCW 27, Addrs 01B
Cx	UCW	12, Addrs 00C		UCW 28, Addrs 01C
Dx	UCW	13, Addrs 00D		UCW 29, Addrs 01D
Ex	UCW	14, Addrs 00E		UCW 30, Addrs 01E
Fx	UCW	15, Addrs 00F		UCW 31, Addrs 01F

Example: Unit control word 27 is located at position B8 in auxiliary-storage module 2. The unit address is 01B.

\* These eight MPX UCW's may be used for single-address subchannels or shared subchannels.

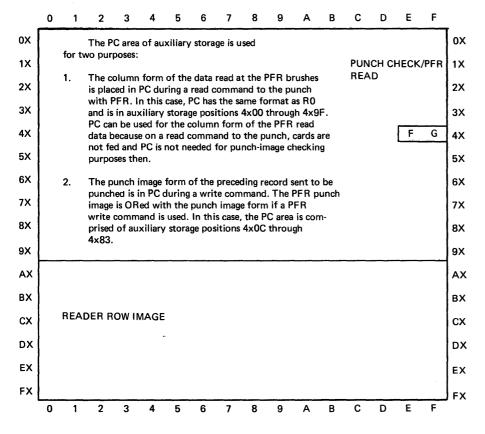
Figure 1-10. Auxiliary Storage Module 2

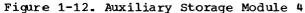
	_																-
TENS	0	1	2	3	4	5	6	7	8	9	Α	В	С	D	Е	F	ſ
0X	40	F1	F2	F3	F4	F5	F6	F7	F0	61	E2	E3	E4	E5	E6	E7	ox
1X	60	D1	D2	D3	D4	D5	D6	D7	DO	A1	A2	A3	A4	A5	A6	A7	1X
2X	50	C1	C2	СЗ	C4	C5	C6	C7	со	81	82	83	84	85	86	87	2X
зх	6A	91	92	93	94	95	96	97	70	B1	B2	В3	B4	B5	B6	В7	зх
4X	F9	31	32	33	34	35	36	37	E9	21	22	23	24	25	26	27	4X
5X	D9	11	12	13	14	15	16	17	A9	E1	62	63	64	65	66	67	5X
6X	C9	01	02	03	04	05	06	07	89	41	42	43	44	45	46	47	6X
7X	99	51	52	53	54	55	56	57	В9	71	72	73	74	75	76	77	7X
8X	F8	79	7A	7B	7C	7D	7E	7F	E8	69	EO	6B	6C	6D	6E	6F	8X
9X	D8	59	5A	5B	5C	5D	5E	5F	A8	A0	AA	AB	AC	AD	AE	AF	]9X
AX	C8	49	4A	4B	4C.	4D	4E	4F	88	80	8A	8B	8C	8D	8E	8F	AX
вх	98	90	9A	9B	9C	9D	9E	9F	B8	в0	вА	BB	вС	BD	BE	BF	вх
сх	38	39	ЗА	3B	3C	3D	3E	3F	28	29	2A	2B	2C	2D	2E	2F	cx
DX	18	19	1A	1B	1C	1D	1E	1F	68	20	EA	EB	EC	ED	EE	EF	DX
EX	08	09	0A	0B	0C	0D	OE	0F	48	00	СА	СВ	сс	CD	CE	CF	ĒΧ
FX	58	10	DA	DB	DC	DD	DE	DF	78	30	FA	FB	FC	FD	FE	FF	FX
	0	1	2	3	4	5	6	7	8	9	Α	в	с	D	Е	F	

UNITS

.

Figure 1-11. Auxiliary Storage Module 3





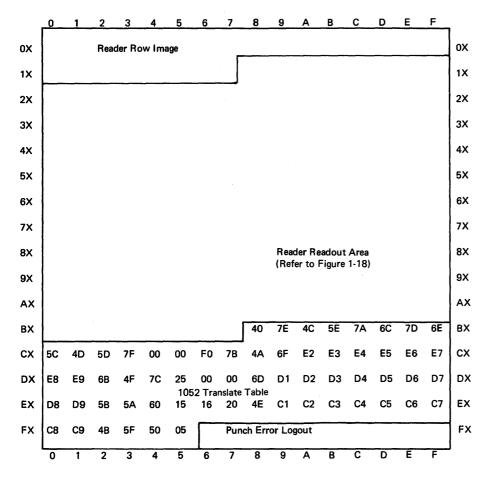


Figure 1-13. Auxiliary Storage Module 5

		PUNCH TRANSLATE TABLE															
	0	1	2	3	4	5	6	7	8	9	Α	В	С	D	E	F	
0X	В9	<b>8</b> 9	8A	8B	8C	8D	8E	8F	98	99	9A	9B	9C	9D	9E	9F	0X
1X	D9	49	4A	<b>4</b> B	4C	4D	4E	4F	58	59	5A	5B	5C	5D	5E	5F	1X
2X	79	29	2A	2B	2C	2D	2E	2F	38	39	3A	3B	3C	3D	3E	3F	2X
3X	F9	09	0A	0B	0C	<b>0</b> D	0E	0F	18	19	1A	1B	1C	1D	1E	1F	зх
≁ 4X	00	A9	AA	AB	AC	AD	AE	AF	B8	91	92	93	94	95	96	97	4X
5X	80	С9	СА	СВ	сс	CD	CE	CF	D8	51	52	53	54	55	56	57	5X
~ 6X	40	21	6A	6B	6C	6D	6E	6F	78	31	C0	33	34	35	36	37	6X
7X	E0	E9	EA	EB	EC	ED	EE	EF	F8	11	12	13	14	15	16	17	7X
8X	В1	A1	A2	A3	A4	A5	A6	Α7	в0	A8	B2	B3	B4	B5	B6	B7	8X
9X	D1	C1	C2	СЗ	C4	C5	C6	C7	D0	C8	D2	D3	D4	D5	D6	D7	9X
AX	71	61	62	63	64	65	66	67	70	68	72	73	74	75	76	77	AX
вх	F1	E1	E2	E3	E4	E5	E6	E7	F0	E8	F2	F3	F4	F5	F6	F7	вх
сх	AO	81	82	83	84	85	86	87	90	88	ВА	вв	вс	BD	BE	BF	сх
DX	60	41	42	43	44	45	46	47	50	48	DA	DB	DC	DD	DE	DF	DX
EX	32	69	22	23	24	25	26	27	30	28	7A	7B	7C	7D	7E	7F	EX
FX	20	01	02	03	04	05	06	07	10	08	FA	FB	FC	FD	FE	FF	FX
	0	1	2	3	4	5	6	7	8	9	Α	В	С	D	E	F	

Figure 1-14. Auxiliary Storage Module 6

		NON	INCS	CSL L	UAD.	(REF	ЕКІС	J SEC	TION	1.14)							
	0	1	2	3	4	5	6	7	8	9	А	В	С	D	Е	F	
оx	04	25	26	27	28	29	2A	2B	2C	2D	2E	2F	30	18	2E	00	оx
1X	16	19	1A	1B	1C	1D	1E	1F	20	21	22	23	24	30	00	00	1X
2X	22	OD	CE	0F	10	11	12	13	14	15	16	17	18	00	17	00	2X
зх	0A	01	02	03	04	05	06	07	08	09	0A	ОВ	OC	0C	OВ	00	зх
4X	00	25	26	27	28	29	2A	2B	2C	2D	2E	2F	30	18	2E	00	4X
5X	16	19	1A	1B	1C	1D	1E	1F	20	21	22	23	24	30	00	00	5X
6X	22	0D	0E	0F	10	11	12	13	14	15	16	17	18	00	17	00	6X
7X	0A	01	02	03	04	05	06	07	08	09	0A	0B	0C	0C	0B	00	7X
8X	16	25	26	27	28	29	2A	2B	2C	2D	2E	2F	30	18	2E	00	8X
9X	22	19	1A	1B	1C	1D	1E	1F	20	21	22	23	24	30	00	00	9X
АХ	00	0D	OE	OF	10	11	12	13	14	15	16	17	18	00	17	00	AX
вх	0A	01	02	03	04	05	06	07	08	09	0A	OВ	0C	0C	ЮB	00	вх
сх	16	25	26	27	28	29	2A	2B	2C	2D	2E	2F	30	18	2E	00	сх
DX	22	19	1A	1B	1C	1D	1E	1F	20	21	22	23	24	30	00	00	DX
ΕX	00	0D	OE	OF	10	11	12	13	14	15	16	17	18	00	17	00	EX
	0A	01	02	03	04	05	06	07	08	09	0A	ов	0C	ос	ов	00	FX
	0	1	2	3	4	5	6	7	8	9	A	В	C	D	E	F	
	AN CHAIN – 1234567890#@/STUVWXYZ&,%JKLMNOPQR-\$*ABCDEFGHI+. □																
		SITIO															
			- 11									_				2223	
				123	456/8	AARC	UEFC	11 2 3	456	78 9A	BCDE	+01	234 5	6789	ABC	DEFC	)

PRINTER TRANSLATE TABLE (FOLDED, DUALED, BLOCK DATA CHECK) NON MCS CSL LOAD (REFER TO SECTION 1.14)

Figure 1-15. Auxiliary Storage Module 7

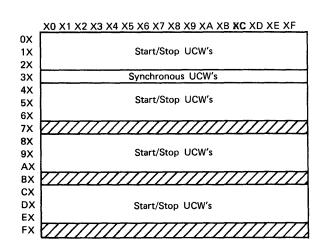


Figure 1-16. Auxiliary Storage Module 8

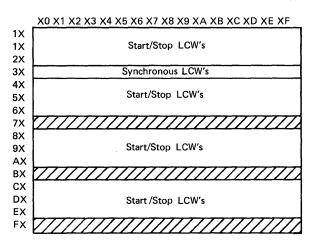


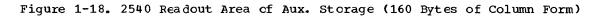
Figure 1-17. Auxiliary Storage Module 9

	BYTE	0	1	2	3	4	5	6	7	8	9	Α	В	С	D	Ē	F
	5 x 10	<b>.</b>								1U	1L	2U	2L	зU	3L	4U	4L
		5U	5L	etc												12U	12L
А		13U	13L													20U	20L
D		21U	21L													28U	28L
D		29U	29L													36U	36L
R		37U	37L													44U	44L
E		45U	45L													52U	52L
S		53U	53L													60U	60L
S		61U	61L													68U	68L
	Ļ	69U														76U	76L
	5 x B0	77U	77L	78U	78L	79U	79L	80U	80L								
	U = Upper half of a card column. L = Lower half of a card column.																

#### 1.3 2540 READER/PUNCH (FIGURES 1-18 THROUGH 1-23)

1U corresponds to data-record byte 1; 80L corresponds to data-record byte 160.

Hole patterns in a column:	•••			11 5	1 7	2 8	3 9
Correspond to bit patterns in	R0:	1	t	3 either		6 Iower	7



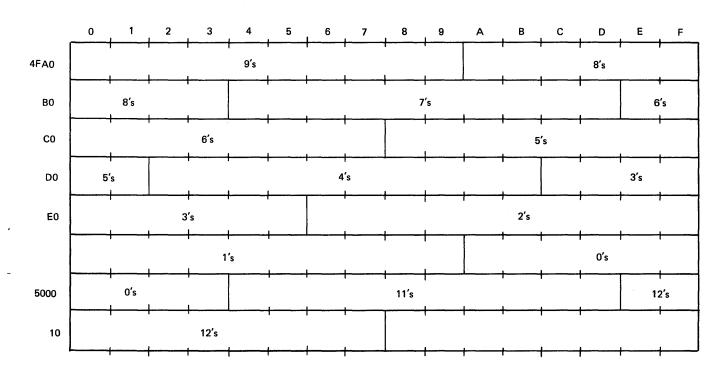
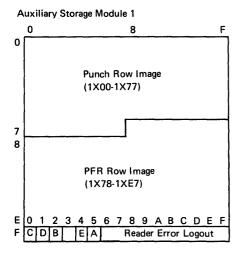


Figure 1-19. 2540 Reader Row Image, Auxiliary Storage

		0	1	2	3	4	5	6	7	8	9	A	В	с	D	E	F
	0	40	F1	F2	F3	F4	F5	F6	F7	FO	61	E2	E3	E4	E5	E6	E7
	1	60	D1	D2	D3	D4	D5	D6	D7	D0	A1	A2	A3	A4	A5	A6	A7
	2	50	C1	C2	СЗ	C4	C5	C6	C7	CO	81	82	83	84	85	86	87
	3	6A	91	92	93	94	95	96	97	70	B1	B2	В3	В4	B5	B6	B7
	4	F9	31	32	33	34	35	36	37	E9	21	22	23	24	25	26	27
	5	D9	11	12	13	14	15	16	17	A9	E1	62	63	64	65	66	67
	6	C9	01	02	03	04	05	06	07	89	41	42	43	44	45	46	47
TENS	7	99	51	52	53	54	55	56	57	B9	71	72	73	74	75	,76	77
Ē	8	F8	79	7A	7B	7C	7D	7E	7F	E8	69	EO	6B	6C	6D	6E	6F
	9	D8	59	5A	5B	5C	5D	5E	5F	A8	A0	AA	AB	AC	AD	AE	AF
	A	С8	49	4A	4B	4C	4D	4E	4F	88	80	8A	8B	8C	8D	8E	8F
	в	98	90	9A	9B	9C	9D	9E	9F	B8	BO	BA	BB	вс	BD	BE	BF
	с	38	39	3A	3B	3C	3D	ЗE	ЗF	28	29	2A	2B	2C	2D	2E	2F
	D	18	19	1A	1B	1C	1D	1E	1F	68	20	EA	EB	EC	ED	EE	EF
	E	08	09	0A	OB	0C	0D	0E	0F	48	00	CA	СВ	сс	CD	CE	CF
	F	58	10	DA	DB	DC	DD	DE	DF	78	30	FA	FB	FC	FD	FE	FF

Figure 1-20. 2540 Reader Translate Table, Auxiliary Storage--30xx

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"C" - Reader*Indicator Byte (10F0)	"D" - Sense* Indicator Byte (10F1)

Chain	Stkr	Stkr			Count			Cmd	Not		Equip	Val		Unusl	
Data	Sel	Sel		Read	Stor	Feed	WLR	Rej	Rdy		Check	Check		Cmd	
	1,2,3	1,2,3													
0	1	2	3	4	5	6	7	0	1	2	3	4	5	6	7

"в" -	Punch	Old	Stacker	(10F2)

	Sktr	Stkr					
	Sei	Sel					
	1,2,3	1,2,3					
0	1	2	3	4	5	6	7

"E" ·	"E" - Punch Indicator Byte (10F4)						"A" - Punch Sense Byte (10F5)								
Data		Stkr Sel 1,2,3		PFR Read	Count Stor	PFR Count		Cmd Rej	Not Rdy		Equip Check	Val Check		Unusl Cmd	
0	1	2	3	4	5	6	7	0	1	2	3	4	5	6	7

\* Reader and sense indicators reset on SIO decode (error).

Figure 1-21. 2540 Sense Indicator Bytes

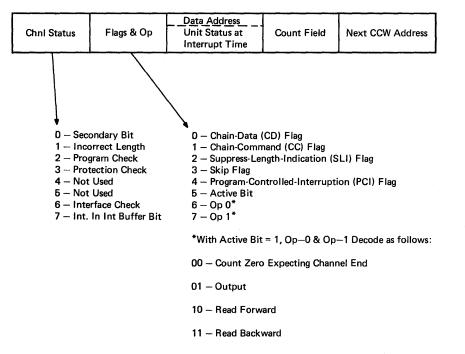
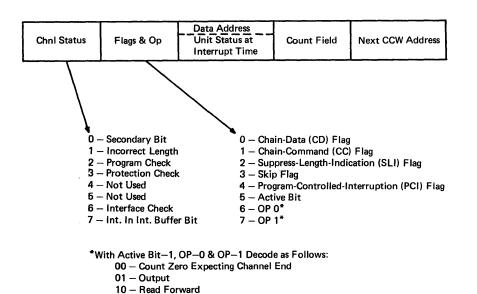
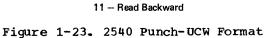


Figure 1-22. 2540 Reader-UCW Format





#### 1.4 STORAGE PROTECTION FEATURES (FIGURES 1-24 THROUGH 1-26)

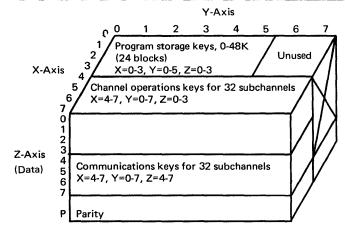


Figure 1-24. STP1 Allocations Map

				Y-Ax	is <sup>* *</sup>			
	0	_1	2	3	4	5	6*	7*
0	0000-	2000-	4000-	6000-	8000-	A000-	C000-	E000-
	07FF	27FF	47FF	67FF	87FF	A7FF	C7FF	E7FF
	0-2K	8-10K	16-18K	24-26K	32-34K	40-42K	48-50K	56-58K
1	0800-	2800-	4800-	6800-	8800-	A800-	C800-	E800-
	0FFF	2FFF	4FFF	6FFF	8FFF	AFFF	CFFF	EFFF
	2-4K	10-12K	18-20K	26-28K	34-36K	42-44K	50-52K	58-60K
<u>X-Axis</u> 2	1000- 17FF <b>4-</b> 6K	3000- 37FF 12-14K	5000- 57FF 20-22K	7000- 77FF 28-30K	9000- 97FF 36-38K	B000- B7FF 44-46K	D000- D7FF 52-54K	F000- F7FF 60-62K
3	1800-	3800-	5800-	7800-	9800-	8800-	D800-	F800-
	1FFF	3FFF	5FFF	7FFF	9FFF	BFFF	DFFF	FFFF
	6-8K	14-16K	22-24K	30-32K	38-40K	46-48K	54-56K	62-64K

\* These columns are shown for reference only. The storage locations represented are never used for program storage, and thus are not subject to the storage protection feature.

\*\* For systems with less than 48K bytes of program storage, the locations above the installed program storage are not protected.

Figure 1-25. STP1 Allocations for Program Storage

	0	1	2	3	4	5	6	7
4	00-07	20-27	40-47	60-67	80-87	A0-A7	C0-C7	E0-E7
	(1)	(5)	(9)	(13)	(17)	(21)	(25)	(29)
5	08-0F	28-2F	48-47	68-67	88-8F	A8-AF	C8-CF	E8-EF
	(2)	(6)	(10)	(14)	(18)	(22)	(26)	(30)
<u>X-Axis</u>	10-17	30-37	50-57	70-77	90-97	B0-B7	D0-D7	F0-F7
6	(3)	(7)	(11)	(15)	(19)	(23)	(27)	(31)
. 7	18-1F	38-3F	58-5F	78-7F	98-9F	B8-BF	D8-DF	F8-FF
	(4)	(8)	(12)	(16)	(20)	(24)	(28)	(32)

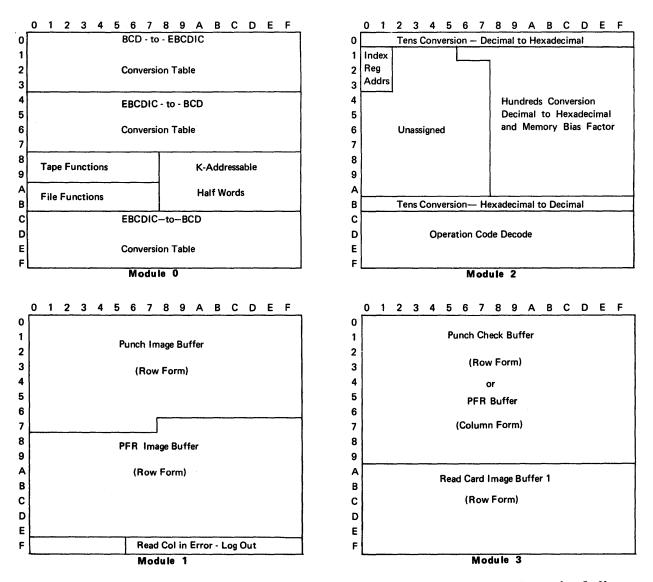
<u>Y-Axis</u>

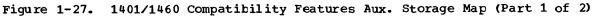
<u>Note</u>: For channel operations, bits 0-3 (Z-axis) are used for a maximum of 32 keys (shown in parentheses).

For communications channel operations, bits 4-7 are used for a maximum of 32 keys.

Figure 1-26. STP1 Allocations for Channel and Communications Channel Operation

#### 1.5 1400 COMPATIBILITY FEATURE (FIGURES 1-27 THROUGH 1-33)





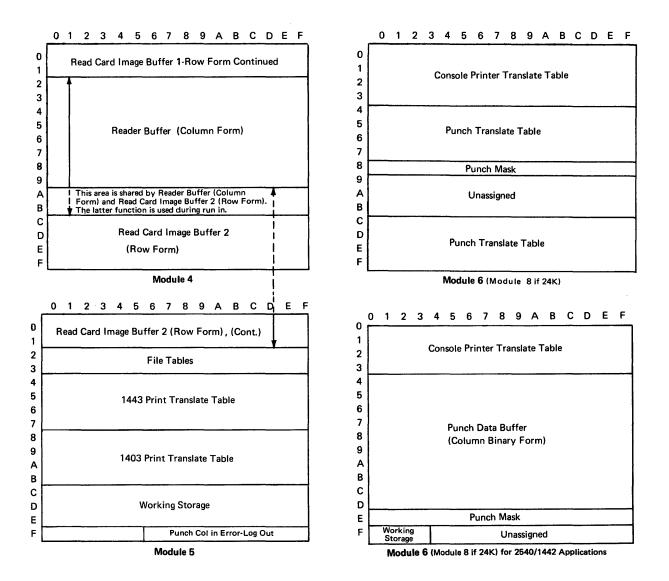


Figure 1-27. 1401/1460 Compatibility Features Aux. Storage Map (Part 2 of 2)

1.5.1 AUXILIARY STORAGE MODULE 0 (1400 COMPATIBILITY)

<u>Rows 0-3</u>; <u>BCD to EECDIC Conversion Table</u>: These 4 rows provide the constants for translating the 64 possible BCD configurations to the appropriate EBCDIC bytes.

Rcws 4-7 and C-F; EBCDIC to BCD Conversion Table: These 8 rows provide a 128 character table that contains a BCD code corresponding to each EBCDIC character. EBCDIC to BCD translation is required during the execution of instructions such as Bit Tests, Move Zone and Move Numeric.

Rows 8 and 9, Bytes 0 through 7; Tape Assignments: The utilization of the tape control and initial load bytes in auxiliary storage module 0 is as follows.

- ByteBitUse0Last Command Write or WTM
- 80 1-3 Last 1400 tape unit addressed (initialized to 000). 4-7 Tape Control Unit Address
- 81 0-1 Tape density for 1400-mode tape drive 1: 00=200 bpi on 7-track tape drive 01=556 bpi on 7-track tape drive 10=800 bpi on 7-track tape drive 11=9-track tape drive
  - 2 If on, a backspace was the last operation performed on 1400-mode tape drive 1 (initialized to 0).

3 If on, an end-of-file condition is outstanding on 1400-mode tape drive 1(initialized to 0).

Used internally
5-7 System/360 unit address assigned to be 1400-mode tape drive 1.

- 82-86 Same as byte 81, for 1400-mode tape drives 2 through 6.
- 87 Last status byte received from tape-control unit (initialized tc 40).
- 88-8F Refer to K-addressable halfwords.
- 90 Tape sense byte 0
- 91 Tape sense byte 1
- 92 Tape sense byte 2 (tape track in error)

Tape sense byte 3

93

94-95 Tape O-STAR backup location

96	0	Temporary command information
	1	1400 tape drive 1 EOF-block bit
	2	1400 tape drive 2 EOF-block bit
	3	1400 tape drive 3 EOF-block bit
	4	1400 tape drive 4 EOF-block bit
	5	1400 tape drive 5 EOF-block bit
	6	1400 tape drive 6 EOF-block bit
	7	Temporary command information
97		MCS control; Print Character Counter Length (PCCL) Bit significance
	0	Unassigned
	1	240 character
	2	120 character
	3	80 character
	4	60 character
	5	48 character
	6	40 character
	7	16 character

Rows A and B, bytes 0 through 7 are used for disk file functions:

<u>Byte</u>	<u>Bit</u>	Compatibility Mode Use
A0-A1		1400 Drive-0 Assignment
A0	0-3 4-7	Must be set to 0000 Modular addresses 0 to 19,999=0000 Modular addresses 20K to 39,999=0010 Modular addresses 40K to 59,999=0100 Modular addresses 60K to 79,999=0110 Modular addresses 80K to 99,999=1000
A1	0-3	System/360 File Select Addresses: File 0=1000 File 1=0100 File 2=0010 File 3=0001
	4-5 6 7	Not used Compare Disable. 6=0; compare disable is inactive. A successful address compare on a 1400-series indelible address (I/A) must occur before an I/A read or write can be executed. 6=1; compare disable is active. Read or write with I/A is executed without first doing an address compare on the 1400-series indelible address. This bit should be set to 1 only when initializing a disk pack in 1400 mode. Module overflow detection. 7=0; module overflow detection is active. The 1400-program

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	dis aga pro If a d dis Une Co: se loo de	dule value, within each sk-control field, is compared ainst a module value that is esent in auxiliary storage. the module values disagree, coded stop occurs with 60 splayed. In addition, equal Address Compare is set. rrect module values must be t in auxiliary storage 0 cations A0, A2, etc. 7=1; module-overflow tection is inactive. (Most er applications set bit 7 to		9D	<pre>Forms command 1403 Printer (Integrated Attachment Only) 1 On Channel (Integrated Attachment Only) 2 3 4 Go to Set Up after Rmt/Rst (Integrated Attachment Only) 5 From General Stop Loop (Integrated Attachment Only) 6 Last CMD Skip or Spc Sup. 7 Forms After Cmd</pre>
1400 0	drives 2,	A6-A7 and B6-B7 represent 4, 6, and 8 respectively.	К7	9E 9F	Reader-1 address Reader-2 address
format	t as A0-A1 e-overflow e A1 byte. Dis	llow the same structure L. Compare disable and w detection need only be set sk Error information for agnostic use.	K8	84	0 Sense switch A (last card) 1 Sense switch B 2 Sense switch C 3 Sense switch D 4 Sense switch E 5 Sense switch F 6 Sense switch G 7 Sense switch b for sense and be a
<u>K-add</u> K-add stora 1401/:	r <u>essable</u> 1 ressable 1 ge module	B. Pytes 8 through F. Halfwords: The 16 halfwords of auxiliary 0 are used as follows for 1440 compatibility mode.		A9	7 Sense switch A for second serial reader punch 0 High-compare result (U) 1 Unequal-compare result (/) 2 Low-compare result (T) 3 Equal-compare result (S) 4 Inquiry clear indicator (*) 5 Overflow indicator (Z) 6 Inquiry request indicator
К0	88-89	Bias constant. Refer to Figure 1-30 for correct value.			(ç) 7 Not used
K1 K2 K3 K4	8A-8B 8C-8D 8E-8F 98-99	Working storage B-STAR backup for local storage V0,V1 A-STAR backup for local storage U0,U1 Working storage	К9	ΑΑ	<pre>0 Not move or load instruction (PR-KB) 1 H-Typehead installed (PR-KB) 2 Secondary bit (PR-KB) 3 Load mode (PR-KB) 4 Stop message being performed (PR-KB) 5 Reader error 6 Punch error 7 Printer error</pre>
K5	9 <b>A-9</b> B	Working storage		AB	Unassigned
к6	9C (Integ 0 1 2 3 4 5 6 7	grated Attachment Printer) 132 print position 1403 Channel 9 Channel 12 Invalid channel Secondary bit Device end Print wordmark operation Printer error	KA	AC AD	<pre>0 48K* 1 24K, 32K* 2 16K, 32K, or 48K* 3-7 Initialized to 1*  *High-order byte of highest  storage address  initialized to 3F,5F,7F,  or BF. 1442/1443 Status 0 Skip GMWM check</pre>
K6	0 1 2	nel Attached Printer) 132-position 1403; or greater than 120 positions if 1443. Channel 9 Channel 12 7 Device address			<ol> <li>Skip GAWA Check</li> <li>Channel end only</li> <li>Last card on</li> <li>Column binary mode</li> <li>Print operation</li> <li>Output command</li> <li>6-7 00=R/W, 01=Test I/O, 10=Sense, 11=Control</li> </ol>

KΒ	AE AF	0-7 0 1 2 3 4 5 6 7	Previous file operation Read back check interlock Recalibrate sequence bit Unequal-address compare (X) Access busy (\) Wrong-length record (W) Any disk err condition (Y) Disk error (V) Not ready (N)	KD	BB	0 1 2 3 4 5	0=0 tape drive 0=800 bpi density 0=11600 bpi 1=0 tape drive 1=800 bpi density 1=11600 bpi 2=0 tape drive 2=800 bpi density 2=11600 bpi 3=0 tape drive 3=800 bpi density 3=11600 bpi 4=0 tape drive 4=800 bpi density 4=11600 bpi
ĸĊ	Β8		<pre>I/O check-stop switch Not used Expanded print-edit feature Period-corma inversion (World Trade only) Column binary feature No punch huffer Model-G emulation 51-column cards ge of bits 5, 6, and 7 when</pre>	1.5.2	AUXIL	6 7 Worl	5=0 tape 5=800 bpi density 5=11600 bpi 6=0 tape drive 6=800 bpi density 6=11600 bpi 7=0 tape drive 7=800 bpi density 7=11600 bpi king Storage STORAGE MODULE 1 (1400
	B 9	usi: 5 6 7 0 1 2 3 4 5	ng 2540 as 1442: Simulate read and punch in same card Select read-error card to pocket R2 Use 2540 as 1442 Alternate read mode 120-print position printer Tape erase (initialized off) Alternate 9-track tape Temporary Status Channel printer Sterling feature (World Trade only)	Rows for Rows Row F err 1.5.3 COMPA <u>Row 0</u> provid BCD t	m) 7(8)-E : (F6 ors. AUXIL: TIBILI ; Tens des ten	: Pu : Pi -FF) LARY TY) <u>Conv</u> ns co IC.	Unch Image Buffer, (row FR Image Buffer, (row form) Logout area for card read STORAGE MODULE 2 (1400 Version Constants: This row onversion for translating OA through OF contain alues.
KD	BA	0 1 2 3 4 5 6 7	System/360 tape drive 0 is a 9-track unit System/360 tape drive 1 is a 9-track unit System/360 tape drive 2 is a 9-track unit System/360 tape drive 3 is a 9-track unit System/360 tape drive 4 is a 9-track unit System/360 tape drive 5 is a 9-track unit System/360 tape drive 6 is a 9-track unit System/360 tape drive 7 is a 9-track unit	Regis give for t respe Rows and B this the 1 the s Entry hundr Thus, hundr simul exten trans Row B Table	ter Add the add he tens ctively <u>1-A, By</u> ias Con table a 401/140 ize of into t eds and the r eds, th taneous sion of late th ; Hexad : Thi:	tes tress tress tress tress tress the the tress the tress the tress the tress	3; Bytes 0 and 1; Index <u>ses</u> : These three halfwords ses for the index registers aracter zones A, B, and AB <u>8-F; Hundreds, Thousands</u> <u>sicn Table</u> : The values in letermined by the sizes of r 1440 being emulated and 2025 program storage area. table is according to ndreds zones (thousands). t from the table solves ands, and bias translation The halfword at 16 is an e table and is used to character. <u>mal-to-Decimal Conversion</u> w gives the decimal
				equiv value		of th	ne second crder hex digit

Rows C through F; Operation Code Decode Table: These four rows provide the translation of 1401/1460 and 1440 operation codes to a bit significant form that is usable by the 2025. In the chart (Figure 1-28), the 1400-series op-code is shown in parentheses. Code 34 is used to indicate an invalid 1400-series op-code. Code 06 is used to indicate a No-op.

1.5.4 AUXILIARY STORAGE MODULE 3 (1400 COMPATIBILITY)

- Rows 0-9: Punch Check Buffer (rcw form) or PFR Buffer (column form).
- Rows A-F: Read Image Buffer 1 (row form). Partial; remainder of buffer area is in module 4, rows 0 and 1.

1.5.5 AUXILIARY STORAGE MODULE 4 (1400 COMPATIBILITY)

Rcws 0-1: Read Image Buffer 1 (row form) continued from module 3. Rcws 2-B: Reader Buffer (column form).

Rcws A-F: Read Image Buffer 2 (row form). Partial; remainder of buffer is in module 5, rows 0 and 1. Rows A and B are shared with the column form buffer.

1.5.6 AUXILIARY STORAGE MODULE 5 (1400 COMPATIBILITY)

Rcws 0 and 1: Read Image Buffer 2 (row form). Continued from module 4.
Rcws 2 and 3: Disk File Tables, conversion tables for cylinder and head decode, file cp-code conversion, etc.
Rows 4-7: 1443 Translate Table
Rcws 8-B: 1403 Translate Table
Rcws C-E: Working Storage
Row F: (F6-FF) Logout area for card punch errors.

1.5.7 AUXILIARY STORAGE MODULE 6 (8 IN 24K SYSTEMS--1400 CCMPATIBILITY)

Rows 0-3: Console Printer Translate Table Rcws 4-7: Punch Translate Table Row 8: Punch Mask Rcws 9-B: Unassigned Rows C-F: Punch Translate Table.

- Differences for 2540/1442 applications: Rows 4-D: Punch Data Buffer (column binary form) Row E: Punch Mask
- Row F: Working Storage and Unassigned.

1.5.8 LOCAL STORAGE (1400 COMPATIBILITY)

The 64-byte local storage is divided into six zones that are used in the same general manner in the 1400 mode as in System/360 mode.

Zone	0,	CPU Mode;	16 bytes
Zone	1,	2311 Mode;	8 bytes
Zone	4,	Backup area;	16 bytes
Zone	5,	Undefined;	8 <b>bytes</b>
Zone	6,	2540 Mode;	8 bytes
Zone	7.	Channel Mode;	8 bytes

Local storage is used when operating in 1401/1460 or 1440 compatibility mode for intermediate storage for factors unique to this mode of operation. Example: I-STAR, A-STAR, B-STAR, Op-register and A-register. In addition, local storage is used for problem-program factors and microprogram factors, Also, data stored in local storage is used by control words to perform some problem-program functions.

1.5.8.1 Zone 0 (1400 Compatibility)

Zone 0 is addressed when the Model 25 is operating in CPU mode. There are 16 bytes within the zone-0 area addressed by X-lines 0-7 and Y-lines 0 and 1. Not all bytes have assigned functions.

#### AS/BS

30 (50

<u>Decode</u>	Sym	X	Y	Assigned Function
0	UÖ	0	0	A-Address Register
1	U1	1	0	A-Address Register
2	V0	2	0	B-Address Register
3	V1	3	0	B-Address Register
4	G0	4	0	Working Register
5	G1	5	0	Op-Register
6	D0	6	0	Status Indicators
7	D1	7	0	A-Register
8	<b>I</b> 0	0	1	I-Address Register
9	<b>I1</b>			I-Address Register
A	тО	2	1	Working Register
в	т1	3	1	Working Register
С	Р0	4	1	Working Register
D	P1	5	1	Working Register
Е	нО	6	1	Working Register
F	H <b>1</b>	7	1	Working Register

#### 1.5.8.2 Zone 1 (1400 Compatibility)

Zohe 1 is addressed when the Model 25 is operated in 2311 mode. There are 8 bytes within the zone-1 area addressed by X-lines 0-7 and Y-line 2, as follows.

AS/BS				
Decode	Sym	X	Ϋ́	Assigned Function
8	10	0	2	Count Register
9	11	1	2	Count Register
А	тО	2	2	Data Address Register
В	т1	3	2	Data Address Register
С	Р0	4	2	
D	P1	5	2	
$\mathbf{E}$	HO	6	2	
F	H1	7	2	

#### 1.5.8.3 Zone 4 (1400 Compatibility)

Zone 4 is used as the backup area for all modes of operation except 2311 mode. There are 16 bytes within the zone-4 area addressed by X-lines 0-7 and Y-lines 3 and 4.

For the CPU mode operation the backup area can be addressed by setting mode register bits 5, 6, and 7 to 1,0,0. For operation in 2540 or channel mode (MMSK bits 0, 2, 3, or 4 on), the low-order 8 bytes of zone 4 can be addressed. None of the bytes of the backup area can be addressed when operating in 2311 mode (MMSK bit 1 on).

All 16 bytes of the backup area can be addressed manually by console switches C and D. Assignments are as follows.

#### AS/BS

HOLPO				
<u>D e corde</u>	<u>Sym</u>	X	Ϋ́	Assigned Function
0	<b>U</b> 0	0	4	High-order Level-1 Backup
				addr
1	U1	1	4	Low-order Level-1 Backup
				addr
2	<b>V</b> 0	2	4	High-order Level-2 Backup
				addr
3	<b>V1</b>	3	4	Low-order Level-2 Backup
				addr
4	G 0	4	4	High-order Level-3 Backup
				addr
5	G1	5	4	Low-order Level-3 Backup
				addr
6	D0	6	4	High-order Machine-Check
				Backup Addr
7	D1	7	4	Low-order Machine-Check
				Backup Addr
8	I 0	0	3	High-order CPU Branch and
				Link Backup Address
9	<b>I1</b>	1	3	Low-order CPU Branch and
				Link Backup address
A	то			Spare
в	<b>T1</b>	3		Spare
С	Р0	4	3	Workarea
D	P1			Workarea
E	HO			Workarea
F	Н1	7	3	Workarea

#### 1.5.8.4 Zone 6 (1400 Compatibility)

Zone 6 is addressed when cperating in 2540 mode (MMSK bits 3 or 4 cn). There are eight bytes in the zone-6 area addressed by X-lines 0-7 and y-line 6. Also, zone 6 can be addressed when in CPU mode by setting the mode register bits 5, 6, 7 to 1, 1, 0 respectively.

#### AS/BS

Decode	Sym	X	Y	Assigned Function
0	U0	0	6	Reader Image Buffer Address
1				Reader Image Buffer Address
2	<b>V</b> 0	2	6	Punch Image Buffer Address
3	V1	3	6	Punch Image Buffer Address
4	G <b>0</b>	4	6	Reader/Punch Status
5	G <b>1</b>	5	6	Stacker-Select Information
6	D0	6	6	Punch Count
7	D <b>1</b>	7	6	Read Count

#### 1.5.8.5 Zone 7 (1400 Compatibility)

Zone 7 is address when operating in channel mode (MMSK bits 0 or 2 on). There are 8 bytes in the zone-7 area addressed by X-lines 0-7 and Y-line 7. The functional assignments for these bytes are:

AS/BS				
Decode	Sym	X	Y	Assigned Function
0	U0		7	
1	U1	1	7	
2	<b>V</b> 0	2	7	Data Address Register
3	V1	3	7	Data Address Register
4	G0	4	7	-
5	G1	5	7	Data Register
6	D0	6	7	Status Register
7	D1	7	7	Word Secarator

Sequ	uence of Operation for Combination Operations Is Print, Read, and Punch
1400 Operation	
Read ( <u>1</u> )	Starts as 21, and during read ending routine (LRDR) is changed to 20. In case of error (and the I/O Stop switch is on,) the code remains 21 and display stop occurs.
Print ( <u>2</u> )	Starts as 22 and is reset to 00 at the end of the normal print routine (MPRT) before return to LOPD and ICYC.
Print, Read ( <u>3</u> )	Starts as 23 and is changed to 21 at end of the print routine. Routine branches back to ICYC VALADR 0, is decoded as a 1 Op and executed.
Punch ( <u>4</u> )	Starts as 24 and is changed to 20 during punch ending routine (LPCH).
Punch Col Bin (4C)	In case of error, code remains 24 and a display stop occurs.
Read, Punch ( <u>5</u> )	Starts as 25 and is changed to 24 at read ending (LRDR). In case of error (with I/O Stop switch on) code remains 25 and display stop occurs. No error routine branches back to LOPD, performs punch op and is changed to 20.
Print, Punch ( <u>6</u> )	Starts as 26 and is changed to 24 at end of Print routine. Routine branches back to ICYC VALADR 0 and is decoded as a punch op. Operation is then the same as a 4 op and is changed to 20 at the ending.
Print, Read, Punch ( <u>7</u> )	Statts as 27, changes to 25 at end of print operation. 25 causes a read op, at end of read op code changes to 24 and causes a punch op. At end of punch op, code changes to 20. All error limitations for the various operations apply.
Punch Feed Read ( <u>4</u> R)	Starts as 24. The d-modifier causes the op code to change to A4, then a normal punch routine is started. At the end of the punch routine the code is changed to 28 and a punch feed read operation is performed. At end op code changes to 20.
Read Column Binary ( <u>1</u> C)	Starts as 21. Changes to 20 during read ending routine (RDREND). Error handling same as for Read op. (Validity not checked.)

Figure 1-28. Op-Code Information (1400 Compatibility)

4567	WI 1 0123 -		RDMA	RK	N	) wof	RDMAF	Rκ	wi	гн wo	RDMA	RK	N	) WOR	DMAF	к
4507	0123	<b></b>	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
0000	Blank	&	-		Blank	&			?	I	‡	0	?	1	+	0
0001			/				1		A	J		1	Α	J		1
0010									В	к	S	2	В	к	S	2
0011									С	L	Т	3	С	L	Т	3
0100									D	М	U	4	D	М	U	4
0101								E	N	V	5	E	N	V	5	
0110									F	0	W	6	F	0	W	6
0111									G	Р	X	7	G	Р	X	7
1000									н	Q	Y	8	н	۵	Y	8
1001									1	R	Ζ	9	1	R	Z	9
1010				ъ				ð								
1011		\$		#	•	\$	•	#								
1100	ц	*	%	0	п	*	%	@								
1101			v	:		J	V	:								
1110	<			>	<	;		>								
1111	ŧ	Δ	+++	<b>v</b>	ŧ	Δ	+#	<b>v</b>								

Figure 1-29. 1400 Defined Characters

	0	1	2	3	4	5	6	7	8	9	Α	В	С	D	E	F
с	(?)	(A)	(B)	(C)	(D)	(E)	(F)		(H)			(•)	(□)			
Ŭ	1C	18	ОВ	1 F	12	16	2A	34	B1	34	34	02	15	34	34	34
D	(!)		(K)	(L)	(M)	(N)		(P)	(Q)							
U	1D	34	29	90	80	06	34	1E	F1	34	34	34	34	34	34	34
Е		(/)	(S)		(U)	(V)	(W)		(Y)	(Z)		(,)	(%)			
-	34	05	19	34	20	0E	0F	34	13	17	34	04	1B	34	34	34
F		(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)	(9)		(#)	(@)			
•	34	21	22	23	24	25	26	27	06	06	34	14	1A	34	34	34

#### Notes:

- 1. The 1400-series operation code is shown in parentheses.
- 2. The code 34 is used to indicate an invalid 1400-series operation code.
- 3. The code 06 is used to indicate a No Op (no operation).
- 4. Notice that several 1400-series special features, such as Branch if Bit Equal (W op code), Divide (% op code), etc. are standard with the compatibility feature. These 1400-series operations can be made invalid by inserting the invalid code (34) in the corresponding table location, if desired.

## Figure 1-30. 1400 Operation-Code Decode Table

F
3F
2F
1F
0F
5C
5D
56
5F

Figure 1-31. EBCDIC-to-BCD Translate Table (1400)

25 1400	16,3	384	24,5	576	32,7	68	49,1	52
	Bias Constant	File Table	Bias Constant	File Table	Bias Constant	File Table	Bias Constant	File Table
16K	0180	0000	2180	2000	4180	4000	8180	8000
12K	1120	1000	3120	3000	5120	5000	9120	9000
8К	20C0	1F00	40C0	3F00	60C0	5F00	A0C0	9F00
4K	3060	2F00	5060	4F00	7060	6F00	B060	AF00
2К	3830	3700	5830	5700	7830	7700	B830	B700
1.4K	3A88	3900	5A88	5900	7A88	7900	BA88	в900

Bias Constant: Located in byte 88-89, (K0) in Module 0.

File Table Address: Developed from bias constant during file routine.

Figure 1-32. Storage Bias Constant Values and File Table Addresses (1400 Compatibility)

	6	7	8	9	Α	В	С	D	Е	F
1X	B+(	044C	B+	OBB8	B+(	07D0	B+(	03E8	B+	0000
2X			B+	0C1C	B+(	0834	B+(	044C	B+	0064
3X			B+	0C80	B+(	0898	B+(	04B0	B+	8000
4X			B+	OCE4	B+0	08FC	B+(	0514	B+	012C
5X			B+	0D48	B+0	0960	B+(	0578	B+	0190
6X			B+	ODAC	B+(	09C4	B+0	05DC	B+	01F4
7X			B+	0E10	B+(	DA28	B+0	0640	B+	0258
8X			B+	0E74	B+(	DA8C	B+(	06A4	B+	02BC
9X			B+	0ED8	B+(	DAFO	B+(	0708	B+	0320
AX			B+	0F3C	B+(	DB54	B+0	076C	В+	0384

### AUXILIARY STORAGE MODULE 2

Note: B=Halfword bias constant in K0 (Module 0; 88-89) See previous figure for value.

Hundreds/Thousands/Bias Conversion

#### AUXILIARY STORAGE MODULE 2

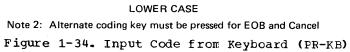
0 1 2 3 4 5 6 7 8 9 A B C D E F 0X000A141E28323C46505A010101010101

**Tens Conversion** 

Figure 1-33. Decimal-to-Hex Conversion Tables (1400 Compatibility)

# 1.6 PR-KB (PRINTER-KEYBOARD) FIGURES 1-34 THROUGH 1-38

BCI	DE	Bits			A	В	ва			A	В	ВА	characte	board code rs are sent PU in 8-bit follows.
				Space	@	-	&		Space	¢		+	Bus-In	КВ
			1	1	1	j	а		=	?	J	А	Bits 0 1	Bits x x X Note
		2		2	s	k	ь		<	S	к	в	2 3 4	B 1 A 8
		2	1	3	t	I	с		;	Т	L	° y C	5 6 7	4 2 1
	4			4	u	m	d		:	U	м	D	Note 1: x = 1	Uppercase
	4		1	EOB 5 Note 2	v	n	е		%	v	N	E	x = 1 ) x = 0 )	
	4	2		6	w	о	f			w	0	F	x = 0 }	Lowercas
	4	2	1	7	×	p	g		>	x	Р	G		
8				8	У	q	h		*	Y	٥	н		
8			1	9	z	r	i		(	z	R	I		
8		2		Cancel 0 Note 2					)					
8		2	1	#	,	\$				I	!			
8	4													
8	4		1			NEW LINE					NEW LINE			
8 4	4	2		UPPER CASE SHIFT			LOWER CASE SHIFT		UPPER CASE SHIFT			LOWER CASE SHIFT		
8	4	2	1											
				L	.OWER CA	ASE		-		UPPE	R CASE			



1-30 (7/69)

4567: 🗖															_	
0000	sp	&	-		sp	&	-	-	@	&	. 1	0	%	>	?	0
0001	sp	n	/	8	sp	n	1	8	а	j	/	1	А	J		1
0010	sp	0	b	,	sp	0	b	,	b	k	S	2	В	ĸ	S	2
0011	sp	0	s	#	sp	0	S	#	С	I	t	3	С	۰L	Т	3
0100	sp	2	@	@	sp	2	@	@	d	m	u	4	D'_	М	U	A
0101	sp	NL	/	8	sp	5	1	8	е	n	v	5	Е	N	` V -	5
0110	sp	6	k	#	sp	6	k	#	f	0	w	6	F	0	W	6
0111	sp	6	S	#	sp	6	S	#	g	р	×	7	G	Р	Х	7
1000	h	q	У	У	н	٥	Y	Y	h	q	У	8	н	Q	Y	8
1001	i	r	z	9	i	r	z	9	i	r	z	9		R	Z	9
1010		\$		,	¢	!	¢	:	@	\$	-	0	%	>	?	0
1011		\$		#		\$	,	#		\$	,	#	¢	1	:	#
1100	3	7	@	@	<	*	%	@	е	n	u	4	E	Ν	υ	4
1101	1	5	/	8	(	)		'	е	n	v	5	E	Ν	V	5
1110	2	6	&	#	+	;	>	=	е	р	u	6	E	Р	U	6
1111	0	4	-	9	1		?	"	е	n	v	5	E	N	V	5

EBCDIC Bits 0123: Bits 0000 0001 0010 0011 0100 0101 0110 0111 1000 1001 1010 1011 1100 1101 1110 1111

Note: Blocked areas show normal decoded Characters using 1052 keyboard Input

.

Figure 1-35. EBCDIC Output with Resulting PR-KB Graphics

1-32 (7/69)

Figure 1-36.

Tilt/Rotate

Code

(PR-KB)

	EBCDIC							Upper	1	EBCDIC							Uppe
Char	Hex	T1	Т2	R5	R2A	R2	R1	Case	Char	Hex	T1	T2	R5	R2A	R2	R1	Case
¢	4A	0	0	0	0	0	0	1	f	86	0	0	0	1	ο	0	0
	4B	0	0	0	0	0	0	0	g	87	0	0	1	1	0	0	0
<	4C	1	1	1	1	1	0	1	h	88	0	0	1	0	0	1	0
Ċ	4D	1	1	1	1	1	1	1	i	89	0	0	0	0	0	1	0
+	4E	1	1	0	1	1	0	1	j j	91	1	0	1	1	1	1	1
1	4F	1	1	0	1	1	1	1	k	92	1	0	0	1	1	0	0
&	50	1	0	0	1	1	1	0		93	1	0	1	1	1	0	0
!	5A	1	0	0	0	0	0	1	m	94	1	0	0	1	0	1	0
\$	5B	1	0	0	0	0	0	0	n	95	1	0	1	1	0	1	0
*	5C	1	1	1	1	0	0	1	0	96	1	0	0	1	0	0	0
)	5D	1	1	1	1	0	1	1	р	97	1	0	1	1	0	0	0
;	5E	1	1	0	1	0	0	1	q	98	1	0	1	0	0	1	C.
÷	5F	1	1	0	1	0	1	1	r	99	1	0	0	0	0	1	0
_	60	0	1	0	1	1	1	0	s	A2	0	1	0	1	1	0	0
1	61	0	1	1	1	1	1	0	t	A3	0	1	1	1	1	0	0
;	6B	0	1	0	0	0	0	0	u u	A4	0	1	0	1	0	1	0
%	6C	0	0	0	1	1	1	1	v	A5	0	1	1	1	0	1	0
_	6D	0	1	1	1	1	1	1	w	A6	0	1	0	1	0	0	0
>	6E	1	0	0	1	1	1	1	×	A7	0	1	1	1	0	0	0
?	6F	0	1	0	1	1	1	1	y y	A8	0	1	1	0	0	1	0
:	7A	0	1	0	0	0	0	1	z	A9	0	1	0	0	0	1	0
#	7B	1	1	0	0	0	0	0	0	F0	1	1	0	1	1	1	0
@	7C	0	0	0	1	1	1	0	1	F1	1	1	1	1	1	1	0
▼	7D	1	1	1	0	0	1	1	2	F2	1	1	0	1	1	0	0
=	7E	1	1	0	0	0	0	1	3	F3	1	1	1	1	1	0	0
"	7F	1	1	0	0	0	1	1	4	F4	1	1	0	1	0	1	0
а	81	0	0	1	1	1	1	0	5	F5	1	1	1	1	0	1	0
b	82	0	0	0	1	1	0	0	6	F6	1	1	0	1	0	0	0
с	83	0	0	1	1	1 -	0	0	7	F7	1	1	1	1	0	0	0
d	84	0	0	0	1	0	1	0	8	F8	1	1	1	0	0	1	0
e	85	0	0	1	1	0	1	0	9	F9	1	1	0	0	0	1	0

Note: For alphabetic characters, only the lowercase is shown. The tilt/rotate code for an uppercase alphabetic character is the same as the corresponding lowercase character.

Table		EBCDIC	Table	1	EBCDIC
Addr	Char	Hex	Addr	Char	Hex
				<u> </u>	
50B8	Space	40	D8	_	6D
B9	=	7E	D9	J	D1
BA	<	4C	DA	к	D2
BB	;	5E	DB	L	D3
BC	:	7A	DC	м	D4
BD	%	6C	DD	N	D5
BE	'	7D	DE	0	D6
BF	>	6E	DF	Р	D7
со	*	5C	EO	Q	D8
C1	(	4D	E1	R	D9
C2	)	5D	E2	\$	5B
C3	"	7F	E3	!	5A
C4	Space	00	E4	-	60
C5	Space	00	E5	New Line	15
C6	0	FO	E6	BKSP	16
L				(Not used)	
C7	#	7B	E7	Space	00
C8	¢	4A	E8	+	4E
C9	?	6F	E9	A	C1
CA	S	E2	EA	В	C2
СВ	Т	E3	EB	С	C3
CC	U	E4	EC	D	C4
CD	V	E5	ED	E	C5
CE	W	E6	EE	F	C6
CF	х	E7	EF	G	C7
D0	Y	E8	F0	н	C8
D1	Z	E9	F1	]	C9
D2	,	6B	F2	<u> </u>	4B
D3		4F	F3		5F
D4	@	7C	F4	&	50
D5	LF	25	F5	H. Tab	05
	(not used)			(not used)	
D6	Space	00		1	
00					

Figure 1-37. PR-KB Translate Table (Keyboard Code to EBCDIC)

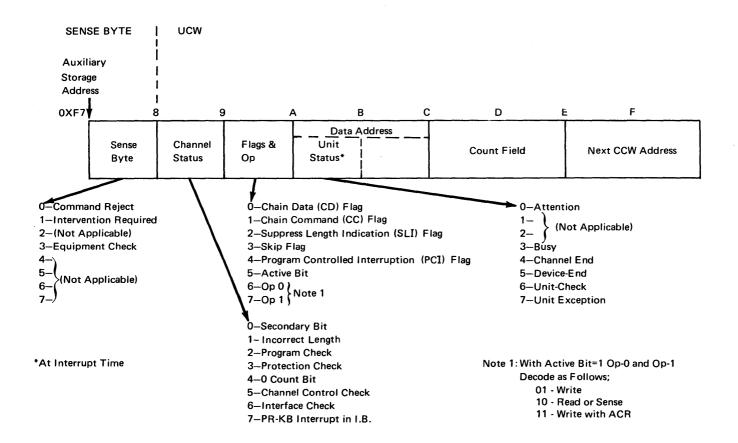


Figure 1-38. PR-KB Sense Byte and Unit Control Word -- UCW Format

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## 1.7 CONTROL WORDS (MICRO) FIGURES 1-39 THROUGH 1-46

	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
Set/Reset	0	0	R e s t / S e	K H i g h	CS-F	ield			K-L	ow			K-H	igh		0
Arithmetic/	0	0	t CD-	0	0	1	2	3	0	1	2	3		2	3	
Constant.	0	U	FId 0	1	AS-1	ield 1	2	3	К-F	iela 1	2	. 3	CC-F	- ield 1	2	1
Storage	0	1	RCS RAS SCS SAS	5		Field	2	B y t e S e l e c t		-ield	2	M a i n S t o r		Field		0
					0	1	2	3	0	1	2		0	1	2	
Move/ Arithmetic	0	1	CD- Fld 0	1	AS-F	<sup>-</sup> ield 1	2	3	BS-F	ield	2	3	CC-F	ield	2	1
Branch	1	0	RPO						RP1							0
Unconditional			2	3	4	5	6	7	0	1	2	3	4	5	6	
Branch on Mask	1	0	Masi 0	< 1	AS-F	Field S T / X		3	L S / E x t	RP1	2	0	RPO 5	6	7	1
Branch on Condition	1	1	BC- Fld	1	AS-F	s T X		3	L S / E x t	RP1	2	3	4	5	6	T e s t

Figure 1-39. Control-Word Alignment

Figure		ORD /PE		к нідн		SET/RST	SOURCE	FIELD		BS	OURCE OF	RKLOW	FIELD			K HIGH	FIELD	
n	0	1	2	3	4	5	6	7		8	.9		10.	11	12	13	14	15
1-40. Set/Reset Word (Word Type 0)	0	0	0 = RST 1 = SET WHE WOI	K HIGH O BIT	0000 = 0010 = 0100 = 0110 = 1000 = 1001 = RP 1011 = DI 1011 = DI 1011 = GA 1100 = DI 1101 = RP 1101 = FI 1101 = RP 1101 = CS 1101 = GE 1110 = FII 1111 = CP 1111 = FII 1111 = FII 1111 = FII 1111 = FII 1111 = CO 1111 = GC K REGISTEF DINDICATES	S REGIS MMSK R MODE F BC FAC DR REG DD F AB F AB F AC F AA F AA F AA F AA F AA F AA F A F A F	ACILITY ACILITY	ALL MODE	5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5	WHEN M OR RI B S 0000 = U 0010 = V 0100 = G 0110 = D 1000 = I 1010 = T 1100 = P 1110 = H WHEN U BIT 8 = F BIT 10 = BIT 11 = BIT 11 =	MSK ADDF ETURN FU OURCE DE LOCAL STO REGISTEF REGISTEF REGISTEF REGISTEF REGISTEF SED AS TH K LOW BIT K LOW BIT K LOW BIT	RESSED NCTION ECODES ORAGE R R R R R R R R R R R R R R R T 2 T 2 T	FOR A I, THE ARE F(	LINK	1 BIT	2 BIT	3 BIT	0

rıgure 1-40. Set/Reset Word (Word Type 0)

WQI TYF			CTION CODE		A-SOURCE	FIELD			FIEL	2			FUNCTIC			WOF TYP
0	1	2	3	4	5	6	7	8	9	10	11	12	13	14		1
0	0				$\begin{array}{rcrcrc} 0000 & = \\ 0001 & = \\ 0010 & = \\ 0010 & = \\ 0100 & = \\ 0111 & = \\ 0111 & = \\ 1000 & = \\ 1001 & = \\ 1011 & = \\ 1101 & = \\ 1101 & = \\ 1111 & = \\ 1111 & = \\ \end{array}$	V0 V1 G0 G1 D0 D1 I0 T0 T1 P0 P1			0000 0001 0010 0011 0100 0101 0111 1000 1001 1010 1011 1100 1101 1110	-		00 01 10 10 11 11 11 00 00 01 01 10 10	$\begin{array}{cccccccccccccccccccccccccccccccccccc$	Α*-КL Α*-КН Α*-КК Α + КН Α Α Ι ΚΙ Α Α Ι ΚΙ	- - - - -	1
		0 1 1 1 1 1 1 1 1 1 1 1 1 1	1 0 0 0 0 0 0 0 0 0 0 0 1 1 1 1 1	WORD THE AND 1 LISTE AND 1 THE AND 1 THE *-	E FUNCTIO BITS 2, 3, E -A- SYMBO 4 CAN BE A D UNDER T E SYMBOL 4 INDICAT E \$ SYMBOL 4 INDICAT SYMBOL IN 4 INDICAT	12, 13, AN DL IN THE ANY OF TH THE A-SOU THE A-SOU THE A-SOU THE A-SOU THE A-SOU THE A-SOU THE A-SOU THE FOR N THE FOR	D 14. FORMU HE LOCA IRCE FIE FORMU CLUSIVE FORMULAS	ILAS UNI IL STORA ILD. ILAS UNI - ORO FU AS UNDI ION. UNDER	DER COLI AGE BYTI DER COLI INCTION ER COLUI	UMNS 12 E SOURC UMNS 12 MNS 12, S 12, 13,	2, 13, CES 2, 13, 13,	00 00 01 10 10 10 11 11 11 00 00 00 01	$\begin{array}{rrrrrrrrrrrrrrrrrrrrrrrrrrrrrrrrrrrr$	0 - KL 0\$KL 0\$KH 0\$KK A - KH A + KL A + KK 0 - KL 0\$KL 0\$KL 0\$KK		
		1 1 1 1	1 1 1 1									10 11	0 - A = 1 - A = 0 - A = 1 - A =	A - KL A - KH		

Figure 1-41. Arthimetic Constant Word (Word Type 1)

Figure 1-42. Storage Word (Word Type 2)

WORD STORAGE TYPE CONTROL	DATA REGISTER ADDRESS	ADDRESS REGISTER OR K FIELD MODIFIER CONTROL	WORD TYPE
0 1 2 3	4 5 6 7	8 9 10 11 12 13 14	
00 = READ CONTROL 01 = READ AUX OR PROGRAM 10 = STORE CNTL 11 = STORE AUX OR PROGRAM	THIS FIELD MAY ADDRESS LOCAL STORAGE FOR A BYTE OR HALFWORD. BYTE SELECTION OF LOCAL STORAGE IS LIMITED TO THE ODD ADDRESSES. HALFWORD SELECTION IS LIMITED TO EVEN ADDRESS	FOR INDIRECT ADDRESSING000NO UPDATETHE ADDRESS REGISTER SELECTED BY THIS FIELD IS A HALFWORD LOCAL STORAGE REGISTER000NO UPDATEBIT 11 DOES NOT ENTER INTO THE ADDRESSING OF THE LOCAL011NO ACCESS, PLUS UPDATE.011NO ACCESS, MINUS UPDATE.011NO ACCESS, MINUS UPDATE.011NO ACCESS, MINUS UPDATE.	0
BIT 11 DETERMINES IF THE AUXILIARY STORAGE AREA OR THE PROGRAM STORAGE AREA IS ACCESSED FOR BIT 2, 3 DECODES OF 01 and 11. THIS IS ONLY TRUE WHEN INDIRECTLY ADDRESSING.	EXTERNAL FACILITY ADDRESSING IS ALWAYS DONE IN BYTE MODE. THEREFORE ONLY THE EXTERNALS WITH ODD ADDRESSES CAN BE ACCESSED. LOCAL STORAGE DECODES 0000 - U0 0001 - U1 0010 - V0	STORAGE REGISTER. BUT DOES INDICATE THE FOLLOWING100CLOCAL STORAGE DATE REG, ACCESS, PLUS UPDATEBITBITSMEANING 11101101LOCAL STORAGE DAT REG, ACCESS, MINUS UPDATE001READ AUXILIARY 111STORE AUXILIARY ACCESS, PLUS UPDATI10111 STORE AUXILIARY REG, ACCESS, PLUS UPDATE111STORE AUXILIARY ACCESS, PLUS UPDATI111STORE PROGRAM ACCESS, MINUS UPDATI	).    E
WHEN NO ACCESS TO STORAGE IS DESIGNATED BY THE MODI- FIER CONTROL FIELD. BITS 2 and 3 INDICATE THE UPDATE VALUE. BITS VALUE 2,3 00 0 01 +OR - 1 10 +OR - 2 11 +OR - 2	0011 -       V1         0100 -       G0         0101 -       G1         0110 -       D0         0111 -       D1         1000 -       I0         1001 -       I1         1000 -       I0         1011 -       T1         1010 -       P0         1011 -       P1         1110 -       H0         1111 -       H1         ALL EVEN ADDRESSES CAN BE       USED AS ADDRESS REGISTERS IN         THE FIELD DESIGNATED BY CON-       TROL WORD BITS 8, 9, 10, and 11.	FOR DIRECT ADDRESSINGFOR K ADDRESSABLETHIS FIELD CONTAINS BIT CODES THAT FORCE THE ADDRESS REG- ISTER M1 TO SPECIFIC VALUES THESE VALUES AREAUX M0 = 0000000 CTRL M0 = XX00011BITS BITS R9,10,11FORCED M1 8,9,10,11DEPENDENT ON STORAGE SIZE0000 0001 88 0001 0010 0101 0100 0101B8 1000 0111DEPENDENT ON STORAGE SIZE0100 0111 0110 0111 0111 0111 0111B8 B1 1011 0111 0111 0111B8 B1 1011 0111 	

Figure 1-43. Move/Arthmetic (Word Type 3)

۰ **،** 

11		FUNCTION DÉCODE A SOURCE FIELD			B SOU	B SOURCE FIELD				NCTION CODE		WORD TYPE		
D	1	2	3	45	e	37	8	9	10	11	12	13	14	15
0	1	0	0	0000	=	U0	0000	=	UO		000	- B=АХ ¤ В		1
		0	0	0001	=	U1	0001	=	U1		001	- B = AXH + BL		
		0	0	0010	=	V0	0010	=	V0		010	- B = AXL \$ BH		
		0	0	0011	=	V1	0011	=	V1		011	-		
		0	0	0100	=	G0	0100	=	G0		100	- B = A + B		
		0	0	0101	=	G1	0101	=	G1		101	- B = AH + BL		
		0	0	0110	=	D0	0110	=	D0		110	- B = AL + BH		
		0	0	0111	=	D1	0111	=	D1		1111	- EXT = B		
				1000	=	10	1000	=	10		]]			
	]	0	1	1001	=	11	1001	=	11		000	- B = AX		
		0	1	1010	=	то	1010	=	то		001	- B = AXH		
		0	1	1011	=	Т1	1011	=	T1		010	- B = AXL		
		0	1	1100	=	P0	1100	=	P0		011	- B = 0 (STOP)		
		0	1	1101	=	P1	1101	=	P1		100	- B = A		
		0	1	1110	=	H0	1110	=	HO		101	- B = AH		
		0	1	1111	=	H1	1111	=	H1		110	- B = AL		
		0	1								111	- B = EXT		
		1	 0	THE FL	JNCTI	ON DEC	CODE IS A	сомв	INATION OF	:	000	- А=А¤В		
		1	.0	CONTROL	WOR	D BITS	2, 3, 12, 13	, AND	) 14-		001	- A = A + B	ļ	
		1	0								010	- A = A \$ B		
		1	0	IF THE	FUNC	TION E	ECODE IS	EQU/	AL TO 00111		011	- A = A * B		
		1	0	THE A-SO	URCE	FIELD	ADDRESS	ES AN	IEXTERNAL		100	- AC = A + B + 1		
		1	0	FACILITY	΄.						101	- AC = A + B	1	1
		1	0	IF THE	FUNC	TION D	ECODE IS	EQUA	AL TO 01111	THE	110	- AC = A + B + C		
		1	0						ERNAL FAC		111	- AC = AL + B + C		
		1	1		AS, RE	FERS T	O ANY OF	THE	LOCAL STO		000	- A = A - B + 1		
		1	1						CTION DECO	DE	001	- A = A - B		
		1	1	1	AS, RE	FERST	O ANY OF	THE	LOCAL STO		010			
		1	1								011	-		
		1	1			C- RE	FERS TO 1	THE A	DDER CARR	Y		- AC = A - B + C		
		1		(S3) LATC	Η						11.01			
			1	THE SY	MBOL		ICATES A	N EX	CLUSIVE-OR		11	- AC = 0 - B + C		
		1	1	FUNCTIO							110	- AC = A $\pm$ B + C		
		1	1	THE SY	MBOL				FUNCTION.		111	- AC = A @ B + C		1
														1
				DECIMAL			JUATESA	AN AD	D/SUBTRAC	1				

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WORD TYPE		REPLACEMENT BITS FOR THE MOREGISTER						REPLACEMENT BITS FOR THE M1-REGISTER							WORD TYPE
0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
1	0	THE V. THE M REGIS FORCE THE M	ALUES TH 0-REGIST EN THIS W TER, BIT ! ED TO A 1 0-REGIST	7 OF THIS ( HAT ARE GA ER WHEN T WORD IS GA 5 OF THE CC . THE REPL/ ER BIT 5 PO DATA BUS B	ATED TO BI HIS WORD TED INTO T DNTROL RE ACEMENT Y SITION IS (	TS 2 THRU IS EXECUT THE CONTI EGISTER IS VALUE FO GATED FR	7 OF ED ROL R	TO BI	S 8 THRU 1 TS 0 THRU ECUTED						0
				SEC	WHEN THIS WORD IS EXECUTED, THE ADDRESS OF THE NEXT SEQUENTIAL CONTROL WORD IS STORED IN THE I-REGISTER OF LOCAL STORAGE ZONE 4.										

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WORD TYPE	BRANCH CONTROL	A SOURCE FI	ELD	REPLACEMENT BITS FOR M1-REGISTER			REPLACEMENT BITS FOR MO-REGISTER			WORD TYPE	
0 1	2 3	4 5	6 7	8	9	10	11	12	13	14	15
1 0	C0 = 4 WAY BR 01 = 8 WAY BR 10 = 2 WAY BR (A SOURCE NOT ZERO) 11 = 16 WAY BR	A-REG BIT 5 = 1 MEA A-REG WHEN THIS CONTRO INTO THE CONTRO IS FORCED TO 1. T THE FACILITIES TI ADDRESSED BY TH TO THOSE THAT H 5 = 1 IN THEIR A-SO BECAUSE BIT 5 CONTROL REGISTI STATUS OF BIT 5 IS THE STORAGE DAT A-REG GATING. EITHER DECODE IN CONTROL STORAGE. 0000 OR 0100 0001 OR 0110 0011 OR 0111 1000 OR 1100 1001 OR 1110 1011 OR 1111	G OUTPUT COL WORD IS READ OL REGISTER. BIT 5 HIS RESTRICTS HAT CAN BE HE A-SOURCE FIELD AVE AT LEAST BIT DURCE DECODES. IS FORCED IN THE ER, THE TRUE S TAKEN FROM TA BUS OUT, FOR LOCAL STORAGE REGISTER G0 G1 D0 D1 P0 P1 H0 H1 ACILITIES HAVE		REPLA BIT 1 o M1-F BIT 10 REPLA BIT 2 O REGIST BIT 11 REPLA	REGISTER. CONTAINS TH CEMENT VAL IF THE M1 TER. CONTAINS TH CEMENT VAL IF THE M1	ue for Ie Ue for Ie	CONTAII VALUES	2, 13, AND 1 N THE REPL FOR BITS 5, F THE MORI	ACEMENT , 6,	1

-

WORD TYPE
0 1
1 1

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# 1.8 EXTERNAL DECODES, MNEMONICS, AND ADDRESSING (FIGURE 1-47)

This section summarizes the detailed bit definitions of external facilities. AS-decodes followed by asterisk (\*) can be tested with the Branch on Condition or Branch on Mask words.

## CPU Mode

AS-Field		
Decode	Ext to CPU	CPU to Ext
0000	SWAB	
0001	SWCD	
0010	STP0	STP0
0011	SIP1	STP1
0100*	DYN	SM
0101*	S	
0110*	MMSK	
0111*	BA	JO
1000	JI	
1001	XINI	JA
1010	TIM	
1011		
1100*	DR	
1101*		
1110*	MC	
1111*	BB	MW

## 2311 Disk Mode

AS-Field		
Decode	Ext to CPU	CPU to Ext
0000	TGRI	
0001	EBI	
0010	STP0	STP0
0011	FOB	FEBO
0100*	DYN	
0101*	DASI	
0110*	MMSK	
0111*	BA	
1000	CHI	
1001	CLI	MS
1010	TC	
1011	SDI	TGRO
1100*	FGA	
1101*	FFI	FFC
1110*	DS	FBO
1111*	FOP	FCP

## <u>2540 Punch Mode</u>

Ext to CPU	CPU to Ext
	*** -=-
STP 0	STP0
STP1	STP1
DYN	
S	
MMS K	
BA	
RPD1	
RPD2	
RP2	
RP1	
RS	
RPS	
PS	PO
	STP 0 STP1 DYN S MMSK BA RPD1 RPD2 RP2 RP1  RS RPS

## 1403 Mode

AS-Field		
Decode	Ext to CPU	<u>CPU to Ext</u>
0000		
0001		
0010	STP0	STP0
0011	STP1	STP1
0100*	DYN	
0101*	S	
0110*	MMSK	
0111*	BA	
1000		
1001		PCCL
1010	PRT	
1011	PRI	PRO
1100*		
1101*		PRC
1110*	PRS	
1111*	PRD	PR

### 1052 (PRKB) Mode

AS-Field		
Decode	Ext to CPU	CPU to Ext
0000		***
0001		
0010	STP0	STP0
0011	STP1	STP1
0100*	DYN	
0101*	S	
0110*	MMSK	
0111*	BA	
1000		
1001		
1010	TI	
1011	TR	
1100*		
1101*	TD	
1110*	TT	
1111*	TU	TE

## Communications Mode

AS-Field		
Decode	Ext to CPU	CPU to Ext
0000		
0001	<b>**</b> *	
0010	STP0	STPO
0011	STP1	STP1
0100*	DYN	
0101*	S	CADR
0110*	MMSK	
0111*	BA	PARCK
1000		
1001		LADR
1010	DAIN	
1011	LAIN	DAOUT
1100*	IACCN	
1101*	LASTAT	DILOUT
1110*	DIIIN	
1111*	GSTAT	LAOUT

#### 2540 Reader Mode

AS-Field		
Decode	Ext to CPU	CPU to Ext
0000		
0001		
0010	STP0	STP0
0011	STP1	STP1
0100*	DYN	
0101*	S	
0110*	MMSK	
0111*	BA	
1000	RPD1	
1001	RPD2	
1010	RP 2	
1011	RP1	
1100*		
1101*	RS	
1110*	PRS	
1111*	PS	PO

#### Channel Mode

AS-Field			Console Add	lre
Decode	Ext to CPU	CPU to Ext	MDM 4-35	
0000				
0001			0001 0 Sw	i
0010	STP0	STP0	1 Sw	it
0011	STP1	STP1	2 SW	it
0100*	DYN		3 Sw	i
0101*	S		4 Sw	ni 1
0110*	MMSK		5 Sw	i
0111*	BA		6 Sw	n'
1000			7 Sw	it
1001				
1010				
1011			Storage Pro	t
1100*	GS		MDM 4-41	
1101*	GT			
1110*	GD		0010 0 ST	'P(
1111*	GB/IN	GB/OUT	1 ST	P
			2 ST	P

Note: The GA and GB external facilities cannot be displayed directly, but can be displayed in GP, GS, or GT external facilities. GB/IN and GB/OUT have the same external decode.

### 2560 MFCM Mcde

xt

\* These fields may be tested with Branch on Condition or Branch on Mask control words.

\*\*Fields in parentheses apply to 2540 Emulate operation.

# External Field Definitions, CPU Mode (EXT to CPU)

Console Address Switch 0 (SWAB) MDM 4-35

0	Switch	Α	bit	0
1	Switch	Α	bit	1
2	Switch	Α	bit	2
3	Switch	Α	bit	3
4	Switch	В	bit	0
5	Switch	в	bit	1
6	Switch	в	bit	2
7	Switch	в	bit	3
	1 2 3 4 5	1 Switch 2 Switch 3 Switch 4 Switch 5 Switch 6 Switch	1 Switch A 2 Switch A 3 Switch A 4 Switch B 5 Switch B 6 Switch B	1 Switch A bit 2 Switch A bit 3 Switch A bit 4 Switch B bit 5 Switch B bit

Console Address Switch 1 (SWCD) MDM 4-35

~ ~	•		-		~
01	0	Switch	С	bit	0
	1	Switch	С	bit	1
	2	Switch	С	bit	2
	3	Switch	С	bit	3
	4	Switch	D	bit	0
	5	Switch	D	bit	1
	6	Switch	D	bit	2
	7	Switch	D	bit	3

Storage Protect 0 (STP0) MDM 4-41

0010	0	STP0	bit 0	(Q0)
	1	STP0	bit 1	(Q1)
	2	STP0	bit 2	(Q 2)
	3	STP0	bit 3	(Q3)
	4	STP0	bit 4	(Q4)
	5		bit 5	
	6	STP0	bit 6	(Q6)
	7	STP 0	bit 7	(Q7)

Storage Protect 1, Manual Only (STP1) Direct Control In (JI) \*\* MDM 4-41 MDM 4-41 0011 0 STP1 kit 0 1000 0 Dir In bit 0 STP1 bit 1 1 1 Dir In bit 1 STP1 bit 2 2 Dir In bit 2 2 STP1 bit 3 3 3 Dir In bit 3 STP1 kit 4 Dir In bit 4 ti. Ш 5 STP1 bit 5 5 Dir In bit 5 6 STP1 bit 6 6 Dir In bit 6 7 STP1 kit 7 7 Dir In bit 7 External Interruption (XINT) or Dir Ctl \*\* Dynamic Condition Register (DYN) MDM 4-41 MDM 4-40 1001 0 Timer interruption (Int Timer 0100\* 0 Z=0 (DC Bit 0) feature) Console interruption Storage wrap latch 1 1 OVFL (overflow) (DC Bit 2) 2 Ext Int or Dir Ctl sig-in, bit 2 2 Adder carry (DC Bit 3) Not hold in (Dir Ctl feat) 3 Ext Int or Dir Ctl sig-in, bit 3 3 Ext Int or Dir Ctl sig-in, bit 4 Ext Int or Dir Ctl sig-in, bit 5 Ext Int or Dir Ctl sig-in, bit 6 4 Ц Check disable switch 5 5 DYN Reg bit 6 (HZ=0) (DC Bit 6) 6 6 DYN Reg bit 7 (LZ=0) (DC Bit 7) 7 Ext Int or Dir Ctl sig-in, bit 7 7 Timer Count (TIM) \*\* MDM 4-41 Status Register (S) MDM 4-16 1010 0 0 0101\* 0 0 S0 True/Compl latch 1 S1 Z=nonzero (all arith ops) 0 1 2 2 S2 Z=nonzero (log, dec, & binary 3 Ω Timer count bit 4 4 ops) 3 S3 ALU 0-tit carry 5 Timer count bit 5 Timer count bit 6 Ц S4 Invalid decimal digit 6 Timer count bit 7 5 S5 (general purpose) 7 S6 Not execute (MDM 4-40) 6 S7 Not exceptional condition (MDM 1011 Unassigned 7 4-40) Diagnostic Register (DR) MDM 4-13 MMSK Register, Bits 0-7 (MMSK) MDM 4-15 1100\* 0 Disable stop on error 1 Force all A-Reg ALU entries on 0110\* 0 MMSK0 Channel high trap Force stor-data parity bits on 2 MMSK1 2311 disk control trap 3 Block actual, gen. pseudo I/O 1 MMSK2 Channel low trap trap requests 2 MMSK3 2540 reader trap L 0 3 MMSK4 2540 punch trap 5 Force external entry to A/B-Regs μ. 5 MMSK5 Comm chnl bit service PSW Restart Latch 6 MMSK6 Comm chl char service 7 Turn on diag-branch latch 6 7 MMSK7 Level 1 priority hold 1011\* Unassigned Branch Conditions (BA) MDM 4-40 Error Register (MC) MDM 4-10 0111\* 0 Chnl 0 interruption latch Mode bit 0 1110\* 0 File control check 1 Mode tit 1 Storage address check 2 2 Mode bit 2 3 Control word parity latch 3 Storage data parity latch 11 IPL latch 11 5 LS zone bit 0 5 ALU error latch 6 A-Reg parity latch IS zcne kit 1 6 7 LS zone bit 2 7 B-Reg parity latch

Soft-Stop Branch Conditions (BB) MDM 4-40

- 1111\* 0 Not soft stop 1 Integrated I/O request Not chnl 0 Int (masked) 2 3 Not Ext Int (masked) Set IC latch Ц 5 Instruction step latch Not chnl 1 Int (masked) 6 Not comm chnl Int (masked) 7 These eight fields tested with Branch cn Condition or Branch on Mask control words. \*\* The active level is minus. External Field Definitions, CPU Mode (CFU to EXT) 1001 0000 Unassigned 0001 Unassigned Storage Protect 0 (STP0) MDM 4-41 0010 0 STP0 bit 0 (00) 1 STPO bit 1 (Q1) STPO bit 2 (Q2) 2 3 STPO bit 3 (Ç3) 4 STPO bit 4 (Q4) 1100 5 STPO bit 5 (C5) 6 STP0 bit 6 (06) 1101 7 STPO bit 7 (Q7) Storage Protect 1 (STP1) MDM 4-41 0 STP1 bit 0 0011 1 STP1 bit 1 1111 STP1 bit 2 2 3 STP1 bit 3 4 STP1 bit 4 5 STP1 bit 5 STP1 bit 6 6 STP1 bit 7 7 System Mask (SM) MDM 4-50 0100 0 Chnl 0 mask Chnl 1 mask 1 2 Chnl 2 mask 3 Ignored 4 Ignored 0000 5 Igncred 6 Ignored
  - 7 Ext Int mask
- 0101 Unassigned
- 0110 Unassigned

Direct Control -1 (JO) MDM 4-92 0111 0 Dir Bus Out bit 0 1 Dir Bus Out bit 1 Dir Bus Out bit 2 2 Dir Bus Out bit 3 3 Dir Bus Out bit 4 Ц Dir Bus Out bit 5 5 Dir Bus Out bit 6 6 Dir Bus Out bit 7 7 1000 Unassigned

Direct Control -2, Timing (JA) MDM 4-92

- 0 0 0 1 Sig Out bit 2 2 3 Sig Out bit 3 Sig Out bit 4 Ц 5 Sig Out bit 5 Sig Out bit 6 6 7 Sig Out bit 7
- 1010 Unassigned
- 1011 Unassigned
  - 100 Unassigned
- 101 Unassigned
- 1110 Unassigned

MW Bits (2) of AMWP Bits (MW) MDM 4-50

0 0 0 1 2 0 3 0 4 0 5 Machine check mask 6 Wait state latch 7 n

#### External Field Definitions, 2311 Disk Mode (FXT to CPU)

Tag Register In (TGRI) MDM 4-46

0 Set difference Set Cylinder 1 2 Set head 3 Control 4 Not 2311 trap latch 5 Machine check Storage protect check 6 7 Storage wrap check

File Bus In (FBI) MMSK Register, Bits 0-7 (MMSK) MDM 4-46 MDM 4-15 0001 0 Cyl addrs 128 0110\* 0 MMSK0 Channel high trap 1 Cyl addrs 64 1 MMSK1 2311 disk control trap 2 Cyl addrs 32 2 MMSK2 Channel low trap 3 Cyl addrs 16 3 MMSK3 2540 reader trap 4 MMSK4 2540 punch trap 4 Cyl addrs 8 5 MMSK5 Comm chnl bit service 6 MMSK6 Comm chnl char service Cyl addrs 4 5 6 Cyl addrs 2 7 MMSK7 Level 1 priority hold 7 Cyl addrs 1 2311 Storage Protect Key (STPO) Branch Conditions (BA) MDM 4-40 MDM 4-41 0111\* 0 Chnl 0 interruption latch 0010 0 STP0 bit 3 (FQ0) 1 STPO bit 1 (FQ1) Mode bit 0 1 2 STP0 bit 2 (FQ2) 3 STP0 bit 3 (FQ3) 2 Mode bit 1 Mode bit 2 3 4 STP0 bit 4 (04) 4 IPL latch 5 STP0 bit 5 (Q5) 5 LS zone bit 0 6 LS zone bit 1 6 STPO bit 6 (Q6) 7 STP0 bit 7 (Q7) 7 IS zone bit 2 File Out Bus (FCB) - Diagnostic Counter 1 High in (CHI) - Diagnostic Set MDM 4-46 Set Cyl Hd/Dir Difference Ccntrol 0011 0 Write gate 128 Frwd 1 Not 128 1000 0 Counter position 32,768 1 Read gate 64 x Not 64 1 Counter position 16,384 Seek start 32 x Restr hd reg 16 x 2 Seek start Not 32 2 Counter position 8,192 3 Counter position 4,096 4 Counter position 2,048 5 Counter position 1,024 Not 16 3 Erase gate 8 Select head 4 Head 8 Not 8 **L**L 8 Head 4 Not 4 5 Return 000 Head 2 Not 2 6 Counter position 512 6 2 7 Head adv 1 Head 1 Not 1 7 Counter position 256 Note: Bit 2 can also be Clock Through K and D. Counter 1 Low In (CLI) - Diagnostic MDM 4-46 Dynamic Condition Register (DYN) MDM 4-40 1001 0 Counter position 128 Counter position 64 Counter position 32 1 0100\* 0 Z=0 2 1 Storage wrap latch 3 Counter position 16 2 OVFL (overflow) 4 Counter position 8 3 Adder carry
4 Not hold in (Dir Ctl feat) 5 Counter position 4 6 Counter position 2 7 Counter position 1 5 Check disable switch 6 DYN Reg kit 6 (HZ=0) 7 DYN Reg bit 7 (LZ=0) Terminating Conditions (TC) Disk Attachment Status In (DASI) MDM 4-46 MDM 4-46 1010 0 Data check in count \*\* 1 Track overrun \*\* 0101 0 Compare home address Skip 2 No record found \*\* 1 2 Selected or any gated attention Missing address mark \*\* 3 3 Erase gate 4 Data check \*\* 4 Unusual condition 5 Overrun \*\* 5 Status modifier not short search 6 Track condition \*\* 6 Control unit end 7 0 7 Control unit busy

Serializer/Deserializer In (SDI) - Diag. MDM 4-46 Read huffer position 128 1011 0 1 Read buffer position 64 Read huffer position 32 2 3 Read buffer position 16 Read tuffer position 8 Read buffer position 4 Ц 5 Read tuffer position 2 6 7 Read buffer position 1 File Gated Attention (FGA) MDM 4-46 1100 \* 0 Module 0 \*\*\* Module 1 \*\*\* 1 Module 2 \*\*\* 2 Module 3 \*\*\* 3 Wrong length record Ш 5 Unit Exception \*\* Flag Bit  $\tilde{6}$ Selected index hold 6 7 File Flags In (FFI) MDM 4-46 1101\* 0 Chain data (CD) Command chain (CC) 1 2 CC or CD and not unusual condition Status modifier 3 4 Program-controlled interruption (PCI) 5 Interruption latch Interrupt condition 6 7 Suppress length indicator (SLI) Disk Status (DS) -- This register is multiplexed for diagnostic uses (MDM 4-345). Nondiagnostic 1110\* 0 Ready \*\* On line \*\* 1 2 Unsafe \*\* 3 0 Ц Trap gate latch \*\* 5 End of cylinder \*\* 6 low compare 7 Seek incomplete \*\* Diag Addr 0 Write kuffer 128 Write kuffer 64 Write buffer 32 0 1 2 Write buffer 16 3 ш Write Luffer 8 5 Write buffer 1 Write buffer 6 2 7 Write buffer 1

<u>Diag Addr 1</u> 0 Test unit exception 1 Read Op 2 Erase Op 3 Scan Op 4 Space count Op 5 Home address Op 6 Home address or R0 Op 7 Count Op Diag Addr 2 0 Key Op Data Op 1 2 R0 Op

R0 Op
 Count, key, or data Op
 Count or key Op
 Write check Op
 Standard index
 Bit ring inhibit

Diag Addr 3 0 CYC code position 1 CYC code position 16 1 2 CYC code position 17 3 CYC code error latch Unequal compare 4 5 Bit ring 7 Write clock bit 6 Write data bit 7

	Diag Addr 4
0	Zone A
1	Zone B
2	Zone 1
3	Zone 2
4	Zcne 3
5	Zcne 4
6	HA field
7	Count field

0 1 2 3	<u>Diag Addr 5</u> Key field Data field Flag bit 0 Flag bit 6	
4 5 6	Flag bit 7 Counter decode Counter decode	-
7	Counter decode	2

Diag Addr 6					
Counter	decode	3			
Counter	decode	4			
Counter	decode	5			
Counter	decode	6			
		-			
Counter	decode	9			
Count =	000				
	Counter Counter Counter Counter Counter Counter Counter	Diag Addr 6 Counter decode Counter decode Counter decode Counter decode Counter decode Counter decode Counter decode Counter decode Counter decode			

File Op Register (FOP) Module Select Register (MS) MDM 4-46 1001 0 Module select 0 1111\* 0 Search high Module select 1 1 Module select 2 1 Multiple/track 2 Search high or equal 3 Module select 3 2 h 3 Count Λ 5 4 0 Key 5 Data 6 0 7 0 6 Read 7 Write 1010 Unassigned These eight fields tested with Branch on Condition or Branch on Mask control Tag Register Out (TGRO) words. MDM 4-349 Any of these bits turn on DASI bit 4. 1011 0 Set difference \*\*\* Any of these bits turn on DASI bit 2. 1 Set cylinder Set head and direction 2 3 Control External Field Definitions, 2311 Disk Mode 4 0 (CFU to EXT) 5 0 Trap gate 6 0000 Unassigned 7 Control single shot 0001 Unassigned 1100 Unassigned File Flags Out (FFO) 2311 Storage Protect (key (STP0) 1101 0 Chain data (CD) Command chain (CC) 0010 0 SIPO bit 3 (FQO) 1 STP0 bit 1 (FQ1) 2 Suppress length indicator (SLI) 1 2 STPO bit 2 (FC2) 3 Skip STPO bit 3 (FQ3) Ц Program-controlled int (PCI) 3 5 4 STPO bit 4 0 5 STP0 bit 5 6 0 7 6 STP0 bit 6 0 7 STPO bit 7 File Bus Out (FBO) MDM 4-349 File 1400 Emulator Bus Cut (FEBO) Set Set 0011 0 FEBC bit 0 Control Cyl Hd/Dir Difference FEBC bit 1 1110 0 1 Write gate 128 Frwd 1 Not 128 FEBO bit 2 FEBC bit 3 1 Read gate 2 64 x Not 64 Not 32 3 \*\*2 Seek start 32 х FEBC bit 4 3 4 Rstr hd reg Not 16 16 х FEBO bit 5 Head 8 Not 8 5 4 Erase gate 8 5 Select head 6 FEBO bit 6 4 Head 4 Not 4 FEBO bit 7 \*\*6 Return 000 2 Head 2 Not 2 \*\*7 Head adv 1 Head 1 Not 1 0100 Unassigned **\*\*** Timed Operations 0101 Unassigned File Op Register (FOP) 1111 0 Multiple/track 0110 Unassigned Search high 1 2 Search equal 3 Count 0111 Unassigned Ц Key 5 Cata 6 Read 7 Write 1000 Unassigned

External Field Definitions, 2540 Punch Mode MMSK Register, Bits 0-7 (MMSK) (EXT to CPU) MDM 4-15 0000 Unassigned 0110\* 0 MMSK0 Channel high trap MMSK1 2311 disk control trap 1 0001 Unassigned MMSK2 Channel low trap 2 3 MMSK3 2540 reader trap
4 MMSK4 2540 punch trap
5 MMSK5 Comm chnl bit service 6 MMSK6 Comm chnl char service Storage Protect 0 (STP0) MDM 4-417 MMSK7 Level 1 priority hold 0010 0 STPO bit 0 (Q0) 1 SIPO bit 1 (Q1) 2 STP0 bit 2 (02) Branch Conditions (BA) STPO bit 3 (Q3) MDM 4-40 3 4 STPO bit 4 (Q4) 0111\* 0 Chnl 0 interruption latch 5 STP0 bit 5 (Q5) Mode bit 0 STPO bit 6 (Q6) 6 1 7 STP0 bit 7 (Q7) Mode bit 1 2 Mode bit 2 3 4 IPL latch 5 LS zone bit 0 LS zone bit 1 Storage Protect 1 (STP1) 6 MDM 4-41 7 LS zone bit 2 0011 0 STP1 bit 0 STP1 bit 1 1 STP1 bit 2 Diagnostic R/P Conditions 1 (RPD1) 2 MDM 4-43 3 STP1 bit 3 4 STP1 bit 4 5 STP1 bit 5 0 R/P tens AR A 1000 6 STP1 bit 6 1 R/P tens AR B 7 STP1 bit 7 2 R/P tens AR C 3 R/P tens AR D 4 R/P tens AR E Punch address check 5 Dynamic Condition Register (DYN) Punch overrun latch 6 MDM 4-40 7 Punch sync check latch 0100\* 0 X=0 1 Storage wrap latch Diagnostic R/P Conditions 2 (RPD2) OVFL (overflow) 2 3 Adder carry MDM 4-43 4 Not hold in (Dir Ctl feat) 5 Check disable switch 1001 0 R/P units AR A R/P units AR B 6 DYN Reg bit 6 (HZQ=0) 1 R/P units AR C 7 dyn Reg bit 7 (LZ=0) 2 R/P units AR D 3 R/P units AR E 4 5 Reader address check Status Register (S) Reader overrun latch 6 Reader sync check latch MDM 4-16 7 0101\* 0 S0 True/Compl latch S1 Z=ncnzero (all arith ops) 1 S2 Z=nonzero (log, dec, & bin ops) S3 ALU 0-bit carry Reader/Punch Data In 2 (RP2) 2 MDM 4-110 3 Ц S4 Invalid decimal digit 5 S5 (general purpose) 1010 0 Col 1 RD2 punch check, data in Col 2 RD2 punch check, data in Col 3 RD2 punch check, data in Col 4 RD2 punch check, data in S6 Not execute 1 6 S7 Not exceptional condition 2 3 Col 5 RD2 punch check, data in Ц 5 Col 6 RD2 punch check, data in Col 7 RD2 punch check, data in 6 7 Col 8 RD2 punch check, data in

Reader/Punch Data In 1 (RP1) External Field Definitions, 2540 Punch Mode MDM 4-110 (CPU to EXT) 1011 0 Ccl 1 RD1 PFR data in 0000 Unassigned Ccl 2 RD1 PFR data in 1 2 Col 3 RD1 PFR data in 0000 Unassigned 3 Col 4 RD1 PFR data in 4 Col 5 RD1 PFR data in 5 Col 6 RD1 PFR data in Col 7 RD1 PFR data in 6 Storage Protect 0 (STP0) 7 Col 8 RD1 PFR data in 0010 0 STP0 bit 3 (Q0) 1 STP0 bit 1 (Q1) STPO bit 2 (Q2) 1100 \* Unassigned 2 STP0 bit 3 (Q3) 3 STPO bit 4 (Q4) L 5 STP0 bit 5 (Q5) Reader Branch Conditions (RS) 6 STP0 bit 6 (Q6) MCM 4-43 7 STP0 bit 7 (Q7) 1101\* 0 Not gate read complete 2540 1 Not rdr intervention (rdr ready) Storage Protect 1 (STP1) 2 Unit exception gate reader 3 Reader check 4 Reader validity check5 Reader device-end (hardware) 0011 0 STP1 bit 0 STP1 bit 1 1 Reader status request 2 STP1 bit 2 6 7 Not 1400 unit exception 3 STP1 bit 3 4 STP1 bit 4 5 STP1 bit 5 6 STP1 bit 6 Reader/Punch Branch Conditions (RPS) STP1 bit 7 7 MDM 4-43 1110\* 0 Reader punch on-line 0100 Unassigned 1 2540 rdr trap req (data avail, CSL) 2 Nct 1400 time cut 0101 Unassigned 3 2540 Pch Trap Req/Diag Stacker 4 Punch brush CL 0110 Unassigned 5 Punch decode Reader select latch 6 0111 Unassigned 7 Punch select latch 1000 Unassigned 1001 Unassigned Punch Branch Conditions (PS) MDM 4-43 1010 Unassigned 1111\* 0 Not punch intervention (pch ready) 1011 Unassigned Not 4-bit mod pull-on 1 2 PFR unit exception gate 1100 Unassigned 3 Punch equipment check Punch PFR validity Ц 1101 Unassigned 5 Punch device-end (hardware) 6 Punch status request 1110 Unassigned 7 0 \* These eight fields tested with Branch on Punch Data Out (PO) Condition or Branch on Mask control words. 1111 0 Pch data cols 1, 9, 17, etc. 1 Pch data cols 2, 10, 18, etc. 2 Pch data cols 3, 11, 19, etc. 3 Pch data cols 4, 12, 20, etc.

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4 Pch data cols 5, 13, 21, etc. 5 Pch data cols 6, 14, 22, etc. Pch data cols 7, 15, 23, etc. Pch data cols 8, 16, 24, etc.

6 7

External Field Definitions, 1403 Mode (EXT MMSK Register, Bits 0-7 (MMSK) to CPU) MDM 4-15 0000 Unassigned 0110\* 0 MMSK0 Channel high trap MMSK1 2311 disk control trap 0001 Unassigned 1 MMSK2 Channel low trap 2 MMSK3 2540 reader trap 3 MMSK4 2540 punch trap MMSK5 Comm chan bit service L Storage Protect 0 (SIPO) 5 MDM 4-41 MMSK6 Comm chan char service 6 MMSK7 Level 1 priority hold 7 STPO bit 0 (Q0) 0010 0 1 STP0 bit 1 (Q1) 2 STPO tit 2 (C2) 3 STP0 Lit 3 (03) Branch Conditions (BA) STPO bit 4 (C4) Ц MDM 4-40 5 STP0 Lit 5 (Q5) STPO bit 6 (Q6) 6 0111\* 0 Chnl 0 interruption latch STP0 Lit 7 (C7) Mode bit 0 7 1 Mode bit 1 2 Mode bit 2 3 4 IPL latch Storage Protect 1 (STP1) 5 LS zone kit 0 MDM 4-41 LS zone bit 1 6 LS zone kit 2 7 STP1 kit 0 0011 0 STP1 bit 1 1 2 STP1 bit 2 1000 Unassigned 3 STP1 bit 3 STP1 kit 4 4 5 STP1 bit 5 1001 Unassigned SIP1 bit 6 6 7 STP1 kit 7 1403 PLBAR Data In (PRT) MDM 4-207 Dynamic Condition Register (DYN) MDM 4-40 1010 0 PLBAR 128 PLBAR 64 1 0100\* 0 X=0 PLBAR 32 2 Storage wrap latch OVFL (overflow) PLBAR 16 3 1 2 4 PLBAR 8 Adder carry PLBAR 4 5 3 μ. Not hold in (Dir Ctl feat) PLBAR 2 6 Check disable switch 5 7 PLBAR 1 DYN Reg tit 6 (HZ=0) 6 DYN Reg bit 7 (LZ=0) 7 1403 PIB Data In (PRI) MDM 4-208 Status Register (S) MDM 4-16 PLB 128 1011 0 1 PLB 64 0101\* 0 S0 True/Compl latch 2 PLB 32 S1 Z=nonzero (all arith ops) 3 PLB 16 1 2 S2 Z=nonzero (log, dec, & bin 4 PLB 8 ops) 5 PLB 4 3 S3 ALU 0-tit carry 6 PLB 2 4 S4 Invalid decimal digit 7 PLB 1 5 S5 (general purpose) 6 S6 Not execute 7 S7 exceptional condition 1100\* Unassigned 1101\* Unassigned

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Sense/Status Conditions (PRS) Storage Protect 0 (STP0) MDM 4-44 0010 0 STP0 bit 0 (Q0) 1110 \* 0 Device-end STP0 bit 1 (Q1) 1 Print ready STPO bit 2 (Q2) 1 2 3 STP0 bit 3 (Q3) 2 Channel 9 3 Channel 12 4 STP0 bit 4 (Q4) 4 Initial ready 5 STP0 kit 5 (Q5) 5 Hammer check 6 STPO bit 6 (Q6) 7 6 Parity check STP0 bit 7 (Q7) 7 Print request 1403 Diagnostic Conditions (PRD) 1 Storage Protect 1 (STP1) MDM 4-202 1111\* Diagnostic Decode 1 0011 0 STP1 bit 0 0 PCC TR 128 STP1 bit 1 1 PCC TR 64 2 STP1 bit 2 1 PCC TR PCC TR 2 32 3 STP1 bit 3 3 16 Ш STP1 bit 4 STP1 bit 5 PCC TR 4 5 8 5 PCC TR 4 6 STP1 bit 6 PCC TR 2 6 7 STP1 bit 7 7 PCC TR 1 0100 Unassigned Diagnostic Decode 2 0 Print Control 1 Print Scan 0101 Unassigned PSS Gate 3 Home Gate 0110 Unassigned Ц SS3 IR 5 Print Compare 0111 Unassigned 6 Last Scan 7 Sync Check Latch 1000 Unassigned Diagnostic Decode 3 Print Character Counter Length (PCCL) 0 Carriage Busy 1001 0 Spare Space Drive 1 2 Skip Drive 1 Spare 3 Carriage Settling PCCL 120 2 Carriage Brush Reg 8 LL L 3 PCCL 80 5 Carriage Brush Reg 4 4 PCCL 60 PCCL 48 6 Carriage Brush Reg 2 5 Carriage Brush Reg 1 7 PCCL 40 6 7 PCCL 16 Diagnostic Decode 4 Note: If 00, 40, or 80 is specified by the PCCL=AS Move/Arithmetic word, a 0  $\mathbf{PLC}$ 1 PIB C1 graphic-set length of 240 is set. A count 2 PLB C2 of 48 applies to all printers without MCS. 3 PIB C3 MCS Mode 4 1010 Unassigned 5 Addr Hd Off 6 E1 Emitter 7 Channel 1 Latch 1403 PLB Data Out (PRO) \* These eight fields tested with Branch on 1011 0 PLB data out 128 Condition or Branch on Mask control 1 PLE data out 64 words. 2 PLB data out 32 3 PLB data out 16 External Field Definitions, 1403 Mode (CPU L PLB data out 8 5 PLB data out 4 tc EXT) 6 PLB data out 2 0000 Unassigned 7 PLB data out 1 0001 Unassigned 1100 Unassigned

1403 Carriage Data Out (PRC) Dynamic Condition Register (DYN) MDM 4-40 1101 0 Skip Carriage control 8 0100\* 0 Z=0 1 Carriage control 4 Storage wrap latch 1 2 Carriage control 2 CVFL (overflow) 3 2 Adder carry L Carriage control 1 3 Not hold in (Dir Ctl Feat) 5 Ш 0 6 Set carr-busy if 6-7 both cn 5 Check disable switch Set carr-kusy if 6-7 both on DYN Reg bit 6 (HZ=0) 7 6 7 DYN Reg bit 7 (LZ=0) 1110 Unassigned Status Register (S) MDM 4-16 1403 PLBAR Data Out (PR) 0101\* 0 S0 True/compl latch S1 Z=nonzero (all arith ops) 1 S2 Z=nonzero (log, dec, & bin ops) S3 ALU 0-bit carry 1111 0 PLB AR data out 128 2 PLB AR data out 64 1 3 PLB AR data out 32 S4 Invalid decimal digit 2 ш PLB AR data out 16 5 S5 (general purpose) 3 4 PLB AR data out 8 6 S6 Not execute 5 PLB AR data out 4 7 S7 Not exceptional condition 6 PLB AR data out 2 7 PLB AR data out 1 MMSK Register, Bits 0-7 (MMSK) MDM 4-15 External Field Definitions, Console Printer-Keyboard Mode (EXT to CPU) 0110\* 0 MMSK0 Channel high trap MMSK1 2311 disk control trap 1 2 MMSK2 Channel low trap 0000 Unassigned 3 MMSK3 2540 reader trap 4 MMSK4 2540 punch trap 0001 Unassigned MMSK5 Comm chnl bit service 5 MMSK6 Comm chnl char service 6 7 MMSK7 Level 1 priority hold Storage Protect 0 (STP0) MDM 4-41 Branch Conditions (BA) 0010 0 STPO bit 0 (CO) MDM 4-40 STP0 bit 1 (01)1 STP0 bit 2 (C2) 0111\* 0 Chnl 0 interruption latch 2 3 STP0 bit 3 (Q3) Mode bit 0 1 Mode bit 1 4 STP0 bit 4 (C4) 2 STP0 bit 5 (Q5) Mode bit 2 5 3 STP0 bit 6 (Q6) IPL latch 6 Ц 7 SIPO bit 7 (Q7) 5 LS zone 0 LS zone 1 6 7 LS zcne 2 Storage Protect 1 (STP1) 1000 Unassigned MDM 4-41 1001 Unassigned STP1 bit 0 0011 0 1 STP1 bit 1 2 STP1 bit 2 1052 Data In (TI) STP1 bit 3 3 MDM 4-73 Ш STP1 bit 4 5 STP1 bit 5 1010 0 Uppercase store latch (bits 0-1) Uppercase store latch (bits 0-1) 6 STP1 bit 6 1 7 STP1 bit 7 KB bit B 2 KB bit A 3 KB bit 8 Ц 5 KB bit 4 6 KB bit 2 7 KB bit 1 P KB bit C

1052 Tilt/Rotate Register (TR) Storage Protect 0 (STP0) MDM 4-74 0010 0 STP0 bit 0 (Q0) 1011 0 Tilt bit 1 1 STP0 bit 1 (Q1) Tilt bit 2 STPO bit 2 (Q2) 1 2 2 Rotate bit 5 3 STP0 bit 3 (Q3) 4 STP0 bit 4 (Q4) Rotate bit 2A 3 5 STP0 bit 5 (Q5) 4 Rotate bit 2 5 Rotate bit 1 6 STP0 bit 6 (Q6) 6 Uppercase character 7 STP0 bit 7 (Q7) Function cycle 7 1100\* Unassigned Storage Protect 1 (STP1) 0011 STP1 bit 0 0 STP1 bit 1 1 PRKB Diagnostic Branch Conditions (TD) STP1 bit 2 2 MDM 4-75 3 STP1 bit 3 4 STP1 bit 4 1101\* 0 0 5 STP1 bit 5 STP1 bit 6 1 0 6 2 Read/write share latch 7 STP1 bit 7 3 New line latch 4 Key switch (On), CE mode 0100 Unassigned 5 Shift cycle latch Lowercase decode 6 7 Uppercase decode 0101 Unassigned PRKB Branch Conditions (TT) 0110 Unassigned MDM 4-71 0111 Unassigned 1110\* 0 Attn Request key 1 Not-ready to ready 1000 Unassigned Intervention required 2 3 Alter/display Unassigned 1001 4 Keyboard check 5 Alternate coding key 1010 Unassigned 6 PRKB request 7 Logout latch 1011 Unassigned 1100 Unassigned PRKB Branch Conditions (TU) 1101 Unassigned MDM 4-71 1110 Unassigned 1111\* 0 Read latch 1 Write latch Microforce (Int Stkd) PRKB Data Out (TE) 2 3 Alter/display active 4 Cycle interlock latch 1111 0 TE bit 0 5 Data ready latch 1 TE bit 1 TE bit 2 6 Initialize printer 2 TE bit 3 7 Printer Lusy 3 L TE bit 4 \* These eight fields tested with Branch on 5 TE bit 5 condition or Branch on Mask control 6 TE bit 6 7 TE bit 7 words. External Field Definitions, Communication External Field Definitions, Console Printer-Keyboard Mode (CPU TO EXT) Mode (EXT TO CPU) 0C00 Unassigned 0000 Unassigned 0001 Unassigned 0001 Unassigned

Storage Protect 0 (STP0) Branch Conditions (BA) MDM 4-90MDM 4-40 0010 0 STP0 bit 0 (HQ0) 0111\* 0 Chnl 0 interruption latch STPO bit 1 (HQ1) Mode bit 0 1 1 STP0 bit 2 (HQ2) 2 2 Mode bit 1 3 STPO bit 3 (HC3) 3 Mode bit 2 4 STP0 bit 4 (04) 4 IPL latch 5 LS zone kit 0 5 STP0 bit 5 (Q5) 6 STP0 bit 6 (Q6) LS zone bit 1 6 7 STP0 bit 7 (Q7) 7 LS zone bit 2 1000 Unassigned Storage 1 (STP1) MDM 4-41 1001 Unassigned 0011 0 STP1 bit 0 STP1 bit 1 1 2 STP1 bit 2 Data In (DAIN) 3 STP1 bit 3 MDM 4-47 L STP1 bit 4 STP1 bit 5 1010 0 Sync data in bit 0 5 STP1 bit 6 1 Sync data in bit 1 6 STP1 bit 7 7 2 Sync data in bit 2 3 Sync data in bit 3 4 Sync data in bit 4 Sync data in bit 5 5 Sync data in bit 6 Dynamic Condition Register (DYN) 6 MDM 4-40 7 Sync data in bit 7 0100 \* 0 Z=0 Storage wrap latch 1 2 CVFI (overflow) Line Address In (LAIN) MDM 4-47 3 Adder carry 4 Not hold in (Dir Ctl Feat) Check disable switch 5 1011 0 Comm line address in bit 0 Comm line address in bit 1 DYN reg bit 6 (HZ=0) 6 1 7 DYN Reg Lit 7 (LZ=0) Comm line address in bit 2 2 Comm line address in bit 3 3 Ш Comm line address in bit 4 5 0 Status Register (S) 6 0 MDM 4-16 7 0 0101\* 0 S0 True/compl latch 1 S1 Z=nonzero (all arith cps) 2 S2 Z=nonzero (log, dec, & bin ops) 3 S3 ALU 0-bit carry Line Adapter Conditions (LACON) MDM 4-47 S4 Invalid decimal digit 4 S5 (general purpose) 5 Sync Start/Stop 1100\* 0 IA Enable latch LA Enable latch 6 S6 Not execute 7 S7 Not exceptional condition 1 Sync Clock Ind. 2 Even/odd parity Even/odd parity
3 Leased/switched L'S'D/SW'D NETWORK Interface A/B Bit overflow Ц MMSK Register, Bits 0-7 (MMSK) 5 Test Mode latch Recv bit buffer MDM 4-15 6 Transmit latch 7 Req to send lat 0110\* 0 MMSK0 Channel high trap 1 MMSK1 2311 disk control trap 2 MMSK2 Channel low trap 3 MMSK3 2540 reader trap 4 MMSK4 2540 punch trap 5 MMSK5 Comm chnl bit serv 6 MMSK6 Comm chnl char serv MMSK7 level 1 priority hold

Line Adapter Status (LASTAT) MDM 4-47 1101\* 0 Sync Start/Stop Clr to send off Clear to send off Data set rdy on Data set ready on 1 2 Sync Char trap TC type II/I Type TTY/IEM Char overflow 3 4 Transmit latch Char phase Transmit line trigger (mrk/sp) 5 1-sec timeout trap 6 3-sec timeout Line quiet; recv line (mark/space) trap 7 Sync chain trap Telegr line adptr Dial In (DILIN) MDM 4-47 1110\* 0 Not Pwr Indicator on (PWI) Not Akandon Call and Retry (ACR) 1 Not Present Next Digit (PND) 2 Not Digit Present (DPR) 3 4 Not Call Reqst (CRQ); cr Nct Diag NBRB (if DPR on) 5 Not Dial NBR4 (diag) Not Diag NBR2 (diag) 6 7 Valid address; dial NBR1 (if DPR on) General Status (GSIAI) MDM 4-47 1111\* 0 Sync trap 1 Start/stop chain trap Start/stop Data set ready trap 2 3 Dial trap Ц Start/stop char trap 5 Timeout update trap 6 7 Timeout remember \* These eight fields tested with Branch on Condition or Branch on Mask control words. External Field Definitions, Communication Mode (CPU TO EXT) 0C00 Unassigned 0001 Unassigned Storage Protect 0 (STPO) 0010 0 SIP0 bit 0 (Q0) STP0 kit 1 (Q1) 1 2 STPO bit 2 (Q2) STP0 kit 3 (Q3) 3 STPO bit 4 (C4) 4 5 STPO Lit 5 (Q5) 6 STPO bit 6 (Q6) 7 STPO tit 7 (Q7)

Storage Protect 1 (STP1) 0011 0 STP1 bit 0 (Q0) STP1 bit 1 (Q1) 1 2 STP1 bit 2 (Q2) 3 STP1 bit 3 (Q3) STP1 bit 4 (04) 4 5 STP1 bit 5 (Q5) 6 STP1 bit 6 (Q6) 7 STP1 bit 7 (Q7) 0100 Unassigned Communications Adptr Diag Register (CADR) 0101 0 Bit trap check 1 General trap 2 First priority-check trap 3 ш 5 6 7 0110 Unassigned Communications Parity Check (PARCK) 0111 0 Data bit 0 Data bit 1 1 Data bit 2 2 3 Data bit 3 Ц Data bit 4 5 Data bit 5 6 Data bit 6 7 Data bit 7 1000 Unassigned Line Adapter Diag Register (LADR) Sync Start/Stop Sync Diag ctls Adpt Grp Test Ocs Gate A-Reg DAIN Adpt Grp Test Ocs 1001 0 1 2 Gate B-Reg DAIN Gate TRCR to DAIN 3 Ц Gate Diag Stat-DAIN 5 Recv data mark diag 6 Select diag clcck 7 Diag clock

1010 Unassigned

Data Out (DAOUI)

1011	0	Cata	out	bit	0	(sync)
	1	Data	out	bit	1	(sync)
	2	Data	out	bit.	2	(sync)
	3	Data	out	bit	3	(sync)
	4	Data	out	bit	4	(sync)
	5	Data	out	bit	5	(sync)
	6	Data	out	bit	6	(sync)
	7	Data	out	bit	7	(sync)

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1100 Unassigned Dynamic Condition Register (DYN) 0100\* 0 Z=0 Dial Out (DILOUT) 1 Storage wrap latch 2 CVFL (overflow) 1101 0 Diag 1 Adder carry 3 Diag 2 Not hold in (Dir Ctl Feat) 1 L 2 Direct present (DPR) Check disable switch 5 3 Call request (CRQ) 6 DYN Reg bit 6 (HZ=0) 4 Dial digit NBR8 7 DYN Reg bit 7 (LZ=0) 5 Dial digit NBR4 Dial digit NBR2 6 7 Dial digit NBR1 Status Register (S) 0101\* 0 S0 True/compl latch 1110 Unassigned S1 Z=nonzero (all arith ops) 1 S2 Z=nonzero (log, dec, & bin ops) 2 S3 ALU 0-bit carry 3 Line Address Out (LAOUT) 4 S4 Invalid decimal digit 5 S5 (general purpose) 1111 LAOUT bit 0 0 6 S6 Not execute LAOUT bit 1 1 7 S7 Not exceptional condition 2 IAOUT kit 2 LAOUT bit 3 3 4 IACUT bit 4 5 MMSK Register, Bits 0-7 (MMSK) 6 7 0110\* 0 MMSK0 Channel high trap MMSK1 2311 disk control trap 1 2 MMSK2 Channel low trap MMSK3 2540 reader trap MMSK4 2540 punch trap MMSK5 Comm chnl bit service External Field Definitions, 2540 Reader 3 Mode (EXT TO CPU) 4 5 0000 Unassigned 6 MMSK6 Comm chnl char service 7 MMSK7 Level 1 priority hold 0001 Unassigned Branch Conditions (BA) Storage Protect 0 (SIP0) 0111\* 0 Chnl 0 interruption latch 0010 0 STP0 bit 0 (Q0) 1 Mode bit 0 1 STPO bit 1 (C1) 2 Mode bit 1 STP0 bit 2 (Q2) Mode bit 2 2 3 3 STPO bit 3 (C3) 4 IPL latch Ц 5 LS zone bit 0 STP0 bit 4 (Q4) 5 STPO bit 5 (C5) 6 LS zone bit 1 STP0 bit 6 (Q6) STP0 bit 7 (Q7) 7 LS zone bit 2 6 7 Diagnostic R/P Conditions 1 (RPD1) Storage Protect 1 (STP1) MDM 4-43 0011 0 STP1 bit 0 1000 0 R/P tens AR A STP1 bit 1 R/P tens AR B 1 1 STP1 bit 2 2 R/P tens AR C 2 R/P tens AR D STP1 bit 3 3 3 STP1 bit 4 R/P tens AR E 4 Ш 5 STP1 bit 5 5 Punch address check 6 STP1 bit 6 6 Punch overrun latch STP1 bit 7 7 Punch sync check latch 7

Diagnostic R/P Conditions 2 (RPD2) MDM 4-43 1001 0 R/P units AR A R/P units AR B 1 2 R/P units AR C R/P units AR D 3 ш R/P units AR E 5 Reader address check Reader overrun latch 6 7 Reader sync check latch Reader/Punch Data in 2 (RP2) MEM 4-110 Col 1 RD2 punch check data in 1010 0 1 Col 2 RD2 punch check data in Ccl 3 RD2 punch check data in 2 Col 4 RD2 punch check data in 3 Col 5 RD2 punch check data in 4 5 Col 6 RD2 punch check data in 6 Col 7 RD2 punch check data in Col 8 RD2 punch check data in 7 Reader/Punch Data In 1 (RP1) MDM 4-110 0010 0 Col 1 RD1 PFR dat in 1011 Col 2 RD1 PFR data in 1 2 Col 3 RD1 PFR data in Col 4 RD1 PFR data in 3 Col 5 RD1 PFR data in 4 5 Col 6 RD1 PFR data in Col 7 RD1 PFR data in 6 Col 8 RD1 PFR data in 7 1100\* Unassigned 0011 Reader Branch Conditions (RS) MDM 4-43 1101\* 0 Not gate read complete 2540 Not reader intervention (rdr 1 readv) 2 Unit exception gate reader Reader check 3 Reader validity check Reader device end (hardware) L 5 0101 Reader status request 6 7 Not 1400 unit exception 0110 0111 Reader/Punch Branch Conditions (RPS) MDM 4-43 1000 1110\* 0 Reader punch on-line 2540 rdr trap req (data avail, 1 CSL) 1010 Not 1400 timeout 2 3 0 1011 4 Punch brush CL 5 1100 Punch decode Reader select latch 6 7 Punch select latch

Punch Branch Conditions (PS) MDM 4-43 1111\* 0 Not pch intervention (pch ready) Not 4-bit mod rull-on 1 2 PFR unit exception gate Punch equipment check 3 Punch PFR validity 4 5 Punch device end (hardware) Punch status request 6 7 \* These eight fields tested with Branch on Condition or Branch on Mask control words. External Field Definitions, 2540 Reader Mode (CPU TO EXT) 0000 Unassigned 0001 Unassigned Storage Protect 0 (STP0) STPO bit 0 (QO) 0 STP0 bit 1 (01) 1 STPO bit 2 ( $\tilde{Q}2$ ) 2 3 STP0 bit 3 (Q3) 4 STPO bit 4 (Q4) STP0 bit 5 (Q5) 5 6 STPO bit 6 (Q6) 7 STP0 bit 7 (Q7) Storage Protect 1 (STP1) STP1 bit 0 0 STP1 bit 1 1 STP1 bit 2 2 STP1 bit 3 3 4 STP1 bit 4 5 STP1 bit 5 STP1 bit 6 6 7 STP1 bit 7 0100 Unassigned Unassigned Unassigned Unassigned Unassigned 1001 Unassigned Unassigned Unassigned

- 1100 Unassigned
- 1101 Unassigned

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1110 Unassigned Status Register (S) MDM 4-16 Punch Data Out (PO) 0101\* 0 S0 True/compl latch S1 X=nonzero (all arith ops) 1 S2 Z=nonzero (log, dec, & bin ops) 0 PO bit 0 1111 2 1 PO bit 1 3 S3 ALU 0-bit carry S4 Invalid decimal digit 2 PO bit 2 4 3 PO bit 3 5 S5 (general purpose) PO bit 4 4 6 S6 Not execute 5 PO bit 5 7 S7 Not exceptional condition 6 PO bit 6 7 PO bit 7 MMSK Register, Bits 0-7 (MMSK) External Field Definitions, Channel Mode MDM 4-15 (EXT TO CPU) 0110\* 0 MMSK0 Channel high trap MMSK2 Channel low trap 0000 Unassigned 2 3 MMSK3 2540 reader trap MMSK4 2540 punch trap Ш 0001 Unassigned 5 MMSK5 Conn chnl bit service MMSK6 Comm chnl char service 6 7 MMSK7 Level 1 priority hold Stcrage Protect 0 (STF0) MEM 4-90 Branch Conditions (BA) MDM 4-40 0010 0 STPO bit 0 (GQO) STPO bit 1 (GC1) 1 STP0 bit 2 ( $\overline{GQ2}$ ) 2 0111\* 0 Chnl 0 interruption latch STPO bit 3 (GC3) 3 1 Mode tit 0 μ STPO bit 4 (Q4) 2 Mode bit 1 5 STPO bit 5 (Q5) Mode bit 2 3 STP0 bit 6 (Q6) STP0 bit 7 (Q7) 4 IPL latch 6 LS zone bit 0 5 7 LS zcne kit 1 6 7 LS zone bit 2 Storage Protect 1 (STP1) MDM 4-41 1000 Unassigned STP1 bit 0 0011 0 1 STP1 bit 1 1001 Unassigned STP1 bit 2 2 3 STP1 bit 3 4 STP1 bit 4 1010 Unassigned 5 SIP1 bit 5 6 STP1 bit 6 STP1 bit 7 1011 Unassigned Dynamic Condition Register (DYN) Channel Branch Conditions (GS) MDM 4-40 MDM 4-45 0100\* 0 Z=0 1100\* 0 Data chain request latch Storage wrap latch Buffered device latch 1 1 2 CVFL (overflow) 2 Burst latch 3 Adder carry 3 Channel parity-error latch Ц Not hold in (Dir Ctl Feat) 4 Initial select latch 5 Check disable switch 5 Channel 1 interrupt buffer latch Spare DYN Req bit 6 (HZ=0) 6 6 7 DYN Req Lit 7 (LZ=0) 7 Suppress control latch

Channel Branch Conditions (GT) Storage Protect 1 (STP1) MDM 4-409 STP1 bit 0 (Q0) 0011 0 1101\* 0 Address in 1 STP1 bit 1 (Q1) STP1 bit 2 (Q2) Not select in 2 1 Service in 3 STP1 bit 3 (Q3) 2 STP1 bit 4 (Q4) Status in LL L 3 Operational in 4 5 STP1 bit 5 (Q5) 5 Not request in 6 STP1 bit 6 (Q6) 6 Channel identification latch 7 STP1 bit 7 (Q7) 7 Channel diagnostic latch 0100 Unassigned Channel Diagnostic Register (GD) MDM 4-411 0101 Unassigned 1110 \* 0 Operational out Service out 0110 Unassigned 1 2 Address out 3 Command out 4 0 0111 Unassigned 5 Select out 6 0 7 Suppress out 1000 Unassigned 1001 Unassigned Channel Bus In (GB/IN) MDM 4-405 1010 Unassigned 1111\* 0 Channel bus in bit 0 Channel bus in bit 1 1 Channel bus in bit 2 1011 Unassigned 2 Channel bus in bit 3 3 Channel bus in bit 4 Ш 5 Channel bus in bit 5 1100 Unassigned Channel bus in bit 6 6 Channel bus in bit 7 7 1101 Unassigned \* These eight fields tested with Branch on 1110 Unassigned Condition or Branch on Mask control words. Channel Bus Out (GB/OUT) External Field Definitions, Channel Mode 1111 0 Channel bus out bit 0 Channel bus out bit 1 (CPU TO EXT) 1 Channel bus out bit 2 2 Channel bus out bit 3 0C00 Unassigned 3 4 Channel bus out bit 4 0001 Unassigned 5 Channel bus out bit 5 Channel bus out bit 6 6 Channel bus out bit 7 Storage Protect 0 (STP0) External Field Definitions, 2560 Mode (EXT 0010 0 STP0 bit 3 (Ç0) to CPU) STPO bit 1 (Q1) 1 2 STP0 bit 2 (Q2) 2560 External 3 (MFD3) (20 Mode Operation) STPO bit 3 (C3) 3 4 STPO bit 4 (Q4) 0 0000 + SEC first PCH EJSEL 5 STP0 bit 5 (Q5) 1 - FCB4 to FCB5 FL 6 STP0 bit 6 (Q6) 2 + SEC PRE PCH REG SEL 7 STP0 bit 7 (Q7) 3 - FCB3 to FCB6 4 + SEC read inject SEL - Card PRT MAG strobe 5 + Secondary hopper SEL 6 7 + 100 micro SEC LW POT

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2560 External 3 (MFD3) (2540 Emulator Storage Protect 1 (STP1) (2540 Emulator Operation) Operation) 0000\*\*0 + PRI hopper empty 0011\*\*0 + STP1 bit 0 1 + STP1 bit 1 + SEC hopper empty 1 2 + Punch check light FL 2 + STP1 bit 2 3 Spare 3 + STP1 bit 3 See Note 5 + Punch status request 4 + STP1 bit 4 AAAD Routine 4 5 + Read check 5 + STP1 bit 5 \*E60 Listing 6 Spare 7 Spare + STP1 bit 6 + STP1 bit 7 6 7 2560 External 1 (MFD1) 0100\* Same as in CPU Mode 0101\* Same as in CPU Mode 0110\* Same as in CPU Mode 0001 0 + Feed CB6 + Feed CB5 0111\* Same as in CPU Mode 1 2 + Feed CB4 - Feed CB3 3 + Feed CB2 L 5 Spare 2560 Read Rows 4-9 (MFR1) + Feed Clutch select 6 7 - Motor ready 1000 0 - PRE RD SEC SC2 EXP 1 + 2540 RDR device end 2 + Card ccde FL4 + Card code FL5 3 2560 External 4 (MFD4) (20 Mode Operation) Ц + Card code FL6 5 + Card code FI7 0010 0 + Corn kick SC9 EXP + Card code FL8 6 + AFT PRT SC8 EXP + Card code FL9 1 2 + PRE PRT SC7 EXP + PRE PCH PRI SC5 EXP 3 LL. - Read cell 3 exposed 5 - Cell 3 dark FL 2560 External 5 (MFD5) + Input station SC1 EXP 6 + Feed CB1 7 1001 0 - Cell 1 dark FL - Cell 4 dark FL 1 2 - Cell 5 dark FL - Punch CB1 3 Storage Protect 0 (STF0) (2540 Emulator - Punch CB2 LL LL Operaticn) 5 - PCH INCR DR CEE + PCH push clutch SEL 6 0010\*\*0 + STP0 kit 0 (Q0) + Cell 8 dark FL 1 + STP0 bit 1 (01) 2 + STPO kit 2 (C2) + STP0 bit 3  $(\bar{Q}3)$ 2560 Read Rows 12-3 (MFR2) 3 4 + STP0 kit 4 (Q4) 5 + STP0 bit 5 (Q5) 1010 0 + Diag feed check 6 + STPO bit 6 (Q6) 1 + 2540 PCH device end 7 + STP0 bit 7 (07) 2 + Card code FL12 3 + Card code FL11 Ц + Card ccde FL0 5 + Card code FI1 2560 External 2 (MFD2) (20 Mode Operation) 6 + Card code FL2 7 + Card code FI3 0011 0 + PRI first PCH EJ SEI - Allow COL emitter FL 1 + PRI PRE PCH REG SEL 2560 External 6 (MFD6) 2 - FCB1 to FCB2 FL 3 4 + PRI read inject SEL 1011 0 + PRT gate SEL/TRAN RL 1 - Cell 7 dark FL 5 + Read cell - 4-9 EXP - COL emitter test FL 6 + Primary hopper SEL 2 3 + 2560 stacker SEL REQ 7 + Any punch DR 4 + Corner kick MAG SEL 5 - Pass print FL 6 - Pass punch FL + PRE RD PRI SC3 EXP

2560 Conditions 1 (MFS) 2560 Stacker Select (MFSS) 1100\* 0 + Cycle run 1 + 2560 primary 2 + Card in PRE PUNCH 0001 0 1 2 3 - SC7 DRK FL-CD in PRT 3 See Note 1 4 + 2560 punch execute 5 + 2560 read execute 6 + 2560 card in PRE RD 4 Set STS latch 4 Set STS latch 2 5 6 Set STS latch 1 + Any feed CB 7 2560 Punch Date (MFPU) (20 Mode Operation) 2560 External 7 (MFD7) 0011 0 Set data BFR LCH12 1101 0 - Punch push CB1 1 Set data BFR LCH11 1 - Punch push FI1 2 Set data BFR LCH0 2 + SEC punch push SEL 3 + PRE FCH SEC SC4 EXP 3 Set data BFR LCH8 4 Set data BFR LCH9 4 + PRI punch push SEL 7 Set data BFR LCH1 See Note 2 5 + PRE PCH PRI SC5 EXP 6 Set data BFR LCH2 6 - Cell 2 dark FL 6&7 Set data BFR LCH3 5 Set data BFR LCH4 7 + Mechan cycle 587 Set data BFR LCH5 566 Set data BFR LCH6 5,667 Set data BFR ICH7 2560 Conditions 2 (MFT) 0100 Unassigned 1110 \* 0 + Feed check - 2560 card print REQ 1 2 + 2560 punch REQ 2560 PRT Head Select (MFHS) 3 + Print execute FL 4 - 2560 read REC FL 0101 0 Set head SEL latch 4 5 - Run out REQ Set head SEL latch 2 1 - 2540 RDR status REQ 6 2 Set head SEL latch 1 7 + PCH INCR DR CBA 3 4 5 6 2560 External 8 (MFD8) 7 1111 0 + Read or punch check 0110 Unassigned 1 + Print husy - 2560 ready 2 3 - Hopper check 2560 Print Latches 1-8 (MFPR1) - COL EM FL L 5 - RD stroke INIK FL 0111 0 Set print latch 1 6 + Read cell 12-3 EXP 1 Set print latch 2 + Read COI EM 2 Set print latch 3 3 Set print latch 4 4 Set print latch 5 5 Set print latch 6 \* These fields may be tested with Branch on 6 Set print latch 7 Condition or Branch on Mask control words. 7 Set print latch 8 **\*\***These field definitions apply when 2540 Emulate latch is on. 1000 Unassigned External Field Definitions, 2560 Mode (CPU 2560 Print Latches 9-16 (MFPR2) to EXT) 1001 0 Set print latch 9 0C00 Unassigned Set print latch 10 1 2 Set print latch 11 3 Set print latch 12 4 Set print latch 13 5 Set print latch 14 6 Set print latch 15 7 Set print latch 16

1010 Unassigned

2560 Print Latches 17-24 (MFPR3)

1011	0	Set	print	latch	17
	1	Set	print	latch	18
	2	Set	print	latch	19
	3	Set	print	latch	20
	4	Set	print	latch	21
	5	Set	print	latch	22
	6	Set	print	latch	23
	7	Set	print	latch	24

1100 Unassigned

2560 Print Latches 25-32 (MFPR4)

1101	0	Set	print	latch	25
	1	Set	print	latch	26
	2	Set	print	latch	27
	3	Set	print	latch	28
	4	Set	print	latch	29
	5	Set	print	latch	30
	6	Set	print	latch	31
	7	Set	print	latch	32

1110 Unassigned

2560 Print Latches 33-S5 (MFPR5)

1111	0	Set	print	latch	33			
	1	Set	print	latch	34			
	2	Set	print	latch	35			
	3	Set	print	latch	S1	See	Note 3	3
	4	Set	print	latch	S2			
	5	Set	print	latch	S3			
	6	Set	print	latch	S4			
	7	Set	print	latch	S5			

#### Notes:

- 1. MFSS--Decode sets stacker SEL interlock
- MFSS-Decode sets stacker SET Interfock latch automatically as data is loaded into stacker select registers.
   MFPU--If punch time FL is on, data is XFERED to data BFR reg. If punch time FL is off, data is compared to data BFR req.
- 3. MFPR5--Sets print latches 33 thru S5 and turns on PRT REQ INIK.

EXTERNAL MNEMONIC	DEFIN	DISPLAYABLE FACILITY	SWITCH C	SWITCH D	ACCESSED B SET/RESET WORD ONLY		
BA	BRANCH CONDITIONS	ALL MODES	EXT TO CPU	YES		7	
BB	SOFT STOP BRANCH CONDITIONS	CPU MODE	EXT TO CPU	YES	CPU	F	
BC	EXTERNAL FACILITY	ALL MODES				-	YES
CADR	COMM ADAPTER DIAGNOSTIC REG	COMM MODE	CPU TO EXT			_	
CCTRL	START-STOP CONTROL	COMM MODE				-	YES
CHI	COUNTER 1 HIGH IN-DIAGNOSTIC	2311 MODE	EXT TO CPU	YES	2311	8	1
CLI	COUNTER 1 LOW IN-DIAGNOSTIC	2311 MODE	EXT TO CPU	YES	2311	9	1
CPF	READ DIRECT ENABLE	CPU MODE				-	YES
CSFTF	START STOP/SYNC	COMM MODE				-	YES
DAIN	DATA IN	COMM MODE	EXT TO CPU	YES	COMM	A	
DAOUT	DATA OUT	COMM MODE	CPU TO EXT			-	[
DASI	DISK ATTACHMENT STATUS IN	2311 MODE	EXT TO CPU	YES	2311	5	
DIAB	DIAGNOSTIC REG	2311 MODE				-	YES
DIAC	DIAGNOSTIC REG	2311 MODE				_	YES
DILIN	DIAL IN	COMM MODE	EXT TO CPU	YES	СОММ	E	
DILOUT	DIALOUT	COMM MODE	CPU TO EXT			-	
DR DC	DIAGNOSTIC REGISTER	ALL MODES		YES	CPU	C	NOTE 1
DS	DISK STATUS	2311 MODE	EXT TO CPU	YES	2311	E	
DYN	DYNAMIC CONDITION REGISTER	ALL MODES		YES		4	
FBI	FILE BUS IN FILE BUS OUT	2311 MODE	EXT TO CPU	YES	2311	1	
FBO FEBO	FILE BOS OUT	2311 MODE	CPU TO EXT			-	
FFI	FILE FLAGS IN	2311 MODE 2311 MODE	CPU TO EXT EXT TO CPU	YES	2311	- D	]
FFO	FILE FLAGS IN	2311 MODE	CPU TO EXT	163	2311	U	
FGA	FILE GATED ATTENTION	2311 MODE	EXT TO CPU	YES	2311	c	[
FIA	FILE INFORMATION	2311 MODE				0	YES
FIB	FILE INFORMATION	2311 MODE				-	YES
FIC	FILE INFORMATION	2311 MODE					YES
FOB	FILE OUT BUS-DIAGNOSTIC	2311 MODE	EXT TO CPU	YES	2311	3	1 120
FOP	FILE OP REGISTER	2311 MODE		YES	2311	F	j
GA	CHANNEL SIGNALS	CHAN MODE				_	YES
GB	CHANNEL SIGNALS	CHAN MODE				_	YES
GB/IN	CHANNEL BUS IN	CHAN MODE	EXT TO CPU	YES	CHNL	F	
GB/OUT	CHANNEL BUS OUT	CHAN MODE	CPU TO EXT				
GC	CHANNEL SIGNALS	CHAN MODE				_	YES
GD	CHANNEL DIAGNOSTIC REGISTER	CHAN MODE	EXT TO CPU	YES	CHNL	Е	
GS	CHANNEL BRANCH CONDITIONS	CHAN MODE	EXT TO CPU	YES	CHNL	С	ļ
GSTAT	GENERAL STATUS	COMM MODE	EXT TO CPU	YES	СОММ	F	
GT	CHANNEL BRANCH CONDITIONS	CHAN MODE	EXT TO CPU	YES	CHNL	D	1
JA	DIRECT CONTROL-2 TIMING	CPU MODE	CPU TO EXT			-	
JI	DIRECT CONTROL IN	CPU MODE	EXT TO CPU	YES	CPU	8	1
JO	DIRECT CONTROL-1	CPU MODE	CPU TO EXT			-	ł
LACON	LINE ADAPTER CONDITIONS	COMM MODE	EXT TO CPU	YES	СОММ	С	1
LADR	LINE ADAPTER DIAG REGISTER	COMM MODE	CPU TO EXT			-	]
LAIN	LINE ADDRESS IN	COMM MODE	EXT TO CPU	YES	СОММ	В	
LAOUT	LINE ADDRESS OUT	COMM MODE	CPU TO EXT			-	
LASTAT	LINE ADAPTER STATUS	COMM MODE	EXT TO CPU	YES	COMM	D	1
MC	ERROR REGISTER	CPU MODE	EXT TO CPU	YES	CPU	E	
MMSK MODE	MICROPROGRAM MASK REGISTER MODE REG (LS AND EXT ADDR	ALL MODES		YES (0 - 7)		6	NOTE 2 NOTE 3
10		ALL MODES	0011 70 717			-	
MS	MODULE SELECT REGISTER	2311 MODE	CPU TO EXT			-	[
MW P	MACH CHK. WAIT STATE LATCHES	CPU MODE	CPU TO EXT			-	VEO
	PUNCH SIGNALS	2540 MODE				-	YES
PARCK	COMMUNICATIONS PARITY CHECK PRINT CHAR COUNTER LENGTH		CPU TO EXT			-	
PCCL PO		1403 MODE	CPU TO EXT			-	1
PO		2540 MODE	CPU TO EXT CPU TO EXT			-	
PR	1403 PLBAR DATA OUT	1403 MODE	GPU TU EXT			-	VEC
FINA [	PRINTER SIGNALS	1403 MODE				-	YES

Figure 1-47. External Mnemonics and Addressing (Part 1 of 2)

EXTERNAL MNEMONIC	DEFIN	ITION		DISPLAYABLE FACILITY	SWITCH C	SWITCH D	ACCESSED BY SET/RESET WORD ONLY
PRB	PRINTER SIGNALS	1403 MODE				_	YES
PRC	1403 CARRIAGE DATA OUT	1403 MODE	CPU TO EXT			_	
PRD	1403 DIAGNOSTIC CONDITIONS	1403 MODE	EXT TO CPU	YES	1403	F	
PRI	1403 PLB DATA IN	1403 MODE	EXT TO CPU	YES	1403	В	
PRO	1403 PLB DATA OUT	1403 MODE	CPU TO EXT				
PRS	SENSE/STATUS CONDITIONS	1403 MODE	EXT TO CPU	YES	1403	Е	
PRT	PLBAR DATA IN	1403 MODE	EXT TO CPU	YES	1403	А	
PS	PUNCH BRANCH CONDITIONS	2540 MODE	EXT TO CPU	YES	2540	F	
R	READER SIGNALS	2540 MODE					YES
RP	2540 SIGNALS	2540 MODE				-	YES
RP1	READER/PUNCH DATA IN 1	2540 MODE	EXT TO CPU	YES	2540	В	
RP2	READER/PUNCH DATA IN 2	2540 MODE	EXT TO CPU	YES	2540	Ā	
RPD	2540 SIGNALS DIAG	2540 MODE				_	YES
RPD1	DIAGNOSTIC R/P CONDITIONS 1	2540 MODE	EXT TO CPU	YES	2540	8	120
RPD2	DIAGNOSTIC R/P CONDITIONS 2	2540 MODE	EXT TO CPU	YES	2540	9	
RPS	READER/PUNCH BR CONDITIONS	2540 MODE	EXT TO CPU	YES	2540	Ĕ	
RS	READER BRANCH CONDITIONS	2540 MODE	EXT TO CPU	YES	2540	D	
s	STATUS REGISTER	ALL MODES	LATIONO		NOT 2311	5	NOTE 4
SDI	SERIALIZER/DESERIALIZER IN	ALL MODES		11.5	101 2311	5	
301	DIAG	2311 MODE	EXT TO CPU	YES	2311	в	
SM	SYSTEM MASK	CPU MODE	CPU TO EXT	165	2311	D	
STPO	STORAGE PROTECT KEY	ALL MODES	CPU TU EXT	YES	NOTE 5	NOTE 5	
STP1	STORAGE PROTECT NET	ALL MODES	(NOT 0211)	-	NOTE 5		
SWAB			(NOT 2311)	YES		NOTE 5	
SWCD	CONSOLE ADDRESS SWITCHES A-B		EXT TO CPU				
TA	CONSOLE ADDRESS SWITCHES C-D 1052 SIGNALS		EXT TO CPU			· _	VEO
тс	TERMINATING CONDITIONS	1052 MODE	EVE TO OBL			-	YES
		2311 MODE	EXT TO CPU	YES	2311	A	
TD TF	PRKB DIAGNOSTIC REGISTER	1052 MODE	EXT TO CPU	YES	PRKB	D	ļ
1	PRKB DATA OUT	1052 MODE	CPU TO EXT			-	
TGRI		2311 MODE	EXT TO CPU	YES	2311	0	1
TGRO	TAG REGISTER OUT	2311 MODE	CPU TO EXT				
TI	1052 DATA IN	1052 MODE	EXT TO CPU	YES	PRKB	A	
TIM		CPU MODE	EXT TO CPU	YES	CPU	A	1
TR	1052 TIIT/ROTATE REGISTER	1052 MODE	EXT TO CPU	YES	PRKB	В	
TT	PRKB BRANCH CONDITIONS	1052 MODE	EXT TO CPU	YES	PRKB	E	-
TU	PRKB BRANCH CONDITIONS	1052 MODE	EXT TO CPU	YES	PRKB	F	
XINT	EXTERNAL INTERRUPT	CPU MODE	EXT TO CPU	YES	CPU	9	L
NOTE 1	THE DR REGISTER IS SET BY THE SE WORD OR A RETURN WORD WITH BI LATCH.						
NOTE 2	THE MMSK REGISTER 0-9 IS SET OR FOR OTHER WORD ACCESSES AND I ADDRESSED.						

NOTE 3 THE MODE REGISTER IS SET BY THE SET/RESET WORD. THE ACTUAL BIT STRUCTURE OF THE MODE REGISTER IS NOT ALWAYS WHAT IS DISPLAYED IN THE CONSOLE INDICATORS LABELED MODE/ZONE REG. THE MODE BIT DECODE IS DISPLAYED IN BITS 2, 3, 4, AND THE LS ZONE BIT DECODE IS DISPLAYED IN BITS 5, 6, AND 7. THESE COULD BE THE FORCED DECODES CAUSED BY AN MMSK BIT BEING SET.

NOTE 4THE S REGISTER IS SET OR RESET BY THE SET/RESET WORD. IT CAN ALSO BE ACCESSED<br/>BY A BRANCH WORD.BITS 0-6 CAN BE DISPLAYED DIRECTLY BUT BIT 7 OF THE DISPLAY INDICATES THE<br/>STATUS OF THE S7 BRANCH CONDITION LINE. TO DISPLAY THE ACTUAL CONDITION<br/>OF THE S7 LATCH, THE BA FACILITY MUST BE DISPLAYED AND BIT 0 WILL INDICATE<br/>THE S7 LATCH STATUS.

NOTE 5 REFER TO ROUTINE AAAD IN THE MICROPROGRAM LISTINGS FOR STP DISPLAY DETAILS.

Figure 1-47. External Mnemonics and Addressing (Part 2 of 2)

#### 1.9 LOCAL-STORAGE LOCATION DECODE

Figures 1-48 through 1-53 give the local storage locations designated by the AS- or BS-field decodes for the various operation mcdes specified by the mode register or the microprogram mask (MMSK) register. The mcde register is used for normal operations. The MMSK register is used during microprogram trap routines.

AS/BS Field	C o d		Zo	ne					
Decode	e	0	1	4	5	6	7		
0000 0001 0010 0011 0010 0101 0110 0111	U0 U1 V0 V1 G0 G1 D0 D1	CPU		Backups	Comm Chnl	2540	Chnl		
1000         10         CPU Bal Backup           1001         11         CPU 2311         CPU Bal Backup           1010         T0         CPU Bal Backup         Comm. Chnl Backup           1011         T1         Comm. Chnl Backup         Comm. Chnl Backup           1100         P0         Lv 1 work area for         local-storage           1110         H0         zones 4, 5, 6,         and 7.									
1	<u>Note:</u> The local storage areas are defined in the associated Figures.								

Figure 1-48. Local-Storage Zones for System/360 Operation

AS or BS	LS					
Field	Area					
Decode	Code	Local-Storage Area				
0000	υo	First operand address,				
		high-order byte				
0001	U1	First operand address,				
		low-order byte				
0010	VO	Second operand address,				
	{	high-order byte				
0011	V1	Second operand address,				
		low-order byte				
0100	G0	Operation code, byte 0				
0101	G1	Operation code, byte 1				
0110	DO	Data				
0111	D1	High-order 8 bits, 24-bit				
		2nd operand address				
1000	10	Instruction counter,				
		high-order byte				
1001	11	Instruction counter,				
	1	low-order byte				
1010	ТО	Working area (0 at start of				
		I-cycles)				
1011	T1	Gen Register Addr (B, X, R)				
1100	PO	Condition code				
1101	P1	Program mask and AMWP bits*				
1110	но	Data				
1111	H1	High-order 8 bits, 24-bit				
		instruction counter, or				
		first operand address				
Nata 1. *		I, machine check, wait state, and				
		state bits.				
P	nopietu :	State Dits.				
Note 2: Z	Zone 0 is	also used for integrated 2540 status				
		ning, and console attachment				
		between execution of CPU				
instructions.						

Figure 1-49. Local-Storage Decodes when Mode Register Bits 5-7 are 000: CPU Functions

Local-Storag	Local-Storage Allocations, Zone 1							
AS or BS	LS							
Field	Area							
Decode	Code	Local-Storage Area						
1000	10	Integrated file attachment						
		CCW count field,						
		high-order byte						
1001	11	Integrated file attachment						
		CCW count field,						
		low-order byte						
1010	то	Integrated file attachment						
		data address,						
		high-order byte						
1011	T1	Integrated file attachment						
		data address,						
		low-order byte						
1100	PO	Working area (Flags)						
1101	·P1	Working area (Command)						
1110	но	Integrated file attachment						
		next CCW address,						
		high-order byte						
1111	H1	Integrated file attachment						
		next CCW address,						
		low-order byte						

Figure 1-50. Local-Storage Decodes when Mode Register Bits 5-7 are 001: 2311 Disk Locations

Local-Stora	ge Allocat	ions, Zone 4
AS or BS	LS	
Field	Area	
Decode	Code	Local-Storage Area
0000	UO	Level-1 backup,
Į		high-order byte
0001	U1	Level-1 backup,
		low-order byte
0010	V0	Level-2 backup,
		high-order byte
0011	V1	Level-2 backup,
		low-order byte
0100	G0	Level-3 backup,
0101		high-order byte
0101	G1	Level-3 backup, low-order byte
0110	DO	Machine-check backup,
0110		high-order byte
0111	D1	Machine-check backup,
		low-order byte
The followi	ng locatio	ns are shared between zones
4, 5, 6, and		
	[	
1000	10	CPU branch and link backup,
		high-order byte
1001	11	CPU branch and link backup,
1010	то	low-order byte
1010	T1	Spare Spare
1100	PO	Level-1 working area
1100	P1	Level-1 working area
1110	но	Level-1 working area
1111	H1	Level-1 working area
	L <u></u>	

Figure 1-51. Local-Storage Decodes when Mode Register Bits 5-7 are 100: Address Backup Locations

Local-Storage	Local-Storage Allocations, Zone 5							
AS or BS	LS							
Field	Area							
Decode	Code	Local-Storage Area						
0000	UO	Line control word (LCW) address, high-order btye						
0001	U1	Line control word (LCW) address, low-order byte						
0010	VO	Character service pointer,						
		high-order byte						
0011	V1	Character service pointer,						
[		low-order byte						
0100	G0	Line control word (LCW)						
0101	G1	Line control word (LCW) +1						
0110	D0	Line control word (LCW) +2						
0111	D1	Line control word (LCW) +3						
The followin 4, 5, 6, and	•	ns are shared between zones						
1000	10	CPU branch and link backup, high-order byte						
1001	11	CPU branch and link backup, low-order byte						
1010	то	Comm chnl branch and link function, high-order byte						
1011	T1	Comm chnl branch and link function, low-order byte						
1100	PO	Level-1 working area						
1101	P1	Level-1 working area						
1110	но	Level-1 working area						
1111	H1	Level-1 working area						

Local-Storage	Allocat	tions, Zone 6
AS or BS	LS	
Field	Area	
Decode	Code	Local-Storage Area
0000	UO	Reader image buffer address, high-order byte
0001	U1	Reader image buffer address, low-order byte
0010	V0	Punch image card-image address, high-order byte
0011	V1	Punch image card-image address, low-order byte
0100	G0	Punch trap count, high-order byte
0101	G1	Not used
0110		Indicators
••••	D0	
0111	וט	Reader trap count
The followin 4, 5, 6, and	-	ons are shared between zones
1000	10	CPU branch and link backup, high-order byte
1001	11	CPU branch and link backup, low-order byte
1010	то	Spare
1011	T1	Spare
1100	PO	Level-1 working area
1101	P1	Level-1 working area
1110	но	Level-1 working area
1111	Н1	Level-1 working area

Figure 1-52. Local-Storage Deccdes when Mode Register Bits 5-7 are 101: Communications Channel

Figure 1-53.

Local-Storage Decodes when Mode Register Bits 5-7 are 110: 2540 Reader Punch

## 1.10 CODE CONVERSIONS (FIGURES 1-54 THROUGH 1-60)

Hex	Card Code	Hex	Card Code	Hex	Card Code	Hex	Card Code	Hex	Card Code
00	12-0-1-8-9	34	4-9	67	11-0-7-9	9A	12-11-2-8	CD	12-0-5-8-9
01	12-1-9	35	5-9	68	11-0-8-9	9B	12-11-3-8	CE	12-0-6-8-9
02	12-2-9	36	6-9	69	0-1-8	9C	12-11-4-8	CF	12-0-7-8-9
03	12-3-9	37	7-9	6A	12-11	9D	12-11-5-8	D0	11-0
04	12-4-9	38	8-9	6B	0-3-8	9E	12-11-6-8	D1	11-1
05	12-5-9	39	1-8-9	6C	0-4-8	9F	12-11-7-8	D2	11-2
06	12-6-9	3A	2-8-9	6D	0-5-8	A0	11-0-1-8	D3	11-3
07	12-7-9	3B	3-8-9	6E	0-6-8	A1	11-0-1	D4	11-4
08	12-8-9	3C	4-8-9	6F	0-7-8	A2	11-0-2	D5	11-5
09	12-1-8-9	3D	5-8-9	70	12-11-0	A3	11-0-3	D6	11-6
0A	12-2-8-9	3E	6-8-9	71	12-11-0-1-9	A4	11-0-4	D7	11-7
OB	12-3-8-9	3F	7-8-9	72	12-11-0-2-9	A5	11-0-5	D8	11-8
OC	12-4-8-9	40	No Punches	73	12-11-0-3-9	A6	11-0-6	D9	11-9
0D	12-5-8-9	41	12-0-1-9	74	12-11-0-4-9	A7	11-0-7	DA	12-11-2-8-9
OE	12-6-8-9	42	12-0-2-9	75	12-11-0-5-9	A8	11-0-8	DB	12-11-3-8-9
OF	12-7-8-9	43	12-0-3-9	76	12-11-0-6-9	A9	11-0-9	DC	12-11-4-8-9
10	12-11-1-8-9	43	12-0-3-9	70	12-11-0-7-9	AS	11-0-2-8	DD	12-11-5-8-9
11	11-1-9	45	12-0-5-9	78	12-11-0-8-9	AB	11-0-3-8	DE	12-11-6-8-9
12	11-2-9	46	12-0-6-9	78 79	1-8	AC	11-0-3-8	DF	12-11-7-8-9
13	11-3-9	40	12-0-0-9	79 7A	2-8	AC	11-0-5-8	EO	0-2-8
14	11.4.0	40	12.0.9.0	70	2.0	4.5	11.0.0.0		11.0.1.0
15	11-4-9 11-5-9	48 49	12-0-8-9	7B	3-8	AE	11-0-6-8	E1	11-0-1-9
1			12-1-8	7C	4-8	AF	11-0-7-8	E2	0-2
16	11-6-9	4A	12-2-8	7D	5-8	BO	12-11-0-1-8	E3	0-3
17 18	11-7-9 11-8-9	4B 4C	12-3-8 12-4-8	7E 7F	6-8 7-8	B1 B2	12-11-0-1 12-11-0-2	E4 E5	0-4 0-5
19	11-1-8-9	4D	12-5-8	80	12-0-1-8	B3	12-11-0-3	E6	0-6
1A	11-2-8-9	4E	12-6-8	81	12-0-1	B4	12-11-0-4	E7	0-7
1B	11-3-8-9	4F	12-7-8	82	12-0-2	85	12-11-0-5	E8	0-8
10	11-4-8-9	50	12	83	12-0-3	B6	12-11-0-6	E9	0-9
1D	11-5-8-9	51	12-11-1-9	84	12-0-4	B7	12-11-0-7	EA	11-0-2-8-9
1E	11-6-8-9	52	12-11-2-9	85	12-0-5	B8	12-11-0-8	EB	11-0-3-8-9
1F	11-7-8-9	53	12-11-3-9	86	12-0-6	B9	12-11-0-9	EC	11-0-4-8-9
20	11-0-1-8-9	54	12-11-4-9	87	12-0-7	BA	12-11-0-2-8	ED	11-0-5-8-9
21	0-1-9	55	12-11-5-9	88	12-0-8	BB	12-11-0-3-8	EE	11-0-6-8-9
22	0-2-9	56	12-11-6-9	89	12-0-9	BC	12-11-0-4-8	EF	11-0-7-8-9
23	0-3-9	57	12-11-7-9	8A	12-0-2-8	BD	12-11-0-5-8	FO	0
24	0-4-9	58	12-11-8-9	8B	12-0-3-8	BE	12-11-0-6-8	F1	1
25	0-5-9	59	11-1-8	8C	12-0-4-8	BF	12-11-0-7-8	F2	2
26	0-6-9	5A	11-2-8	8D	12-0-5-8	CO	12-0	F3	3
27	0-7-9	5B	11-3-8	8E	12-0-6-8	C1	12-1	F4	4
28	0-8-9	5C	11-4-8	8F	12-0-7-8	C2	12-2	F5	5
29	0-1-8-9	5D	11-5-8	90	12-11-1-8	СЗ	12-3	F6	6
2A	0-2-8-9	5E	11-6-8	91	12-11-1	C4	12-4	F7	7
2B	0-3-8-9	5F	11-7-8	92	12-11-2	C5	12-5	F8	8
2C	0-4-8-9	60	11	93	12-11-3	C6	12-6	F9	9
2D	0-5-8-9	61	0-1	94	12-11-4	C7	12-7	FA	12-11-0-2-8-
2E	0-6-8-9	62	11-0-2-9	95	12-11-5	C8	12-8	FB	12-11-0-3-8-
2F	0-7-8-9	63	11-0-3-9	96	12-11-6	C9	12-9	FC	12-11-0-4-8-
30	12-11-0-1-8-9	64	11-0-4-9	97	12-11-7	CA	12-0-2-8-9	FD	12-11-0-5-8-
31	1-9	65	11-0-5-9	98	12-11-8	СВ	12-0-3-8-9	FE	12-11-0-6-8-
32	2-9	66	11-0-6-9	99	12-11-9	cc	12-0-4-8-9	FF	12-11-0-7-8-

Figure 1-54. Hexadecimal/Punched-Card Translate Table

1-70 (7/69)

							Zones a	nd 9								
Twelve (T) Eleven (E) Zero (0)					т 0	T E	E O	T E O	T O	T E	E O	T E O	т	E	0	Black
	9	9	9	9	9	9	9	9								, a
Blank	С9	D9	E9	F9	89	99	Α9	B9	C0	6A	D0	70	50	60	FO	4
۱	01	11	21	31	41	51	<u>E1</u>	71	81	91	Al	B1	C1	DI	<u>61</u>	I
2	02	12	22	32	42	52	62	72	82	92	A2	B2	C2	D2	E2	I
3	03	13	23	33	43	53	63	73	83	93	A3	B3	C3	D3	E3	
4	04	14	24	34	44	54	64	74	84	94	A4	B4	C4	D4	E4	
5	05	15	25	35	45	55	65	75	85	95	A5	B5	C5	D5	E5	
6	06	16	26	36	46	56	66	76	86	96	A6	B6	C6	D6	E6	
7	07	17	27	37	47	57	67	77	87	97	A7	B7	C7	D7	E7	
8	08	18	28	38	48	58	68	78	88	98	A8	B8	C8	D8	E8	
18	09	19	29	39	00	10	20	30	80	90	A0	BO	49	59	69	
28	0A	۱A	2A	3A	CA	DA	EA	FA	8A	9A	AA	BA	4A	5A	<u>E0</u>	
38	ОВ	1 B	2B	ЗВ	СВ	DB	EB	FB	8B	9B	AB	BB	4B	5B	6B	
48	0C	۱C	2C	3C	сс	DC	EC	FC	8C	90	AC	BC	4C	5C	6C	
58	OD	۱D	2D	3D	CD	DD	ED	FD	8D	9D	AD	BD	4D	5D	6D	
68	OE	١E	2E	ЗE	CE	DE	EE	FE	8E	9E	AE	BE	4E	5E	<b>6</b> E	
78	OF	1F	2F	3F	CF	DF	EF	FF	8F	9F	AF	BF	4F	5F	6F	

Note: Exceptions to sequence are underlined

Figure 1-55. New Program Card Code to Hexadecimal

#### Extended Binary-Coded-Decimal Interchange Code (EBCDIC)

ositions 			<b>D1</b> 00		,	(	)1		۱ <b>г</b>		1	0	1	[	1	1	
4567	÷23	01	10	11	00	01	10	11		00	01	10	11	00	01	10	1
0000	NULL				blank	&	-		[					>	<	‡	(
0001							1			a	i			A	J		1
0010										b	k	s		В	к	S	2
0011										c	1	t		С	L	Т	:
0100	PF	RES	BYP	PN						d	m	U		D	м	U	
0101	нт	NL	LF	RS						e	n	v		E	N	V	
0110	LC	BS	EOB	UC						f	0	w		F	0	W	
0111	DEL	IDL	PRE	EOT					[	9	р	×		G	Р	X	
1000										h	q	у		н	Q	Y	1
1001					•		,			i	r	z		1	R	Z	
1010					?	1		:									
1011					•	\$	,	#									
1100					•-	*	%	a.									
1101					(	)	$\sim$	'									
1110					+	;	_	=									
1111					ŧ	Ø	+		[								

Figure 1-56. EBCDIC Chart

Positions		>7€ 00	;		_							0						
	→X5			<b>-</b> 1	ſ		)1		ור			0					1	
-4321	00	01	10	11	00	01	10	11		00	01	10	11		00	01	10	1
0000	NULL	DC			15 blank	0						@	Р					
0001	SOM	DC,			1	1						A	Q				a	
0010	EOA	DC2			"	2			11			В	R				Ь	
0011	EOM	DC3		1	#	3			11			С	S				c	
0100	EOT				8	4						D	т				d	
0101	WRU	ERR			%	5						E	U	] [			е	
0110	RU	SYNC			&	6						F	V	1 [			f	
0111	BELL	LEM			,	7			11			G	w				9	
1000	BKSP	s <sub>o</sub>			(	8						н	X				h	
1001	нт	S <sub>1</sub>			)	9						1	Y				i	
1010	LF	S <sub>2</sub>			*	:			11			J	Z				i	
1011	VT	S3			+	;						к	С				k	
1100	FF	S <sub>4</sub>			,	<			11			ι	$\overline{\}$				1	
1101	CR	\$5			-	=			11			M	5				m	
1110	so	S6			•	>						N	1			-	n	E
1111	SI	S7			7	?			11			0		11			0	D

#### American Standard Code for Information Interchange (ASCII) Extended to Eight Bits

Figure 1-57. ASCII-8 Chart

DEF CHAR	CARD CODE	BCD	СМ6	CM6 WM
Blank Blank ■ I : ▲ - / , % > /# * # @ : > J ? A B C D E F G H I ! J K L M N O P Q R + S T U > W X Y Z O 1 2 3 4 5 6 7 8 9	$\begin{array}{c} 12-3-8\\ 12-4-8\\ 12-5-8\\ 12-5-8\\ 12-7-8\\ 12\\ 11-3-8\\ 11-5-8\\ 11-5-8\\ 11-5-8\\ 11-5-8\\ 11-5-8\\ 11-7-8\\ 11\\ 0-1\\ 0-3-8\\ 0-4-8\\ 0-5-8\\ 0-7-8\\ 2-8\\ 3-8\\ 4-8\\ 5-8\\ 7-8\\ 12-0\\ 12-1\\ 12-2\\ 12-3\\ 12-4\\ 12-5\\ 12-6\\ 12-7\\ 12-8\\ 12-9\\ 11-0\\ 11-1\\ 11-2\\ 11-3\\ 11-4\\ 11-5\\ 11-6\\ 11-7\\ 11-8\\ 11-9\\ 0-2-8\\ 0-2\\ 0-3\\ 0-4\\ 0-5\\ 0-6\\ 0-7\\ 0-8\\ 0-9\\ 0\\ 1\\ 2\\ 3\\ 4\\ 5\\ 6\\ 7\\ 8\\ 9\\ \end{array}$	C BA8 21 BA84 BA84 1 BA842 BA8421 BA B 8 21 B 84 B 84 1 B 842 B 8421 B 84 B 8421 B 8421 B 8421 B 8421 A 1 A 8421 A 844 1 A 8421 A 844 1 A 8421 BA 82 BA 21 BA 82 BA 21 BA 82 BA 21 BA 82 BA 21 BA 84 BA 21 BA 8421 BA	40 48 4C 4D 4E 4F 50 5B 5D 5E 5F 60 61 88 6C 6E 6F 7A 7C 7D 7E 7C 01 22 34 5C 7D 10 23 45 5C 7D 5E 5F 60 61 88 6C 6A 86 7A 7C 7D 7E 7C 01 22 34 5C 7C 7D 7E 7C 01 22 34 5C 7C 7D 7E 7C 7D 7E 7C 7D 7E 7C 7D 7E 7C 7D 7E 7C 7D 7E 7C 7D 7E 7C 7D 7E 7C 7D 7E 7C 7C 7C 7C 7C 7C 7C 7C 7C 7C 7C 7C 7C	00 00 00 00 00 00 00 00 00 00 00 00 00

Collating	Grap 8 Bit	BCD	0	1	2	8 Bit 3	Cod	5	6	7	в	A	ВС   Е	CD 4	2	
00	blank	_	0	1	0	0	0	0	0	0	0	0	0	0	0	
01			0	1	0	0	1	0	1	1	1	1	1	0	1	
02	+	X)	0	1	0	0	1	1.	0	0.	1	1	1	1	0	
03	(		0	1	0	0	1	1	0	T	1	1	1	1	0	-
04	+	<	0	1	0	0	1	1	1	0	1	1	1	1	1	
05	GМ	GM	0	1	0	0	1	1	1	1	1	1	1	1	1	
06	&	& +	0	1	0	1	0	0	0	0	1	1	0	0	0	
07	s	s	0	1	0	1	1	0	1	1	1	0	1	0	1	
08	*	*	0	1	0	1	1	1	0	0	1	0	1.	1	0	
09	)		0	1	0	1	1	1	0	1	1	0	1	1	0	
10	;	;	0	1	0	1	1	1	1	0	1	0	1	1	1	L
11	мс	мс	0	1	0	1	1	1	1	1	1	0	1	1	1	_
12	-	-	0	1	1	0	0	0	0	0	1	0	0	0	0	_
13	/	/	0	1	1	0	0	0	0	1	0	1	0	0	0	-
14	,	,	0	1	1	0	1	0	1	1	0	1	1	0	1	
15	%	% (	0	1	1	0	1	1	0	0	0	1	1	1	0	_
16	<u>ws</u>	<u>ws</u>	0	1	1	0	1	1	0	1	0	1	1	1	0.	
17	+	1	0	1	1	0	1	1	1	0	0	1	1	1	1	-
18	SM	SM	0	1	1	0	1	1	1	1	0	1	1	1	1	_
19	15 "	ъ	0	1	1	1	1	0	1	0	0	1	0	0	0	
20		"= @/	0	1	1	1	1	0	1	1	0	0	1	0	1	-
21	@	@'	0	1	1	1	1	1	0	0	0	0	1	1	0	-
	⊽	:	0	1	1	1			0	1	0	0	1	1	0	-
23 24	= TM	> TM	0	1	1	1	1	1	1	0	0	0	1	1	1	-
24	тм t	1M 5	1	1	0	0	0	0	1	1	1	1	1	0	1	$\vdash$
25	° A	o A	1	1	0	0	0	0	0	1	1	1	0	0	0	
20	В	В	1	1	0	0	0	0	1	0	$\frac{1}{1}$	1	0	0	1	┢
28	c	c	1	1	0	0	0	0	1	1	1	1	0	0	;	$\vdash$
29	D	D	1	1	0	0	0	1	0	0	1	1	0	1	0	-
30	E	E	1	1	0	0	0	1	0	1	$\frac{1}{1}$	1	0	1	0	
31	F	F	1	1	0	0	0	1	1	0	1	1	0	1	1	-
32	G	G	1	1	0	0	0	1	1	1	1	1	0	1	1	┢
33	н	н	1	1	0	0	1	0	0	0	1	1	1	0	0	-
34	1	1	1	1	0	0	1	0	0	1	1	1	1	0	0	-
35	õ	ō	1	1	0	1	0	0	0	0	1	0	1	0	1	-
36	J	J	1	1	0	1	0	0	0	1	1	0	0	0	0	
37	к	к	1	. 1	0	1	0	0	1	0	1	0	0	0	1	
38	L	L	1	1	0	1	0	0	1	1	1	0	0	0	1	
39	м	м	1	1	0	1	0	1	0	0	1	0	0	1	0	
40	N	N	1	1	0	1	0	1	0	1	1	0	0	1	0	
41	0	0	1	1	0	1	0	1	1	0	1	0	0	1	1	
42	P	Р	1	1	0	1	0	1	1	1	1	0	0	1	1	
43	Q	Q	1	1	0	1	1	0	0	0	1	0	1	0	0	
44	R	R	1	1	0	1	1	0	0	1	1	0	1	0	0	
45	RM	RM	1	1	1	0	0	0	0	0	0	1	1	0	1	
46	S	s	1	1	1	0	0	0	1	0	0	1	0	0	1	
47	T	T	1	1	1	0	0	0	1	1	0	1	0	0	1	
48	U	U	1	1	1	0	0	1	0	0	0	1	0		0	-
49	V	V	1	1		0	0	1	0	1	0	1	0	1	0	
50	w v	w v	1	1	1	0	0	1	1	0	0	1	0	1	1	-
51	X Y	X Y	1	1	1	0	1	0	1	1	0	1	0	1	0	
52	Y Z	Y Z		1	1	0	1	0	0	1	0	1	1	0	0	-
53 54	2	0	1	1	1	1	0	0	0	0	0	0	1	0	1	-
55	1	1	1	1	1	1	0	0	0	1	0	0	0	0	0	-
56	2	2	1	1	1	1	0	0	1	0	0	0	0	0	1	
57	2	2	1	1	1	1	0	0	1	1	0	0	0	0	1	-
57	3 4	4	1	1	1	1	0	1	0	0	0	0	0	1	0	┝
59	<b>4</b> 5	5	1	1	1	1	0	1	0	1	0	0	0	1	0	$\vdash$
59 60	5	6	1	1	1	1	0	1	1	0	0	0	0	1	1	-
61	° 7	0 7	1	1	$\frac{1}{1}$	1	0	1	1	1	0	0	0	1	1	-
	8	8	1	1	1	1	1	0	۱ 0	0	0	0	1	0	0	
62											· ·	· ·				. 1

\*BCD code for blank is: C bit for odd parity C and A bits for even parity

Figure 1-58. BCD-to-CM6 Conversion

Figure 1-59. 8-Bit Code--BCD Relations (7-and 9-Track Tape)

CHARACTER	CHARACTER	CHARACTER	CHARACTER
IN STORAGE	TO 1443	IN STORAGE	TO1443
&	&	Q	Y
0	~ ~	9	8
1	0	<del>,</del> Z	
	A ①		R
/		R	× ₹
<u> </u>		<u> </u>	9
	/ ②	-	
2		+	>
<u>S</u>	В	· · · · ·	<
В	K	•	+
<u> </u>	S	#	:
3	2	,	· · ·
T	С	•	\$\$
C	L	\$	
L	T	@	#
4	3	%	<b></b>
U	D	П	*
D	м	*	%
M	U	:	<u>e</u> .
5	4	V	(
V	E	(	)
E	N	)	~
N	V	>	∀
6	5	\	+
W	F	<	;
F	0	;	-
0	W	v	=
7	6	+++	<b>#</b>
X	G	#	¢
G	P	Δ	±
P	X	Blank	v
8	7	Blank	Blank
Y	Н	<u>لا</u>	Blank

Sent As 01000001
 Sent As 11100001

52- and 63-Character Typebar Decode (1400 Compatibility) Figure 1-60.

## 1.11 PROGRAM CCDES AND PSW (FIGURES 1-60 THROUGH 1-63)

Condition Code	0	1 1		
Mask bit position	8	4	2	3
			۷	
Floating-Point Arithmetic	_	_	_	
Add Normalized S/L	Zero	< Zero	>Zero	Overflow
Add Unnormalized S/L	Zero	< Zero	>Zero	Overflow
Compare S/L (A:B)	Equal	A Low	A High	
Load and Test S/L	Zero	< Zero	>Zero	]
Load Complement S/L	Zero	< Zero	>Zero	
Load Negative S/L	Zero	< Zero		]
Load Positive S/L	Zero		>Zero	
Subtract	_	_		
Normalized S/L	Zero	<zero< td=""><td>&gt;Zero</td><td>Overflow</td></zero<>	>Zero	Overflow
Subtract	_			
Unnormalized S/L	Zero	< Zero	>Zero	Overflow
Fixed-Point Arithmetic				
Add H/F	Zero	<zero< td=""><td>&gt;Zero</td><td>Overflow</td></zero<>	>Zero	Overflow
Add Logical	Zero	Not Zero,	Zero,	Not Zero,
-	No Carry	No Carry	Carry	Carry
Compare H/F (A:B)	Equal	A Low	A High	
Load and Test	Zero	<zero< td=""><td>&gt;Zero</td><td></td></zero<>	>Zero	
Load Complement	Zero	<zero< td=""><td>&gt;Zero</td><td>Overflow</td></zero<>	>Zero	Overflow
Load Negative	Zero	<zero< td=""><td></td><td></td></zero<>		
Load Positive	Zero		Zero	Overflow
Shift Left Double	Zero	<zero< td=""><td>&gt; Zero</td><td>Overflow</td></zero<>	> Zero	Overflow
Shift Left Single	Zero	<zero< td=""><td>&gt;Zero</td><td>Overflow</td></zero<>	>Zero	Overflow
Shift Right Double	Zero	<zero< td=""><td>&gt;Zero</td><td> ]</td></zero<>	>Zero	]
Shift Right Single	Zero	<zero< td=""><td>&gt;Zero</td><td></td></zero<>	>Zero	
Subtract H/F	Zero	<zero< td=""><td>&gt;Zero</td><td>Overflow</td></zero<>	>Zero	Overflow
Subtract Logical		Not Zero	Zero,	Not Zero,
Ŭ		No Carry	Carry	Carry
Decimal Arithmetic	j			
Add Decimal	Zero	-7	>Zero	0
Compare Decimal (A:B)	Equal	<zero< td=""><td>A High</td><td>Overflow</td></zero<>	A High	Overflow
Subtract Decimal	Zero	A Low	>Zero	Overflow
Zero and Add	Zero	<zero <zero< td=""><td>&gt;Zero</td><td></td></zero<></zero 	>Zero	
Zero ana Ada	2010	< Zero	>2010	Overflow
Logical Operations				
AND	Zara	Net Zara		
	Zero	Not Zero A Low	A LI.	
Compare Logical (A:B)	Equal		A High	
Edit Edit and Marti	Zero Zero	<zero <zero< td=""><td>&gt;Zero</td><td></td></zero<></zero 	>Zero	
Edit and Mark			>Zero	
Exclusive OR	Zero	Not Zero		
	Zero Zero	Not Zero		One
Test Under Mask		Mixed		One
Translate and Test	Zero	Incomplete	Complete	
Input/Output Operations				
Halt I/O	Int. Pending	CSW Stored	Stopped	Not Oper
Start I/O	Available	CSW Stored	Busy	Not Oper
Test Channel	Not Working	1	Working	Not Oper
Test I/O	Available	CSW Stored	Working	Not Oper
	, wandble	Com siored	TOTKING	oper

Figure 1-61. Condition-Code Settings

Interr	uption	Code	
Dec	Hex	Binary	Program Interruption Cause
1	01	0000 0001	Operation
2	02	0000 0010	Privileged operation
3	03	0000 0011	Execute
4	04	0000 0100	Protection
. 5	05	0000 0101	Addressing
6	06	0000 0110	Specification
7	07	0000 0111	Data
8	08	0000 1000	Fixed-point overflow
9	09	0000 1001	Fixed-point divide
10	0A	0000 1010	Decimal overflow
11	ОВ	0000 1011	Decimal divide
12	0C	0000 1100	Exponent overflow
13	0D	1011 0000	Exponent underflow
14	OE	0000 1110	Significance
15	OF	0000 1111	Floating-point divide

## Figure 1-62. Program Interruption Codes

Systen Mask	n	8 11 Key	12 15 AMWP *	16 Interruption Code	31 32 33 ILC	34 35 CC	36 39 Program Mask *	40 Instruction Address
			l			I	L	l
		lexer chann			Machine check	mask (M)		
		or channel 1			Wait state (W)			
2 5	Selecto	or channel 2	mask	15	Problem state (	P)		
3 3	Selecto	or channel 3	mask	32-33	Instruction Leng	gth code (IL)	C)	
4 9	Selecto	or channel 4	mask	34-35	Condition code	(CC)		
5 5	Selecto	or channel 5	i mask	36	Fixed-point ov	erflow mask		
6 9	Selecto	or channel 6	mask		Decimal overflo			
7	Externo	al mask		38	Exponent under	flow mask		
		mode (A)			Significance me			

Figure 1-63. Program Status Word (PSW)

1.12 CHANNEL	COMMAND	AND	ADDRESS	FORMATS	(FIGURES	1-64	THROUGH	1-68)

	Command for CCW	0	 ] 1	2	3-Bit   3	Cod	5	6	7	Hex	Dec
1052	Read Inquiry BCD Read Reader 2 BCD Write BCD, Auto Carriage Return Write BCD, No Auto Carriage Return No Op Sense Alarm	000000000000000000000000000000000000000	000000000000000000000000000000000000000	000000000000000000000000000000000000000	0 0 0 0 0 0 0	1 0 1 0 0 0	0 0 0 0 1 0	1 0 0 1 0 1	0 0 1 1 1 0 1	0A 02 09 01 03 04 0B	10 02 09 01 03 04 11
2540	Read, Feed, Select Stacker SS     Type AA       Read,     Type AB       Read, Feed (1440 compatibility mode only)     Type BA       Freed, Select Stacker SS     Type BA       PRF Punch, Feed Select Stacker SS     Type BA       Punch, Feed, Select Stacker SS     Type BB       SS     Stacker       O     R1       O1     R2       10     RP3	S 1 1 S S S	S 1 S S S	0 0 1 0 0	0 0 1 0 0	000000000000000000000000000000000000000	0000000	1 1 1 0 0	0 0 1 1 1		
1442 N1	M         M         M         M         Read           Read         0         0         X         Eject and SS1         Control           Read         1         0         X         Eject and SS1         Control           Read         0         1         X         Eject and SS1         Control           Read         1         1         X         Eject and SS2         Sense           Write         0         X         Eject and SS1         Write         I         X         Eject and SS1           Write         1         1         X         Eject and SS1         Control         Control         I         SS2           Control         0         I         SS2         SS1         SS2         SS2	M M M 0 0	M M 0 0	M 0 0 M	0 0 0 M	000000000000000000000000000000000000000	000000000000000000000000000000000000000	1 0 1 1 0			
1403 or 1443	Write, Sopace I After Print Write, Space I After Print Write, Space 3 After Print Write, Space 3 After Print Write, Skip to Channel N After Print Diagnostic Read Test I/O Sense	00000	0 0 0 0 0 0 0 0 0 0 0	0 0 0 0 H 0 0 0	0 0 1 A 0 0 0	0 1 0 1 N 0 0 0	0 0 0 0 0 0 0 1	0 0 0 0 1 0 0	1 1 1 1 0 0	01 09 11 19 02 00 04	01 09 17 25 02 00 04
Carriage Control	Space 1 Line Immediately           Space 2 Line Immediately           Space 3 Line Immediately           Skip to Channel N Immediately           No Op           C         H A N           O         0           0         0           0         1           0 <td< td=""><td>000000000000000000000000000000000000000</td><td>00000</td><td>0 0 0 H 0</td><td>0 1 A 0</td><td>101Z0</td><td>00000</td><td>1</td><td>3 1 1 1 0</td><td>08 13 18 03</td><td>11 19 27 03</td></td<>	000000000000000000000000000000000000000	00000	0 0 0 H 0	0 1 A 0	101Z0	00000	1	3 1 1 1 0	08 13 18 03	11 19 27 03
2400 Таре*	Transfer in Channel Sense Read Backward** Write Read Cantrol Mode Set	0 0 0 0 0 D	0 0 0 0 0 0 0 0 0 0	000000	0 0 0 0 0 0 0 0 0 0 0 0 0 0 0	1 0 1 0 C M	0 1 0 0 1	0 0 0 1 1	0 0 1 0 1	08 04 0C 01 02	08 04 12 01 02
7 tra 7 tra **Over	ck op. forces 800 BPI and odd parity; also, it overrides ck but does not reset 7 track. Load/Sys Reset forces to 800 BPI, add parity; date converter on, translator off. $ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	dition k onl	y		-	XIXI I I XI I Set Odd Parity	 - ×	- - - -	X   X   1   1   1 Translator On	   	

Figure 1-64. Channel Command Codes

Command Code		Data Address		Flags	000	Ignored	Count
(8)	0000000	(24)		(5)	(3)	(8)	(16)
Command ( 0 1 2 3 4 5 * * * * 0 0 mmmm 0 1 * * * * 1 0 mmmmm 1 mmmmmm mmmmmm	567 000 Invalid 100 Sense 000 TIC 100 Read Ba n01 Write n10 Read	2-SLI 3-SKIP ackward 4-PCI	Bit 33, caus Bit 34, caus Bit 35, supp	es the comm es a possible resses the tr	and coc incorre ansfer o		ess in the next CCW to be used. ation to be suppressed. main storage.
*-Bit Ignor m-Modifie							

## Figure 1-65. Channel Command Word (CCW)

CHANNEL ADDRESS WORD

	Key	0 0	0 0		Command	i Address	-
0	3	4	7	8	1516	2324	31

Figure 1-66. Channel Address Word (CAW)

Mem Prot Tag (4)	0000	Next CCW Address (24)	Ste Unit (8)	atus   Channel   (8)	Residual Count Bits 48–63 form the residual count for the last CCW used. (16)
0 3	4 7	8 31	32	47	48 63

Unit Status	Channel Status
0-Attention	0-PCI
1–Status Modifier	1-Incorrect Length
2-Control Unit End	2–Program Check
3-Busy	3-Protection Check
4-Channel End	4–Channel Data Check
5-Device End	5–Channel Control Check
6-Unit Check	6–Interface Control Check
7-Unit Exception	7–Chaining Check

#### Figure 1-67. Channel Status Word (CSW)

Halfword 0		Halfv	vord 1	Halfv	vord 2	Halfw	ord 3				
Byte 0	Byte 1	Byte 2	Byte 3	Byte 4	Byte 5	Byte 6	Byte 7				
Channel	Flags & Op	Data A	Address								
Status		Unit status	Unit address								
		at interrupt	at interrupt	Byte	Count	Next CC	V Address				
	Byte	v e 1 (Flags and	Op)								
	E	Bit		Significa	ince		······				
		0 CDA	CDA (Data Chain in progress)								
		1 Chai	Chain Command (Chain Command in progress)								
		2 SLI	SLI (Suppress Length Indication)								
		3 Skip									
		4 PCI	(Program Cont	rolled Inte	errupt)						
			ve (On from tir UCW until cha	•							
		6 Op 0	(See note)								
		7 Op 1	(See note)								
	** \		s on, bits 6 and it zero, expect				;				
			Test I/O or Interrupt (during initial selection). If								
latter, bit $3=0$ means Test I/O; bit $3=1$ means interv											

- latter, bit 3=0 means Test I/O; bit 3=1 means interrupt.
- 01 = Output
- 10 = Read Forward
- 11 = Read Backward

#### Byte 0 (Channel Status)

Bit	Significance
0	Secondary *
1	Incorrect Length
2	Program Check
3	Protection Check
4	Channel Data Check**
5	Channel Control Check
6	Interface Control Check
7	Interrupt in Interrupt Buffer*
E .	1

\*Bits 0 and 7 indicate the following:

- 00 = Handling data, expecting data
- 01 = Handling data, expecting status
- 10 = Status queued at I/O device
- 11 = Status in Interrupt Buffer
- \*\* Channel Data Check can be set on only during input operations. The parity check is detected in the CPU A-Register, and no machine check occurs.

Figure 1-68. Channel-UCW Format

1.13	I NTEGRATED	CCMMUNICATIONS	ADAPTER (F	IGURES	1-69	AND 1-72)	

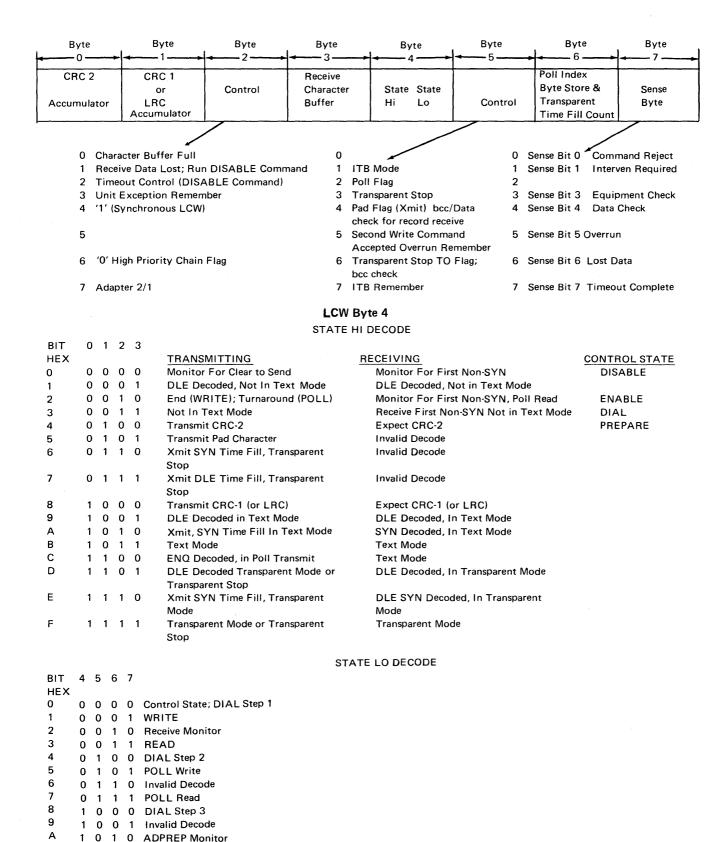
		с	Code Assignment					
Name	Mnemonic	EBCDIC	Hex	USASCII	Bex			
Start of Heading	SOH	SOH	01	SOH	01			
Start of Text	STX	STX	02	STX	02			
End of Transmission Block	ETB	ETB	26	ETB	17			
End of Text	ETX	ETX	03	ETX	03			
End of Transmission	EOT	EOT	37	EOT	04			
Enquiry	ENQ	ENQ	2D	ENQ	05			
Negative Acknowledge	NAK	NAK	3D	NAK	15			
Synchrcnous Idle	SYN	SYN	32	SYN	16			
Data Link Escape	DLE	DIE	10	DLE	10			
Intermediate Block Character	ITB	IUS	1F	US	1F			
Even Acknowledge	ACK 0	DLE (70) *	1070	DLE0	1030			
Odd Acknowledge	ACK1	DLE/	1061	DLF1	1031			
Wait Before Transmit	WABT	DLE(7F)*	1037	DLE?	103F			
Mandatory Disconnect	DISC	DLE ECT		DLE EOT	1004			
Stop Acknowledge	SAK	DLE,		DLE;	103B			
Reverse Interrupt	RVI	DLEO	022D	DLE<	103C			
Temporary Text Delay	TTD	STX ENQ		STX ENQ	0205			
Transparent Start of Text	XSTX	DLE STX		DLE STX	1002			
Transparent Intermediate Block	XITB	DIE IUS	101F	DLE US	101F			
Transparent End of Text	XETX	DLE ETX	1003	DLE ETX	1003			
Transparent End of Trans. Block	XETB	DIE ETB	1026	DLE ETB	1017			
Transparent Synchronous Idle	XS <b>Y</b> N	DLE SYN		DLE SYN	1016			
Transparent Block Cancel	XENQ	DLE ENQ		DLE ENQ	1005			
* Hexadecimal representation (no cont	rol or grap	hic assign	ment)	*	<b></b>			

Figure 1-69. Bisynchronous Control Character Chart

1-80 (7/69)

0	1		2	3	4	5	6	7						
Channel Status	Flags and	1 Ons	Data	Address	Co	unt	Next CC	N Address						
Channel Glatas	i lago uni	. 0	Unit Status											
Byte 0	Bit 0			STATUS: also befo	pre channel status	is presented acts t	o indicate that a p	ending interrupt						
			<ul> <li>is for a PCI inte</li> </ul>	rrupt only and not a	Channel End-De	vice End interrupt.								
	Bit 1		<ul> <li>Incorrect length</li> </ul>	record check (ILC)										
	Bit 2		<ul> <li>Program check.</li> </ul>											
	Bit 3		<ul> <li>Protection chec</li> </ul>	Protection check.										
Bit 5 - Not used.														
	Bit 6		<ul> <li>Indicates wheth</li> </ul>	er the address of the	e UCW is in the in	terrupt Q table.								
	Bit 7		<ul> <li>Interrupt pendir</li> </ul>	ng bit.										
Byte 1	Bit 0		- Chain Data flag	(CD).										
	Bit 1		- Chain Command	flag (CC).										
	Bit 2		<ul> <li>Suppress Length</li> </ul>	Indication (SLI).										
	Bit 3		- SKIP flag.											
	Bit 4		- Programmed Co	ontrolled Interrupt f	lag (PCI).									
	Bit 5		- Active Bit; on when commands are being executed or when interrupt pends in interrupt Q table.											
	Bits 6 an		- Decoded as follows.											
	0	0		to zero in count fiel d set up to set ILC			ata transfer reques	st to respond with						
	0	1		nand being executed		dente.								
	1		••	nand being executed										
	1		••	nel stop is given and		GEND to signal a p	ossible ILC.							
Bytes 2 and 3				iring command exec										
Byte 2			- Device Status at	Command End.										
	Bit 0		- Not set by ICA											
	Bit 1		- Status Modifier											
	Bit 2		- Not set by ICA											
	Bit 3		- Not set by ICA	Busy set by CC to	SIO, TIO									
	Bit 4		- Channel End 👌	Vivious proported to	action in ICA									
	Bit 5		- Device End Always presented together in ICA											
	Bit 6		- Unit Check											
	Bit 7		- Unit Exception											
Bytes 4 and 5			- Count Field											
Bytes 6 and 7			- Next CCW Add	ess										
Byte 7	Bit 7		- On when I <b>C</b> A U	CW is not operation	al (tested in DCL	.A)								

Figure 1-70. ICA UCW Format



1-82 (7/69)

1 0

1 1

1 1 0 1

1 1

1

Figure 1-71.

1 1

1

0

Invalid Decode

Invalid Decode

Invalid Decode

Synchronous LCW Format

1 0 ADPREP Control

1 1 1 Invalid Decode

в

С

D

Е

F

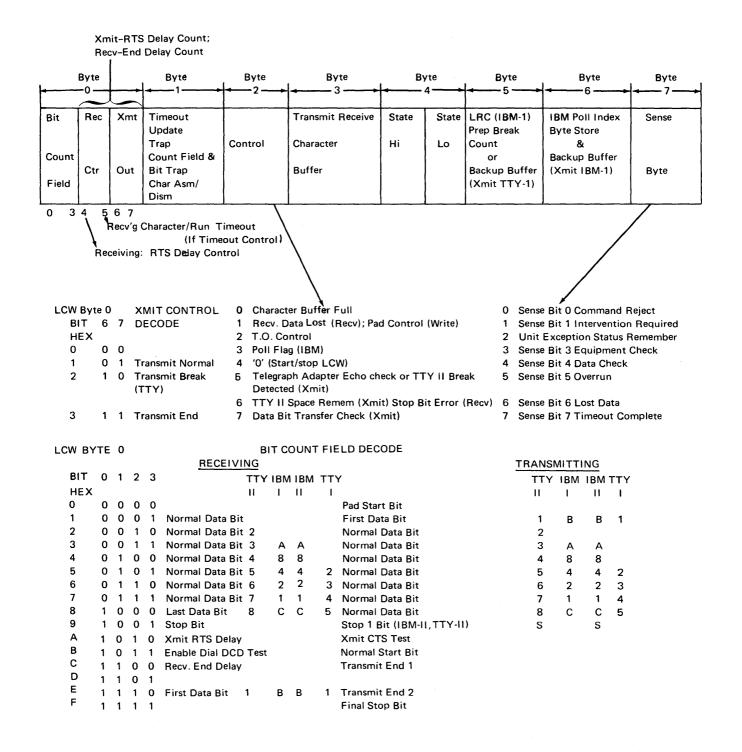


Figure 1-72. Start/Stop LCW Format (Part 1 of 2)

## LCW Byte 4

	STATE HI DECODE												
віт НЕХ	0	1	2	3	IBM XMIT/RECV	TTY XMIT/RECV	CONTROL STATE						
0	0	0	0	0	Receive Monitor	Receive Monitor	Receive Monitor (DISABLE)						
1	0	0	0	1	Invalid Decode	Read Data, TTY-I	PREPARE Break						
2	0	0	1	0			ENABLE (Switched Network)						
3	0	0	1	1	Read Data	Read Data, TTY-II	DIAL (IBM-I, TTY-II)						
4	0	1	0	0	Read LRC, IBM-I	Invalid Decode	PREPARE						
5	0	1	0	1	Read End IBM	Read End TTY							
6	0	1	1	0	Invalid Decode	Read FIGS H Remember, TTY-I							
7	0	1	1	1	Poll Read	Read First Non LTRS, TTY-I							
8	1	0	0	0	Write Data	Write Data, TTY-II							
9	1	0	0	1	Write Stop	Write Stop							
A	1	0	1	0	Write LRC, IBM-I	Break Data							
В	1	0	1	1	Write Prepend	Write Shift Remember, TTY-I							
c	1	1	0	0	Write Shift Remember, IBM-I	Write Data, TTY-I							
D	1	1	0	1	Poll Initial								
E	1	1	1	0	Poll Write	Break Initial							
F	1	1	1	1	Write End	Write End							

					STATE LO DECODE
віт	4	5	6	7	
HEX					
0	0	0	0	0	Control State; DIAL Step 1
1	0	0	0	1	IBM Text in Downshift Mode: IBM POLL Write Step 3
2	0	0	1	0	TTY Downshift Mode
3	0	0	1	1	IBM Control, (Downshift) Mude
4	0	1	0	0	DIAL Step 2
5	0	1	0	1	IBM Text Out. Downshift Mode: POLL Write Step 2
6	0	1	1	0	Invalid
7	0	1	1	1	IBM, Control, Downshift Mode: POLL Write Step 1
8	1	0	0	0	DIAL Step 3
9	1	0	0	1	IBM-I Text In, Upshift Mode
A	1	0	1	0	TTY-I Upshift Mode
В	1	0	1	1	IBM-I Control, (Upshift Mode)
c	1	1	0	0	Invalid
D	1	1	0	1	IBM-I Text Out, Upshift Mode; IBM POLL Write Step 0
E	1	1	1	0	Invalid
F	1	1	1	1	IBM-I Control, (Upshift Mode)

## Figure 1-72. Start/Stop LCW Format (Part 2 of 2)

<u>1.14 1403 PRINTER (FIGURES 1-73 THROUGH 1-95)</u>

Figure 1-73 shows the possible Start I/O command byte configurations for the 1403. The legend for this figure is as follows.

Char in	
Column	Printer Command
b	Sense
с	Write with valid carriage-control
đ	No-Op
е	Carriage control with valid
	carriage-control modifier
f	Load multiple character set (MCS)
	and fold
g	Load multiple character set (MCS)
	and no fold
h	Gate load
j	Block data check
k	Allow data check.

BITS 0123								BITS	4567				<u> </u>			]
ł	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
0000		c		d	b					с		е				
0001		с		е						с		е				
0010																
0011																
0100																
0101																
0110																
0111				j								k				
1000							1			с		∖e				
1001		с		e						с		e				
1010		с		e						c		е				
1011		с		e						с		е				
1100		с		e						c		е				
1101		с		e						с		е				
1110		с		e								h				
1111				f								g				

Figure 1-73. 1403 Command Byte Description

1-86 (7/69)

-		
Figure		S-AN" (3 LEVEL SET-48 "A" GRAPHICS)
gu	Note I	1 2 3 4 5 6 7 8 9 0 , - P Q R # \$ 0 / S T U V W X Y Z II . * 1 2 3 4 5 6 7 8 9 0 , - J K L M N D A B C D E F G H I + . *
re		
	н	S-HN" (3 LEVEL SET - 48 "H" GRAPHICS)
1-	Note I	1 2 3 4 5 6 7 8 9 0 , -   PQ R = \$ 7 / S T U V W X Y Z ) . * 1 2 3 4 5 6 7 8 9 0 , -   J K L M N U AB C D E F G H I + . *
74.		
C b		
Cha i n	Note 🎞	12 3 4 5 6 7 8 90 # 0 / S TU VW XY Z E , % JK LM ND PQ R - \$ * AB CD EF GH I + . Ц
Arra	Note 🎞	1 2 3 4 5 6 7 8 9 0 = ' / S TU VW XY Z & , ( JK LM N D PQ R - \$ * A B C D E F G H I + . )
ra		PL/I (60 GRAPHICS)
ng	Note II	12 34 56 78 90 XY / STUVW   : _ ", = JK LM NO PQ R-Z(ABCDEFGHI+.) % \$ *# & a < ; - "?>
ngerre		PL/I (60 GRAPHICS - 45 PREFERRED)
ſeɪ		12 34 56 78 90 XY / S TU VW'' \$* ,= JK LM N D PQ R- Z ( AB CD EF GH I+ .)
nts		<; #*
		*@ < ?
fo		
Ř		Note I Two full sets per cartridge arrangement
sy		Note II Four full sets per cartridge arrangement
ystem∕360		"FORTRAN COBOL COMMERCIAL (52 GRAPHICS - 47 PREFERRED)       Note III       Five full sets per cartridge arrangement         1 2 3 4 5 6 7 8 9 0 X Y / S T U V W * 0 \$ $\frac{1}{2}$ \$ $$
en		12 34 56 78 90 X Y / S TU VW 'u \$ * , = JK LM N D PQ R - Z (AB CD EF GH I + .) Note IV Six full sets per cartridge arrangement
ω		
60		
Ð		
문		" TEXT PRINTING (84 GRAPHICS - 78 PREFERRED)
(Printout		1234567890 E. / STUVW XY Z, \$* JK LM NO PQ R- ": AB CD EF GH I + ab cd ef gh ij Kl mn op qr st uv wx yz d' () -
ŭ		
₩		?!; # %
ĩ		"TEXT PRINTING (I20 GRAPHICS)
Ϋ́.	Note I	1234567890=./STUVWXYZ, #EJKLMNOPQR-": ABCDEFGHI+abcdefghijK1mn
epresentation)		op q r st uv wx yz ∂ ' ? ; ± ! \$ *% II 1 2 3 4 5 6 7 8 9 0 -+ () ° () ≠ + >< ≤≥ ℓ • []} {
en.		
ເລ		"HIGH SPEED ALPHANUMERIC (40 GRAPHICS)
Ę.	Note IV	12 3 4 5 6 7 8 9 0 , . A B C D E F G H I Z J K L M N D P Q R * \$ S T U V W X Y
g		DA · FIRST ARRAY
0	Note 🎞	12 34 56 78 90 #0 /S TU VW XY Z& ,% JK LM NO PQ R- \$* AB CD EF GH I+ .=
		CNA - FIRST ARRAY
	Note 🎞	12 34 56 78 90 #2 /S TU VW XY ZE , H JK LM NO PQ R- \$* AB CD EF GH IY
	Note 🎞	1234567890#0/STUVWXYZ& %JKLMNOP@R-\$*ABCDEFGHI+.<
		INB-FIRST ARRAY (WTC Only)
	Note 🎞	1 2 3 4 5 6 7 8 9 0 = 1 / ST UV WX Y Z & , > J K L MN DP Q R - \$ * A B C D E F G H I + . <
	14016 111	

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	PCS-	AN"(	3 LE	VEL S	ET-	48 "4	"GRA	PHIC	S)																											
Note I			<u> </u>		-		/ST			<b>n.</b> *	123	456	789	0,-	JKL	MNO	AB	CDE	FG	HI	•.*	1														
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•	PCS-I									r												,														
Note I	123	456	789	0,-	PQR		/ ST	UVW	XYZ	).*	123	456	789	0,-	JKL	MND	AB	CDE	FG	HI	••*															
	L	1		I		18.5					L				L							J														
	AN"					<del></del>	<b>.</b>							·			1																			
Note 🎞	123	456	789	0#0	/st	UVW	XYZ	۶,%	JKL	MND	PQR	-\$*	ABC	DEF	GHI	+.1																				
" Note 🎞	HN"		200	0-1	1/07	hna	1007	c /	Tim	L.			4.0.0	DEE	laux.	<u>.                                    </u>	ı																			
	<b></b>	<b>-</b>	L	10= .	1/51	100%	AT2	۵,۱	JAKL	MNU	PUR	-3*	ABC	UEF	GHI	(+.)	}																			
	PN"		/1			APH			1			<u> </u>					<u>.</u>	1	<u>.</u>			1														
Note II		_					1:_		_		PQR	- Z (	ABC	DEF	бні	(+.)	76.5	<b>*⊭€</b>	<u>مار</u>	;-[	?>	j														
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# Figure 1-75. Train Arrangements for System/360 (Printout Representation)

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	ох	1X	2X	3X	4X	5X	6X	7X	8X	9X	АХ	вх	сх	DX	EX	FX
xo		&	-	0		&	_	0	&			0	8			0
X1	A	J	1	1	A	J	1	1	A	J	1	1	А	J	1	1
X2	В	К	S	2	В	К	S	2	в	ĸ	S	2	В	к	S	2
ХЗ	c	L	т	3	C	L	т	3	С	L	т	3	с	L	Т	3
X4	D	М	U	4	D	M	U	4	D	М	U	4	D	М	U	4
X5	E	N	ν	5	Е	N	V	5	E	N	V	5	E	N	v	5
X6	F	0	W	6	F	0	W	6	F	0	W	6	F	0	w	6
X7	G	Ρ	х	7	G	Ρ	х	7	G	Ρ	x	7	G	Р	х	7
X8	Η	٥	Y	8	H	٥.	Y	8	Н	٥	Y	8	н	٥	Y	8
X9	P	R	Z	9	I	R	z	9	-	R	z	9	I	R	z	9
ХА	+		&	0	+	-	81	0	+		&	0	+		&	0
ХВ		\$	1	#	•	\$	,	#	•	\$	,	#/=		\$	1	#/=
хс	"	*	% (	@	ш	*	%	@,	п/,	*	%	•	п/)	*	%/	@,
XD	%	П		@	% (	П		@	%			e/,	%/	п/)		@
XE	÷.			#/=	+		,	#	+		1	#	+		1	#/=
XF																

\_ AN Graphic

HN Graphic Non shaded- assigned in EBCDIC chart

Characters printed are basic integrated 1403. Non-shaded graphics indicate the defined codes in the EBCD interchange code chart.

Figure 1-76. AN and HN Graphics for Basic 1403 Attachment

Comman	d Byte	
0123	4567	Function
0000	0001	Write and No Space After Print
0000	1001	Write and Space 1 Line After Print
0001	0001	Write and Space 2 Lines After Print
0001	1001	Write and Space 3 Lines After Print
1000	1001	Write and Skip to Channel 1 After Print
1001	0001	Write and Skip to Channel 2 After Print
1001	1001	Write and Skip to Channel 3 After Print
1010	0001	Write and Skip to Channel 4 After Print
1010	1001	Write and Skip to Channel 5 After Print
1011	0001	Write and Skip to Channel 6 After Print
1011	1001	Write and Skip to Channel 7 After Print
1100	0001	Write and Skip to Channel 8 After Print
1100	1001	Write and Skip to Channel 9 After Print
1101	0001	Write and Skip to Channel 10 After Print
1101	1001	Write and Skip to Channel 11 After Print
1110	0001	Write and Skip to Channel 12 After Print

Figure 1-77. 1403 Commands (Write Operation with Various Carriage Functions)

Comman	d Bytes	
0 1 2 3	4567	Function
0000	1011	Space 1 Line Immediately
0001	0011	Space 2 Lines Immediately
0001	1011	Space 3 Lines Immediately
1000	1011	Skip to Channel 1
		Immediately
1001	0011	Skip to Channel 2 Immediately
1001	1011	Skip to Channel 3
		Immediately
1010	0011	Skip to Channel 4
1		Immediately
1010	1011	Skip to Channel 5
}		Immediately
1011	0011	Skip to Channel 6
[		Immediately
1011	1011	Skip to Channel 7
		Immediately
1100	0011	Skip to Channel 8
1100	1011	Immediately
1100	1011	Skip to Channel 9 Immediately
1101	0011	Skip to Channel 10
	0011	Immediately
1101	1011	Skip to Channel 11
		Immediately
1110	0011	Skip to Channel 12
		Immediately

Figure 1-78. 1403 Commands (Independent Carriage Operations)

Command	d Byte	
0123	4567	Function
0000	0011	No-Op
0111	0011	Block Data Check
0111	1011	Allow Data Check
1110	1011	Gate Load
1 1 1 1	0011	Load MCS and Fold
1 1 1 1	1011	Load MCS and No Fold
0000	0100	Sense

Figure 1-79. 1403 Commands (No Printing or Carriage Motion)

7X00	or 9X00	
Not Block Data Check	Block Data Check	Set Length (Decimal)
01	81	16
02	82	40
04	84	48
08	88	60
10	90	80
20	A0	120
40	CO	240
00	80	240

Figure 1-80. PCCL Code for Different Character Set Lengths

Figure 1-81 shows the contents of the translate table for the basic attachment. The table is loaded for dualed and folded AN or HN chains or trains. The table causes the same translation as the non-UCS translator in the 2821 control unit. The table is loaded in the preceding manner

when the control storage is reloaded with a System/360 load. When control storage is loaded with a System/360 load with MCS, the translate table is unaffected.

PCCL byte is shown with block data check not set.

da 700	0				
		2829 1C1D			
		1011 0405	 	 	
		2829 1C1D	 	 	 Note:
		1011 0405		 	Graphics are aswith the IE
		2829 1C1D	 	 	 translator.
		1011 0405	 	 	
		2829 1C1D	 	 	
220D 0A01		1011 0405	 	 	

Note: Graphics are folded and dualed aswith the IBM 2821 non--UCS translator.

Graphic	
Graphine	•

Grap	phic P	ositior	n Code	•																				
$\checkmark$	01	02	03	04	05	06	07	08	09	0A	0B	OC	0D	0E	0F	10	11	12	13	14	15	16	17	18
AN	1	2	3	4	5	6	7	8	9	0	#	0	/	S	Т	U	V	w	х	Y	Z	&	.,	%
HN																								(
	19	1A	1B	1C	1D	1E	1F	20	21	22	23	24	25	26	27	28	29	2A	2B	2C	2D	2E	2F	30
AN	J	к	L	м	N	0	Р	Q	R	_	\$	*	А	В	С	D	Е	F	G	н	-	+		ц
HN	1																							)

Figure 1-81. Printer Translate Table (Basic Attachment)

Figures 1-82 through 1-94 show several different versions of the translate table for different MCS chain or train arrangements.	characters in the other sets are printable positions. These positions are indicated by the heavy bar in the graphic position code charts.
When preferred-character arrangements with MCS are used, only the last character set of the arrangement and unique	PCCL byte is shown with block data check not set.
FFFF       OCFF       OCFF       OCFF       OCFF       OCFF       FFFF       FFFF       FFFF       FFFF       FFFF       OCFF       OCFF       FFFF       FFFF       FFFF       FFFF       FFFF       OCFF       OCFF       FFFF       FFFF       FFFF       FFFF       FFFF       IOCFF       FFFF       IOCFF       FFFF       FFFF       FFFF       FFFF       IOCFF       FFFF       IOCFF       IFFF       IFFF       IOCFF       IFFF       IFFF       IOCFF       IFFF       IFFF       IFFF       IFFF       IOCFF       IFFF       IOCFF       IOCFF       IFFF       IIOCFF       IFFF       IIOCFF       IIIIIIIIIIIIIIIIIIIIIIIIIIIIIIIIIIII	D00         F FFFF FFFF FFFF FFFF FFFF FFFF FFFF

Graphic

Gra	phic P	osition	۲ Code													_								
	01	02	03	04	05	06	07	08	09	0A	0B	0C	0D	0E	0F	10	11	12	13	14	15	16	17	18
L	1	2	3	4	5	6	7	8	9	0		_	\$	*		ц								

Figure 1-82. Printer Translate Table for MCS: Numeric Arrangement; Count Length 10 (Hex)

ı da 7000	da 7000
04FF FFFF FFFF FFFF FFFF FFFF FFFF FFFF	04FF FFFF FFFF FFFF FFFF FFFF FFFF FFFF
FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF	FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF
00FF FFFF FFFF FFFF FFFF FF2F 3018 2EFF 16FF FFFF FFFF FFFF FFF23 2430 FFFF	00FF FFFF FFFF FFFF FFFF FF2F 3018 2EFF 16FF FFFF FFFF FFFF FFFF FF23 2430 FFFF
1 220D FFFF FFFF FFFF FFFF FF17 18FF FFFF 1 FFFF FFFF FFFF FFFF FF0B 0C0C 0BFF	220D FFFF FFFF FFFF FFFF FF17 18FF FFFF FFFF FFFF FFFF FFFF FFFF FF0B 0C0C 0BFF
FFFF FFFF FFFF FFFF FFFF FFFF FFFF	FFFF FFFF FFFF FFFF FFFF FFFF FFFF F
I FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF	! FFFF FFFF FFFF FFFF FFFF FFFF FFFF F
FF25 2627 2829 2A28 FFFF FFFF FFFF FFFF FF19 1A1B 1C1D 1E1F 2021 FFFF FFFF FFFF	FF25 2627 2829 2A2B 2C2D FFFF FFFF FFFF   FF19 1A1B 1C1D 1E1F 2021 FFFF FFFF FFFF
FFFF 0E0F 1011 1213 1415 FFFF FFFF FFFF 0A01 0203 0405 0607 0809 FFFF FFFF FFFF	FFFF 0E0F         1011         1213         1415         FFFF         FFFF

AN (Not Folded)

HN (Not Folded)

Gra	phic P	osition	o Code	<b>b</b> .																				
H	01	02	03	04	05	06	07	08	09	0A	OB	00	0D	0E	0F	10	11	12	13	14	15	16	17	18
AN	1	2	3	4	5	6	7	8	9	0	#	0	1	S	т	U	V	w	x	Y	Z	&	,	%
н											=	,												(
	19	1A	1B	1C	1D	1E	1F	20	21	22	23	24	25	26	27	28	29	2A	2B	2C	2D	2E	2F	30
AN [	J	к	L	м	N	0	Р	٥	R	-	\$	*	А	В	С	D	E	F	G	н	I	+		ц
н																								)

Figure 1-83. Printer Translate Table for MCS: AN-HN Arrangement; Count Length 30 (Hex)

Graphic

ΗN

AN

ΗN

da 7000 da 2	7000
0425 2627 2829 2A2B 2C2D FF2F 3018 2EFF   1042 1619 1A1B 1C1D 1E1F 2021 FF23 2430 FFFF   16	25 2627 2829 2A2B 2C2D FF2F 3018 2EFF   19 1A1B 1C1D 1E1F 2021 FF23 2430 FFFF
	DD 0E0F 1011 1213 1415 FF17 18FF FFFF   01 0203 0405 0607 0809 FF0B 0C0C 0BFF
	25 2627 2829 2A2B 2C2D FF2F 3018 2EFF   19 1A1B 1C1D 1E1F 2021 FF23 2430 FFFF
220D 0E0F 1011 1213 1415 FF17 18FF FFFF 220 0A01 0203 0405 0607 0809 FF0B 0C0C 0BFF 0A	0D 0E0F 1011 1213 1415 FF17 18FF FFFF 01 0203 0405 0607 0809 FF0B 0C0C 0BFF
0025 2627 2829 2A2B 2C2D FF2F 3018 2EFF 003 1619 1A1B 1C1D 1E1F 2021 FF23 2430 FFFF 16	25 2627 2829 2A2B 2C2D FF2F 3018 2EFF 19 1A1B 1C1D 1E1F 2021 FF23 2430 FFFF
	0D 0E0F 1011 1213 1415 FF17 18FF FFFF 01 0203 0405 0607 0809 FF0B 0C0C 0BFF
	25 2627 2829 2A2B 2C2D FF2F 3018 2EFF 19 1A1B 1C1D 1E1F 2021 FF23 2430 FFFF
1220D         0E0F         1011         1213         1415         FF17         18FF         FFFF         1220           10A01         0203         0405         0607         0809         FF0B         0C0C         0BFF         10A0           AN (Folded)         AN (Folded)         And the second se	0D 0E0F 1011 1213 1415 FF17 18FF FFFF 01 0203 0405 0607 0809 FF0B 0C0C 0BFF 1 HN (Folded)

Graphic

01	02	03	04	05	06	07	08	09	0A	0B	0C	0D	0E	0F	10	11	12	13	14	15	16	17	1
1	2	3	4	5	6	7	8	9	0	#	0	1	S	Т	υ	V	W	х	Y	Z	&		Γ
19	1A	1B	1C	1D	1E	1F	20	21	22	23	24	25	26	27	28	29	2A	2B	2C	2D	2E	2F	T

Figure 1-84. Printer Translate Table for MCS: AN-HN Folded; Count Length 30 (Hex)

da 7000	· · · · · · · · · · · · · · · · · · ·	da 7000	ł
08FF FFFF FFFF FFFF F			B 2C2D FF2F 3724 2E13 F 2021 FF32 3330 3839
I FFFF FFFF FFFF FFFF F FFFF FFFF FFFF			B 0C23 FF17 3115 3C3B 7 0809 1434 363A 1816
<sup>1</sup> 00FF FFFF FFFF FFFF F 135FF FFFF FFFF FFFF F			B 2C2D FF2F 3724 2E13 F 2021 FF32 3330 3839
220D FFFF FFFF FFFF F			B 0C23 FF17 3115 3C3B 7 0809 1434 363A 1816
·   FFFF FFFF FFFF FFFF F   FFFF FFFF FF			B 2C2D FF2F 3724 2E13 F 2021 FF32 3330 3839
FFFF FFFF FFFF FFFF F			B 0C23 FF17 3115 3C3B 7 0809 1434 363A 1816
I FF25 2627 2829 2A2B 2 FF19 1A1B 1C1D 1E1F 2			B 2C2D FF2F 3724 2E13 F 2021 FF32 3330 3839
FFFF 0E0F 1011 120B 0	C23 FFFF FFFF FFFF		B 0C23 FF17 3115 3C3B 7 0809 1434 363A 1816
(Not Fo			-olded)

Gra	phic

phic																								
Grap	hic Po	ositior	Code	9 <sup>-</sup>								_												
ୢ୲୷	01	02	03	04	05	06	07	08	09	0A	0B	0C	0D	0E	0F	10	11	12	13	14	15	16	17	18
	1	2	3	4	5	6	7	8	9	0	х	Y	/	S	т	υ	V	w	1	:		"	,	=
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Figure 1-85. Printer Translate Table for MCS: PN Arrangement; Count Length 3C (Hex)

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	01	02 1A	03		05 1D	06 1E	07 1F	08	09 21	0A 22	0B 23	0C	0D 25	0E 26	0F 27		29		13 2B	14 2C	15 2D	16 2E	17 2F	18 
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	19	1A	03 1B 33	1C 34	1D	1E	1F	20	21	22	23	24	25	26	27	# 28	29	@ 2A	2B	2C	2D	2E	2F	30
	19 31	1A 32	03 1B 33	1C 34	1D 35	1E 36	1F 37	20	21 39	22 3A	23 3B	24 3C	25 3D	26 3E	27 3F	# 28 40	29	@ 2A 42	2B 43	2C	2D 45	2E 46	2F 47	30
	19 31 49 P	1A 32 4A Q	03 1B 33 4B R	1C 34 4C &	1D 35 4D \$	1E 36 4E %	1F 37 4F /	20 38 50 S	21 39 51 T	22 3A 52 U	23 3B 53 V	24 3C 54 W	25 3D 55 X	26 3E 56 Y	27 3F 57 Z	# 28 40 58 ¤	29 41 59	@ 2A 42 5A	2B 43 5B 1	2C 44 5C 2	2D 45 5D 3	2E 46 5E 4	2F 47 5F 5	30 48 60 6
	19 31 49	1A 32 4A	03 1B 33 4B R	1C 34 4C &	1D 35 4D	1E 36 4E	1F 37	20 38 50	21 39 51	22 3A 52	23 3B 53	24 3C 54	25 3D 55	26 3E 56	27 3F 57	# 28 40 58	29	@ 2A 42	2B 43 5B	2C 44 5C	2D 45 5D	2E 46 5E	2F 47 5F	30 48 60

da 7000

da 7000

Figure 1-86. Printer Translate Table for MCS: PCS-AN Arrangement; Count Length 78 (Hex)

da 7000	da 7000
20FF FFFF FFFF FFFF FFFF FFFF FFFF FFFF	206D 6E6F 7071 7273 7475 FF77 FF4E 76FF   , 4C67 6869 6A6B 6C49 4A4B FF4D 7858 FFFF
FFFF FFFF FFFF FFFF FFFF FFFF FFFF	664F 5051 5253 5455 5657 FF65 FFFF FFFF 645B 5C5D 5E5F 6061 6263 FFFF FF12 10FF
00FF FFFF FFFF FFFF FFFF FF77 FF4E 76FF 4CFF FFFF FFFF FFFF FFFF FF4D 7858 FFFF	006D 6E6F 7071 7273 7475 FF77 FF4E 76FF 4C67 6869 6A6B 6C49 4A4B FF4D 7858 FFFF
664F FFFF FFFF FFFF FFFF FF65 FFFF FFFF FFFF FFFF	664F 5051 5253 5455 5657 FF65 FFFF FFFF 645B 5C5D 5E5F 6061 6263 FFFF FF12 10FF
FFFF FFFF FFFF FFFF FFFF FFFF FFFF FF	006D 6E6F 7071 7273 7475 FF77 FF4E 76FF 4C67 6869 6A6B 6C49 4A4B FF4D 7858 FFFF
FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF	664F 5051 5253 5455 5657 FF65 FFFF FFFF 645B 5C5D 5E5F 6061 6263 FFFF FF12 10FF
<sup> </sup> FF6D 6E6F 7071 7273 7475 FFFE FFFF FFFF <sup> </sup>  FF67 6869 6A6B 6C49 4A4B FFFF FFFF FFFF	006D 6E6F 7071 7273 7475 FF77 FF4E 76FF 4C67 6869 6A6B 6C49 4A4B FF4D 7858 FFFF
IFFFF 5051 5253 5455 5657 FFFF FFFF FFFF 6458 5C5D 5E5F 6061 6263 FFFF FFFF FFFF	664F 5051 5253 5455 5657 FF65 FFFF FFFF   645B 5C5D 5E5F 6061 6263 FFFF FF12 10FF
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Figure 1-87. Printer Translate Table for MCS: PCS-HN Arrangement; Count Length 78 (Hex)

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Figure 1-88. Printer Translate Table for MCS: QN Arrangement; Count Length F0 (Hex)

da 700	00						
40FF	FFFF	FFFF	FFFF	FFFF	FFFF	FFFF	FFFF
FFFF	FFFF	FFFF	FFFF	FFFF	FFFF	FFFF	
FFFF	FFFF	FFFF	FFFF	FFFF	FFFF	FFFF	FFFF
FFFF	FFFF	FFFF	FFFF	FFFF	FFFF	FFFF	FFFF
00FF	FFFF	FFFF	FFFF	FFFF	FFEF	43E4	EED3
A5FF	FFFF	FFFF	FFFF	FFFF	FF15	D6F0	44A3
E2CD	FFFF	FFFF	FFFF	FFFF	FFD7	D513	7473
FFFF	FFFF	FFFF	FFFF	FFFF	D445	75A4	D814
FFFF	FFFF	FFFF	FFFF	FFFF	FFFF	FFFF	FFFF
FFFF	FFFF	FFFF	FFFF	FFFF	FFFF	FFFF	
FFFF	FFFF	FFFF	FFFF	FFFF	FFFF	FFFF	FFFF
FFFF	FFFF	FFFF	FFFF	FFFF	FFFF	FFFF	
FFE5	E6E7	E8E9	EAEB	ECED	FFFF	FFFF	FFFF
FFD9	DADB	DCDD	DEDF	E0E1	FFFF	FFFF	
FFFF	CECF	D0D1	D2CB	CCE3	FFFF	FFFF	FFFF
CAC1	C2C3	C4C5	C6C7	C8C9	FFFF	FFFF	FFFF
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	da 700	00						,
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FF   FF	E2CD CAC1	CECF C2C3		D2CB C6C7	CCE3 C8C9			
D3 A3	00E5 A5D9	E6E7 DADB	E8E9 DCDD	EAEB DEDF	ECED E0E1	FFEF FF15	43E4 D6F0	EED3 44A3
73   14	E2CD CAC1	CECF C2C3	D0D1 C4C5	D2 CB C6 C7	CCE3 C8C9		D513 75A4	7473 i D814 i
FF1 FF1	00E5 A5D9			EAEB DEDF			43E4 D6F0	
FFI I FFI I	E2CD CAC1		D0D1 C4C5		CCE3 C8C9	FFD7 D445	D513 75A4	7473 D814
FF	00E5 A5D9			EAEB DEDF			43E4 D6F0	
FF	E2CD CAC1		D0D1 C4C5	D2CE C6C7	CCE3 C8C9		D513 75A4	
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Figure 1-89. Printer Translate Table for MCS: QNC Arrangement; Count Length F0 (Hex)

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da 7000										
40FF FFF FFFF FFF		FF FFFF	FFFF FFFF	FFFF FFFF	FFFF FFFF					
FFFF FFF		FF FFFF	FFFF FFFF	FFFF FFFF	FFFF FFFF					
00FF FFF D6FF FFF		FF FFFF FF FFFF	FFD7 FFE3	8EFO E4EE	FF5E 8F90					
E2CD FFF FFFF FFF		FF FFFF FF FFFF	FF2F 5FCB		C0BF 302E					
FFFF FFF FFFF FFF		FF FFFF FF FFFF	FFFF FFFF	FFFF FFFF	FFFF FFFF					
FFFF FFF		FF FFFF FF FFFF	FFFF FFFF	FFFF FFFF	FFFF FFFF					
FFE5 E6E		EB ECED	FFFF FFFF	FFFF FFFF	FFFF FFFF					
FFFF CEC CAC1 C2C	F D0D1 D2 3 C4C5 C6	D3 D4D5 C7 C8C9	FFFF FFFF	FFFF FFFF	FFFF FFFF					
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İ	E2CD CAC1		D0D1 C4C5		D4D5 C8C9		D860 CCBE	COBF 302E				
	00E5 D6D9	E6 E7 DADB	E8E9 DCDD	EAEB DEDF	ECED E0E1	FFD7 FFE3	8EF0 E4EE	EF5E 8F90				
	E2CD CAC1				D4D5 C8C9		D860 CCBE	COBF 302E				
	00E5 D6D9	E6 E7 DADB		EAEB DEDF	ECED E0E1		8EF0 E4EE	EF5E 8F90				
	E2CD CAC1				D4D5 C8C9		D860 CCBE	COBF 302E				
	00E5 D6D9	E6 E7 DADB		EAEB DEDF	ECED E0E1		8EF0 E4EE	EF5E 8F90				
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	C1	C2	C3	C4	C5	C6	C7	C8	C9	CA	СВ	сс	CD	CE	CF	DO	D1	D2	D3	D4	D5	D6	D7	D8
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40E5 E6E7 E8E9 EAEB ECED FFEF A3E4 EEFF |

D3D9 DADB DCDD DEDF E0E1 FFD5 D6F0 FFFF I

E2CD CECF D0D1 D2CB CCE3 FFD7 43FF FFFF I CAC1 C2C3 C4C5 C6C7 C8C9 FF73 D413 D8FF

100E5 E6E7 E8E9 EAEB ECED FFEF A3E4 EEFF

ID3D9 DADB DCDD DEDF E0E1 FFD5 D6F0 FFFF!

E2CD CECF D0D1 D2CB CCE3 FFD7 43FF FFFF

| CAC1 C2C3 C4C5 C6C7 C8C9 FF73 D413 D8FF |

100E5 E6E7 E8E9 EAEB ECED FFEF A3E4 EEFF1

| D3D9 DADB DCDD DEDF E0E1 FFD5 D6F0 FFFF

I E2CD CECF D0D1 D2CB CCE3 FFD7 43FF FFFF CAC1 C2C3 C4C5 C6C7 C8C9 FF73 D413 D8FF

100E5 E6E7 E8E9 EAEB ECED FFEF A3E4 EEFF

D3D9 DADB DCDD DEDF E0E1 FFD5 D6F0 FFFF

| E2CD CECF D0D1 D2CB CCE3 FFD7 43FF FFFF

CAC1\_C2C3\_C4C5\_C6C7\_C8C9\_FF73\_D413\_D8FF

(Folded)

da 7000

Graphic

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40FF FFFF FFFF FFFF FFFF FFFF FFFF

FFFF FFFF FFFF FFFF FFFF FFFF FFFF

FFFF FFFF FFFF FFFF FFFF FFFF FFFF

D3FF FFFF FFFF FFFF FFFF FFD5 D6F0 FFFF

E2CD FFFF FFFF FFFF FFFF FFD7 43FF FFFF

IFFFF FFFF FFFF FFFF FF73 D413 D8FF

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FFFF FFFF FFFF FFFF FFFF FFFF FFFF

FFE5 E6E7 E8E9 EAEB ECED FFFF FFFF FFFF

FFD9 DADB DCDD E0E1 FFFF FFFF FFFF FFFF FFFF CECF D0D1 D2CB CCE3 FFFF FFFF FFFF

CAC1 C2C3 C4C5 C6C7 C8C9 FFFF FFFF FFFF

(Not Folded)

FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF

Figure 1-90. Printer Translate Table for MCS: RN Arrangement; Count Length F0 (Hex)

da 7000	
40FF FFFF FFFF FFFF FFFF FFFF FFFF FFFF	
FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF	
00FF FFFF FFFF FFFF FFFF EEA8 F0E7 CAEA A7FF FFFF FFFF FFFF FFFF ECB3 B4E8 EDFF	•
BEA9 FFFF FFFF FFFF FFFF FFB2 EFFF FFE FFFF FFFF FFFF FFFF C0FF E5E6 FFBF	
FFCB CCCD CECF D0D1 D2D3 FFFF FFFF FFFF FFD4 D5D6 D7D8 D9DA DBDC FFFF FFFF FFFF	
FFFF DDDE DEF0 E1E2 E3E4 FFFF FFFF FFFF FFFF FFFF FFFF FFFF FF	
FFC1 C2C3 C4C5 C6C7 C8C9 FFFF FFFF FFFF FFB5 B6B7 B8B9 BABB BCBD FFFF FFFF FFFF	
FFFF AAAB ACAD AEAF B0B1 FFFF FFFF FFFF A69D 9E9F A0A1 A2A3 A4A5 FFFF FFFF FFFF	

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	49	4A	4B	4C	4D	4E	4F	50	51	52	53	54	55	56	57	58	59	5A	5B	5C	5D	5E	5F	e
L						L																		
	61	62	63	64	65	66	67	68	69	6A	6B	6C	6D	6E	6F	70	71	72	73	74	75	76	77	7
_														·										
L	79	7A	7B	7C	7D	7E	7F	80	81	82	83	84	85	86	87	88	89	8A	8B	8C	8D	8E	8F	9
L												l		L										
r					·				<b>_</b>		·		-	_			_	_						
L	91	92	93	94	95	96	97	98	991	9A	9B	9C	9D	9E	9F	A0	A1	A2	A3	A4	A5	A6	A7	1
													1	2	3	4	5	6	7	8	9	0	&	
P					_	_			,									_	_	_	_			-
	A9	AA	AB	AC	AD	AE	AF	BO	B1	B2	B3	B4	B5	B6	B7	B8	В9	BA	BB	BC	BD	BE	BF	0
	/	S	Т	υ	V	w	х	Y	Z		\$	*	J	к	L	м	N	0	Р	Q	R	_	"	
						_								_	_		_	_	_	_				Ţ
	C1	C2	СЗ	C4	C5	C6	C7	C8	C9	CA	СВ	cc	CD	CE	CF	D0	D1	D2	D3	D4 '	D5	D6	D7	[
L	A	В	С	D	D	F	G	н	1	+	а	b	с	d	е	f	g	h	i	j	k	1	m	
-			-			_	-	_					-	-				<b>q</b>			_			
L	D9	DA	DB	DC	DD	DE	DF	EO	E1	E2	E3	E4	E5	E6	E7	E8	E9	EA	EB	EC	ED	EE	EF	Ľ
	0	р	q	r	s	t	u	v	w	×	y	z	@	'	(	)	-	1	?	!	;	¢	%	Γ

Figure 1-91. Printer Translate Table for MCS: SN Arrangement; Count Length F0 (Hex)

1	da 700	0						1
i	20FF FFFF		FFFF FFFF		FFFF FFFF			FFFF   FFFF
 	FFFF FFFF	FFFF FFFF	FFFF FFFF	FFFF FFFF	FFFF FFFF			FFFF
1	00FF 18FF	FFFF FFFF	FFFF FFFF		FFFF FFFF	6B0C 4E4F		2E78   4C62
1	220D FFFF	FFFF FFFF	FFFF FFFF	FFFF FFFF	FFFF FFFF		5176 494A	674B   0B23
	FF2F FF38		3233 3B3C				695F 5260	5E66   4D6C
1	5D61 5C53		4344 5657			FF71 FF72	736D 746 E	6A75   6577
i	FF25 FF19	2627 1A1B	2829 1C1D	2A2B 1E1F	2C2D 2021	FFFF FFFF	FFFF FFFF	FFFF   FFFF
	FFFF 0A01	0E0F 0203	1011 0405	1213 0607	1415 0809	FFFF	FFFF	FFFF

Graphic

Graphic Position Code

IIC P	ositior	Code	;																				
01	02	03	04	05	06	07	08	09	0A	0B	0C	0D	0E	OF	10	11	12	13	14	15	16	17	Ι
1	2	3	4	5	6	7	8	9	0	=		/	S	Т	U	V	w	х	Υ	Z	,	#	
19	1A	1B	1C	1D	1E	1F	20	21	22	23	24	25	26	27	28	29	2A	2B	2C	2D	2E	2F	I
J	к	L	м	N	0	Р	۵	R	-	"	:	А	В	С	D	E	F	G	н	1	+	а	Ι
31	32	33	34	35	36	37	38	39	3A	ЗB	3C	3D	3E	3F	40	41	42	43	44	45	46	47	T
с	d	е	f	g	h	i	j	k	1	m	n	0	р	q	r	s	t	u	v	w	x	У	Ι
49	4A	4B	4C	4D	4E	4F	50	51	52	53	54	55	56	57	58	59	5A	5B	5C	5D	5E	5F	T
@	'	?	;	±	!	\$	*	%	ц	1	2	3	4	5	6	7	8	9	0	-	+	(	I
61	62	63	64	65	66	67	68	69	6A	6B	6C	6D	6E	6F	70	71	72	73	74	75	76	77	T
0		(	)	¥	+	>	<	<	>	¢		[	1	}	1	L		Ĺ.		•		_	T

Figure 1-92. Printer Translate Table for MCS: TN Arrangement; Count Length 78 (Hex)

da 7000	1 da 7000 i
02FF FFFF FFFF FFFF FFFF FFFF FFFF FFFF	020D 0E0F 1011 1213 1415 FF0C FFFF FFFF FF17 1819 1A1B 1C1D 1E1F FF21 20FF FFFF
FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF	FFFF 2223 2425 2627 2816 FF0B FFFF FFFF 0A01 0203 0405 0607 0809 FFFF FFFF FFFF
OOFF FFFF FFFF FFFF FFFF FFOC FFFF FFFF	000D 0E0F 1011 1213 1415 FF0C FFFF FFFF FF17 1819 1A1B 1C1D 1E1F FF21 20FF FFFF
FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF	FFFF 2223 2425 2627 2816 FF0B FFFF FFFF 0A01 0203 0405 0607 0809 FFFF FFFF FFFF
FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF	000D 0E0F 1011 1213 1415 FF0C FFFF FFFF FF17 1819 1A1B 1C1D 1E1F FF21 20FF FFFF
FFFF FFFF FFFF FFFF FFFF FFFF FFFF	FFFF 2223 2425 2627 2816 FF0B FFFF FFFF 0A01 0203 0405 0607 0809 FFFF FFFF FFFF
FFOD 0E0F 1011 1213 1415 FFFF FFFF FFFF FF17 1819 1A1B 1C1D 1E1F FFFF FFFF FFFF	000D 0E0F 1011 1213 1415 FF0C FFFF FFFF FF17 1819 1A1B 1C1D 1E1F FF21 20FF FFFFI
FFFF 2223 2425 2627 2816 FFFF FFFF FFFF 0A01 0203 0405 0607 0809 FFFF FFFF FFFF	FFFF 2223 2425 2627 2816 FF0B FFFF FFFF 0A01 0203 0405 0607 0809 FFFF FFFF FFFF
(Not Folded)	└ (Folded)

Gra	phic

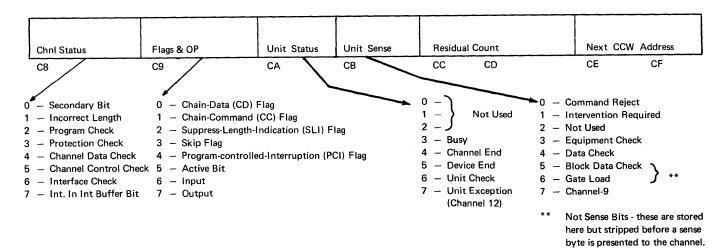
Graphic Position Code

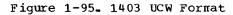
	phic P	osition	Code						+	·····		·									,			
╎┕╾	01	02	03	04	05	06	07	08	09	0A	ОВ	0C	0D	0E	0F	10	11	12	13	14	15	16	17	18
	1	2	3	4	5	6	7	8	9	0	,		A	В	С	D	Е	F	G	н	1	Z	к	к
	19	1A	1B	1C	1D	1E	1F	20	21	22	23	24	25	26	27	28	29	2A	2B	2C	2D	2E	2F	30
			+	+	4		R	+	1	1	+	U	V	w	x		t			+	l	+		

Figure 1-93. Printer Translate Table for MCS: XN Arrangement; Count Length 28 (Hex)

	FFFF   FFFF   FFFF   00FF   FFFF   50FF   FFFF	FFF           FFF	F FF F FF F FF F FF F FF F FF F FF	FF   FF   FF   FF   FF   FF   FF   FF	FFFF FFFF FFFF FFFF FFFF FFFF FFFF FFFF	FFFF FFFF FFFF FFFF FFFF FFFF	FFFF FFFF FFF7 FF51 FF77 FF4F FFFF FFFF	FF FF FF 76 FF FF FF FF	FF F FF F FF F FF F FF F FF F FF F FF	FFF  FFF  FFF  FFF  FFF  FFF  FFF  FFF	             	FF67 50FF 5B52 005E FF67 50FF 5B52 005E FF67	5F60 6869 5C5D 5354 5F60 6869 5C5D 5354 5F60 6869 5C5D	6A6 707 5555 616 6A6 707 5555 616 6A6	B 60 1 72 6 57 2 63 B 60 1 72 6 57 2 63 B 60	C6D 273 758 364 C6D 273 758 364 C6D	6E6F 7475 595A 6566 6E6F 7475 595A 6566 6E6F	FF51 FF77 FF4F FF51 FF51 FF77 FF4F FF78 FF51	76F FFF FFF 76F FFF FFF FFF 76F	F FF F FF F FF F FF F FF F FF F FF	FFI FFI FFI FFI FFI FFI FFI			
	FFFF   FF5E												5354 5F60											
	FF67	686	9 6A	46 B	6C6D	6E6F	FFFF	FF	FF F	FFF	1	FF67	6869	6A6	B 60	C6D (	3E6F	FF51	76F	FFF	FF			
	FFFF   <u>5</u> B5 <u>2</u>												5C5D 5354											
Graphic					(Not F	olded)										(Fol	ded)							
Gra	phic Po	<u> </u>			1 05	06	07	00	09	0A	ОВ	oc	0D	0E	OF	10	11	12	13	14	15	16	17	18
	01	02	03	04	05	00	07	08	09					UE			+	12		14	15	10		10
	L[	l		I		II				<u> </u>	L		1	]			I	L]						ii
	19	1A	1B	1C	1D	1E	1F	20	21	22	23	24	25	26	27	28	29	2A	2B	2C	2D	2E	2F	30
				<u> </u>						<u> </u>	Ĺ													
	31	32	33	34	35	36	37	38	39	3A	3B	3C	3D	3E	3F	40	41	42	43	44	45	46	47	48
				34	- 35	30			- 39		30	30	30	<u>J</u>		40		72						
	L	l		L		<u>ا</u> ا			L	L	L	L	l			L		L I	1					
	49	4A	4B	4C	4D	4E	4F	50	51	52	53	54	55	56	57	58	59	5A	5B	5C	5D	5E	5F	60
		]					#		\$	1	2	3	4	5	6	7	8	9	0	S	т	А	В	С
	61	60	62		CE.	66	67	60	60	64	C.D.	é C	6D	CE.	65	70	71	70	72	74	75	76	77	70
	61 D	62 E	63 F	64 G	65 H	66	67 J	68 K	69 L	6A M	6B N	6C 0	6D P	6E Q	6F R	70 U	71 V	72 W	73 X	74 Y	75 Z	76 *		78
					<u> </u>	<u> </u>					L			<u> </u>		Ľ	Ļ							

Figure 1-94. Printer Translate Table for MCS: YN Arrangement; Count Length 78 (Hex)





## | 1.15 2311/DAC (FIGURES 1-96 THROUGH 1-118)

				,			STER LAT		T FO	R EACH	COMMA	ND
					м/т	SEARCH HI	SEARCH EQ	COUNT	KEY	DATA	READ	WRITE
							CMD E	BYTE PO	SITIO	N		
	COMMAND	HEX VALUE	M/T ON	GO	0	1	2	3	4	5	6	7
	SEEK	07			т					x	x	x
	CYL SEEK	0B			U				X		x	X
	HEAD SEEK	1B			R			X	X		x	×
_	RECALIBRATE	13			N			×			x	X
RO	NO OP	03			Е						x	×
CONTROL	SET FILE MASK	1F			D			×	X	X	X	X
ŏ	SPACE COUNT	0F		**					X	X	X	x
	RESTORE (NO-OP)	17			0			X		X	X	X
	TEST I/O	00			N							
	SENSE I/O	04			F					X		
	RD DATA	06	86	х	0					x	x	
	RD KEY-DATA	OE	8E	X	R				X	X	Х	
	RD C-K-D	1E	9E	X		·		X	X	X	X	
READ	RD HA	1A	9A	X	М/Т			X	×		х	
"	RD RO	16	96	X				×	ļ	X	Х	
	RD COUNT	12	92	X				×	1	<u> </u>	X	ļ
	RD (IPL)	02	82	×	R						×	L
	WR DATA	05		x	E					x		х
	WR KEY = DATA	0D		X	<b>A</b>				X	X		X
WRITE	WR C-K-D	1D		X	D			×	X	X		х
WF	WR HA	19		X	]			×	X			X
	WR R0	15		X	0			х		X		X
ĺ	ERASE	11		X	R			x				X
	SCH ID EQ	31	B1	x	s		×	x				x
	SCH ID HI	51	D1	X	] E	X		X				х
£	SCH ID EQ OR HI	71	F1	X	<b>A</b>	×	X	х				×
SEARCH	SCH KEY EQ	29	A9	X	] R		Х		×			X
ŝ	SCH KEY HI	49	C9	X	] C	X			X			X
	SCH KEY EQ OR HI	69	E9	X	н	X	X		×			×
	SCH HA EQ	39	B9	X	c		X	x	×	<u> </u>	<b> </b>	×
	*SCH K-D EQ	2D	AD	×	м		x		x	x		x
	*SCH K-D HI	4D	CD	X	D	X			X	X		×
	*SCH K-D EQ OR HI	6D	ED	X	S.	x	×		X	X		X
	* File Scan Commands			+	-				-			

OP REGISTER LATCHES SET FOR EACH COMMAND

\* File Scan Commands

\*\* Go Issued unless Space Count is the First Command of a Chain

-Go Issued to DAC for Indicated Cmds.

Figure 1-96. Integrated File Commands

	TIC Command C	ode
Decimal	Hexadecimal	Binary
X8	X8	XXXX1000

R	ecalibrate Comman	nd Code
Decimal	Hexadecimal	Binary
19	13	00010011

Figure 1-99. 2311/DAC Operation Code for Recalibrate Command

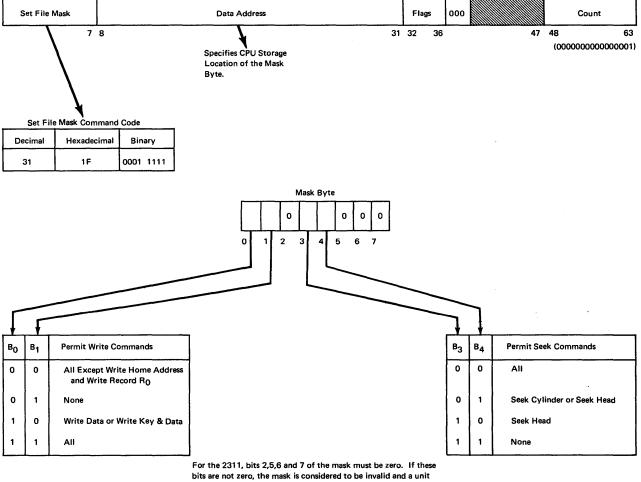
Figure 1-97.	2311/DAC Cperaticn Ccde	fcr
	TIC Command	

Read IPL Command Code			
Decimal	Hexadecimal	Binary	
02	02	0000 0010	

Figure	1-100.	2311/DAC	Read	IPL	Command
-		Code			

No-Operation Command Code			
Decimal	Hexadecimal	Binary	
03	03	00000011	

Figure 1-98. 2311/DAC Operation Code for No-Op Command



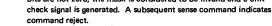


Figure 1-101. 2311/DAC Set File Mask Command

Command	Seek Command Code			
	Decimal Hexade		Binary	
Seek	07	07	00000111	
Seek Cylinder	11	OB	00001011	
Seek Head	27	1B	00011011	

Figure 1-102. 2311/DAC Operation Codes for Seek Commands

	Byte O	Byte 1	Byte 2	Byte 3	Byte 4	Byte 5
Binary		00000000		00000000	00000000	00000000 to 00001001
Hexadecimal Equivalent	00	00	00	00 to CA	00	00 to 09

Figure	1-103.	2311/DAC	6-Byte	Seek
		Commands		

Space Count Command Code

Decimal	Hexadecimal	Binary
15	OF	00001111

# Figure 1-104. 2311/DAC Operation Code for Space Count Command

Sense I/O Command Code

Decimal	Hexadecimal	Binary
04	04	00000100

Figure 1-105. 2311/DAC Operation Code for Sense Command

Read R0 Command Code					
Decimal Hexadecimal Binary					
22 16 00010110					

Read R0 Command Code Multiple-Track			
Decimal	Hexadecimal	Binary	
150	96	10010110	

## Figure 1-106. 2311/DAC Read Track Descriptor Record (RO) Command Codes

	Read HA Con	nmand Code	
Decimal	Hexadecimat	Binary	
26	1A	00011010	

Read HA Command Code Multiple-Track			
Decimal	Hexadecimal	Binary	
154	9A	10011010	

## Figure 1-107. 2311/DAC Read Home Address Command Codes

Read Count Command Code				
Decimal	Hexadecimal	Binary		
18 12 00010010				

Read Count Command Code, Multiple-Track			
Decimal Hexadecimal Binary			
146	92	10010010	

Figure 1-108. 2311/DAC Read Count Command Codes

Read Data Read Key and Data

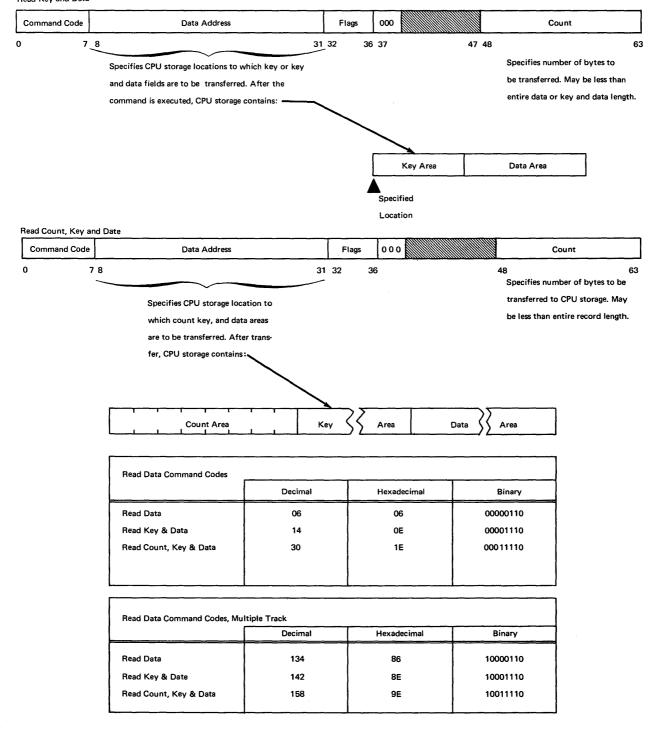


Figure 1-109. 2311-DAC Read Data, Read Key Data, and Read Count Key Data Command Codes

Write Data Command Codes				
	Decimal	Hexadecimal	Binary	
Write Data	05	05	00000101	
Write Key & Data	13	0D	00001101	

Write Data

Write Key & Data

	Command Codes	Data Address	Flags	000	Count
C	) 7	8 31	32 36	48	63

Specifies CPU storage location from which data or key and data fields are to be transferred.

The CCW count field specifies the number of bytes to be I. transferred.

Figure 1-110. 2311/DAC Write Data and Write Key and Data Command Codes

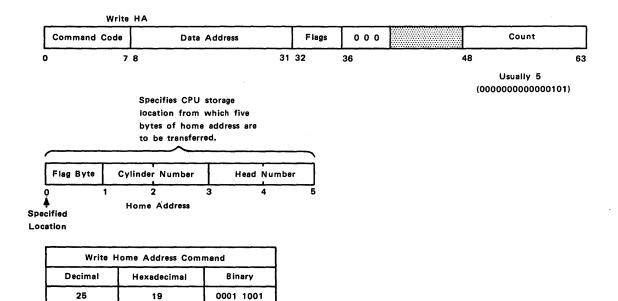


Figure 1-111. 2311/DAC Write Home Address Command Code

	Sense Byte O	Sense Byte 1	Sense Byte 2	Sense Byte 3
Bit 0	Command Reject	Data Check in Count Field	Unsafe	Ready
Bit 1	Intervention Required	Track Overrun		On Line
Bit 2		End-of-Cylinder		Unsafe
Bit 3	Equipment Check	Invalid Sequence	Selected Status	
Bit 4	Data Check	No Record Found	Cyclic-Code Check	On Line
Bit 5	Overrun	File Protected	Unselected File Status	End of Cylinder
Bit 6	Track-Condition Check	Missing Address Marker		
Bit 7	Seek Check			Seek Incomplete

## Figure 1-112. 2311/DAC Sense Byte Summary

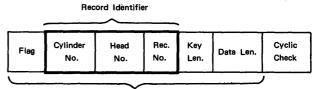
	Search Home Address Equal Command Code			
	Decimal	Hexadecimal	Binar	у
MT Bit Off	57	39	0011	1001
MT Bit On	185	в9	1011	1001

## Figure 1-113. 2311/DAC Operation Codes for Search Home Address Equal Command

Command	Search ID Command Code			
Command	Decimal	Hexadecimat	Binary	
Search ID Equal	49	31	00110001	
Search ID High Search ID Equal	81	51	01010001	
or High	113	- 71	01110001	

Command	Search ID Multipule Track Command Code			
Command	Decimal	Hexadecimal	Binary	
Search ID Equal	177	B1	10110001	
Search ID High	209	D1	11010001	
Search ID Equal				
or High	241	F1	11110001	

Figure 1-114. 2311/DAC Search ID Command Codes

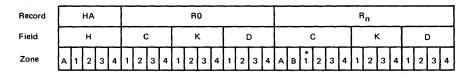


Count Area

Figure 1-115. 2311/DAC Identifier (ID)

Command	Command Sequence	Initial Field and Zone State	Field and Zone State at End of Command	
Read Count, Key and Data None Read Key and Data None		C1 C1	D4 D4	
Read Key and Data	After Search ID	C1	D4	
Read Data	None	C1	D4	
Nead Data	After Search ID	C4	D4	
	After Search Key	К4	D4	
Write Count, Key and Data	Search Equal ID	C4	D4	
	Search Equal Key	К4	D4	
	Write R0	D4	D4	
	Write Count, Key and Data	D4	D4	
Write Key and Data	Search Equal ID	C4	D4	
Write Data	Search Equal ID	C4	D4	
	Search Equal Key	К4	D4	
Search ID	None	C1	C4	
Search Key	None	C1	К4	
·	After Read or Search ID	C4	K4	
Search Key and Data	None	C1	D4	
- · · - ·	After Read or Search ID	C4	D4	
Search Home Address	arch Home Address None		H4	
Read R0	None	HA	D4	
	After Read or Search Home Address	H4	D4	
Write R0	Write Home Address	H4	D4	
	Search Equal Home Address	H4	D4	
Read Home Address	None	НА	H4	
Write Home Address	None	НА	H4	
Read Initial Program Load	None	C1	D4	
Read Count	None	C1	C4	
Erase	Search Equal ID	C4	D4	
	Search Equal Key	К4	D4	
	Write RO	D4	D4	
	Write Count, Key and Data	D4	D4	
No Operation	None	Reset Cond	ition	

Figure 1-116. 2311/DAC Track Orientation Field and Zone State Summary



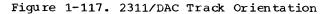
#### Field Definition

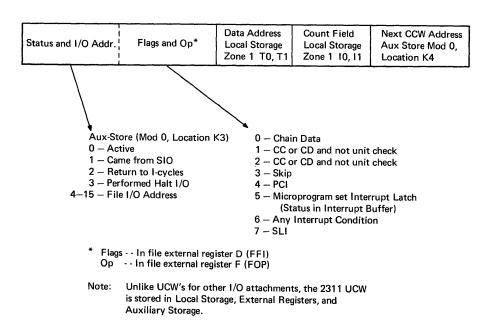
H Home-address area (including gaps)

- C Count area (including gaps)
- K Key area (including gaps)
- D Data area (including gaps)

#### Zone Definition

- 1 Pre-record gap (including address marker)
- 2 Record
- 3 Cyclic code
- 4 Post-record gap
- A Constant gap of 12-ones bytes in the count field, or 28 all-zeros bytes in the home-address field.
- B The 4.9% variable gap between records.
- Notes: The index point immediately precedes the home-address area. \* Location of the address marker.





## Figure 1-118. 2311 UCW Format

## Section 2. Diagnostic Techniques

This section of the manual describes maintenance concepts, system failure and handling procedures, and maintenance program definitions. The <u>Model 25 Field</u> <u>Engineering Maintenance Diagrams Manual</u> (MDM), Y24-3529, contains detailed analysis routines and should be referred to on other than obvious failures requiring minimal diagnosis.

#### 1.16 MAINTENANCE CONCEPTS

Microdiagnostic programs are designed to reduce CE diagnostic time by taking advantage of the CPU speed and capability for self-diagnosis through the reloadable control storage feature. The programs are intended for use:

- 1. During unscheduled maintenance
- 2. During scheduled or deferred
- maintenance
- 3. At installation
- 4. Before and after EC installation.

There are two general types of microdiagnostic programs:

- a. Resident
- b. Nonresident.

The primary repair strategy for both types of programs is to replace an SLT card or cards shown on a fault list or logged out on the Console Printer-Keyboard (PR-KB).

In addition, looping capabilities are designed into the programs for scoping and other diagnostic procedures.

The entire strategy has been condensed into diagnostic technique flow diagrams for easy use by the CE and is included in the Mcdel 25 Maintenance Diagram Manual. On other than obvious failures requiring minimal diagnosis, the CE should refer to the diagrams and execute the appropriate section or sections of these programs.

Where the cause of failure cannot be located by microdiagnostic programs (such as in a channel attached I/O device) DMA4 and the associated diagnostic programs already in existence will be used by the CE. The Model 25 macrodiagnostic package is as follows.

3020 DMA4 Diagnostic Monitor 310A Message Editor E108 DMA4 Expansion Section 338F Meter Test 34E1 Direct Control

FFF0 Disk Initializer 3FE1 SEREP F0FE Disk Utility 3FCZ Syt-25/30 F061 FRIEND C675-C67A File Function C678- File Scan C67C,C67D 2311 Diagnostic Text

All other monitor-controlled macrodiagnostics presently released for I/O devices that can be attached to the Model 25 standard interface channel will be functional on the Model 25. These decks and documentation will be shipped from the plant of control for the I/O control unit for device.

Failures not detected by either the micro or macrodiagnostic programs must be located by use of the system environment program SYS-M30-B or possibly the customer problem program.

#### 1.16.1 MALFUNCTION INDICATIONS

 Customer Problem Program Malfunctions during execution of the customer problem program are indicated by console lights (see <u>3.0 System</u> <u>Failure Detection and Handling</u>) and printed logout on the 1052 (see section 1.17.1.2).

Malfunctions detected during execution of resident microdiagnostics cause a stop word or stop loop. These programs are executed automatically during system reset, CSL and IPL.

- b. Nonresident Micro/Macro Diagnostic Programs
  - Malfunctions are indicated as follows.
    1. Nonresident/nonmcnitor-controlled microprograms cause a stop word or
  - stop loop.
    Nonresident/monitor-controlled programs provide fault-locating information on the console printer-keyboard.
  - Macroprograms under DMA4 Monitor. Error messages are determined by system configuration and memory size. These messages can be printed on the output printer defined by CE option (1052, 1403, or 1443).
  - 4. System environment (SYS-M30-B) Error message printout is the same as DMA4 monitor.

A successful reset is indicated by:

- a. No console check lights.
- b. Manual light turns off then on.
- c. System light turns on then off.

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1.16.2 UNIT IDENTIFICATION

Standard SLT nomenclature applies to the 2025 CPU.

## 1.16.3 MALFUNCTION ISOLATION

The aim of the Model 25 Diagnostic Program Package (DPP) is to achieve a minimum DUI by high-resolution fault location of an easily replaceable component. The package provides effective malfunction isolation to the two general types of exposure:

- A. Logic malfunction in the basic CPU, integrated I/O attachments, channel, and CPU features. Resolution capabilities within the integrated devices are as follows.
  - 2540 1. Hole-count test, read and punch (trush failures),
    - 2. Manual operations, including card transport paths, 3. Sta. PFR.
    - Stacker select.
  - Chnl 1. Check Sel-out wraparound to Sel-in,
    - Test address response. 2.
    - 3. Test I/O; complete initial selection of all possible device addresses, section 1.19.7).
    - Ц. Single-cycle routine; command to a particular address and loop.
  - 1. Print coil checking 1403
    - Drum pulse response 2.
      - 3. Hydraulic speed
      - 4. Carriage brushes/emitter/ mechanics
      - 5. Hammer fire,
      - 6. Frint quality.
  - 1052 1. Manual intervention section: Function of all keys, End-of-forms contact, Capability of repeatedly printing any key.
    - 2. Dynamic section: Ability to print characters for all tilt/rotate combinations.

End-of-forms contact.

B. 2311 - Resolution is provided by macrodiagnostics.

> Hard Core - for malfunctions that would prevent basic CPU functions necessary for execution of resident diagnostics, the following strategy will be used.

- 1. Power, clock, etc. Normal CE repair procedures will be applied using console capabilities, power diagnostic techniques diagram in the maintenance diagram manual, etc.
- 2. Memory A memory diagnostic techniques diagram for diagnosis and repair is provided in the maintenance diagram manual. The capabilities designed into the Model 25 such as SCAN STOR, TEST PATTERN, etc. are used in this strategy. A nonresident memory microdiagnostic is also provided for CPU with two memory modules.

The recommended sequence for executing the DPP as outlined in the Maintenance Diagrams Manual provides for a building block approach to locating the failure. Each program basically builds on the successful execution of the previous lower level program.

## 1.16.4 REPAIR

Repair will generally consist of replacing the failing component (usually an SIT card) from on site or branch office stock.

#### 1.16.5 REPAIR VERIFICATION

The micro- or macro-program where the failure was diagnosed should be reexecuted after the repair. Successful execution will be considered a justification for returning to the customer problem-program.

## 1.16.6 INTERMITTENT MALFUNCTION

Intermittent failures as seen by the customer can take one of two forms:

The failure is actually a solid 1. hardware defect, but appears intermittent because that area of the logic is called on only to function occasionally. Microdiagnostic programs will be

effective to a high degree on this type of failure because by design, they are capable of checking the majority of CPU and integrated I/O attachment logic.

The failure is intermittent due to a 2. degraded or marginal component. The looping capabilities designed into the microdiagnostic programs will

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attack this type of failure effectively by exercising the logic until a pattern can be established.

Other diagnostic capabilities that will also impact intermittent failures are CE Trap (See section 1.18.7) and 1052 Logout (See section 1.17.1.3).

#### 1.16.7 PROTECTION OF CONTROL STORAGE, CSL

Module 0 (first 128 control words) will be protected by the resident CSL routine on all core loads.

Alter control storage from the 1052 will not be operative unless the CE key is on.

The enable control-storage store key on the CPU will not be operative unless the CE key is on.

#### 1.17 SYSTEM FAILURE DETECTION AND HANDLING

The objectives of failure detection and handling procedures for the Model 25 are to provide:

- Assurance to the customer that the a. system is functionally operational.
- Sufficient indication and information b. to enable the CE to locate the failure rapidly and accurately.

A version of the SEREP program is also provided.

#### 1.17.1 ERRCR HANDLING

The Model 25 will come to a hard stop on second error, a second malfunction which occurs before the first malfunction has caused a machine-check interrupt to be taken (Figure 1-119).

There are no special provisions on the Model 25 for continued operation in the presence of a solid malfunction.

Error restart capabilities for such intermittent I/O failures as data checks, punch checks, etc. are provided by the operating system used by the custcmer.

Nonhardware-caused troubles (jams, failures, etc.) are normally not expected

to result in a customer-reported call. The Model 25 Functional Characteristics Manual, Form A24-3510, provides restart procedures for these situations; also consult the index in this manual for the specific area of interest.

1.17.1.1 Machine-Check and Channel Control Check

Any of the following machine-check conditions (if the M-bit of the PSW is on), will cause the corresponding bit to be set in the error register (MC) and initiate the machine-check trap routine:

- File Control Check 0 Storage Protect Check 1
- 2 Storage Address Check
- 3 Control Word Parity Check 4
- Storage Data Parity Check
- 5 ALU Error Latch A-Reg Parity Check 6
- B-Reg Parity Check 7

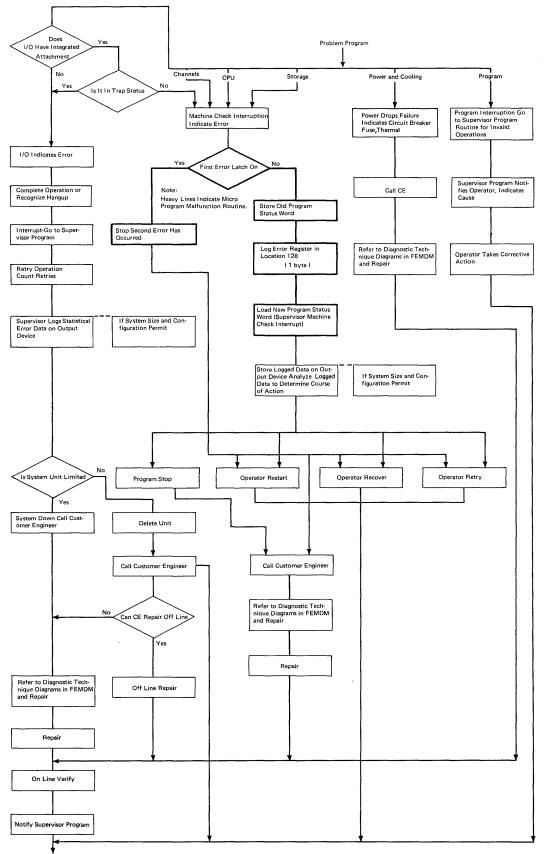
The machine-check trap routine stores the following information into program storage starting at hex location 80.

80 - Trap priority register (MMSK) 81 - Branch condition register (BA) 82 - Machine-check register (MC) 83 - Error count\* 84-85 - Backup address (address of the microword) 86-87 - Unused

\*Bits 1-2 of byte 83 contain the logout code: 00 for machine check or channel control check; or 11 for interface control check.

If none of the 0 through 6 bits of the MMSK register is cn (indication that an I/O trap is not in process), the logout area above is printed on the console printer. The machine-check interrupt will then take place.

If an I/O trap is in process (any of the 0 through 6 bits of MMSK register on) when a machine-check trap occurs, the L/O operation involved will be terminated and then the I/C interrupt will take place. The logout area will be printed on the console printer-keyboard before any CPU instructions are executed.



Continue Problem Program

Figure 1-119. Maintenance Approach

#### 1.17.1.2 Interface Control Check

When an interface control check is detected on either the multiplexer or selector channel, the following information is stored in program-storage locations 80-87 (hex).

- 80 Trap priority register (MMSK)
- 81 Branch conditions register (BA)
- 82 Channel branch conditions register (GS)
- 83 Error count\*
- 84 Channel branch conditions register (GT)
- 85 Channel diagnostic register (GD)
- 86 Code byte

Burst Channel 01XYYYYZ X=1 if time out Z=1 if status trap or chained to CCW. YYYYY=time out counter bits

Byte Channel 001XMMMZ X&Z=same as burst channel M=Misc. use

- 87 Device address
- \*Eits 1-2 of byte 83 contain the logout code: 00 for machine check or channel control check, or 11 for interface control check.

#### 1.17.1.3 1052 Logout

The 1052 logout is a microprogram-supported function that prints out information contained in the diagnostic logout area of program storage, (locations 80-87, hexadecimal). Existing problem programs are not affected by this logout provided they do not use this area. The format and contents of the diagnostic logout area are machine dependent. A version of SEREP that acts on this information is available for use on the Model 25.

In general, the function of such macroprograms is provided by the 1052 logout microprogram. Subsequent tc execution of the 1052 logout microprogram, a System/360 machine-check or I/O interrupt is initiated. Existing restart procedures and problem programs that do not act directly on the diagnostic logout area (such as BPS, DOS, OBR/SDR, etc.) are applicable to the Model 25 within the limits of storage size.

The program-storage byte locations and contents of the diagnostic scanout area are given in section 1.17.1.1.

#### 1.17.2 CPU HARDWARE CHECKS

The setting of the check control switch determines the action taken when a CPU hardware check occurs (see section 1.18).

Checking is provided at the following points; an indicator for the conditions is located on the system control panel:

- A-Register Parity Check
   B-Register Parity Check
   These checks are not always activated
   because some external registers are set
   and reset by bit and do not carry
   parity. In the case cf a byte gated to
   A or B without parity, the check is
   disabled. Local-storage data is always
   checked.
- Storage Address Parity Check A parity check is made on all addresses used to access main storage except on the address after a Branch on Mask word.
- 3. Storage Data Bus-Out Parity Check

This check is made on all data requested from storage. A control-word check occurs on all machine cycles except during the second cycle of a storage word. A storage data check may occur during the second cycle of a storage control word.

4. ALU Check

Parallel logic is used in the ALU to detect an error between the A and B parity checks and the ALU output. Each bit position of ALU (including +6 circuit, complementor and decimal corrector) has two outputs. One output goes to the local store assembler and the system mask register; this output is displayed by the indicators. The other output goes to the Z=0 test. Both outputs go to the parity generator and the ALU check (2-wire check) circuit.

5. Storage Protect Check This is a parity check on the data out of the storage-protect buffer (STP1).

#### 1.17.3 CPU MICROPROGRAM CHECKS

There are some cases during machine operation when a hardware failure that is not detected by hardware checks could occur. In these cases, the microprogram can reach a state from which it must not continue: the microprogram branches to a stop word. The listings will describe the reason for reaching the stop word.

Stop words in Model 25 mode are limited to the system reset diagnostic (BDIA), IPL

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routines, and unused control-stcrage locations.

## 1.17.4 CPU ATTACHMENT CHECKS

This section describes some capabilities for handling check conditions occurring within the integrated I/C attachment devices. For further information, consult the index in this manual for the specific area of interest.

## 1.17.4.1 2540 Attachment Checks

- Overrun--This check occurs when all ten traps that must be completed during each row have not occurred by the time the next row is ready to be read. Priority circuitry ensures that overrun will not occur unless there is a hardware failure.
- Sync Check--This check ensures that the shift registers receiving data from the 1540 are in synchronism with each other.
- Address Check--This check is on the address sent to the 2540 for each bit. It checks for a 2/5 code, and for an address greater than or equal to 90.

Each of these checks will give a unit check to the status byte, with equipment check in the sense information. Hardware checks in the 2540 unit will give the same status and sense information to the program as the 2821. The microprogram interrogates the attachment hardware checks; the 2540 unit checks combines this with the information it may detect itself and places the result in the proper sense bits. The microprogram forms the status and sense information.

## 1.17.4.2 1403 Attachment Checks

- Hammer Check--Equipment check sense bit. This check is made to determine if each hammer driver that was requested to operate, did operate.
- Sync Check--Intervention-required sense bit. This check indicates that the chain or train and the printer controls are out of synchronism.
- 3. Print Buffer Parity Check--Equipment check sense bit. This check is for correct parity on data read from the print buffer while printing a line or when receiving data from the CPU.

The 1403 microprogram interrogates the hardware check information and sets the proper sense and status information. The microprogram also checks information for printability when loading the buffer, and signals data check for unprintable characters. This depends on the information loaded at CSL time into the module of auxiliary storage used as the print translator, or loaded by the UCS utility program UT048. The 1052 (PR-KB) printouts of the printer area of auxiliary storage are shown in Section 1.14.

#### 1.17.4.3 1052 Attachment Checks

The 1052 hardware checks the keyboard data for proper parity. The microprogram detection of a parity error would cause unit-check status and the equipment check sense bit to be set.

#### 1.17.4.4 2311 Attachment Checks

- Data check--unit-check status--data check sense. This check occurs when data read from the file does not generate the proper check character.
- 2. Overrun--unit-check status--overrun sense. This check occurs when the attachment requires service from the CPU and does not receive it scon enough to keep from losing data or causing improper operation.

The 2311 attachment microprogram checks the hardware signals from the 2311 for errors detected in the unit, interrogates the attachment checks and sets the appropriate status and sense information.

#### 1.17.4.5 Channel Checks

- Incorrect Length Check--occurs when the number of bytes contained in the storage areas assigned for the I/O operation is not equal to the number of bytes requested or offered by the I/O device.
- 2. Program Check--occurs when programming errors are detected by the channel.
- 3. Protection Check--occurs when the channel attempts to place data in a portion of main storage that is protected for the current operation on the subchannel; or, the protection key associated with the I/O operation does not match the key of the addressed main-storage location, and the protection key is not zero.
- 4. Channel Data Check--indicates that the channel has detected a parity error in the informaticn transferred to or from main storage during an I/O operation.
- 5. Channel Control Check--caused by any machine malfunction affecting channel controls. This includes parity errors on CCW and data addresses and parity errors on the contents of the CCW. (Logout is initiated.)
- 6. Interface Control Check--caused by an invalid signal on the I/O interface. The condition is detected by the channel and usually indicates malfunctioning of an I/O device. (Logout is initiated.)

The channel microprogram is the path through which all status bytes are set in the CSW. Accesses for sense information are through the same path as for a read operation to the desired unit.

1.17.5 SYSTEM CHECKS

#### 1.17.5.1 Power Check

If any of the dc supplies (except +24V control voltage) falls below its sensed cutput level, if a circuit breaker trips, or if a thermal trip occurs, the machine sequences down to its normal power-cff status and the power-check light turns on.

A power-on sequence cannot occur until the power-check light is reset by pressing the power-off key, and by correcting and resetting the condition that caused the power-off sequence.

#### 1.17.5.2 Iow Temperature

This light turns on when a temperature below 96±5 degrees is detected at the main storage array. When power is turned on initially, this light comes on and remains on until the array is at proper operating temperature (about two minutes.).

## 1.17.6 STATUS BYTES

Because the integrated attachments present the same status information as did the corresponding System/360 control units, the Mcdel 25 does not introduce any new status byte definitions. The only exception is chaining check (bit 47) which is not used on the Model 25.

### 1.17.7 EXTERNAL BRANCH CONDITIONS

The following sections define the external facility bytes for the Model 25 diagnostic microprograms.

#### 1.17.7.1 Integrated Disk Attachment

CHI--COUNTER HIGH IN (for diagnostic analysis)

0	Ctr	Pcs	32,768
1	Ctr	Pos	16,384
2	Ctr	Pcs	8,192
3	Ctr	Pos	4,096
4	Ctr	Pcs	2,048
5	Ctr	Pos	1,024
6	Ctr	Pcs	512
7	Ctr	Pos	256

CLI--COUNTER LOW IN (for diagnostic analysis)

0	Ctr	Pos	128
1	Ctr	Pos	64
2	Ctr	Pos	32
3	Ctr	Pos	16
4	Ctr	Pos	8
5	Ctr	Pos	4
6	Ctr	Pos	2
7	Ctr	Pos	1

#### SDI--SERIALIZER/DESERIALIZER IN (for diagnostic analysis and comparing of home address by Model 25 microprogram)

0	Read	Buffer	128
1	Read	Buffer	128
2	Read	Buffer	64
3	Read	Buffer	32
4	Read	Buffer	16
4	Read	Buffer	8
5	Read	Buffer	4
6	Read	Buffer	2
7	Read	Buffer	1

FOB--FILE-CUT BUS (for diagnostic analysis)

1 2 3 4 5	<u>Ctrl Tag</u> Write Gate Read Gate Seek Start Reset Head Erase Gate Select Head	128 64 32 16 8 4	Set <u>Head Taq</u> Forward Nct Used Nct Used Head 8 Head 4	Not 128 Not 64 Not 32 Not 16 Not 8 Not 4
5	Select Head	4	Head 4	Not 4
	Return to 000 Head Advance	2	Head 1 Head 1	Not 2 Not 1
'	neur navance	*	ncuu 1	100 I

DS--Disk Status When Gated with Diagnostic Controls

	Gat	e Di	lag i	Addr0
0	WR	BUF	128	
1	WR	BUF	64	
2	WR	BUF	32	
3	WR	BUF	16	
4	WR	BUF	8	
5	WR	BUF	4	
6	WR	BUF	2	
7	WR	BUF	1	

Gate Diag Addr1 Test Unit Exec Ω 1 RD Op Erase Cp 2 Scan Op 3 4 Space Count Op 5 HA Op HA or R0 Op 6 7 Count Op

Gate Diag Addr2 0 Key Op 1 Data Cp 2 R0 Op 3 Count or Key or Data Op 4 Count or Key Cp 5 WR CKD Op 6 Standard Index 7 Bit Ring Inhibit Gate Diag Addr3 0 Cyc Code Pos 1 1 Cyc Code Pos 16 2 Cyc Code Pos 17 CC Errcr 3 Ĺ Unequal Compare 5 Bit Ring 7 Write Clock Bit 6 7 Write Data Bit Gate Diag Addr4 0 Zone A 1 Zone B Zone 1 2 3 Zone 2 ц Zone 3 5 Zone 4 HA Field 6 7 Count Field Gate Diag Addr5 0 Key Field 1 Data Field 2 Flag Bit 0 3 Flag Bit 6 Ц Flag Bit 7 Counter Decode 0 5 6 Counter Decode 1 7 Counter Decode 2 Gate Diag Addr6 Counter Decode 3 0 1 Counter Decode 4 2 Counter Decode 5 Counter Decode 6 3 Ш Counter Decode 7 5 Counter Decode 8 Counter Decode 9 6 7 Counter = 0001.17.7.2 Integrated 2540 Attachment RPD=K (CS Decode) 0 R/P Diagnostic Latch 1 R/P Diagnostic Singleshct R/P Diagnostic Single Cycle 3 R/P Reset Shift Register 4 R/P Diagnostic Attachment Reset 5 Unused 6 Un used 7 U nused RPD1--R/P Diag. Cond 1

- 0-4 R/P Tens AR A-E
  - 5 Punch Addr Check

  - 6 Punch Overrun Latch7 Punch Sync Check Latch

RPD2--R/P Diag. Cond. 2 0-4 R/P Units AR A-E 5 Reader Address Check 6 Reader Overrun Lacen 7 Reader Sync Check Latch

## 1.17.7.3 Integrated 1403 Attachment

PRD--Diagnostic Conditions Diagnostic Decode 1 0 PCC TR 128 PCC TR 1 64 2 PCC TR 32 3 PCC TR 16 PCC TR 4 8 5 PCC TR u 2 6 PCC TR 7 PCC TR 1

Diagnostic Decode 2

- 0 Print Control
- 1 Print Scan
- 2 PSS Gate
- 3 Home Gate
- 4 SS3 TR
- 5 Print Compare
- 6 Last Scan
- 7 Sync Check Latch

Diagnostic Decode 3

- 0 Carriage Busy
- 1 Space Drive
- 2 Skip Drive
- 3 Carriage Settling
- 4 Carriage Brush Reg 8
- 5 Carriage Brush Reg 4
- 6 Carriage Brush Reg 2
- 7 Carriage Brush Reg 1

Diagnostic Decode 4

- 0 PLC
- 1 PLB C1
- PLB C2 2
- 3 PLB C3
- 4 MCS Mode
- 5 Addr HD off
- E1 Emitter 6
- 7 Channel 1 Latch

#### 1.17.7.4 Multiplexer or Selector Channel

GA--Channel Conditions Register

- 0 Selective Reset
- 1 Selective Out
- Address Out 2
- 3 Command Out
- 4 Initial Selection
- 5 Select Out
- 6 Channel Reset (diagnostic)
- 7 Spare

GB-Channel Conditions Register

- 0 Data Chain Latch
- 1 Channel Identification Latch
- 2 Burst Latch
- 3 Set Buffered Device Latch or Reset Channel Parity-Error Latch
- 4 Channel Diagnostic Latch
- 5 Channel-1 Interruption Latch
- 6 Spare
- 7 Suppress Cut Control Latch

GD-Channel Diagnostic Register

- 0 Operational Cut
- 1 Service Cut
- 2 Address Cut
- 3 Command Out
- 4 0
- 5 Select Out
- 6 0
- 7 Suppress Out

GS--Channel Branch Conditions

- 0 Data Chain Request Latch
- 1 Buffered Device Latch
- 2 Burst Latch
- 3 Channel Parity-Error Latch
- 4 Initial Select Iatch
- 5 Channel 1 Interrupt Buffer Latch
- 6 Spare
- 7 Suppress Control Latch

GT--Channel Branch Conditions

- 0 Address In
- 1 Not Select In
- 2 Service In
- 3 Status In
- 4 Operational In
- 5 Not Request In
- 6 Channel Identification Latch
- 7 Channel Diagnostic Latch

Bits 0-5 of Sense Byte 1: These bits are common to all devices and are described in the <u>System/360 Principles of Operation</u>, Form A22-6821.

#### 1.18 SYSTEM CONTROL PANEL

This section describes the controls and indicators on the system control panel that are unique to the Model 25 and/or fundamental to maintenance strategy (Figures 1-120 and 1-121). Other controls and functions are explained in the <u>IBM</u> <u>System/360 Model 25 FETOM</u>, Form Y24-3527.

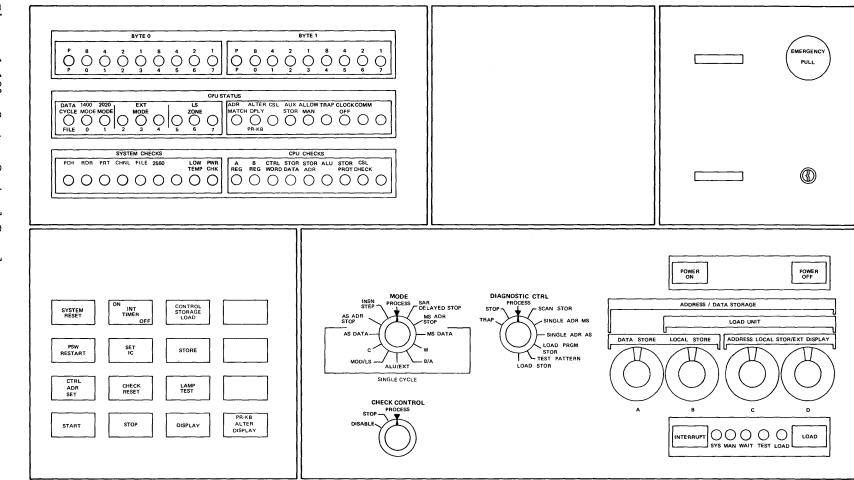
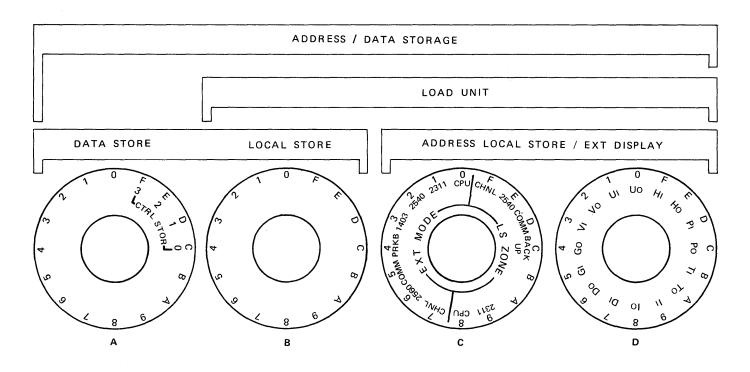


Figure 1-120. System Control Panel



3 CITAL STOR

Note:

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The full view of Switch A shows control storage positions for 48K systems, the partial views of Switch A are used for 16K, 24K, and 32K systems.

Switch A For 16K Systems



Switch A for 24K and 32K Systems

Figure 1-121. Control Panel Switches A, B, C, and D

## 1.18.1 CPU STATUS INDICATORS

#### 1.18.1.1 Address Match

The address match indicator is turned on by:

- a. Address Match Latch when the mode switch is in AS ADR STOP or MS ADR STOP. The CFU clock stops when the address match latch comes cn. It is reset at T1 time.
- b. SAR Delayed Stop Match Latch when the mode switch is in SAR DLY STOP. The instruction in progress is completed and the CPU enters a soft-stop state; the indicator is reset when the start key is pressed (clock start pulse).

## 1.18.1.2 Alter/Display PR-KB

Pressing the PR-KE alter display key turns this light on to indicate that the alter/display microprogram is waiting for an operator response on the 1052 printer-keyboard. This light is turned off by pressing the start key, or after the operator has completed the required keyboard entry.

Control storage cannot be altered from the 1052 unless the CE key is on.

#### 1.18.1.3 CSL

Pressing the control storage load key turns on this light and starts the CSL

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microprogram. The indicator is reset when the CSL routine is completed.

#### 1.18.1.4 Allow Manual

The ALLOW MAN light being on indicates that storage can be manually displayed or altered from the CFU control panel.

The MODE SW must be in the AS DATA or MS DATA positions and the CPU is not stopped after the first cycle of a storage word.

#### 1.18.1.5 Trap

When any TRAP is allowed to occur the trap light is turned on.

#### 1.18.1.6 Clock Off

The CLOCK CFF light is turned on when the CPU clock is not running.

## 1.18.2 SYSTEM CHECKS

#### 1.18.2.1 Low Temperature

The LOW TEMP light indicates that the system is not yet up to minimum core-storage array operating temperature (96F±5F). When system power is turned on, this indicator lights and stays on until the specified operating range is reached (approximately 2 minutes, depending upon room temperature).

#### 1.18.2.2 Power Check

The PWR CHK light turns on if any dc supply falls below its sensed output level (and/or circuit breaker or thermal sensor trip). The machine sequences down to its normal power-off status.

Power restart cannot be activated until the power-check light is reset by pressing the power-off switch and/or resetting the tripped circuit breaker or manually operating the thermal-reset switch. This must be done by a customer engineer.

If no circuit breaker is tripped or no thermal indicator is set in the power tower, the reason for the power failure is a sensed low output from any of the dc supplies (except the 24V dc control voltage).

The power check light also turns on if any of the fuses F30 through F35 are open. These fuses are in the 1403 attachment. The machine will not power-off under this condition. The light will go off when the open fuse is replaced.

## 1.18.2.3 PCH (Punch)

The PCH indicator is turned on for the following error conditions.

- Hole-count check
- Address check
- Shift register sync check
- Overrun
- PFR validity
- Punch not ready at start L/O of a command other than sense or No-Op.

#### 1.18.2.4 RDR (Reader)

The RDR indicator is turned on for the following error conditions.

- Hole-count check
- Address check
- Shift register sync check
- Overrun
- Validity check
- Reader not ready at start I/O of a command other than sense or No-Op.

### 1.18.2.5 PRT (Printer)

The PRT indicator is turned on for the following error conditions.

- Print hammer check
- PLB parity check
- Printer not ready at start I/O of a command other than sense or No-Op.
- Coil-protect check bypass switch in 1403 CE area is on.

### 1.18.2.6 CHNL (Channel)

The CHNL indicator is turned on for a parity check on bus in cr a microprogram-detected channel error.

#### 1.18.2.7 File

The FILE indicator is turned cn for a machine-check trap or a parity error detected during file operation.

#### 1.18.3 CPU CHECKS

#### 1.18.3.1 Control Word

The CTRL WORD light indicates that the control word currently in the C-register has bad parity when read from the storage data register.

#### 1.18.3.2 Storage Data

The STOR DATA light indicates that the information contained in the storage data register contains bad parity.

#### 1.18.3.3 CSL Check

This light is an indication that the checksum microroutine has detected a

difference between the checksum control word and the contents of control storage.

1.18.4 OPERATOR'S CONTROL PANEL (OCP) INDICATORS

#### 1.18.4.1 Power On Key

This key is backlighted in white to indicate that the system power-on sequence is completed. If the key glows rink, the rower-on cr power-off sequence cannot be completed because of a malfunction in a rower surryly or an I/C unit.

#### 1.18.4.2 Pluggable Indicators

Refer to <u>IBM System/360 Model 25 External</u> Field Definitions, Form Z29-2176.

## 1.18.5 KEYS

Only those keys that have special significance in the maintenance strategy are discussed here. Refer to the <u>Mcdel 25</u> <u>FETOM</u>, Form Y24-3527 for a complete description of the console keys.

#### 1.18.5.1 Control Storage Load

This key is used to initialize the system when:

- Operating modes are to be changed (as from Model 25 mode to 1400 mode),
- The contents of control storage have been affected by a system failure, cr
- The system is being returned to the customer after extensive service (such as engineering change activity.)

## 1.18.5.2 PSW Restart

This key is used to restart an application using the IPL PSW, rather than the current PSW used when the system-reset key is pressed.

## 1.18.5.3 Control Address Set

This key must be pressed to allow the CE to restart the microprogram at an address cther than that specified by the normal control-storage addressing means. The CTRL ADR SET key is operational only when the CPU clock is off.

#### 1.18.5.4 Enable Control Storage Store

This switch must be pressed and held during a store into the control storage area of core storage so that the control-storage store circuitry remains activated. The storage operation is successful when the new information is displayed in the byte-0 and byte-1 indicators. This key is effective cnly when the use-meter key switch is in the CE position.

#### 1.18.5.5 Printer-Keyboard Alter/Display

Although this key is available for customer use, it is used in maintenance strategy to control certain phases on the 1052 diagnostics.

#### 1.18.6 MODE SWITCH

Only switch positions that are unique to the Model 25 maintenance strategy are described here. Refer to the <u>Model 25</u> <u>FETOM</u>, Form Y24-3527 for complete information.

#### 1.18.6.1 Main Storage Address Stop

With the switch in MS ADR STOP position, the machine stops at the completion of the microword in progress when the address in switches A, B, C, and D matches the address of the core-storage location being accessed. The address-match indicator turns on. Byte-0 and byte-1 indicators display the address of the position of memory that was just accessed. The match occurs for addresses that specify either program or control storage.

#### 1.18.7 DIAGNOSTIC CONTROL SWITCH

### 1.18.7.1 Stop

When the switch is in this position and no hubs are wired on the CE back panel, the system stops every cycle. When a circuitry line is wired to the COND IN hub on the CE back panel, the system stops every cycle in which the line goes positive.

#### 1.18.7.2 Trap

This position forces a trap to the CE trap area of control storage. With the diagnostic control switch in the trap position and either (1) no wiring to the CE panel. or (2) a positive pulse to the IN hub of the CE panel, the machine-check latch is set and a trap is taken to 0280. If priority is not established in the trap routine, the trap to 0280 is repeated every other cycle. The CE trap routine can be used to log information on the printer-keyboard.

## 1.18.7.3 Scan Storage

With the switch in this position, all core storage positions are read and regenerated. When the check control switch is in the stop position, a parity error on storage data or a storage address causes a hard stop.

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This switch position is also useful in displaying sequential storage locations when used with the mode switch in either the MS DATA or AS DATA position. With the  $\pi$ cde switch in one of these positions, byte-0 and byte 1 indicators display the addressed location each time the start key is pressed.

#### 1.18.7.4 Single Address MS

This position permits the CE to scan a single storage address set in switches A, E, C, and D by pressing the control address set key and then the start key.

## 1.18.7.5 Single Address AS

This position permits the CE to repeatedly access a single auxiliary-storage location set in switches A, B, C, and D by pressing the control address set key and then the start key.

## 1.18.7.6 Test Fattern

This switch position is used to exercise core storage with data set in switches A, E, C, and D. Switches A and E should contain the complement of switches C and D; i.e., ABCD = FF00, 00FF, 01FE, or FE01.

The system must be placed in CE mode by the CE key for the test pattern position of the diagnostic control switch to be effective.

Each storage address is accessed four times before a +2 address update occurs. During these four accesses a readcut, store, readout, and store sequence is performed as follows (ABCD = FF00).

<u>Addr</u>	<u>Cycle</u>	<u>Creration</u>	Data	
0000	1	Readout	Unknown	(1st time)
	2	Store (AB)	FFFF	
	3	Readout	FFFF	
	4	Store (CD)	0000	

0002 Same as address 0000.

0004	1	Readout	Unknown (1st time)
	2	Store (CD)	0000
	3	Readout	0000
	4	Store (AB)	FFFF

0006 Same as address 0004.

This pattern continues for the first 256 bytes of storage and reverses every 256 bytes.

Addr	Cycle	Operation	Data		
0100	1	Readout	Unknown	<b>(</b> 1st	time)
	2	Store (CD)	0000		
	3	Readout	0000		
	4	Store (AB)	FFFF		

0102 Same as address 0100.

0104	1	Readout	Unknown	(1st time)
	2	Store (AB)	FFFF	
	3	Readout	FFFF	
	4	Store (CD)	0000	

0106 Same as address 0104.

This process continues for each program, control, and auxiliary storage location. The resident CSL area of control storage is read out and regenerated only.

#### 1.18.7.7 Load Program Storage

When the switch is in this position, the data in switches A, B, C, and D is loaded into every halfword of program storage. When the control storage area of memory is reached, the locations are accessed in sequence, but the store lines are not activated. A storage scan should follow the load program storage to determine if the data is stored properly.

## 1.18.7.8 Load Storage

This function is similar to the load program storage operation except that <u>all</u> core-storage locations (program, control, and auxiliary, except the resident CSI area) are loaded with the data set from switches A, B, C, and D.

The system must be put in CE mode with the CE key for the load storage position of the diagnostic control switch to be effective.

To store into the CSL area, set the mode switch to MS DATA. The data switches can then be stored into the CSL area in single cycle.

#### 1.19 MAINTENANCE PROGRAMS

The maintenance program package is designed to validate system and unit operation rapidly with a minimum of human intervention. The package is designed to progress from basic CPU-assurance microdiagnostics up through a system environment macrodiagnostic designed to exercise and test a majority of the system in a total system environment. The package provides failing-card locating information of high resolution for rapid repair. Refer to <u>2025 FEMDM</u>, Form Y24-3529, page 1-1.

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## 1.19.1 MACHINE LEVEL CONTROL (MLC) AND ENGINEERING CHANGES (EC'S)

Reloadable control storage is the unique Mcdel 25 concept which requires definition under this objective. All IBM-surported Mcdel 25 microprograms are provided with microprogram listings and punched-card decks. The listings and decks are generated by MAS (Microprogram Automated System). MAS has the capability cf producing customized listings and decks on machine-feature sensitive microprograms.

## 1.19.1.1 FIELD MICROPROGRAM CHANGES

Field microprogram changes are released by Field B/M's and utilize existing Field B/M control procedures. These changes are accomplished with replacement core loads (in card form) and lists. The foregoing arrlies to all IBM-supported emulator and microdiagnostic microprograms.

#### 1.19.2 FIELD CHANGE EXCEPTIONS

The following exceptions exist relative to field changes to any machine-feature sensitive microprogram core load.

- MLC determines field machine requirement for changed microprograms (core load decks and lists).
- MLC requires field machine-feature history information to achieve (1) above.
- 3. Field B/M's of microprogram emulators cannot be prepackaged.

## 1.19.3 UNIQUE CONSIDERATIONS

Unique FE responsibilities fcr field installation of a 2025 microprogram change are:

- Changes to microdiagnostic programs are applied to FE tapes or disks when the M25 diagnostic program package is maintained in either form in addition to card decks. Tape and file utility programs, FOFF and FOFE, are used for such updates.
- Changes to emulator microprograms are installed by replacement of the IBM-maintained customer emulator core load decks. The customer will be notified that affected customer duplicated emulator core loads should be updated.
- 3. On emulator microprogram changes the CE loads appropriate EC level identification into a CSL protected area of control storage. This enables checking for emulation EC level and machine EC level compatibility on CSL.

Check all microprogramming temporary fixes (MPTF) to ensure that they are incorporated in the current EC. Any missing MPTF must be added to the core load deck and recorded on the list before the customer is given the new deck. It is also necessary to alter the checksum in control storage for the emulator affected.

## 1.20 MULTISYSTEM CONFIGURATION

The Model 25 cannot be the host processor, but can be a supplement in a configuration controlled by a larger system having the channel-to-channel adapter feature. The direct control and external interruption features are provided on the Model 25 for the necessary intersystem data and control lines.

No unique maintenance features are provided or required on the Model 25 when it is operated in a multisystem environment.

## <u>4.21\_1401/1460 AND 1440 COMPATIBILITY</u> FEATURES

These special features are implemented almost entirely by microprogramming. The maintainability plan for this mode of operation assumes that the CPU, circuitry for integrated I/O attachments, and the standard I/O interface will be tested by the Model 25 diagnostic routines (resident and nonresident microdiagnostics, and the System/360 macrodiagnostic tests). No special 1400 compatibility diagnostic or function tests are provided for these features, and no special tools or test equipment are required.

The 1401/1460 and 1440 compatibility microprograms incorporate the following maintenance features.

- Resident CPU microdiagnostic (BDIA) and checksum tests,
- FE trap (64 bytes beginning at control-storage address 0280),
- Resident card-reader microdiagnostic (when the card reader is the only input device),
- Machine-check trap and 1052 logout, and
- 1052 alter/display.

The minor additional circuitry required for 1400-mode operation of 2311 and 2540 devices is tested using the microdiagnostics for these attachment features. The 1400-mode test in the CPU nonresident diagnostic must be initiated by a control address to the starting address of routine S14H in the diagnostic.

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#### 1.22 MODEL 20 MODE FEATURE

The Model 20 mode feature is implemented almost entirely by microprograms. It uses the normal Model 25 CPU hardware and I/O devices, except for the 2560 MFCM attachment feature that can be added specifically for Model 20 mode operations when required.

The maintainability plan for this mode assumes that the CFU and all I/O devices (except the 2560) are tested by the Model 25 diagnostics (resident and nonresident microdiagnostics, and the System/360 macrodiagnostic tests). The 2560 attachment is tested by nonresident microdiagnostics, and the 2560 is tested by Impulse Check Routines (ICRs) and Mcdel 20 Machine Function Tests (MFTs). Refer to 2025 MDM, Form Y24-3529, page 1-1.

The Model 20 Mode feature microprograms incorporate the following maintenance features.

- Resident CPU microdiagnostic (BDIA) and checksum tests,
- FE trap (64 bytes beginning at control-storage address 0280),
- Resident card-reader microdiagnostic (when the card reader is the cnly input device).
- Machine-check trap and 1052 lcgcut, and 1052 alter/display.

Operation of these maintenance features under Mcdel 20 Mode is the same as for the basic 2025 except for machine check trap, which is described in the following section.

## 1.22.1 MACHINE-CHECK TRAP AND 1052 LOGOUT

With the check control switch set to PROCESS, detection of machine check will cause a machine-check trap to be taken. This microprogram stores status information in a part of the protected first 144 bytes of program storage. This logout area is also printed out on the 1052 printer-keyboard. The format of the logout is identical to that presented for Model 25 mcde operation, and operation is similar except that after the logout, the machine stops instead of initiating an interrupt. (See Sections 1.17.1.1 and 1.17.1.2.)

#### 1.22.2 DIAGNOSE INSTRUCTION

The Diagnose instruction (Op-code 83) is provided for use with the ICR and machine function tests. This instruction can perform several functions as specified by the D1 field of the instruction. Fcr example, it is used to store the contents

of the six diagnose op switches (auxiliary storage locations 00FC through 00FE) into program storage at locations OOFC through OOFE.

The diagnose instruction permits a diagnostic program to use special diagnostic microprogram routines in conjunction with normal machine instructions. A complete description of diagnose actions is given in the 2560 test descriptions, ID001 in Vol. 44.

#### 1.22.3 CE TRAP

With the diagnostic control switch in the trap position, and any desired signal wired into the CE test panel, a microprogram trap is entered when the chosen signal goes positive. This function is the same for Model 20 mode as it is for Model 25 mode.

#### 1.22.4 CE TEST PANEL HUES

The function of the CE test-panel hubs (sync, switching, and match) is the same for Model 20 and Model 25 mcdes (see Section 1.23).

#### 1.22.5 CE DISPLAY CABLE

This pluggable service aid provides similar information on the Model 25 operating in Model 20 mode as is provided on the Model 20 system. The 2560 attachment feature pluggable display charts are included in the publication, Model 25 External Field Definitions, Form 229-2176, available with the CPU.

#### 1.22.6 PROGRAMMING ERRORS

Programming errors, such as invalid op-code, addressing error, specification error, etc., are detected by microprogramming during execution of the instruction. On the Model 20, such errors are indicated by stopping the system and displaying an error code in the I-register. However, when in Model 20 mode on the Model 25, the error code is printed on the 1052 to provide a corresponding identification of the error. See MDM 5-604 for a summary of error codes.

1.22.7 LOCAL STORAGE ZONE AND EXTERNAL MODE FOR 2560

In 2020 mode (mode register bit 1 on), 2311 data operations cannot cverlap other operations. Therefore, local storage zone 1 is shared by the 2311 and 2560. External

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TEST	GND	1403	PCH	RDR	FILE	1	2	3	+OUT	-OUT	GATE	OUT	IN
0	о	о	о	0	0	ο	о	0	0	0	о	о	ο
SYNC							AND		İ	MA	тсн	COND	

Figure 1-122. CE Panel

mode 6 and local storage zone 1 are assigned for use with the 2560.

For local storage zone 1 to be altered cr displayed when it is being used for a 2560 operation, switch C must be set at the label 2311. External mode for 2560 can be altered or displayed by setting switch C to the label 2560.

#### 1.23 CE PANEL

The CE test panel (Figure 1-122) is located on the A-gate back panel between boards C1 and C2.

Some of the uses of the the panel are to provide:

- 1. Sync points for scoping.
- An AND function for various diagnostic purposes (scope sync, monitor, etc.).
- 3. Capability to stop the system under CE-selected conditions.
- Capability to stop the system under CE-selected conditions,
- 4. Capability to trap into a reserved microprogram area under CE-selected conditions.

The plugs will accept either a banana plug connector or a kare wire.

The sync portion of the CE test panel has the following meanings.

TEST: This lamp is provided to check status of latches, etc. A +3V input to A2E6B12 turns the lamp on. GND (Ground): This plug is provided to reduce kreakage of D08 pins. 1403: +3V print control RDR: +3V reader clutch PCH: +3V punch clutch FILE: +3V share cycle.

The AND huls provide a 3-way positive input AND circuit with both plus and minus outputs when the three inputs are positive. Input lines (1-IN, 2-IN, 3-IN) float positive when not plugged to a signal. The functions of the hubs are:

<u>1 IN</u>: Input to 3-way positive AND <u>2 IN</u>: Input to 3-way positive AND

#### <u>3 IN</u>: Input to 3-way positive AND <u>+CUT</u>: Positive AND plus output <u>-CUT</u>: Positive AND minus output.

The MATCH OUT hub is positive at T7 time when the storage-address register contents match the setting of the console address switches, and the MATCH GATE hub is positive. Because the address match circuits are sampled at T7, the MATCH GATE input must occur before T7.

A positive pulse to the COND IN hub causes either a stop or a trap depending on the setting of the diagnostic control switch.

#### 1.23.1 STOP POSITION

A positive input pulse will stop the clock and cause a hard stop.

## 1.23.2 TRAP POSITION

A positive input pulse will stop the clock and cause a trap to control-storage address 0280. A 64-byte area starting at address 0280 is reserved for CE microprograms.

This area allows the CE to enter microprograms for diagnosing unusual or intermittent failures that do not respond to the primary microdiagnostic maintenance strategy. If desired, a monitor microprogram can be created and executed without affecting the customer problem program.

The system stops every cycle if the diagnostic control switch is placed in either stop or trap positions without the CCND IN hub being wired.

#### 1.24 POWER AND COOLING

1.24.1 FAILURE DETECTION, INDICATION, AND ISOLATION

The power system on the Model 25 features comprehensive circuit protection and failure detection facilities. Each dc power supply has an overcurrent-sensing circuit breaker. An overcurrent condition on any supply causes the associated circuit breaker on that supply to trip mechanically, and the CB-trip light to turn on (light DS1 on the power control chassis). The power-check light on the system console turns on, and a normal power-off sequence occurs. Certain key power supplies have direct overvoltage detection. These are PS-1 (-6), PS-3 (-12), PS-8 (+12), PS-10 (+6), and PS-11 (+6). Detection of an overvoltage condition in these supplies causes the CB for the respective supply to trip, and the power-off sequence to occur as described previously.

A voltage-sensing system determines that all dc voltages are on and are supplying at least a certain minimum output. Failure in any dc supply causes power to be sequenced off and the power-check light on the system console to be turned on.

Thermal sensing switches are provided on logic gates, core storage, and power supply areas. When any of these thermal switches senses a temperature in excess cf its specified limit, a normal power-off sequence is initiated and a thermal trip light on the power control chassis is turned on. The thermal trip prevents subsequent power-on sequence until the condition that caused the thermal trip is corrected and the thermal-trip reset switch on the power control chassis is actuated.

A power system diagnostic strategy has been developed based on the power supply failure detection system. This strategy consists of a guided step-by-step evaluation of the power system based on visual indications to isolate power system failures. To this end, a series of power system diagnostic strategy diagrams have been developed. These are included in the first part of the FE maintenance diagram manual for ready access by the customer engineer.

#### 1.24.2 COOLING FACILITIES

Ccoling facilities for the Model 25 consist of a number of blowers that force air past the component parts. There are three blowers for the power supply tower, three blowers for each SLT gate, three blowers for each core storage unit, and one blower for the 1403 hammer driver board. Each blower pulls air through an air filter to minimize dust accumulation. Warmed air exits through the grille at the top of the Model 25. 1.24.3 WARM-UP

The core storage units are the only devices in the Model 25 requiring a warm-up period. The temperature of these units must be maintained at from 96F±5F (35.6C±2.8C) to 120F±3F (49C±1.7C). If the temperature is below the limit, the low temp light on the system console turns on. If this light is on, correct operation of the core storage unit is not guaranteed. If the temperature is above the limit, a normal power-off sequence occurs and the thermal trip light on the power control chassis turns on. Thermal trip prevents subsequent power-on sequence until the condition that caused the thermal trip is corrected and the thermal trip reset switch is actuated.

Core storage temperature is controlled by maintaining the array inlet temperature at 105F±3F (40.4C±1.7C). An SCR-controlled heating element provides the necessary heat. After initial adjustment, the temperature is monitored by a thermistor in the array inlet air stream. The thermistor controls the SCR that supplies power to the heating element. The warm-up period varies depending upon the ambient temperature when the Model 25 power is turned on. Generally, the warm-up period takes about two minutes.

#### 1.24.4 CONVENIENCE OUTLETS

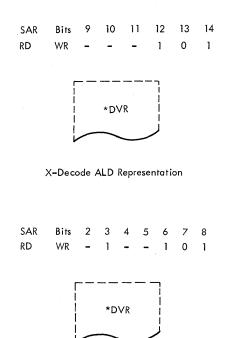
Two convenience outlets provide 115 volts 60 Hz, single phase at a maximum of 15 amperes (200, 220, or 235 volts at 8 amperes for 50 Hz). For 60 Hz machines, an isolation transformer provides the correct voltage. For 50 Hz machines, the convenience outlets are powered either from the line or the adapticn autotransformer.

A pair of convenience outlets are mounted on each side of the power supply tower to minimize the necessity for using extension cords.

#### 1.25 MAIN STORAGE DIAGNOSTIC AIDS

1.25.1 X AND Y DECODE NUMBERING SCHEME

The numbering scheme used to identify the X and Y decode drivers makes it possible to identify the active circuit by knowing which bits are present in the storage address register. See Figure 1-123.



Y-Decode ALD Representation

#### Figure 1-123. X and Y Decode Drivers

<u>X-Decode</u>: The X-decode drivers use storage address register bits 1 and 9 to 14. Three symbols are used in the ALDs to show the conditions necessary to activate a decode driver. They are:

- -: This bit is not used to control this driver.
- 1: This bit must be present in order to activate this driver.
- 0: This bit must not be present in order to activate this driver.

Therefore, the S-decode driver specified in Figure 1-118 is activated when bit 12 of the storage address register is on, bit 13 of SAR is off, and bit 14 of SAR is on. The status of bits 9, 10 and 11 will not affect this driver.

<u>Y-Decode</u>: The Y-decode drivers use SAR bits 2 to 8 and are shown in the ALDs in the same way as the X-decode drivers. Therefore, a Y-decode driver specified as in Figure 1-118 is activated when SAR bits 3 and 6 are on and bits 7 and 8 are off. Bits 2, 4 and 5 will not affect this driver.

#### 1.25.2 SCOPING STORAGE

Use an oscilloscope with a 25-tc 60nanoseccnd rise-time. The DuMont 766H the Tektronix\* 561 S and 453 are oscilloscopes that meet these specifications. Use the oscilloscope probe ground near the point being probed. Use read-call 01 C-B2A3D11 for an oscilloscope sync point.

## 1.25.2.1 Scoping X and Y Source-Terminating Resistors

When storage problems cannot be easily diagnosed from the console by card substitution, scoping the X and Y terminating resistors may provide information that will assist in locating the trouble. When a failure is common to a large block of storage and cannot be easily isolated to a particular X- or Y-line, scoping the X and Y terminating resistor, while using the Model 25 diagnostic scan functions (MDM starting at Diagram 1-100), may indicate where the trcuble might be found.

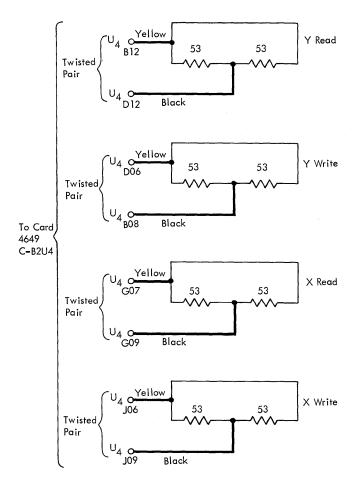
Because of SLT packaging, and because the array plugs into an SLT large board, a current probe can be used in very few places to check or observe the drive currents. However, all X and Y drive current comes from a group of four resistors, two for the X-lines (one for read and one for write) and similarly for the Y-lines. The resistors are mounted on the swing-open side of the store gate and are connected to the current sources via twisted wire cabling.

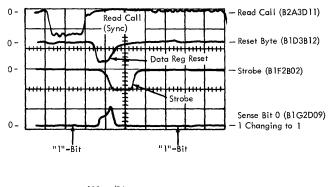
An indirect indication of array current is possible by monitoring any of the yellow wires (for example, the yellow wire to pin U4B12 for Y read current). If a current probe is available this can be done directly on the back panel, or alternatively with a voltage probe always on the yellow side connection of the resistors; the latter method will require the opening of the resistor gate (Figure 1-124).

Figures 1-125 through 1-130 show the waveforms for main storage control and drive lines during a specific condition. A variety of situations is represented by these oscilloscope photographs. Because these waveforms will occur only when a specific address cr group of addresses is accessed, they will be mixed in with many correct waveforms. Under these conditions they can be difficult to distinguish from incorrect patterns. An attempt should be made to locate the failing address(es) and put the 2025 into an address loop while scoping is performed. Refer to <u>Chapter 2</u>.

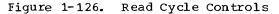
\* Trademark of Tektronix, Inc.

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100 ns/Div. 2V/cm



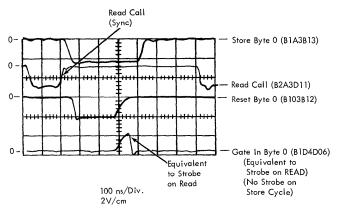
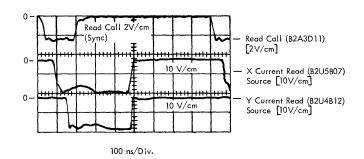
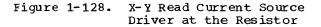
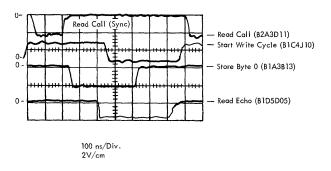


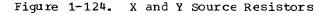
Figure 1-127. Store Cycle Controls



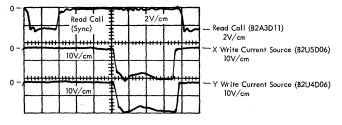


NOTE: All the black wires are grounded in card 4649, pins D12, 808, G09, J09 being internally grounded. Some machines have yellow wire grounded.









100 ns/Div.

Figure 1-129. X-Y Write Current at Resistors for looping and scanning procedures.

#### 1.25.2.2 Scoping Inhibit Drive Terminating Resistors

Inhibit drive current can be checked in the same way as read or write currents by probing the current-limiting resistors associated with each inhibit driver.

The Z inhibit driver source is essentially two NPN transistors in parallel, each transistor having a 70-ohm wire-wound resistor in series with the emitter. These resistors are mounted on the swing-open side of the BSM gate. The black and red wires are returned to the Z driver card. The yellow wire is common -30V. A pair of resistors is, therefore, common to each particular bit position and is also common to the 0-8K segment A and B, and 8-16K segment A and B.

The current probe can be used on the yellow wire, and the voltage probe at the red or black side of the resistors. The resulting waveforms of a correct inhibit driver are shown in Figure 1-130.

Approximately 760 mA is shared between the 70-ohm resistors (380 mA through each). The voltage swing should be approximately 26V at the read and black wire side of the resistors.

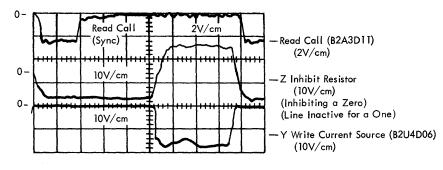
Substitution of the sense amplifier/Z power card can determine the failing location.

### 1.25.2.3 Array Sense Line Checking

Two methods may be used for checking array sense/inhibit lines.

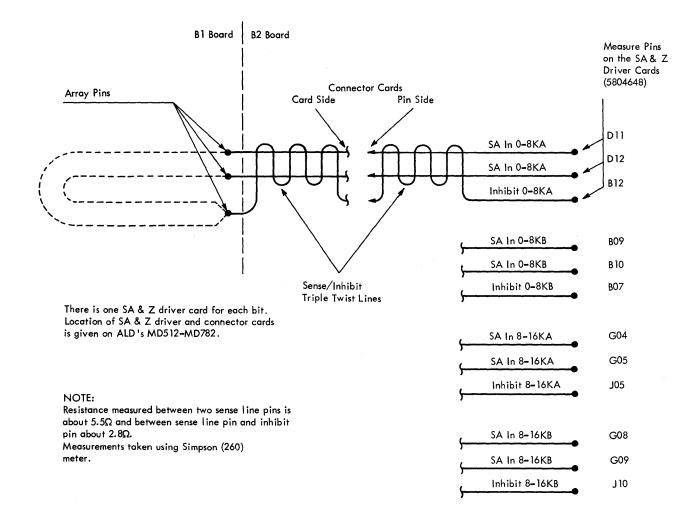
Figure 1-131 identifies the method to be used with the array plugged to the main storage SLT board. It is possible to meter the connections between sense line input pins and the inhibit line pin.

Figure 1-132 identifies the method to be used with the array removed from the machine. (The removal procedure is described in <u>Chapter 4</u> of this manual.)



100 ns/Div.

Figure 1-130. Z-Inhibit Driver (Writing a Zero)



## Figure 1-131. Main Storage Array Measurements

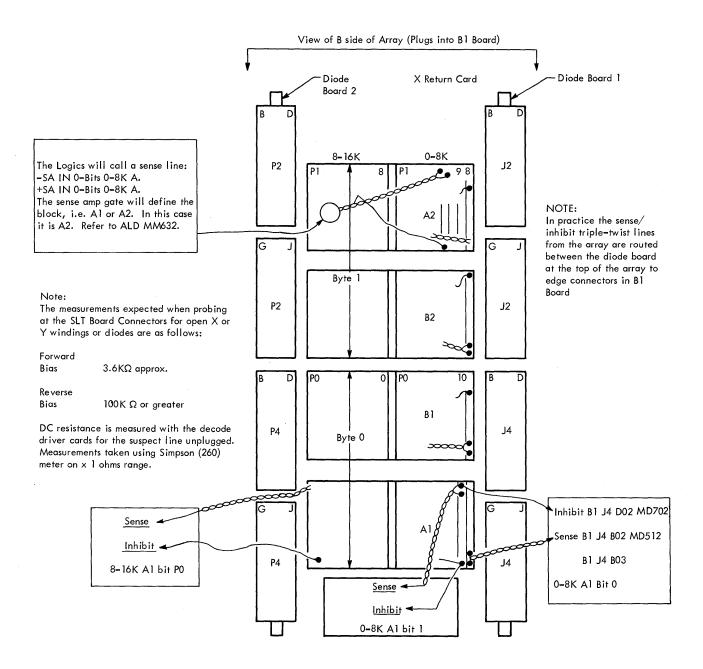


Figure 1-132. Main Storage Array Line Measurements

## 1.25.2.4 Array X and Y Drive Line Checking

With the aid of MDM 4-27 (Part 4 cf 5) and ALD pages MD860-MD891, any of the 136 Y-array wires or the 128 X (sections 0-8K cr 8-16K) array wires can be ascertained.

SAR bits 2-8 select the Y-lines (SAR bit 8 being the least significant). SAR bits 9-14 select the X-lines (SAR bit 14 being the least significant). SAR bit 1 selects the 0-8K or 8-16K section of the array; the 8-16K section is selected when bit 1 is a 1. SAR bit 15 is ignored.

The following example illustrates checking the continuity of any array drive line without first having to unplug the array.

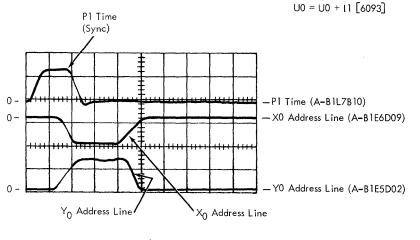
If an open Y-drive line is suspected, determine SAR bits 2-8. If, for example, they are 1011111, then reference to MDM 4-27 (Part 4 of 5) shows the Y-drive line to be 138, C-side. This particular drive line can be traced to storage logic pages MD412 and MD452.

The continuity of array drive line 138 is checked by placing the leads of an ohrmeter between C-B2E2J02 and C-B2S2J04. The forward resistance is usually between 3.6 kilohms and 4.0 kilohms (that is, two array diodes in series). The dc resistance of the array line itself is approximately 12 ohms. The reverse resistance is normally greater than 100K ohms.

The X-lines have forward resistance of 3.6 kilohms, which is measured with the 5808198 cards still plugged in. The forward resistance is similar to that of any Y-line when these cards are removed.

#### 1.26 LOCAL STORAGE DIAGNOSTIC AIDS

Figures 1-133 through 1-141 show the waveforms for local storage (LS). Figures 1-140 and 1-141 show <u>bad</u> waveforms.



40 ns/Div. 2 Volts/cm

Figure 1-133. LS-Addressing (P1-Time Access)

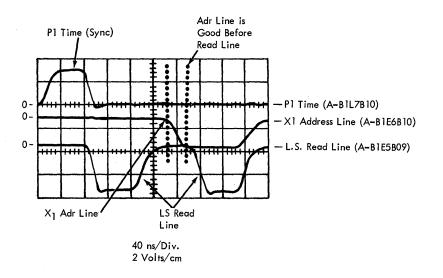
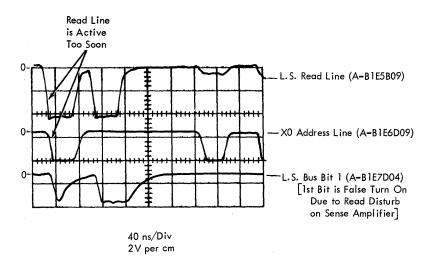
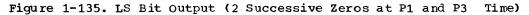


Figure 1-134. LS-Addressing (P3-Time Relationship Between X and Read Line)





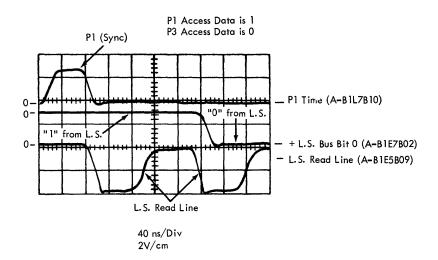


Figure 1-136. LS Bit Output (P1 Access Data is 1, P3 Access Data is 0)

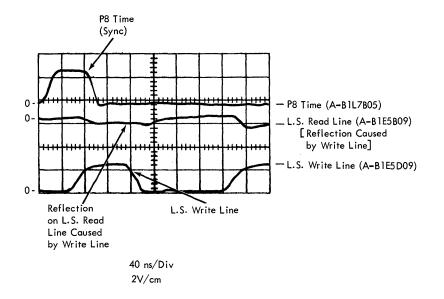
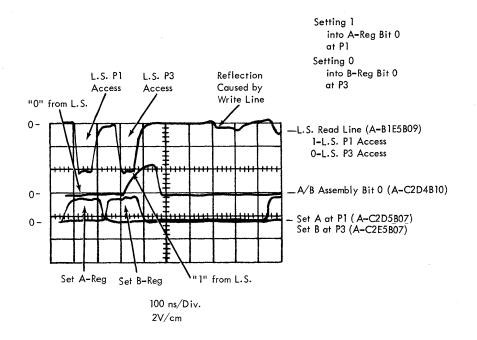
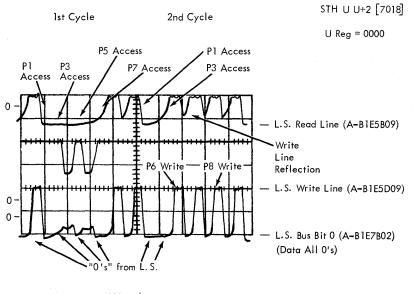


Figure 1-137. LS Write Line (P8-Time)

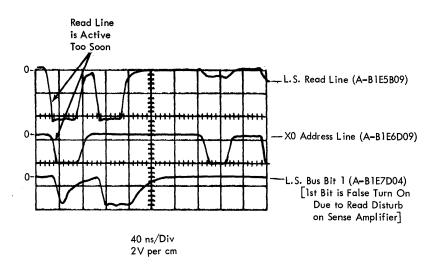


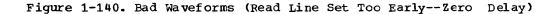




200 us/Div

Figure 1-139. Storage Word (WT-2)





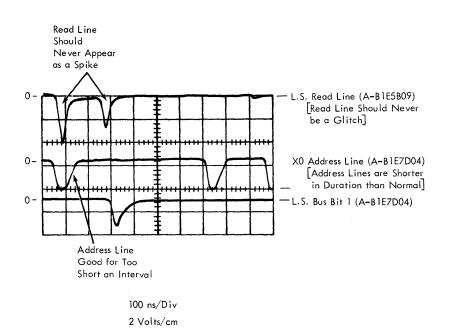


Figure 1-141. Bad Waveforms (LS Address Line Reset Delay Bad--Zero Delay)

# Section 1. Basic Unit

## 2.1 STORAGE PROTECT KEY--DISPLAY

For the storage key to be displayed, the M-register must be set to the 2,048 bytes associated with the CPU storage key. For the protect key associated with an MPX UCW or ICA UCW to be displayed, the M-register must be set to the UCW auxiliary storage address. Therefore, a manual display of auxiliary storage must be done to see the protect key used by an SIC; a manual display of main storage must be done to see the CPU storage key.

After the manual display, turn the mode switch to AIU/EXT position and dial switches CD to 03 (CPU mode external decode 3). Pressing the display switch gates the storage key into byte 1.

The selector channel key can be displayed by using auxiliary storage address XX88 and following the preceding display procedure. This is possible since MPX UCWs cannot be used when channel burst mode is defined.

There are two exceptions to this display procedure. The M-register does not have to be set up to display the effective file protect key. This is possible because the file key is stored in hardware (not STP local storage). To display the effective file protect key, dial 12 in switch CD and dial ALU/FXT.

To check the protect key associated with the integrated 2540, 1403, or 1052 UCW, refer to the auxiliary storage map for module 0 to determine which byte to display. During data transfer, the protect key is stored with the storage key read from STP local storage.

#### 2.2 PATCH CARD GENERATICN

This procedure can be used to make a patch card for entering a microprogram into the FE trap area. The system must have the System/360 emulator loaded. Enter the following data into the locations specified, make the punch ready, set IC to 0058, press the start key. The replace Card will punch in EBCDIC format. This replace card can be inserted before the end card of a CSL deck or you can make up a standalone deck in the following manner. 1. Five card loader

- Four cards from the 360 emulator CSL deck for CS module addresses 0100, 0140, 0180, 01C0 (card numbers 6, 7, 8, and 9)
- 3. The replace card
- 4. The end card, blank in column 3.

If the loading device is on the channel, use the following.

- 1. One-card channel loader
- Four cards from 360 CSL deck addresses: 0100, 0140, 0180, 0100 (card numbers 6, 7, 8, and 9).
- 3. The replace card
- 4. The end card, blank in column 3.

0048-00000 0050 CAW 004C-00000 0000 Spacer to align boundary 0050-0100 0068 2000 0050 CCW, punch 0058-9D00 000D Test I/O clear status 005C-4770 0058 Wait for clear status 0060-9C00 000D Start I/O punch 0064-47F0 0064 Wait 0068-0280 FE trap address 006A-10 10 Cntrl, 20 Aux, 80 PGM No. of halfwords to enter 006B-20 hex006C-xxxx xxxx --etc. Ctrl words up to 128 hex chars

#### 2.3 DEBE-2

Load DEBE-2 from a card reader. When the machine goes to wait state, press the interrupt key. DEBE-2 types out ENTER PROG ID - XX. The correct response to this message is listed as follows.

- CCSPACE Card-to-card 80/80 using units 00C and 00D.
- CPSPACE Card-to-printer 80/80 BCD units 00C and 00E.
- CTSPACE and-to-tape 80/80 using 00C as the card reader. A request will be typed for a tape address.
- TCSPACE Tape-to-card 80/80 using 00D for the card punch. A request will be typed for a tape address.

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TESPACE	Tape display) tape-to-printer hex,
	using OOE for the printer. A
	request will be typed for a tape address.
TPSPACE	- · · · · · · · · · · · · · · · · · · ·
	the printer. A request will be
	typed for a tape address.
TTSPACE	Tape-to-tape. Address will be
	requested.
WTSPACE	Write tape mark.
RWSPACE	Rewind tape. Address will be
	requested.
SRSPACE	-Space records on tape (forward)
	address and number of records to
	be skipped will be requested.
SFSPACE	Forward space file cn tape.

Address will be requested. BSSPACE Backspace records on tare. Address and number of records to backspace will be requested.

A request for a tape address is in the form MMXXX. The MM refers to the mode set command for 7-track tapes. Type 00 for 9-track tapes.

To put DEBE-2 onto a self-loading tape, change the last card of the DEBE-2 deck cclumn 8 to 12-8-4 punches, load the deck, and at IPL wait, alter storage locations 04A0 and 04A1 to the address of the tape drive you are using to build the DEBE tape. Then, press the interrupt key. DEBE-2 will load itself onto the tape. You may then load DEBE by loading directly from the tape.

DEBE CCW are as follows.

Reader CCW location	1 BE0
Punch CCW location	10F0
Print CCW location	1140
Tape in location	1228
Tape put CCW location	1318

Reader CCW	4200	1CF0	0000	0 0 5 0
Punch CCW	4100	1 CF0	0000	0050
Print CCW	0900	1D40	0000	0084
Tape read CCW		1 DC8		
Tape write CCW	0100	1DC 8	2000	0018

# 2.4 L/O EXERCISER ROUTINE WITH VARIABLE DELAY

This program loop will operate the reader or any I/C device at a repetition rate determined by the setting of console switches ABCD. Any value up to 7FFF may be used. This routine is useful when trying to duplicate intermittent I/O failures that seem to occur due to the time frequency at which the I/C device is operated. The channel and device address is in locations 0408-0409 and 0410-0411. The CCW command code is in location 0428. Eighty columns of data are read into or written from

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storage starting at location 0600. Start the program at 0400.

0400-D203	0048	0424	Move CAW
0406-9D00	000C		Test I/O reader
040A-4770	0406		Wait for clear status
040E-9C00	000C		Start I/O reader
0412-8300	0 AD4		Store switches ABCD in
			0410
0416-0000			Locations for switch
			bytes
0418-4820	0416		Store switch amount in
			reg 2
041C-4620	041C		Branch on count reg 2
0420-47F0	0406		Branch to read next
			card
0424-0000	0428		Spare CAW
0428-0200	0600		-
2000 00	50		CCW read and feed

#### 2.5 CONSOLE INQUIRY PROGRAM

Load the program using the console alter/display routine. Set IC to 0424 and press start. The system will enter wait state. Press the request key. The proceed light should come on. Key in up to eighty characters. Press EOB and ALT if less than eighty characters. The information entered should be typed back. The system will enter wait state. To repeat, press the request key etc.

TM attention on
BC SI/O if attention
BC enter wait
SI/O to console
BC CC is not zero
TI/O clear interrupt
BC branch busy
LPSW enter wait
BC wait lcop
Load CAW start here
Store CAW
Unconditional branch
CCW read inquiry
CCW write chained
PSW problem
Stored CAW
PSW I/O new

#### 2.6 1401 EMULATOR CSL DECK

This procedure can be used to make a system overlay card for entering auxiliary storage module 0 control data into the 1401 emulator CSL deck. The system must have the 360 emulator loaded. Enter the following data into the locations specified via the console alter/display routine. Make the punch ready, set IC to location 0058, and press the start key. The configuration card will be punched continuously in EBCDIC format. It should be inserted before the end card of the 1401 emulator CSL deck.

Note: When a blank is specified key 40:

0048-0000 0050	CAW
004C-0000 0000	Zeros to align boundary
0050-0100 0068	
2000 0050	CCW-punch
0058-9D00 000D	Test I/O clear status
005C-4770 0058	Wait for clear status
0060-9C00 000D	Start I/O punch
0064-47F0 0064	Wait
0068-7040*	<b>*9040</b> to be used on 24K
	systems
006A-20	20- Enter auxiliary
	storage
006B-1E	Number of halfwords to be
	entered
006C-XXXX XXXX	
etc.	Enter 120 hex characters

#### 2.7 1403 BUFFER LOAD MICROLOOP

This routine repetitively loads one buffer position with data.

- Manually set I/C to the desired buffer address.
- 2. Manually set T1 to the desired data character.

Hex Address	Hex Word	Statement
0280	2484	Set Mode K=8
0282	4F8F	PR=10
0284	2004	Set PRA K=20
0286	0000	No-Cp
0288	4BBF	PR0=T1
028A	8280	Br to 0280

#### 2.8 SOFT-STOP LOOP--SINGLE CYCLING

At present, the Model 25 does not allow an operator to single cycle through the scft-stcp loop. This happens because the start key resets the soft-stcp latch and the microlcop exits to I-cycle. This is corrected by blocking the reset of the scft-stop latch by the start switch with the diagnostic stop switch.

The procedure to allow single cycle and stay in the loop is to place the diagnostic switch in the stop position. Nothing can be wired to 'condition in' on the CE panel at this time. Exits such as integrated requests, instruction step printcut, etc., will be capable of taking the microprogram out of the soft-stop loop. If an I-cycle exit is desired, the operator must place the diagnostic switch tack to process position.

### 2.9 STCRAGE SCAN

An operator may be confused when scanning auxiliary storage if the diagnostic switch is in scan, load storage, or test pattern position. The storage unit ignores the second hex digit of the auxiliary storage address when auxiliary storage is addressed (0X00). In scan mode, advance the storage addresses by +2 each cycle. As a result, addresses 0000, 0100...0F00 access the same auxiliary storage location 0000. If one syncs on ADDR match or dces an AS ADDR stop on any auxiliary storage address, the machine will stop sixteen times because it accesses each location sixteen times.

#### 2.10 WORST-CASE STORAGE SCAN DEFINITION

The purpose of the test pattern switch is to scan memory and exercise it with a worst-case pattern. The pattern can be one of the following combinations and must be dialed in switches ABCD: FF00, 00FF, 01FE, FE01.

During the first scan, switch CD is stored in the first four-bytes of storage. AB in the next four bytes, and the pattern switches repetitively in this manner. This same pattern flips every 256 addresses (if ADDR 0000 has a FFFF stored in it, hex address 0100 will have 0000).

Each address of storage is accessed four times before a +2 address update occurs. During the first access, the contents of that location are read out. The second access stores the complement of that location in place of the original data. Then, this complement data is read out, and finally, its complement (the original data) is stored back.

For	Example:	ADDR 0000	2
1st	Cycle	Read Out	FEFE
2nd	Cycle	Store	0101
3rd	Cycle	Read Out	0101
4th	Cycle	Store	FEFE

This process continues for each address of main storage, auxiliary storage, and control storage. Only the protected area of control storage remains unchanged.

## 2.11 MS ADDRESS STOP PROCEDURE DURING IPL OR CSL

A condition exists when trying to MS-address stop during IPL and CSI because both the device address and the SAR stop address cannot be in switches ABCD. To bypass this condition, the following procedure should be followed.

	MS-Address Stop Procedure	Curr
During IPL - 1.	Set MCDE sw to MS ADDR STOP.	<u>PSW</u> Cond
2.	Set ABCD sw to CTRL STOR	Prog
	ADDR 0ADA.	Syst
3.	Press CONTRCL STORAGE LOAD.	CPU
4.	Press START.	N
5.	Set MCDE sw to Single Cycle Mode.	as f CC
6.	Set BCD sw to the Load Device Addr.	<u>CC</u> 0 1 2 3
7.	Press START sw three (3) times.	2 3
8.	Set MODE sw to MS ADDR STOP.	-
9.	Set ABCD sw to the desired MS Addr Location.	
10.	Press START.	<u>2.13</u>
During CSL - 1.	Set MCDE sw to Single Cycle Mode.	Cond
2.	Set ABCD sw to the Load Device Addr.	unit load
3.	Press CONTROL STORAGE LCAD.	
4.	Press START 3 times.	
5.	Set MODE sw to MS ADDR STOP.	2.13
6.	Set ABCD sw to the desired MS Addr location.	This fail
7.		the

## 2.12 PSW

#### 2.12.1 PSW RESTART

The function of the PSW restart switch is to perform a PSW restart; this means lcading the restart PSW from locations 0000-0007 of main storage (initial PSW).

## 2.12.1.1 Procedure

- 1. Press PSW RESTART.
- 2. Press SYSTEM RESET.
- 3. <u>Note</u>: In this case, it is not necessary to press the start key to begin program execution. If the system-reset switch is pressed without pressing the PSW restart switch, the current PSW will remain effective.

## 2.12.2 DISPLAY CF CURRENT PSW

The current PSW is displayed from local storage or auxiliary storage locations by setting switches A, B, C, and D, the mode switch as shown in the following, and by pressing the display key.

ent Mode Switches Field Switch A, B, C, & D PO ition code MOD/LS ram mask & AMWP MOD/LS 10,10 em mask AS Data 8A00 key and AMWP AS Data 00A9

Note: The condition code in P0 is coded s follows.

CC	<u>PO High</u>
0	0
1	5
2	2
3	7

#### 2.13 CONTROL STORAGE LOAD FAILURE DETECTION

<u>Conditions</u>: Loading from 2540 integrated unit, a single card at a time, any core load deck.

#### 2.13.1 DESCRIPTION

This test can be used to troubleshoot a failure to CSL, especially on systems where the 2540 is the only program load device. It tests the BCPL, BDIA, BCHK, BSYS, BPSW, and BSWI microprograms, the CSL latch, the reader start, feed, and the data transfer circuits. It also allows the CE to check the contents of the first bootstrap card that contains a microprogram to start the next bootstrap cards and the control program to load.

The BNSR routine is contained on the first two of the five native bootstrap cards. The native bootstrap routine (BNSR) is entered at address 0100 from either the handloaded native bootstrap routine, or the resident control storage load routine (BCPL). Card number one is loaded into control storage starting or the BCPL routine. Address 0100 is branched to and card number two is loaded into the addresses following those occupied by card number one (this data forms the BNSR routine). The information contained in cards number three, four, and five of the native bootstrap is loaded into auxiliary storage to form a translate table which is used to translate the remaining CSL deck into the hex characters that are to be loaded into the control storage area and certain auxiliary and program storage locations.

The CSL procedure, up to the first actual control storage card, is shown in MDM 5-19. The handload procedure is covered in the descriptive text preceding the BCPL routine.

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## 2.13.2 PRCCEDURE

- 1. Set switches A, B, C, and D to EEOC.
- 2. Press SYSTEM RESET.
- 3. Press CONTROL STORAGE LOAD (CSL) The CPU should be in a loop with the system light on. If this does not occur, it indicates a failure in the permanent CSL routine.

Make certain that the CSL light is on. It may be necessary to restart in single-cycle mode to determine that the permanent CSL microprogram does not contain errors and that it correctly executes each statement.

- 4. Set switches A, B, C, and D to 407A (807A for 24K, 807A for 32K, C07A for 48K).
- 5. Set the mode switch to AS AER STOP.
- 6. Place the core load deck in the reader and press the reader start key. The reader will feed one card and stop with the address match light cn.
- 7. Press the CPU start key and a second card should feed.
- At this time, the first bootstrap card has been read at first read. The contents of this card should now be stored in control storage locations 4100 to 4177 as follows.

9	Row	0100-CC05	2040	2F53	3CC 9	2D 07
8	Row	010A-4606	5eef	DE0 C	5 A 9 F	5360
7	Row	0114-6931	C496	5B 3F	F020	6348
6	Row	011E-8122	73C8	736 A	F08C	0 D 0 4
5	ROW	0128-2407	2D04	2E08	2FFF	C48A
4	Row	0132-5404	<b>7</b> F48	05FD	C4B4	4406
3	Row	013C-5469	2E63	2 E4 D	2F45	2F1B
2	Row	0146-8152	794A	FOFB	221D	F4D6
1	Row	0150-6EF3	2785	2265	5 EDF	DD56
0	Row	015A-5ADF	5B9F	6340	63D1	C4E2
11	ROW	0164-CA6D	FE77	5 ECE	8180	5ecd
12	Row	016E-1CFB	C4F8	2C 8 3	8180	817C

To check whether this card read correctly, set switches A, B, C, and D to address 4100 (8100 for 24K machine, 8100 for a 32K machine, C100 for a 48K machine), set the diagnostic control switch to SCAN STOR and the mode switch to MS DATA. Press CTRL ADR SET and then press the CPU start key. Each depression of the start key will cause the next consecutive halfword to be displayed. In this way it can be determined if the card reads correctly. A further depression of the start key should cause the remaining bootstrap cards and the control program to be read.

If the alter/display routine has not been disturted, display the bootstrap card on the PR-KB:

- Turn the mode switch to MS DATA (single cycle mode).
- 2. Press SYSTEM RESET (reset CSL).
- 3. Turn the mode switch to PROCESS.
- 4. Press PR-KB ALTER/DISPLAY.

5. Type DC 0100 on PR-KE (bootstrap card will be typed out on the PR-KB).

After the first feed cycle, the above read-in area should have all bits on in each byte. Because on the first feed cycle the card did not pass the first read brushes and nothing was read, all bits will be on (inverse logic). If all bits are not on at this time, it means not data was transferred.

### 2.13.3 READER CHECKS DURING CSL

If a reader check occurs during control storage load, it is not necessary to reload the whole CSL deck. Add the 5 bootstrap cards to the CSL deck prior to the card that caused the reader check and try to CSL again. In this way, it is possible to complete a CSL in increments on a reader that is giving intermittent reader checks.

## 2.14 CHECKSUM ROUTINE--BCHK

The checksum routine (BCHK), is entered upon completion of the resident CPU microdiagnostic (BDIA). These routines are executed whenever the CSL, system reset, or load keys are pressed.

The checksum routine performs an Exclusive OR on the contents of control storage with the exception of locations 0002-000D and 0280-02BF.

Locations 0002-000D contain the handloaded identification labels of the individual core loads. When a CSI operation is performed, an identification label is selected from this area and placed in location 0EC4 where it becomes part of the area that is subjected to the Exclusive Or result to be zero.

The handloaded labels are:

Address	Lakel
0002	*E60/*E61 (Model 25 mode)
0004	*E62
0006	*E63
8000	*E40 (1401/1460 mode)
A000	*E50 (1440 mode)
000C	*E20 (Model 25 mode).

#### 2.15 INITIALIZING PROCEDURE--CHECKSUM

Effective from the microprogram level EC128226 and later, the initialization procedure should be as follows.

#### Checksum:

A. Do hand load as per instruction in BCPL routine.

- B. CSL the emulator deck in CE mode.
- C. At the completion of CSL (when the CSL light goes out), the logcut should be:
  - 1. For \*E60 emulator: EC level

8226 0E60 0BAD 0000 8226 0E60 0BAD XXXX

XXXX = (OBAD) (YYYY)

where YYYY is the checksum printed on the first page of the associated listing as well as punched in columns 21-24 of the header card (first card) of the CSL deck.

Store the checksum YYYY into location 0002 of control storage.

2. For \*E40 emulator"

8226 0E60 0kad 0000 8226 0E60 0 ad XXXX 0000

Again XXXX should be the result of Exclusive ORing Obad and YYY, where YYYY is the checksum printed on the first page of the associated listing as well as punched in columns 21-24 of the header card (first card) of the CSL deck.

Store the checksum YYYY into location 0008 of control storage.

3. For \*E50 Emulator:

Same as Item 2 except that the second halfword of the first two lines of the logout should be 0E50 instead of 0E40 and the checksum YYYY should be stored in 000A instead of in 0008.

D For this procedure to be verified, the deck should be CSLed again and the following logout should occur (the same logout should occur from this point on whenever the deck is CSLed):

*E60		8226	0E60	YYYY	0000
*E40	+-	8226	0∈40	YYYY	0000
		0000			
<b>*</b> E50		8226	0e50	YYYY	0000
		0000			

- E. If the fourth halfword of the logout in Item D is nonzero when the logout occurs:
  - After the deck is CSLed, it indicates that either the CSL deck is kad (the actual checksum of the deck is different from YYYY), or YYYY might be entered erroneously.

 After the system reset or load button has been pressed with the XSL deck resident in core, it indicates either that the control storage has been altered or possibly a core storage failure.

## 2.16 SYSTEM CONFIGURATION--CSL

Nonstandard address of integrated attached devices or selector channel buffered devices:

A. For \*E60 emulator:

The CSL deck contains a set of standard addresses as defined in the AAAB routine (auxiliary storage module 0 assignment map).

A system configuration card is needed only when a system is using nonstandard addresses. Such a configuration card can be punched as per instruction in the BCPL routine and inserted in the CSL deck prior to the end card (last card of the deck with blank column 3).

B. For \*E40, \*E50 emulator:

Refer to <u>Appendix A</u> - system initializer card of the SRL manual of <u>IBM 1401/1460 and 1440 Compatibility</u> <u>Features</u>, Form A24-3512.

On every EC update of the CSL decks, it is important for the systems with configuration to have the system configuration card removed from the CSL decks being replaced, and inserted into the new decks.

C. Figure 2-1 shows the L/O devices having standard addresses.

DEVICE	STANDARD ADDRESS
1443 or 1445	0 B-84
2540 Reader	0C-85
2540 Punch	0D-86
1403	0E-87
1404 or 2nd 1403	0F-94
2540	15-95

Figure 2-1. Standard Address of Devices

#### 2.17 BCPL ROUTINE

The BCPL routine is normally resident in control storage, and is used to load the initial record of either the channel cr native bootstrap routines.

If the BCPI routine has been altered, the appropriate hand-load information must be entered to be sure of correct CSI operation. Switch settings for CSL:

Swit ches

A, B=CC CSI from channel A, B=DD CSL from integrated 2560 A, B=EE CSI from integrated 2540 A, B=FF CSL from integrated 2311 Switches C, D set to actual unit address

#### 2.17.1 PRCCEDURE FCR FUNCHING CSL CARDS

Refer to BCPI routine in \*E60 microprogram listing. Columns

- 1-2 Contain starting address to be loaded. Contains code information: Hex 80 = Data is for program storage. Hex 40 = Iast CSL card of deck. Hex 20 = Data is for auxiliary storage. Hex 10 = Data is for control Storage.
  4 Contains the number of halfwords to be loaded.
- 5-68 Contain the data.
- 69-72 Crtional, can be used for any information.
- 73-77 \*NNN9 (where N is core load ID).
  78-80 XXX (three digit number indicating sequence of patches).

#### WARNING

Do not punch cards to lcad into auxiliary module 1, 3, 4.

2.17.2 RESTRICTIONS WHEN PUNCHING CSL CARDS

Columns		
1-2	All addresses should be even:	
	Control Storage - These addresses should be in the range of 0000-3FFF only.	69-72 (e.g.
	Auxiliary Storage-The 2nd hex character in column 1 should be a zero.	73-77 (e.g.
	Program Storage - The address must be in the range of the system.	78-80 (e.g.
3	Coded information	
4	Count Field - If a count of 0 is indicated, 257 halfwords will be loaded.	A CSL m reconfigura reconfigura

5-68	Data Field - Can be anything.
69-72	Optional - Can be used for any
	information. Not used by CSL.

73-77 \*NNN9 (where N is core load ID; e.g., E60, 1C0, 300, etc.
78-80 XXX (three digit indicating sequence of patches).

When a full deck is being loaded with replace cards, the replace cards should go just before the end card. When loading replace cards only, it is necessary to put the control storage cards (normally 4) for module 01XX in the deck. Order of the cards is: bootstrap cards, control storage cards for module 01XX, replace cards, end card.

2.17.3 EXAMPLE OF PUNCHING AND LOADING A REPLACE CARD

Assume that the device address for the 1403 on the burst channel needed to be changed to -0A0.

The standard address for the 1403 on the burst channel is -0E- and is located in auxiliary storage module 0, at address -87-.

The card to change this would be punched in the following manner.

Column(s)

COlum	1(3)	
1	(Hex 00)	This addresses module 0.
2	(Hex 86)	Althcugh the change is
		for address 87, the hex
		address represented by
		column 2 must be even.
3	(Hex 20)	This indicates that
		information is for
		auxiliary storage.
4	(Hex 01)	This indicates one
		halfword to be loaded.
5	(Hex OD)	This represents the
		device address of the
		2540 gunch that must be
		reloaded because of the
		addressing restriction
		imposed by column 2.
6	(Hex OA)	This represents the
		device address replacing
		the standard address for
		the 1403 on the burst
		channel.
69-72	(e.g. 0086)	This indicates the
	5	beginning address of
		patch.
73-77	(e.g. *E609)	This indicates that
	<b>-</b>	patch is for *E60 core
		load.
78-80	(e.g. 0001)	This indicates the first
	···· <b>·</b> ·······	patch to the deck.

A CSL must be performed to load this reconfiguration card into the system. The reconfiguration card must precede the end card, and must be present in that position for all CSLs using that particular core load deck.

Each time a new EC level deck is received, all reconfiguration cards in the deck being replaced must be removed and inserted in front of the end card in the new deck.

#### 2.18 METERING SWITCH (CE SWITCH)

The metering switch enables operation of one of two use meters. It is operated by a removable key. Two positions of the metering switch are:

- 1. <u>Normal</u>. Enable process meter, disable CE meter.
- <u>CE</u>. Disable process meter, enable CE meter.

The 2025 console is provided with two direct-reading meter counters that record operating time: a customer meter and a customer engineer meter. The position of a key switch determines whether the customer meter or the CE meter is operating. The customer engineer holds the key for this switch, and when he is performing either scheduled or unscheduled maintenance in the PCU, he sets the switch to cause the CE meter to operate. Cne of these meters (determined by key switch setting) cperates when:

- The CPU clock is running and the CPU is not in the wait state, cr not in the soft-stop loop.
- 2. The metering-in signal is up on an I/O channel.
- 3. Any file is selected.

The last two conditions dc nct cause the meter to run if the hard-stop latch is set. The meter, when started, is forced to operate for a mininum of 400 milliseconds.

The system indicator is cn when either meter is running.

<u>Note</u>: The use-meter key switch must be in the CE position to permit any alteration of the contents of control storage.

#### 2.19 DISPLAY OPERATIONS

Any core-storage locations can be displayed from the system control panel. The position of the mode switch specifies the source of the information to be displayed, as follows.

	control storage, depending upon
	the address being used)
AS DATA	
MOD∕IS	Arithmetic modifier and local storage
ALU/EXT	Arithmetic-logic unit and external facilities
С	C-register (control register)
B/A	B-register and A-register (the inputs to ALU and core storage)
W	W-register (storage-address register backur register).

MS DATA Core storage (program storage or

Only those data-flow components the operator needs to display are discussed. Other functions of the mode switch (C, B/A, and W) are used by the customer engineer, as is the control-storage area of main storage.

#### 2.19.1 PROGRAM STORAGE DISPLAY

Press the stop key and wait until the manual light comes on. Set the mode switch to MS DATA. Set switches A, B, C, and D to the program-storage address to be displayed: for 16K systems, this address is from hexadecimal 0000 through 3FFF; for 24K systems, this is 0000-5FFF; for 32K systems, 0000-7FFF; and for 48K systems, 000-BFFF. Press the display key. The addressed halfword is displayed in the byte-0 and byte-1 indicators.

#### 2.19.2 CONTROL-STORAGE DISPLAY

This procedure is identical to the display of program storage except that switches A, B, C, and D are used to address a control-storage location. For 16K systems, this is hexadecimal 4000-7FFF; for 24K or 32K systems, 8000-BFFF; and for 48K systems, C0000-FFFF.

The procedure for displaying control storage is intended only for customer engineering use.

#### 2.19.3 AUXILIARY-STORAGE DISPLAY

Press the stop key and wait until the manual light comes on. Set the mode switch to AS DATA. Set switches A, C, and D to the auxiliary-storage address to be displayed. (Switch B is not used.) This address is from 0x00 through 7xFF for 16K systems; 0x00-5xFF and 8x00-BxFF for 24K systems; 0x00-BxFF for 32K systems, and 0x00-FxFF for 48K systems.

Normally, only the general and floating-point registers, and the MPX UCW areas of auxiliary storage, are displayed by the user.

#### 2.20 STCRE OPERATIONS

Information can be manually stored into any core-storage location. A halfword (two bytes) is always affected. If a single bytes is to be changed, the remainder of the halfword must be reentered. The store operation <u>must</u> be preceded by a display operation of the location to be altered.

For all store operations, the manual and the allow-manual lights must be cn.

Note: Storage into a control-storage location requires that the use-meter key switch he in the CE position.

#### 2.20.1 PROGRAM-STORAGE STORE

Tc alter the contents of a halfword in the program storage:

- 1. Set the mode switch to MS DATA.
- 2. Turn switches A, B, C, and D to the location to be altered.
- 3. Press the display key. The byte-0 and byte-1 indicators show the present contents of this halfword location.
- 4. Set the data halfword into switches A., B, C, and D. If only part of the halfword is to be changed, the unchanged portion must be included as part of the two bytes.
- 5. Press the store key. Th byte-0 and byte-1 lights indicate the new information that has been entered into

the location specified in step 2.6. Repeat steps 2 through 5 for each halfword to be changed.

#### 2.20.2 CONTROL-STORAGE STORE

This function is identical to the program storage store procedure, except that control-storage addresses are used, the use-meter key-switch must be in the CE position, and the enable control storage store key must be pressed.

#### 2.20.3 AUXILIARY-STORAGE STORE

To alter the contents of a halfword in auxiliary storage:

- 1. Set the mode switch tc AS DATA.
- Set switch A, C, and D to the address of the location. (Switch B is not used.)
- 3. Press the display key.
- 4. Enter the new data into switches A, B, C, and D.
- 5. Press the store key.
- Repeat steps 2 through 5 for each halfword to be changed.

Note: Except for changes to the general and floating-point registers and for customer engineering diagnostic purposes, undisturbed after it has been initialized using the CSL procedure.

# Section 1A. PR-KB Procedures

## 2.21 ADDRESSING, CONSOLE PRINTER-KEYBOARD

The integrated console printer-keybcard attachment is addressed as if it were connected to channel 0. The 16-bit address developed from the I/C instruction identifies the attachment and the printer-keyboard. The device address is nct limited by the usual channel-0 UCW addressing requirements because the attachment has its own UCW that is not device-address dependent. In theory, the printer-keybcard may have nay address from:

<u>Binar</u>	:y	Нех
	0000	00
to	C	to
1111	1111	$\mathbf{FF}$

In practice, the integrated PR-KB is assigned an address of 1F to standardize with other System/360 usage. This addressing makes use of one cf the channel-0 subchannel addresses and prevents its use for the channel. If channel configurations require use of the subchannel, the PR-KB address can be changed by the customer engineer.

Under no condition should an address assigned to any other I/O device be assigned to the console printer-keyboard.

2.22 PROGRAM-CONTROLLED OPERATIONS

2.22.1 CHANNEL CCMMANDS

\_ . .

Valid commands for PR-KB operations are:

Code Bits	
0123 4567	Command Name
0000 0001	Write
0000 0011	No-Op
0000 0100	Sense
000 <b>0 1</b> 000	TIC
0000 1001	Write with ACR
	(Automatic Carrier Return)
0000 1010	Read

Any command code (issued to PR-KB) with a bit structure other than those listed, results in unit-check status (bit 6) and command reject sense (bit 0) indications.

#### 2.23 CONSCLE PRINTER MANUAL ALTER/DISPLAY

This facility provides for altering or displaying the contents of:

- auxiliary storage
- control storage
- program storage
- print buffer (display only).

Two advantages provided by this facility are:

- Current I/O operations (data transfers and chaining) do not overrun, as they might if alter/display operations were initiated from the system console.
- The console printer provides a printed copy specifying the operation (alter or display), the locations(s) accessed, and the data used.

#### 2.23.1 SETUP

To initiate an alter or display operation, the operator must first press the PR-KB alter/display button (on the CPU console) and wait for the proceed light and the alter/display light to turn on. If the printer-keyboard is busy executing another operation, these lights do not turn on until that operation is ended.

When these lights turn on, the operator types a two-character sequence. Depending on the desired operation, these characters (called the operation characters) can be:

First Characters	Specifies
a d	alter creration display operation
G	aropraj oporatiron
<u>Second Character</u>	<u>Specifies</u>

a	auxiliary storage
С	<pre>*contrcl stcrage</pre>
р	program storage
b	**print buffer

\*Can be done only in CE mode.
\*\*Display only.

#### 2.23.2 ADDRESSING

Next, the operator must type an address for:

	Address Format
Area	(lowercase* hexadecimal)
auxiliary storage	XXXX
control storage	XXXX
program storage	XXXX

\*Uppercase characters can be used if they do not differ from the lowercase character.

The four-digit hexadecimal address for control storage is typed <u>as it appears</u> on the microprogram listing; i.e., 0000 through 3FFF only.

## 2.23.2.1 Execution of Alter or Display

After the operation character and address have been typed, the console printer advances to the keginning of a new line.

1. For a display operation:

- The keyboard is locked and printing begins starting with the contents of the specified address. After 16 hexadecimal digits (4 halfwords) have been printed, the console printer stops, the keyboard unlocks, and the proceed light turns on. At this point the operator has two choices:
  - a. Successive blocks of 4 halfwords can be printed by pressing the spacebar (or any other valid character) after each block is printed.
  - b. This particular pass of the alter/display routine can be terminated by pressing either the ECB key or cancel key. This causes a return to the beginning of the routine, allowing the operator to initiate another alter cr display operation.

2. For an alter operation:

The keybcard is unlocked and the data to be stored can be typed immediately. However, it is good practice to first verify the address in the typed input message.

## 2.23.2.2 End Operation

Either the ECB key or the cancel key (in conjunction with the alternate coding key) can be used to end an alter or display operation, except when the keyboard is locked during a display printout. Pressing either key causes a return to the beginning of the alter/display routine so that the operator can perform another display or alter operation.

An alter or display operation is normally ended by pressing the ECE key after the required data has been typed. If the cancel key is used to end an alter operation, the last character is stored only if it completes a byte. (This is explained later in this section.)

An exit is <u>not</u> made from the alter/display routine until:

- the ECB key or cancel key is operated to end the current alter or display operation; then
- 2. the CPU start key is pressed.

Therefore, the operator can perform as many alter and/or display operations as desired without exiting from the routine. Until the exit is accomplished, CPU instruction processing is stopped. CPU instruction processing is resumed when, after an exit is made from the alter/display routine, the start key on the CPU console is pressed.

During an alter operation, data is altered on a byte basis. For example, assume that the byte data to be entered is  $\underline{af}$ , but that the operator types  $\underline{sf}$  instead of  $\underline{af}$ . The characters  $\underline{sf}$  are stored. The operator must then press either the EOB or the cancel key to return to the beginning of the routine for a retry of the entire operation.

If the error is noticed before the  $\underline{f}$  is typed, the byte is not stored. If the cancel key is then operated (before the  $\underline{f}$ is entered), a return to the beginning of the routine is made, and the operation can be retired if desired. In either case, the entire manual operation must be repeated to store the <u>af</u>. If the operator types one too many characters (such as <u>aff</u> for the foregoing example), the operation is not repeated.

#### 2.24 MESSAGE FORMATS

The microprogram initiates a line feed and carrier return after sixteen halfwords have been printed on a line (fcr either alter or display). Data is column-justified, and blanks are provided between halfwords for either display or alter data. Also, the routine provides offsetting of two spaces at the left margin if an odd-starting address is specified for alter or display of main, auxiliary, or control storage (see following formats).

All input typing is lowercase (uppercase can be used if the uppercase character does not differ from the lowercase character). All output printing of hexadecimal alpha characters is in uppercase. In the following formats, x represents any valid hexadecimal digit.

#### 2.24.1 ALTER STORAGE

The second operation character can be  $\underline{a}$  (auxiliary),  $\underline{c}$  (Control), cr  $\underline{r}$  (program).

Note: Valid only if in CE mode.

Input message: aa xxxx Address-----+

Input data:

(odd address):	XX	XXXX XX (EOB)
(even addresses):	XXXX	XXXX XXXXXXXX
	XXXX	(EOB) t
Carrier rtn after	16th	halfwordJ

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#### 2.24.2 DISPLAY STORAGE

The second operation character can be <u>a</u> (auxiliary), <u>c</u> Control), cr <u>r</u> (program).

Input message: dp xxxx Address-----+

Output data: (odd address): xx xxxx xxxx xxxx

(even address): xxxx xxxx xxxx xxxx

## 2.25 ERRORS

The error message, INVALID CHAR, is printed if any one of the following operator errors is made.

1. An operation character is other than: First character: a or d Second character: a, c, p, or b

- 2. A character other than a valid hexadecimal digit is typed for an address or input alter data.
- A key other than EOB or cancel is operated while the alternate coding key is pressed.

A keybcard check causes a return to the beginning of the alter/display routine.

The error message, INVALID ADDR, is printed if the program, control, or auxiliary storage address is invalid for the system.

Note: Address checking is performed by the alter/display microprogram (not by storage-wrap checking circuits in the hardware).

The valid address boundaries for the various systems are as follows.

System size: 16K Program Storage Address Range: 0000-3FFF Control Storage Address Range\*: 0000-3FFF Auxiliary Storage Address Range: 0x00-7xFF

System Size: 24K Program Storage Address Range: C000-5FFF Control Storage Address Range\*: 0000-3FFF Auxiliary Storage Address Range: 0x00-5xFF and 8x00-ExFF

System Size: 32K Program Storage Address Range: 0000-7FFF Control Storage Address Range\*: 0000-3FFF Auxiliary Storage Address Range: 0x00-ExFF

System Size: 48K Program Storage Address Range: 0000-BFFF Control Storage Address Range\*: 0000-3FFF Auxiliary Storage Address Range: 0x00-FxFF \* The four-digit hexadecimal address for control storage is typed <u>as it appears</u> on the microprogram listing; i.e., 0000 through 3FFF.

The following are examples of the invalid-address error message.

- If the address typed in the input message is invalid, the error message is printed after the conscle printer advances to a new line.
  - Input message: dr 4000 Invalid address (16K)...t

Data: INVALID ADDR Error message...†

- Input message: aa 8000 Invalid address (16K)... f
- Data: INVALID ADDR Error message...†
- If an invalid address is encountered during the alter or display operation (such as storage wrap), the error message begins begins on the same line with the data.
  - Input message: ac 3FFE Assume 16K system......
  - Data: XXX INVAIID ADDR

Note: First two bytes are valid. Error message applies to addresses beyond this point.

Input message: dp 3FFF

Data: xx INVALID ADDR 2 blanks for odd addr.+

#### 2.26 LOGOUT

The PR-KB logout is a microprogram function that prints (in hexadecimal notation) the information area of program storage. This typeout is initiated for each machine check (when the machine-check mask bit is the current PSW, kit 13, is set to 1). Problem programs are not affected by this logout. The SEREP problem program is used to interpret and print information from the logout area (refer to Figure 1-116).

Subsequent to the PR-KB logout, a System/360 machine-check interruption is initiated. Existing restart procedures and problem programs that dc nct act directly upon the diagnostic logout area (such as BPS, DCS, CLTEP, etc.) are applicable to the Model 25 within the limits of core storage. The program storage byte locations and contents of the diagnostic logout area are as follows.

Address

Decimal)	<u>Bit</u>	<u>Contents</u>	message
130	~	Machine-check (MC) register	operato
	0	File control check	The
	1 2	Storage protection check Storage address check	minimum
	2		when the
	4	Control-word parity latch Storage-data parity latch	in the
	5	AIU error latch	In the
	6	A-register farity latch	The
	7	B-register parity latch	sense i
	,	E register parity fattin	bits ar
128		Microprogram mask (MMSK)	choice
120		register	operato
	0	Channel high trap	install
	ĩ	2311 disk control trap	INCOLL
	2	Channel low trap	
	3	2540 reader trap	
	4	2540 punch trap	2.27.1
	5	Communications bit service	2.42/41
	6	Communications character	Provide
	U	service	this er
	7	Level-1 priority hold	reject
	'	Tever-1 biloticy lord	error a
132 <del>-</del> 133		Address of control word at	valid t
197-199		which the machine check	attachm
		occurred.	actacina
		occurred.	
129		Branch condition (EA)	2.27.2
		register	
	0	Channel-0 interrupt	The PR-
	1	Mode tit 0	(interv
	2	Mode bit 1	one of
	3	Mode kit 2	1. The
	4	IPL latch	(Po
	5	IS zone bit 0	2. The
	6	LS zone bit 1	2. 110
	ž	IS zone bit 2	The
	•		indicat
131		Count of machine-check	1. loa
TOT		errors (low-order 6-bits;	for
		2-7):	2. pre
		Bits 0 1	2. pre out
÷		0 0=Machine Check	out
		1 1=Interface Control	
		Check	2.27.3
		Check	2.27.5
			Not use
2.27 SUGGES	TED H	RESTART PROCEDURES FOR	
INTEGRATED	PR-K	B	
		-	2.27.4
An I/O erro	r ca	uses an interrupticn	
ccnditicn.	The	condition causing the	Provide
interruption	n is	indicated in the CSW	failure
(Channel St	atus	Word). The CSW (a	one of
dcublewcrd)	is :	located in CPU main storage	

locations 40 through 47 (hexadecimal). Eit 38 of the CSW, when on, indicates a unit-check condition. This bit is bit 6 of the byte at main storage address 44 (hexadecimal).

When unit-check is detected by the program, a sense command should be executed

for the PR-KB. Sense information sent from the attachment provides more detailed information concerning the cause of the unit-check. As a result of program analysis of the sense information, an error message should be made available to the operator to indicate the condition.

The following information describes the minimum actions that should be performed when the program detects unit-check status in the CSW.

The actions are related to particular sense indications that can occur. These bits are analyzed by the program. The choice of action(s) to be taken by the operator must be established at the installation.

## 2.27.1 COMMAND REJECT (SENSE BIT 0)

Provide an operator message and exit from this error-recovery procedure. Command reject occurs because of a programming error and indicates that a command not valid to the PR-KB was received at the attachment.

2.27.2 INTERVENTION REQUIRED (SENSE BIT 1)

The PR-KB enters a not-ready condition (intervention-required light cn) because one of the following has occurred.

- The not-ready key is cperated. (Possible operator error).
- 2. The PR-KB has run out of forms.

The intervention-required light on indicates the operator should:

- load new forms if the PR-KB is out of forms and then press the ready key, or
- press the ready key if the PR-KB is not out of forms.

2.27.3 BUS-OUT CHECK (SENSE BIT 2)

Not used for PR-KB operations.

2.27.4 EQUIPMENT CHECK (SENSE BIT 3)

Provide an operator message to indicate failure to read the input message and do one of the following.

- 1. If there is no additional error recovery procedure, continue operation but consider the PR-KB inoperative.
- 2. If there is an additional error recovery procedure defined, exit to it. If the additional error recovery procedure fails, continue the operation but consider the PR-KB inoperative.

Equipment check is indicated for read cperations only, and it indicates that bad parity was detected on a bit pattern sent from the keyboard to the CPU. The read command operation, however, is not terminated until its normal ending point, even if equipment check occurs.

2.27.5 SENSE BITS 4, 5, 6, AND 7

Nct used for PR-KB operations.

#### 2.28 EXTERNAL TO CPU FACILITIES (1052)

2.28.1 TI (1052 DATA IN)

This location is accessed by a move word with AS-decode=A. TI is set to the keyboard bit pattern when a character key is operated. The contents of TI are then moved to the A-register, in the CPU, where a parity check is made on the byte.

<u>Bit</u>	Name	<u>Value</u>	Signifies
0	C	0	Iowercase
1	UC	0	Lowercase
0	UG	1	Uppercase
1	UC	1	Uppercase (Bcth 0 and 1
			are set to a value cf
			1 for an uppercase
			character.)
2	KB bit B		Bits 2 through 7
3	KB bit A		represent the character
4	KB bit 8		bit pattern from the
5	KB kit 4		keyboard.
6	KB bit 2		-
7	KB tit 1		
Р	KB bit C		Bit C is set cr reset to
			maintain odd parity.

## 2.28.2 TR (1052 TILT/ROTATE REGISTER)

This register can be tested (diagnostic) to determine if a correct translation from the EBCD interchange code bit pattern to the tilt/rotate code has been made. A move word with AS-DECCDE=B can be used to move TR contents to local storage where the bits can be tested. A branch word cannot be used to test TR directly.

<u>Bit</u>	Name	Signifies (when bit=1)
0	Tilt kit 1	Bits 0 through 7
	Tilt bit 2	are coded to cause the
2	Rotate kit 5	desired functicn or
3	Rotate bit 2A	tilt/rotate magnet
4	Rotate bit 2	activation.
0	Tilt kit 1	Bits 0 through 7
1	Rotate bit 5	desired function or
3	Rotate bit 2A	tilt/rotate magnet
4	Rotate bit 2	activation.
5	Rotate hit 1	
6	Uppercase	
	Character	
7	Function Cycle	
	_	

2.28.3 TD (1052 DIAGNOSTIC BRANCH CONDITIONS)

A branch (on condition cr cn mask) word having an AS-decode=D can be used to test the contents of the TD-register.

## Bit Name Signifies (when bit is on)

- 2 RD-WR Share Latch
- 3 New Line Latch
- 4 Key Switch On CE Mode
- 5 Shift Cycle Latch
- 6 Lowercase Deccde
- 7 Uppercase Deccde

2.28.4 TT (1052 BRANCH CONDITIONS)

A kranch (on condition cr cn mask) word with AS-decode=E can be used to test the contents of TT. Bits in TT are set/reset by circuit conditions in the 1052.

		Ci avifi ca
D-1-1-	Nama	Signifies
BIC	Name	(when bit value = 1) $\frac{1}{2}$
0	Attention	The request key has
	No.1	been crerated.
1	Not-ready to	Ready key pressed and
	ready	fcrced not-ready to
		ready request.
2	Intervention	The 1052 is out of
	Required	forms or the
		nct-ready key has
		been operated.
3	Alter/Display	The alter/display key
		cn the CPU console
		has been operated.
4	Keyboard check	A parity check was
		detected on a bit
		pattern sent from the
		1052 keyboard to the
		CPU A-register.
5	Alt coding key	The alternate-coding
		key is in its
		operated position.
6	1052 share	On when the 1052
	request	requests service for
	-	status or data
		transfer.
7	Ioqout latch	Branch bit to test if
	J	loqcut latch is on or
		off.

2.28.5 TU (1052 DIAGNOSTIC BRANCH CONDITIONS)

A kranch (on condition or mask) word with AS-decode=F can be used to test the contents of TU. TU contains the bit values set into TA by the microprogram or 1052 hardware.

		Signifies
Bit	Name	(when kit value = 1)
0	Read latch	A read operation
		(command, cr read
		portion of
		alter/display) is in
		progress.
1	Write latch	A write operation
_		(connand, write
		portion of
		alter/display, cr
		logout) is in
		progress.
2	Microforce	Cn if status is queued
-	latch	at the 1052
	20.001	attachment.
3	Alter/display	An alter/display
•	active	operation is in
		progress.
4	Cycle inter-	Cutput of cycle
•	lock latch	interlock latch used
		to check if 1052 is
		in the process of a
		print cycle.
5	Ready latch	Used to check if 1052
-		is in ready
		condition.
6	Initialize	On when in uppercase
•	printer	and initializing 1052
	L	to lowercase.
7	Printer busy	On when 1052 is
	1	performing some
		operation and until
		ready for another
		operation.
		- L · · · · · · · · · · · · · · · · · ·

- . . . .

## 2.29 CPU TO EXTERNAL FACILITIES (1052)

## 2.29.1 TA

A set/reset word with CS-decode=F is used to set/reset bits in TA. TA bits are set/reset to signify the conditions described for the same bits in the TU-register description. Setting bit 6 of TA causes the testable TU bit-6 condition of initialize printer. Resetting TA bit 6 causes a pulse to reset a 1052 share-request condition.

Bit 7 of TA (not testable in TU), when set, causes a force-share-request pulse; bit 7, when reset, causes a reset of the attention latch.

Bit 5 is set to indicate that the TA diagnostic singleshot is set. Bit 5 is reset when the TA attachment is reset (normally under diagnostic control).

## 2.29.2 TE (1052 DATA OUT)

A move word with AS-decode=F can be used to set a bit pattern in this register. TE (an 8-bit register) is set with the EBCDIC bit pattern from the CPU during a print operation.

# Section 1B. 1403 Procedures

## 2.30 ADDRESSING, 1403 PRINTER ATTACHMENT

The one-byte unit address of the 1403 used with the printer attachment control is set into auxiliary storage by the CSL routine. This address is used to select the printer prior to each command.

The integrated 1403 is normally addressed OE for compatibility with other System/360 usage. This permits the maximum interchange of programs when required. This addressing makes use of one of the channel-0 subchannel addresses and prevents its use for the channel. If channel configurations require the use of the subchannel, the 1403 address can be changed by the customer engineer to any address between 00 and FF that is not used by another channel-0 device. The integrated 1403 has its own subchannel (UCW) that is not dependent on the address assignment.

#### 2.31 COMMANDS, 1403 PRINTER ATTACHMENT

The following commands are for a write operation with various carriage functions.

Command Byte

$\begin{array}{cccccccccccccccccccccccccccccccccccc$	Function
00000001	Write and No Space After
	Frint
0 0 0 0 1 0 0 1	Write and Space 1 Line
	After Print
0 0 0 1 0 0 0 1	Write and Space 2 Lines
	After Print
0001	Write and Space 3 Lines
	After Print
1000 1001	Write and Skip to Channel
1001 0001	1 After Print
1001 0001	Write and Skip to Channel
1001 1001	2 After Print Write and Skip to Channel
1001 1001	3 After Print
1010 0001	Write and Skip to Channel
1010 0001	4 After Print
1010 1001	Write and Skip to Channel
10101001	5 After Print
1011 0001	Write and Skip to Channel
	6 After Print
1011 1001	Write and Skip to Channel
	7 After Print
1100 0001	Write and Skip to Channel
	8 After Print
11001001	Write and Skip to Channel
	9 After Print
1 1 0 1 0 0 0 1	Write and Skip tc Channel
	10 After Print
1 1 0 1 1 0 0 1	Write and Skip to Channel
	11 After Print
1 1 1 0 0 0 0 1	Write and Skip to Channel
	12 After Print

The following commands are for independent carriage operations.

Command	Byte	
0 1 2 3	<u>4567</u>	Function
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	<u>4567</u> 1011	Space 1 Line Immediately
0001	0011	Space 2 Lines
		Immediately
0001	1011	Space 3 Lines
		Immediately
1000	1011	Skip tc Channel 1
		Innediately
1001	0011	Skip to Channel 2
		Innediately
1001	1011	Skip to Channel 3
		Immediately
1010	0011	Skip to Channel 4
		Innediately
1010	1011	Skip to Channel 5
		Immediately
1011	0011	Skip to Channel 6
		Immediately
1011	1011	Skip to Channel 7
		Immediately
1 1 0 0	0011	Skip to Channel 8
		Immediately
1100	1011	Skip to Channel 9
		Innediately
1101	0011	Skip to Channel 10
		Immediately
1 1 0 1	1011	Skip tc Channel 11
		Immediately
1 1 1 0	0011	Skip to Channel 12
		Innediately

The following commands are for operations that cause no printing or carriage motion.

С	om	naı	nd	Byt	te			
0	1	2	3	4	5	6	7	<u>Functicn</u>
0	0	0	0	0	0	1	1	No-Op
0	1	1	1	0	0	1	1	Elock Data Check*
0	1	1	1	1	0	1	1	Allow Data Check*
1	1	1	0	1	0	1	1	Gate Load*
1	1	1	1	0	0	1	1	Load MCS and Fold*
1	1	1	1	1	0	1	1	Load MCS and No Fold*
0	0	0	0	0	1	0	0	Sense
*	Va	<b>a</b> li	iđ	on	1y	W	Ĺth	MCS feature.

#### 2.32 CHECKS (1403)

Several kinds of checks are performed while the printer is operating.

#### 2.32.1 PLB PARITY CHECK

The data kits in the data register are checked for proper parity when the data is written into the buffer. The check bits are not included in the parity check.

## 2.32.2 HAMMER CHECK

This check occurs if the hanner drivers and compare circuitry do not operate properly. Each of the conditions detected sets the harmer check latch. In addition, unique combinations of check bits (C1, C2, and C3) are set to indicate which error causes the hammer check. The check planes can be analyzed to help correct the errcr-causing condition. Listed here are the error conditions detected and the check planes that are set. Hammer driver on but no compare--PIC, C2 Compare but hammer driver did not turn on--PIC, C1, C2 Compare with FIC already on--PLC, C1, C2, C3 Hammer driver on with PLC already on--PLC, C2, C3 No compare at last scan--PLC, C3 Any other combinations of PLC with C1, C2, or C3 indicate failures in the check circuitry. The FIC kit alone indicates

#### 2.32.3 CCIL-PROTECT CHECK

proper operation.

This check occurs when a condition occurs that may cause damage to hammer coils and drivers. The +60V return to the hammer coils is opened by turning off the 60V control contactor. This contactor is controlled by a reed relay. If no check exists, the reed relay is picked and the +60V control is present.

A coil-protect check can cccur for 3 reasons.

- The hammer check circuitry detects that a hammer driver is on but should not be. This is detected for each hammer driver when printing is taking place.
- 2. A special current sense reed relay assembly detects that +60V control current of at least 3 amps is being drawn by the harmer coils at a time when no hammer drivers should be on. This detects any harmer coil current that cocurs when no printing is taking place.
- 3. The special current sense reed relay assembly is checked during printing to see if the reed relay picks if a harmer driver is on. This ensures that the check as stated in item 2 is creative.

The check in item 1 can be blocked by creating the coil protect check byrass switch S3. This switch blocks setting the coil-protect check latch due to a harmer check. This switch should be used only if it has been determined that a false errcr is causing the check. Eliminating this check may delay detecting a coil-protect check until printing is complete. This switch causes the printer attention light on the console to light. All of the preceding checks can be prevented from dropping the +60V control by operation of the current-limit switch S4. This switch opens a short circuit across a 100-ohm resistor in the +60V line to the hammer With this resistor in the coil returns. circuit, a maximum of 600mA can be drawn through any one circuit. This limited current prevents damage tc hammer coils and drivers even if they are on all of the time. A relay operated by the switch blocks the coil-protect check from dropping the +60V control.

#### 2.32.3.1 Hammer Driver Coil--Fuses

There are four 6-amp fuses in the 2025: F30, F31, F32 and F33. Their purpose is to protect the harmer coil return wiring in the 1403 and the 1403 signal cables. Under certain power-down conditions, these fuses may blow because all of the hammer drivers may be on for up to 50 milliseconds. The power-down condition that may cause this problem is the loss of one of the logic voltages that control the addressing matrix to the hammer drivers. Another condition that may blow one or more of the fuses is a short on one of the hammer coil return lines in the 1403.

After the fuse has blown, coil protect checks occur. Print ready is off, print check is on, and the chain motor is not running because +60V CTR1 is turned off. If this condition occurs only when printing is attempted, the S3 switches should be turned on. If the coil protect check no longer occurs, one or more of the fuses is probably blown.

The power-check light is also turned on if any fuse (F30 through F35) is open. A power-down condition does not occur. The light is turned off when the open fuses are replaced. Because these fuses have ceramic cases, it is necessary to check them with a meter or test light.

#### 2.32.4 SYNC CHECK

This check occurs when the PCC counter gets out of step with the chain or train. This is detected at home gate time, which is generated by an extra drum pulse from the chain or train, and indicates that the PCC should contain a count of hex 01 (non-MCS).

A resync circuit is used to resync the PCC automatically at MCS Home, except if a sync check could cause an improperly printed line. A reset is given to the printer-in-sync latch just before the home-gate time, unless a block-reset latch is on. The block-reset latch is set when a print line starts and is reset by the next MCS home gate that occurs when printing is not taking place.

## 2.32.5 ADDITIONAL CHECKS

Additional checks such as forms check etc., occur due to conditions in the printer.

## 2.32.5.1 Forms Check

This light indicates paper feed trouble or that the carriage-stop key has been operated. This light must be turned off by the check-reset key before the print start key is effective.

## 2.32.5.2 End Of Forms

When an end-of-forms condition occurs, unit-check (status bit 6) is sent to the channel at the next initial selection. Subsequently, intervention required (sense bit 1) is sent during a sense operation. Also, the printer-ready light turns off and the printer end-of-forms light turns on when the end->-forms condition occurs.

To reset the printer, press the printer start key. The remaining lines of the form are then printed under program control. (The operator does not press the start key for each remaining line to be printed. He presses the start key only once.) Alternately, the single-cycle key can be used. In this case, one line of print occurs for each operation of the single-cycle key.

When a hole is sensed in channel 1 (either space or skip to or by channel 1) of the carriage tape, the operation is terminated with the end-of-forms light on. Therefore, you must provide a carriage tape with a hole in channel 1 for proper ending of the printing operation. If there is no hole in channel 1, printing continues even though there are no forms in the printer. (Printing does not occur for any command fcllowing one in which the channel-1 hole is sensed.)

To make the printer ready after channel 1 has been sensed, correct the end-cf-fcrms condition and press the 1403 start or single-cycle key.

#### 2.33 SUGGESTED RESTART PRCCEDURES FOR 1403

An L/O error causes an interruption condition. The condition causing the interruption is indicated in the CSW (Channel Status Word). The CSW (a double word) is located in CPU main storage locations 40 through 47 (hexadecimal). Bit 38 of the CSW, when on, indicates a When unit-check is detected by the program, a sense command should be executed for the 1403 that caused the unit-check. Sense information sent from the 1403 attachment provides more detailed information concerning the cause of the unit-check. As a result of program analysis of the sense information, an error message should be made available to the operator to indicate the condition. Depending on installation procedures, the error message can be printed out.

The following information describes the minimum actions that should be performed when the program detects unit-check status in the CSW.

The actions are related to particular sense indications that can occur. These bits are analyzed by the program. The choice of action(s) to be taken by the operator must be established at the installation.

## 2.33.1 COMMAND REJECT (SENSE BIT 0)

Provide an operator message and exit from this error recovery procedure. Command reject occurs because of a probable programming error and indicates that a command or a command sequence not valid to the 1403 was received at the 1403 attachment.

#### 2.33.2 INTERVENTION REQUIRED (SENSE BIT 1)

The printer enters a not-ready condition (ready light off) because one of the following has occurred.

- The 1403 stop key is pressed. (Possible operator error.)
- A mechanical interlock, such as the print unit, is open. (Possible operator error.)
- 3. A forms check. When the forms-check light is on, paper feed trouble has occurred or the carriage-stop key has been pressed. The program should provide an operator message and exit from this error recovery procedure. The operator should then perform one of the following.
  - a. Correct the not-ready condition, accept the record, and allow the application program to proceed without further retries of the command, or
  - b. Correct the not-ready condition and

restart the program from a logical restart point. The logical restart point should be determined at the installation and specified to the operator.

4. End of forms. If an end-of-forms has occurred, the end-of-forms light is on and the ready light is cff. To reset the printer, press the printer start key. The remaining lines of the form are then printed under program control. (The start key is pressed only once.)

When a hole is then sensed in channel 1 of the carriage tape (either space tc, cr skip to or by channel 1., the operation is terminated with the end-of-forms light on and the ready light off. Printing does not occur for the line at which the channel-1 hole is sensed. Therefore, a carriage tape with a hole punched in channel 1 should be on the carriage. If there is nc hole in channel 1, printing continues even if no forms are in the printer. If nc skip-to-channel-1 command is issued, lines are printed (after the last form) until the channel-1 punch is sensed.

The program should provide an operator message and exit from this error recovery procedure when the end-of-forms indication is detected. The operator should then perform a forms runout (as just described) and satisfy the requirements of the application program.

- 5. Sync check. This condition can occur whenever the print chain or train is out of synchronism with the print circuitry. Depending upon when the sync check occurs, one of the following conditions exists.
  - The sync check occurred during a print operation and one line was printed.
  - b. The sync check occurred during printing and two lines were printed. Provide an operator message and exit from this error recovery procedure. The operator should then:
  - C. Correct the not-ready condition (press the check-reset key and then the start key) and allow the application program to proceed without further retries of the command, or
  - d. Correct the not-ready condition (press the check-reset key and then the start key) and restart the program from a logical point.
- 6. Coil-Protect Check. A condition occurred that could cause possible damage to the print-harmer coils or harmer-driver circuits. A coil-protect check resets the printer to a not-ready

condition, turns on the print check light, and turns off the power (+60V Ctrl) to the hammer coils. Depending upon when the coil-pretect check occurs, one of the following conditions exists.

- The check occurred when no printing was in progress (no line was printed).
- the check occurred during a print operation (one line was printed). The line may be only partially printed.
- c. The check occurred during carriage motion. The carriage motion may not have been completed. Provide an operator message and edit from this error recovery procedure. The operator should then:
- d. Correct the not-ready condition (press the check-reset key and then the start key) and allow the application program to proceed without further retries of the command, or
- e. Correct the not-ready condition (press the check-reset key and then the start key) and restart the program from a logical point.
- 7. The single-cycle key is pressed (possible operator error).

2.33.3 BUS-OUT CHECK (SENSE BIT 2)

Not used.

2.33.4 EQUIPMENT CHECK (SENSE BIT 3)

Equipment check indicates that a program-resettable malfunction is detected in the printer controls.

Provide an operator message and exit from this error recovery procedure. The operator should then:

- Accept the record and indicate that the application program is to proceed without further retries of the command, or
- 2. Cause the application program to restart from a logical point.

If the error persists, call the customer engineer.

2.33.5 DATA CHECK (SENSE BIT 4) -- MCS ONLY

Data check indicates that a data character sent to the printer does not compare equally with data loaded in the MCS table. Print does not occur for the print position for which the unmatching code applies. The remainder of the line prints correctly. Data check normally indicates improper data in the data record sent to be printed, but the MCS table may have been loaded improperly.

Provide an operator message and exit from this error recovery procedure. The operator should then:

- Accept the record and indicate that the application program is to proceed without further retry of the command, or
- 2. Cause the application program to restart from a logical point.

2.33.6 SENSE BIT 5

Not used.

2.33.7 SENSE BIT 6

Nct used.

2.33.8 CHANNEL 9 (SENSE BIT 7)

The carriage brushes sensed channel 9 during the previous carriage space. Accept the record and indicate that the program is to proceed without further retries of the command. Local installation practices may indicate other action to be taken.

#### 2.34 USE METER (1403)

The use meter for the integrated 1403 printer is conditioned when the printer is ready and a write operation is performed. The meter remains conditioned until the carriage space or restore key is cperated.

The use meter records time when it is conditioned <u>and</u> the CPU customer use meter 4 is operating.

#### 2.35 RESETS (INTEGRATED 1403)

A power-on reset places the integrated 1403 in a reset state; all 1403 check circuitry is reset, and the 1403 is placed in the not-ready state. A system reset places the 1403 in the same condition as a power-on reset, except that if the 1403 is ready when the system reset is given, it remains ready after the system reset is completed.

System reset should not be given while a printer operation is in progress because the results of the operation are unpredictable.

## 2.36 EXTERNAL TO CPU FACILITIES (1403)

2.36.1 PRI (PRINT LINE EUFFER DATA-IN)

This 8-bit register is used during diagnostic operations to provide data from the PLB to the CPU data flow.

A move word with AS-decode=B is used to move data from PRI to local storage.

2.36.2 PRT (PRINT LINE EUFFER ADDRESS REGISTER DATA-IN)

This 8-bit register is used to send PIB addresses to the CPU data flow during a diagnostic operation.

A move word with AS-decode=A is used to move the address from PRT to local storage.

2.36.3 PRS (1403 SENSE/STATUS CONDITIONS)

The AS-decode=E for a move or branch (on condition or on mask) word accessing this external facility. Bit significance is:

PRS		
<u>Bit</u>	Name	<u>Significance if Bit On</u>
0	Device-end	Device-end has occurred.
1	Print ready	The printer is in the ready state.
2	Channel 9	A channel-9 punch has been sensed in the carriage tape during a
3	Channel 12	<pre>space (nct skip) operation. A channel-12 hole has been sensed in the carriage tape during a</pre>
		space (nct skip) operation.
4	Initial ready	The printer has gone from the not-ready to
5	Hammer check	the ready state. A hammer check has been detected.
6	Parity check	A parity check has been detected during a PLB readcut or store.
7	Print request	Set on when device-end occurs for a command, or when the printer goes from the nct-ready to the ready state, or if channel-end was queued by the channel, or if the diagnostic request gate latch is on and the printer clock is at time 7-0.

# 2.36.4 PRD (DIAGNOSTIC CONDITIONS)

The AS-decode=F in a move cr a branch (cn condition or on mask) word accesses this diagnostic external. The diagnostic conditions listed here are defined by the settings of PRB kits 0, 1, and 2. See the PRB description in the <u>CPU to External</u> Facilities (1403). For example, if PRB bits 0, 1, and 2=000, diagnostic decode 1 will be used when FRD is addressed.

## 2.36.4.1 Diagnostic Decode 1

Hex, the 8-bit PRD register contains the print character counter data-in; i.e., chain position.

## 2.36.4.2 Diagnostic Decode 2

PRD		
<u>Bit</u>	Name	<u>Significance_if_Bit_On</u>
0	Print control latch	Printing is cccurring.
1	Print scan latch	If bit-0=1, this bit is turned cn every time a PSS pulse occurs.
2	PSS gate latch	Set on by PSS pulses from the printer.
3	Home gate lat ch	Set on when home pulse is detected.
4	SS3 trigger	The operation is in subscan 3.
5	Print compare	The PCC and PIB data match.
6	Last scan latch	Print complete has occurred and the last scan (for checking) is in progress.
7	Sync check latch	The chain or train and PCC were out of synchronism at home-gate time.

## 2.36.4.3 Diagnostic Decode 3

# PRD

<u>Bit</u>	Name	<u>Significance if Eit On</u>
0	Carriage tusy	An immediate carriage
		command is in
		progress.
1	Space drive	On for space or skip
		operations.
2	Skip drive	Cn for skip operations.
3	Carriage	The carriage is in the
	settling	15. 7 us carriage
	-	settling interval.
4	Carr brush 1	Bits 4-7 display the
5	Carr brush 2	contents of the
6	Carr brush 4	carriage brush
7	Carr brush 8	register.
		-

# 2.36.4.4 Diagnostic Decode 4

0 1 2 3	Name PIC PIB C1 PLB C2 PIB C3 MCS mode	Significance if Bit On Print line complete. Bits 1-3 indicate check conditions as a result of a print operation. A chain with an MCS emitter is installed on the printer, or a train has operated the MCS switch on a 1403-N1.
5	Space extended	The cutput of the hammer driver being addressed is cver 40V.
6	E1 emitter	The cutput of the magnetic emitter in the printer that indicates the carriage has moved one space.
7	Channel 1	A channel-1 punch has been sensed in he carriage tape during a carriage operation.

## 2.37 CPU TO EXTERNAL FACILITIES (1403)

2.37.1 PRC (CARRIAGE CONTROL REGISTER DATA-CUT)

A move word with AS-decode=D is used to set bits in PRC.

PRC	
<u>Bit Name</u>	Significance if Bit On
0 Skip	Bits 0-4 are set to the
1 Carr Ctl 8	value of the modifier
2 Carr Ctl 4	bits in the command to
3 Carr Ctl 2	be executed. This
4 Carr Ctl 1	setur indicates to the
	printer the number of
	spaces to be spaced or
	the channel to which
	to slip.
5 Not used	
6	If bits 6-7 are 11, a
7	printer-busy condition
	and an immediate
	carriage control
	operation are
	indicated.

- K- Name and Significance if Set/Reset Bit Bit = 1 (when K-Bit = 1)
- 0 Set single-cycle mode latch
- 1 Reset single-cycle mode latch
- 2 Not used
- 3 Set diagnostic gate latch latch
- 4 Reset diagnostic requires gate latch
- 5 Set diagnostic decode-2 latch
- 6 Set diagnostic decode-3 latch
- 7 Set diagnostic decode-4 latch. Bits 5-7 (diag decodes 2-4) are set to allow the various diagnostic modes used in the FRD external. If bits 5, 6, and 7 are all off, diagnostic mode 1 is specified. The diagnostic decode latches remain on until another PRB set word is given. If neither tit 5, 6, nor 7 is on, the diagnostic decode 1 comes cn.

K- Name and Significance if Set/Reset

- Bit Bit = 0 (when K-Bit = 1)
- 0 Not used
- 1 Set single-cycle clock run latch
- 2 Not used
- 3 Not used
- 4 Set diagnostic PSS pulse latch (set PSS gate)
- 5 Reset diagnostic PSS pulse latch
- 6 Not used
- 7 Not used

## 2.38 MCS TABLE--UTILITY PROGRAM

Utility Program Number 360P-UT-048 is available to load the table. In addition, the program gives the option of using folding and blocking data checks. Diagnostic functions are also performed to ensure that the data cards are correct.

# Section 1C. 2311/DAC Procedures

## 2.39 ADDRESSING--2311 DISK STORAGE DRIVE

From one to four 2311 DASDs can be attached tc channel 1 through a single integrated attachment. The addresses for these units consist of three parts:

- Channel address
- Control unit address
- Device address.

The channel address is always 01. The control unit address can be any address within the range of 8 through F (hex). The device address can be 0 through 3 (hex).

The DAC is limited to the control of one tc four 2311 disk storage drives connected directly to the control unit interface in the CPU. No additional 2311s can be attached to the system through the channel because of the data transfer rate of the channel. The 16 address bits developed from the I/C instruction identify the DAC and the disk drive for the operation.

The program views the disk attachment as if it is a <u>channel</u> with an attached control unit and disk drives. The sixteen bits of the I / O address are assigned as follows.

Channel Number (Bits 16 to 23) 01 Hex (Channel 1)

Control-Unit Number (Bits 24 to 27) 8-F Hex (Assigned at Installation)

Eit 28 set to 0 for system compatibility

Device Number (Bits 29 to 31) 000 Unit 1 001 Unit 2 010 Unit 3 011 Unit 4.

For example, a system with fcur 2311s with the control unit address assigned as 9 would have the following addresses:

	Channel	Control Unit
2311	Address	and Device Address
0	01	90
1	01	91
2	01	92
3	01	93

1

If fewer than four 2311s are attached, the device address for each can be any value in the range 0-3, providing each has a different device address and all have the same control unit address. In the previous example, if only two 2311s were attached, the addresses could be 90 and 91, 91 and 92, or 90 and 92, etc. In any case, twc (or mcre) different addresses cannot be assigned to the same 2311.

The 2311 control unit address must be different than of any other device attached to channel 1 through the standard I/O interface.

#### 2.40 CPERATICN COMMANDS, DAC

Figure 2-2 lists the channel commands recognized by the DAC for control of the attached 2311 units. These commands are presented to the DAC in the first byte of each channel command word (CCW) from the processing unit. Any other command configuration except that of the transfer-in-channel command is considered invalid by the DAC.

			r
		Single	Multi-
Туре	Command Name	Track	Track
Control	No Operation	03	
	Recalibrate	13	
	Restore	17	
	Set File Mask	1F	
	Seek	07	
	Seek Cylinder	0B	
	Seek Head	1B	
	Space Count	0F	
Sense	Sense I/O	04	
Read	Read Home Address	1A	9A
	Read Count	16	92
	Read Record Zero	16	96
	Read Data	06	86
	Read Key and Data	0E	8E
	Read Count, Key and Data	1E	9E
	Read IPL	02	
Write	Write Home Address	19	
	Write R0	15	
	Write Count, Key and Data	1D	
	Erase	11	
	Write Data	05	
	Write Key and Data	0D	
Search	Search Home Address Equal	39	B9
	Search ID Equal	31	B1
	Search ID High	51	D1
	Search ID Equal or High	71	F1
	Search Key Equal	29	A9
	Search Key High	49	C9
	Search Key Equal or High	69	E9
	* Search Key and Data Equal	2D	AD
	* Search Key and Data High	4D	CD
	*Search Key and Data Equal or High	6D	ED
		l	

\*Used with File Scan feature (standard).

Figure 2-2. DAC Commands

The commands are chained to execute the desired sequence of events. The transfer-in-channel command (Figure 2-3) is

used to repeat search commands until the desired area is located. A read or write command is then given for the desired data. Each of the channel commands is acted upon in the same manner as a control unit connected to a System/360 channel. The usual status is returned after initialization and at the completion of the command. Sense information is developed for unusual conditions and is available through the sense command. A parity error that occurs during the transfer of the CCW causes a machine check.

	FIC Command C	ode
Decimal	Hexadecimal	Binary
X8	X8	XXXX1000
Positions	Marked ''XX'' A	re Ignored

Figure 2-3. Operation Code for TIC Command

#### 2.41 SENSE CONDITIONS, DAC

Six bytes of sense-conditions information are provided by the DAC tc ccmpletely identify the setting of unit-check. These six bytes are transferred to the system by issuing a sense ccmmard (Figure 2-4).

#### 2.42 TRACK QRIENTATION

Figure 2-5 shows the relationship of the fields and zones to the track format and Figure 2-6 shows the initializing states of fields and zones and the command sequences required to perform a data command.

Record	НА		R0			R <sub>n</sub>	
Field	н	С	к	D	С	к	D
Zone	A 1 2 3 4	1234	1234	1234	A B 1 2 3 4	1234	1234

Field Definition

H Home-address area (including gaps)

C Count area (including gaps)

- K Key area (including gaps)D Data area (including gaps)
- D Data area (mcruding gaps)

Zone Definition

- 1 Pre-record gap (including address marker)
- 2 Record
- 3 Cyclic code 4 Post-record of
  - Post-record gap
- A Constant gap of 12-ones bytes in the count field, or 28 all-zeros bytes in the home-address field.
   B The 4.9% variable gap between records.
- B The 4.9% variable gap between records.
- Notes: The index point immediately precedes the home-address area. \* Location of the address marker.

Figure 2-5. Track Orientation

	Sense Byte 0	Sense Byte 1	Sense Byte 2	Sense Byte 3
Bit 0	Command Reject	Data Check in Count Field	Unsafe	Ready
Bit 1	Intervention Required	Track Overrun		On Line
Bit 2		End-of-Cylinder		Unsafe
Bit 3	Equipment Check	Invalid Sequence	Selected Status	
Bit 4	Data Check	No Record Found	Cyclic-Code Check	On Line
Bit 5	Overrun	File Protected	Unselected File Status	End of Cylinder
Bit 6	Track-Condition Check	Missing Address Marker		
Bit 7	Seek Check			Seek Incomplete

Figure 2-4. Sense-Eyte Summary (DAC)

		Initial Field and	Field and Zone State
Command	Command Sequence	Zone State	at End of Command
Read Count, Key and Data	None	C1	D4
Read Key and Data	None	C1	D4
	After Search ID	C4	D4
Read Data	None	C1	D4
	After Search ID	C4	D4
	After Search Key	K4	D4
Write Count, Key and Data	Search Equal ID	C4	D4
	Search Equal Key	К4	D4
	Write R0	D4	D4
	Write Count, Key and Ddata	D4	D4
Write Key and Data	Search Equal ID	C4	D4
Write Data	Search Equal ID	C4	D4
	Search Equal Key	К4	D4
Search ID	None	C1	C4
Search Key	None	C1	K4
	After Read or Search ID	C4	К4
Search Key and Data	None	C1	D4
	After Read or Search ID	C4	D4
Search Home Address	None	НА	H4
Read R0	None	НА	D4
	After Read or Search Home Addrs	H4	D4
Write RO	Write Home Address	H4	D4
	Search Equal Home Address	H4	D4
Read Home Address	None	HA	H4
Write Home Address	None	НА	H4
Read Initial Program Load	None	C1	D4
Read Count	None	C1	C4
Erase	Search Equal ID	C4	D4
	Search Equal Key	K4	D4
	Write R0	D4	D4
	Write Count, Key and Data	D4	D4
No Operation	None	Reset Condi	tion

Figure 2-6. Track Orientaticn Field and Zone State Summary

## 2.43 TRACK INITIALIZATION (DEFECTIVE-TRACK DETERMINATION)

The following procedure must be followed by track-initialization programs for the IEM 2311 files. This procedure is intended to write home addresses on each track and to analyze the condition of the recording surface. The program should be written to handle the tracks in cylinder mode to reduce running time.

- Read home address. Verify that the track has not been previcusly flagged. This step must be bypassed by operator action when initializing the recording surface for the first time. Unless specifically optioned by the operator, no program should change the flagging of a previously flagged alternate or defective track.
- Write home address and record zerc (R0) with a maximum-length data field on all

tracks. The data pattern should be hexadecimal 55.

- 3. Read home address and R0 of each track to ensure that the data can be recovered successfully. If an error occurs, go to step 7.
- Repeat step 2, using a data pattern of hexadecimal 00.
- 5. Repeat step 3. If an error occurs, go to step 7.
- Rewrite home address and a standard length record 0 on all good tracks. Read and verify that these records can be recovered successfully. If an error occurs, go the step 7. The surface analysis is new complete.
- 7. When an error occurs, an analysis of the sense information must be made. If the error is a data-check in the count

field an/or a data-check, an attempt is made to reread the home address and R0 ten times on the track in question. If a data check (also includes a count-field data check) occurs a second time on the track, the track must be flagged as defective. Tc tc step 8. Other errors should be handled as defined in Section 2.44. If all ten rereads are successful, return to the program at point of exit.

- 8. Assign an alternate track.
- 9. Write home address and R0 on the defective track. Set the home-address flag byte to hexadecimal 02. The home address is the physical address of the <u>defective</u> track. The R0 count field contains the address of the <u>alternate</u> track. The content and length of the data-field length (DL) should be kept to a minimum (but greater than zero) to avoid spanning the track defect. No other records should be written on the track.
- 10. Read-check the home address and R0. If a data check (also includes a count-field data check) cr missing address marker and no-record found errors occur, go to step 14. Other errors should be handled as in Section 2.44, Error Recovery Procedure, DAC.
- 11. Seek the alternate track.
- 12. Write home address and record zero on the alternate track. Set the home-address flag byte to hexadecimal 01. This home address is the physical address of the <u>alternate</u> track. The R0 count field normally contains the address of the <u>original defective</u> track. Surface analysis must be completed on the alternate track candidates before they can be assigned as alternates.
- 13. Continue initialization on next track.
- 14. Track flogging requires a perfect recording surface from the index point to the end of record zero. If attempts to write home address and R0 indicate that this area is defective, the recording medium (disk pack) must be repaired.

The basic requirement is one pass through the test (steps 2-5). An option should be provided to increase the number of tests to 255. Additional requirements for programs that write the home address and R0 area (and in particular, Surface Analysis, Diagnostic, and other track utility programs such as UT069, UT098, and DASDI) are as follows.

- Unless specifically crticned by action of the operator, no program should change the flagging cf a previously flagged alternate or defective track.
- Specific action by an operator should be required to unflag a track.
- Provision must be made to flag or unflag individual cr groups of tracks.
- Operating programs that have provisions for dynamically flagging tracks must perform the 14 steps given previously.

### 2.44 ERROR RECOVERY PROCEDURES, 2311 DAC

2.44.1 ERRCR MESSAGES, 2311 DAC

The following two error messages should be included in the operating environment of all DAC users.

<u>Message 1</u> (should be printed on all uncorrectable errors).

- a. Message code
- b. Error type-read, write, or control
- Unit designation, cell number, cylinder number, head number and head position;
   i.e., device addresses and seek address.
- d. Channel designation
- e. Status and sense bytes sent to CPU

<u>Message 2</u> (should be printed periodically, upon completion of a run, cr in response to operator request).

- a. Unit designation
- b. Number of entries into error routine
- c. Number of uncorrectable errors.

## 2.44.2 ERROR CONDITIONS TABLE, 2311 DAC

This section gives the recommended corrective action for the error conditions that may occur when using IBM 2311 units attached to the System/360 Model 25 through the disk attachment control The recovery procedures are listed in the <u>Action</u> column. These are given in detail following the Error Condition Table (Figure 2-7).

Sense Bit and Name	Explanation	Error Type	Action
Byte 0, bit 0 (Command Reject)	The DAC has received an invalid command code.	Program error	1
Byte 0, bit 0 (Command Reject) and byte 0, bit 7 (Seek Check)	The DAC has received an invalid seek address.	Program error	1
Byte 0, bit 0 (Command Reject) byte 1, bit 3 (Invalid Sequence)	The DAC has received an invalid sequence of commands.	Program error	1
Byte 0, bit 0 (Command Reject) and byte 1, bit 5 (File Protected)	The DAC has received a command that violates the Inhibit Write portion of the File Mask.	Program error	1
Byte 0, bit 1 (Intervention Required)	<ul><li>The specified 2311 unit is:</li><li>1. Not on line, or</li><li>2. Not available for use due to cover interlock open, file motor off, etc.</li></ul>	Equipment error	2
Byte 0, bit 3 (Equipment check) and	An unusual condition has been detected in the DAC or the file unit. The condition is indicated by sense-byte 2.	Equipment error	2
Byte 2, bit 0 (Unsafe) or	A file malfunction has been detected.		
Byte 2, bit 4 (Cyclic Code Check) or	Circuitry used to generate the cyclic-code check did not function properly.		
Byte 2, bit 3 (Selected Status) or	Microprogram decode of the status byte yielded self-contradictory results.		
Byte 2, bit 5 (Unselected Status)	The status line from the files is on, but no file has been selected.		
Byte 0, bit 4 (Data Check)	The DAC has detected an error in the data field received from the file.	Equipment error	8
Byte 1, bit 6 (Missing Address Marker)	The DAC has received: 1. Two index points without an intervening address marker, or 2. Two successive count fields with equal bit conditions in bit 0 of the flag bytes.	Equipment error	5
Byte 0, bit 5 (Overrun)	The DAC access to main storage was suppressed longer than one byte time on the 2311, or a chained CCW was received too late to be properly executed.	Equipment error	3
Byte 0, bit 6 (Track Condition Check)	<ol> <li>A Search, Read, or Write command was attempted on a flagged defective track (track-condition bit 6 was set to 1). Exceptions: HA and R0 operations.</li> <li>Command chaining and multitrack code signals indicate that operations from an alternate track are to continue on the next higher-order track.</li> </ol>	Program error	6
Byte 0, bit 7 (Seek Check)	The 2311 has been unable to complete the Seek because:	Equipment error	4
	<ol> <li>The access mechanism failed to reposition properly, or</li> <li>The home-address-compare failed after automatic head switching on a multitrack operation</li> </ol>		. •
Byte 1, bit 0 (Data Check in count Field) and byte 0, bit 4, (Data Check)	The DAC has detected an error in the count field received from the 2311.	Equipment error	8
Byte 1, bit 1 (Track Overrun)	The index point was detected before writing was completed	Program error	1
Byte 1, bit 2 (End of Cylinder)	An end-of-cylinder was detected before the CCW command chain was completed while in multitrack mode.	Program error	1
Byte 1, bit 4 (No Record Found) and not byte 1, bit 6 (missing address marker)	Two index points were detected while executing a chain of CCWs with no intervening Read or Write operation on the data field of any record, or Read HA or Read R0 CCW. Note: This could be an expected condition on Search command chains.	Program error or equipment error	7
Byte 1, bit 5 (File Protect)	The DAC has received a Seek, a multitrack Read, or multitrack search that violated the Seek File Mask.	Program error	1
Byte 1, bit 4 (No Record Found) and byte 1, bit 6 (Missing Address Marker)	Home address or R0 cannot be found on the track.	Equipment error	9

Figure 2-7. Error Condition Table 2311/DAC (Fart 1 cf 2)

Action	Recovery Procedure
1	Exit with Program Error indication.
2	Repeat original sequence once.
1	If the error condition still occurs, print Message 1 for the operator and/or customer engineer notification. This is considered an uncorrectable error; the recovery procedure depends on the application.
3	Repeat the original sequence ten times if the error persists.
	After ten unsuccessful retries, print Message 1 for the operator and/or CE notification.
4	Issue a Recalibrate command.
	Seek to the original address.
	Repeat the original sequence ten times if the error persists.
	Print Mesaage 1 and exit with the error indication.
5	Repeat the original sequence ten times if the error persists.
	After ten unsuccessful retries, the error is said to be "hard". At this point, the hard-error recovery procedure may be employed at the user's option.
	Print Mesasge 1 and exit with the error indication and option information.
6	If this is an alternate track, use the defective-track address, plus 1, in the Seek command. (This is found in the ID field of the R0 count area.) Resume the operation after searching to the desired track position.
	If this is a defective track, use the alternate-track address in the Seek command. (This is found in the ID field of the R0 record.) Resume the operation after searching to the desired track position.
7	Issue a Read Home Address command to verify that the correct track has been reached. (Correct cylinder is sufficient on multitrack operation.)
	If the correct cylinder (and/or track) is found, perform Action 1.
	If the incorrect cylinder (and/or track) is found, perform Action 4.
8	Repeat the original sequence sixteen times if the error persists.
.	After sixteen unsuccessful retries, issue instructions to Recalibrate, and then Seek to the original cylinder. Repeat first two steps sixteen times if the error persists.
	After sixteen unsucceesful retries of second step (a total of 256 entries for the data), the data-error is said to be "hard". At this point, the hard-error recovery operations may be employed at the user soperation.
	Print Message 1 and exit with the data-error indication and option information.
9	Issue a Recalibrate and then a Seek to the original address.
	Repeat the operation that failed.
	Repeat the first two steps twice if the error persists.
	Issue a Read HA to a different track in some cylinder.
	If the Read HA is successful, return to the original track and perform Action 3.
	If the Read HA is unsuccessful after two tries and causes the same error indication, print Message 1 for operator and/or CE notification.

Figure 2-7. Error Condition Table 2311/DAC (Part 2 of 2)

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## 2.45 ADDRESSING, INTEGRATED 2540 ATTACHMENT

The integrated 2540 attachment is addressed as if it were connected to <u>channel 0</u>. The sixteen-bit address developed from the I/O instruction identifies the attachment and the reader or punch unit. The device address is not limited by usual channel-0 UCW addressing requirements because the attachment has its own UCWs that are not device address dependent. In theory, the attachment may have any address from:

Binary	Нех
0000 0000	00
to	to
1111 1111	$\mathbf{FF}$

In practice, the integrated 2540 is assigned an address of OC for the reader and OD for the punch, to standardize with other System/360 usage. This addressing makes use of two of the channel-0 subchannel addresses and prevents their use for the channel. If the channel configurations require the use of the subchannels, the 2540 addresses can be changed by the customer engineer.

Under no condition should an address assigned to any other I/O device be assigned to either the 2540 reader cr or gunch.

# 2.46 ERRCR RECEVERY ROUTINE--INTEGRATED

This procedure is included at the beginning of the Native Punch Trap Routine (ETRP).

For examining punch-check problems, the following procedure can be followed.

- 1. SAR delay stop at the address labeled PCH CHK in this routine.
- When PCH CHK is detected the processor will stop with the punch attention light on.
- 3. Display of error logout (auxiliary storage 50F6-50FF) can be performed using 1052. The bit significance of the error logout is as follows. AR 50F6 50F7 50F8 50FF BIT 01234567 01234567 01234567 01234567 Col 1--8 9--16 17--24 73--80

When bit=1, that column is in error.

- 4. Manually clear logout area after analysis is completed.
- 5. The punch image for a card in error is located in auxiliary storage 400C through 4083. The format for this area starting at address 400C is 10 bytes, for the 12 row of the card, the next 10 bytes for the 11 row etc. A bit being a zero in this area designates a hole in the card.

The registers are used as follows. GC=Trap count V=Auxiliary storage address modification D05=1 normal write indicator D07=1 12-row punch

# 2.47 ERRCR RECOVERY ROUTINE--INTEGRATED READER

The reader check logout format is as follows.

 AUX ADR
 10F6
 10F7
 10FF

 BITS
 01234567
 01234567
 01234567

 COL
 1 THRU 8
 9 THRU 16
 73 THRU 80

The format for the row form in auxiliary storage (4FA0 through 5017) is as follows. The first 10 bytes, row 9 of card; the next 10 bytes, row 8 of the cards; etc. A bit being zero signifies a punched hole.

#### 2.48 2540 RESTARTS FROM ERROR CONDITIONS

The 2540 uses the flexible System/360 command set; therefore, different external error conditions can each require different restart procedures, depending on whether the 2540 operation is reading, punching or PFR. If the program provides some programmed message to indicate the 2540 sense conditions (such as PR-KB typeout), the operator can use this message to determine which specific restart procedure he should follow. To locate the error card for read-check and validity-check errors, the operator should be familiar with the with the type of processing used by the program; that is, whether the program is reading and stacking each card with a single command, or delaying the stacker selection until the data from the card is analyzed.

Figure 2-8 shows the various 2540 error indications and appropriate restart procedures for standard operations, and for PFR operations.

<ol> <li>Remove cards from stacker R1.</li> <li>Open hopper joggler gate and remove cards from hopper.</li> <li>Open covers and remove any jammed cards from read feed. Reconstruct any damaged cards.</li> <li>With joggler gate still open, press reader start key to clear feed.</li> <li>Remove cards just run out into stacker R1, place them and any reconstructed cards, in proper sequence, ahead of cards removed from hopper, and replace this deck in hopper or ahead of cards in file feed magazine.</li> <li>Close joggler gate.</li> <li>Press reader start key.</li> </ol>
This combination of error indications accompanies a 2540 read clutch failure; there may be cards in stacker R1 that have not been read. Restart the job from the last checkpoint.
<ol> <li>Remove cards from stacker R1. Determine (perhaps with aid from programmed message) which was last card read into processing unit, and correct any off-registration punching in it. Place this corrected card in stacker R1.</li> <li>Open joggler gate and remove cards from hopper.</li> <li>With joggler gate open, press reader start key to clear read feed.</li> <li>Remove cards from stacker R1 and place them ahead of cards removed from hopper. Place this deck in hopper or ahead of cards in file feed magazine.</li> <li>Close joggler gate.</li> <li>Press reader start key.</li> </ol>
<ol> <li>Remove cards from stacker R1.</li> <li>Follow steps 2-6 of preceding procedure, correcting any off-registration punching in first card run out into stacker R1.</li> </ol>
<ol> <li>Remove cards from stacker R1. Determine (perhaps with aid from programmed message) which was last card read into processing unit (this card may be in another stacker) and correct any errors in this card. Place the corrected card in stacker R1.</li> <li>Open joggler gate and remove cards from hopper.</li> <li>With joggler gate open, press reader start key to clear read feed.</li> <li>Remove cards from stacker R1 and place them ahead of cards removed from hopper. Place this deck in hopper or ahead of cards in file feed magazine.</li> <li>Close joggler gate.</li> </ol>

Figure 2-8. Restart Procedures--Standard and PFR Operation (Part 1 of 3)

Indications	Restart Procedures
Validity Check Light Sense Bit 4—Data Check	1. Remove cards from stacker R1.
(If stacker selection is delayed.)	2. Open joggler gate and remove cards from hopper.
	<ol> <li>With joggler gate open, press start key to clear read feed.</li> <li>Locate and correct invalid character(s) in first card in stacker R1.</li> </ol>
	5. Place corrected card ahead of cards in stacker R1. Place all cards in stacker R1 ahead of
	cards removed from hopper. Place this deck in hopper ahead of cards in file feed magazine.
	6. Close joggler gate.
Punch Feed Stop Light (Only) Sense Bit 1—Intervention Required Only) (If the 2540 is not performing PFR operations.)	<ol> <li>Press reader start key.</li> <li>Remove cards from stacker P1.</li> </ol>
	2. Remove cards from hopper.
	3. Open covers and remvoe any jammed cards from punch feed.
	4. Press punch start key to clear punch feed.
	5. Discard last card punched (2540 will repunch this card automatically).
	<ol><li>Replace blank cards in hopper and press punch start key. Last card will be repunched automatically and 2540 enters ready status.</li></ol>

Figure 2-8. Restart Procedures--Standard and PFR Operation (Part 2 of 3)

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Indications	Restart Procedures
Punch Feed Stop (Only) Sense Bit 1—Intervention Required (Only) (If 2540 is performing PFR operation.)	<ol> <li>Remove cards from stacker P1.</li> <li>Remove cards from hopper.</li> <li>Open covers and remove any jammed cards from punch feed. Press punch start key to clear feed.</li> <li>Any card removed or run out from between punch station and punch check brushes should be reconstructed, because it has been punched but not punch checked.</li> <li>Place reconstructed cards and cards run out into stacker P1 in proper sequence ahead of cards removed from hopper, and place this deck in hopper.</li> <li>Press punch start key.</li> <li>Reconstruct internal data in the system as necessary to restart at the Start I/O instruction that caused the first card removed or run out to be read at the PFR station. Note: In some programs, reconstruction of internal data may not be provided for. In that case, restart the job from the last checkpoint.</li> </ol>
Punch Check Light Sense Bit 3—Equipment Check (If 2540 is not performing PFR operation and using stacker P1.)	<ol> <li>Remove cards from hopper.</li> <li>Press punch start key to clear punch feed.</li> <li>Remove last four cards from stacker P1. The last two cards are blank; the first two should be discarded.</li> <li>Replace blank cards and cards removed from hopper in hopper.</li> <li>Reconstruct internal data in the system as necessary to restart at the Start I/O instruction that caused the first card removed from stacker P1 to be punched. Note: In some programs, reconstruction of internal data may not be provided for. In that case, restart the job from the last checkpoint.</li> </ol>
Punch Check Light Sense Bit 3–Equipment Check (If 2540 is not performing PFR operation and is not using stacker P1.)	<ol> <li>Examine and correct, if necessary, error card, which is last card in stacker P1. (2540 automatically routes error cards to stacker P1.)</li> <li>Place this card in appropriate stacker.</li> <li>Press punch start key.</li> <li>The 2540 will force the card following the error card into stacker P1, also. Place this card in the appropriate stacker. Note: Because the error card and the card following it are both directed to stacker P1, the program can correct a non-PFR punch check without operator intervention by repunching both cards and directing them to appropriate stackers. The operator can then discard all cards in stacker P1 at the end of the job.</li> </ol>
Punch Check Light Sense Bit 3–Equipment Check (If 2540 is performing PFR operation.)	<ol> <li>Remove cards from punch hopper.</li> <li>Press punch start key to clear feed.</li> <li>Remove last four cards from stacker P1. The last two cards are correct; pre-punching in the first two must be reconstructed.</li> <li>Place the two reconstructed cards, the two correct cards, and the cards removed from the hopper, in that sequence, in the hopper.</li> <li>Reconstruct internal data in the system as necessary to restart at the Start I/O instruction that caused the first reconstructed card to be read at the PFR station. Note: In some programs, reconstruction of internal data may not be provided for.</li> </ol>

Figure 2-8. Restart Procedures--Standard and PFR Operations (Part 3 of 3)

2.49 JAM REMOVAL

For a description of how card jams can be cleared from the 2540, refer to <u>IPM 2540</u> <u>Component Description and Operating</u> <u>Procedures</u>, Form A21-9033.

2.50 EXTERNAL TO CPU FACILITIES (2540)

2.50.1 RP1 (READER-PUNCH DATA IN)

Eits are shifted into this register during reading from read station 1 cr from the PFR brushes. A move word with AS-deccde=B is used to move the contents cf RP1 tc auxiliary storage.

2.50.2 RP2 (READER-PUNCH DATA IN)

The same as RP1, but for the read staticn 2 and punch check trushes. A move word with AS-decode=A is used to move the contents of RP2 to auxiliary storage.

2.50.3 RS (READER BRANCH CONDITIONS)

A branch (on condition or on mask) word with AS-decode=D is used to test the following conditions.

<u>Bit</u>: 0 <u>Name</u>: Not gate read complete <u>Value</u>: 0 <u>Signifies</u>: No cards in read feed, cr a card is passing read station 2.

<u>Bit</u>: 1 <u>Name</u>: Reader ready <u>Value</u>: 1 <u>Signifies</u>: The reader is in the ready state.

<u>Bit</u>: 2 <u>Name</u>: Reader unit exception gate <u>Value</u>: 1 <u>Signifies</u>: All cards have been run out of the read feed and end-of-file is cn.

<u>Bit</u>: 3 <u>Name</u>: Reader check <u>Value</u>: 1 <u>Signifies</u>: A hole-count, shift-register, or address check occurred in the reader.

<u>Bit</u>: 4 <u>Name</u>: Reader validity check <u>Value</u>: 1 <u>Signifies</u>: More than one punch was detected in rows 1-7 of a single card column during reading in data mode 1. <u>Bit</u>: 5 <u>Name</u>: Reader hardware DE <u>Value</u>: 1 <u>Signifies</u>: Device-end is set on because of either an overrun condition or a not-ready to ready transition.

<u>Bit</u>: 6 <u>Name</u>: Reader status request <u>Value</u>: 1 <u>Signifies</u>: Set on for channel-end or device-end.

<u>Bit</u>: 7 <u>Name</u>: 1400 unit exception Value<u>: 0</u> <u>Signifies</u>: The last card has passed the read station 2 and end-cf-file is on.

2.50.4 PS (PUNCH ERANCH CONDITIONS)

A tranch (on condition or on mask) word with AS-decode=F is used to test these conditions.

<u>Bit</u>: 0 <u>Name</u>: Punch ready <u>Value</u>: 1 <u>Signifies</u>: The punch is in the ready state.

<u>Bit</u>: 1 <u>Name</u>: Not 4-bit mod pull on <u>Value</u>: 0 <u>Signifies</u>: A normal run-in has occurred (two feed cycles).

<u>Bit</u>: 2 <u>Name</u>: PFR unit exception gate <u>Value</u>: 1 <u>Signifies</u>: The last card has passed the punch station and end-of-file is on.

<u>Bit:</u> 3 <u>Name</u>: Punch check <u>Value</u>: 1 <u>Signifies</u>: A hole count, shift register, or address check occurred in the punch. <u>Bit</u>: 4

<u>Name</u>: PFR validity <u>Value</u>: 1 <u>Signifies</u>: More than one punch was detected in rows 1-7 of a single card column of a card read at the PFR brushes.

<u>Bit:</u> 5 <u>Name</u>: Punch hardware DE <u>Value</u>: 1 <u>Signifies</u>: Device-end is set on because of either an overrun condition or a not-ready to ready transition.

2.50.6 RPD1 (DIAGNOSTIC READER/ PUNCH BRANCH Bit: 6 Name: Punch status request CONDITIONS) Value: 1 Signifies: Set on for channel-end or A branch (on condition cr cn mask) word with AS-decode=8 is used to test these device-end. conditions. Bit: 7 Nct used Bit: Name: Tens AR A Value: 1 Signifies: Address for brushes or punch magnets. 2.50.5 RPS (READER AND PUNCH BRANCH CONDITIONS) Bit: 1 Name: Tens AR B A branch (on condition or on mask) word Value: 1 with AS-decode=E is used to test these Signifies: Same as bit 0. conditions. Bit: 2 Name: Tens AR C <u>Bit</u>: 0 <u>Nang</u>: Availatle <u>Value</u>: 1 Value: 1 Signifies: Same as bit 0. Signifies: The 2540 is on line. Bit: 3 Name: Tens AR D Value: 1 <u>Bit</u>: 1 Name: Data available (CSL) Signifies: Same as bit 0. Value: 1 Signifies: A branch condition during a CSL Bit: 4 operation with the reader. Indicates to Name: Tens AR E the microprogram to perform the same action Value: 1 as that occurring during reader traps. Signifies: Same as bit 0. Bit: 2 Bit: 5 Name: Pch Address Reg Check Value: 1 Signifies: 1400 time out. Value: 1 Signifies: Address check in diag op. <u>Eit</u>: 3 Name: 2540 Pch Trap Rqst Bit: 6 Name: Pch overrun check Value: 1 Signifies: Punch trap request or stacker Value: 1 conditions when using microdiagnostic Signifies: Punch overrun in diag op. \*500. Bit: 7 Bit: 4 Name: Pch shifting reg sync check Nang: Punch brush CL Value: 1 Value: 1 Signifies: Shift register check in Signifies: Card at prepunch check brushes. diagnostic operation. Bit: 5 Name: Punch decode D 2.50.7 RPD2 (DIAGNOSTIC READER/PUNCH BRANCH Value: 1 Signifies: Diagnostic function. Indicates CONDITIONS) that data is keing sent to the punch out of PC in single-cycle operation. A kranch (on condition or on mask) word with AS-decode=9 is used to test these conditions. Bit: 6 Name: Reader select D Value: 1 Bit: 0 Signifies: Same as bit 5 but for data from Name: Unit AR A the reader brushes to RP1 and RP2. Value: 1 Address for brushes or punch Signifies: <u>Bit</u>: 7 <u>Nare</u>: Punch select D <u>Value</u>: 1 magnets. <u>Bit</u>: 1 Signifies: Same as kit 6, but for data Name: Units AR B from PFR and punch check brushes to RP1 <u>Value</u>: 1 and RP2. Signifies: Same as bit 0.

<u>Bit</u>: 2 <u>Name</u>: Units AR C Value: 1 Signifies: Same as kit 0. <u>Bit:</u> 3 <u>Name</u>: Units AR D <u>Value</u>: 1 Signifies: Same as bit 0. <u>Bit</u>: 4 <u>Name</u>: Units AR E <u>Value</u>: 1 Signifies: Same as bit 0. <u>Bit</u>: 5 Name: Reader address reg check Value: 1 Signifies: Address check in diag op. Bit: 6 Name: Reader overrun check Value: 1 Peader overrun : Signifies: Reader overrun in diag op. Bit: 7 Name: Reader shift reg sync check Value: 1 Signifies: Shift register check in diagnostic operation. 2.51 CPU TO EXTERNAL FACILITIES (2540) The following are set on or off by means of a set/reset word in which the CS decode has the value listed. 2.5.1.1 R = K (CS DECCDE = E) Bi<u>t</u>: 0 Name: Reader check Value: 1 Signifies: Set on to indicate a hole-count error in reader. <u>Bit</u>: 0 Name: Reader check Value: 0 Signifies: Reset reader sense byte. Bit: 1 Name: Read feed Value: 1 Signifies: Signals reader to feed cards. Bit: 2 Name: Read select stacker R2 Value: 1 Signifies: Sets up for stacker selection in R2. Bit: 3 Name: Read select stacker R3 Value: 1

Value: 1 Signifies: Same as kit 2, but for stacker R3. <u>Bit</u>: 4 <u>Name</u>: Validity check <u>Value</u>: 1 <u>Signifies</u>: Set on when more than one hole is read from columns 1-7 of a single card column in the reader.

Bit: 5 Name: Sense set reader Value: 1 Signifies: Sets reader-check light on if bit 0 is on.

<u>Bit</u>: 6 Name: Reader status latch Value: 1 Signifies: Set at channel-end or device-end so that reader can request to present status in channel OIB. Value: 0 Signifies: Reset reader status and reader queued latches. <u>Bit:</u> 7 Name: Reader queued Value: 1 Signifies: Blocks attachment from sending reader status to channel OIB (Interrupt Buffer). Value: 0 Signifies: Reset reader device-end.

2.51.2 P = K (CS DECODE = F)

<u>Bit</u>: 0 <u>Name</u>: Punch check <u>Value</u>: 1 <u>Signifies</u>: Set on to indicate a hole-count error in the punch; turns punch-check light on.

Bit: 0 Name: Punch check Value: 0 Signifies: Resets punch sense byte. Bit: 1 Name: Punch feed Value: 1 Signifies: Signals the punch to feed cards. Bit: 2 Name: Punch select stacker P2 Value: 1 Signifies: Sets up for stacker selection in P2. Bit: 3 Name: Punch select stacker P3 Value: 1 Signifies: Same as bit 2, but for stacker

P3.

Bit: 4 Name: PFR validity check 1 Value: Signifies: Set on when more than one hcle is read by the PFR brushes, from columns 1-7 of a single card column. Bit: 5 Name: Punch restart gate (PFR write and feed comd) Value: 1 Signifies: Prevents rerun-in cf 3 cards; provides for normal run-in cf 2 cards after a PFR write and feed command in which a feed check occurred, or a feed check and a punch check occurred simultaneously. <u>Bit</u>: 6 Name: Punch status latch Value: 1 Signifies: Set at channel-end cr device-end so that punch can request to present status in channel OIB. Value: 0 <u>Signifies</u>: Reset device-end, punch status, and punch queued latches. Bit: 7 Name: Pch queued Value: 1 Signifies: Blocks attachment from sending punch status to channel OIB. 2.51.3 RP = K (CS DECODE = D)Bit: 0 Name: Unit-exception status reader accepted. Value: 1 Signifies: Indicates to reader circuits that reader ready can be turned off (i.e., the last card has been read and stacked on an end-of-file operation and unit-exception status has then been accepted by channel 0). Bit: 1 Name: 1400 latch Value: 1 Signifies: Causes a delayed feed for 1400 operations. Value 0 not used. <u>Bit</u>: 2 Name: Reader card interlock Value: 1 Signifies: Set on when any command is accepted by the reader. Resets when device-end is sent, for the command, to channel OIB. Bit: 3 Name: Reader machine check Value: 1 <u>Signifies</u>: Machine check occurred during reader trap microprogram. Value 0 not load PC from the punch-image area of used. auxiliary storage.

Bit: 4 Name: Punch command interlock <u>Value</u>: 1 Signifies: Same as bit 2, but for the punch. Bit: 5 Name: Punch machine check Value: 1 Signifies: Machine check occurred while microprogram was in a punch trap. Value 0 not used. <u>Bit:</u> 6 Value: 1 Signifies: Reader device-end. Bit: 7 Value: 1 Signifies: Punch device-end. 2.51.4 D = K (CS DECODE = 9)Bit: 0 Name: R/P diagnostic latch Value: 1 Signifies: Allows other diagnostic external lines to function. Bit: 1 Name: R/P diagnostic singleshot Value: 1 Signifies: Simulates reader or punch scan impulse to start read or punch (i.e., shifting into RP1 and RP2 or out of PO). <u>Bit</u>: 2 <u>Name</u>: R/P diagnostic single cycle Value: 1 Signifies: Allows bits to be shifted one at a time through RP1 and RP2 or PO. Bit: 3 Name: Diagnostic reset shift reg (reset) Value: 1 Signifies: Simulates a machine reset. Bits: 4,5,6,7 Not used 2.51.5 PC (CARD-PUNCH DATA OUT) Bits are set into this 8-bit register from P (punch image area of auxiliary storage). From PC the bits are then shifted out to the punch magnet latches during punching. A storage word with AS-decode=F is used to

## Section 1E. Channel Procedures

### 2.52 MULTIPLEXER CHANNEL DEVICE ADDRESSING

The multiplexer channel address (eight high-order bits of the 16-bit address) is 00 hex. Device addressing on the multiplexer channel depends upon how a device and its control unit operate with the channel. The Model 25 multiplexer channel has 32 subchannels, each cf which is associated with an individual device address. For devices that have their own control unit self-contained, and for control units that operate two or more devices simultaneously (such as the 2821), individual subchannel addresses are assigned to each device. These addresses are designated with a 0-bit in the high-order position of the device address. All of the 32 subchannels can be assigned to individual control units using the addressing shown in Figure 2-9.

Subchannel	Device Ad	dress
(UCW)	Binary	Hex
0	0000 0000	00
to	to	to
31	0001 1111	1F

Figure 2-9. Subchannel Addresses

For a third class of control units that can operate two or more devices of which only one can operate at a time, a single subchannel can be used with a special addressing scheme. The first eight subchannels also can be addressed and operated as shared subchannels. In this case, the 0-kit position of the device address is set to 1. The remaining three bits of the high-order byte are used to designate the subchannel instead of the normally used three tits in the low-order byte. The bits of the low-order byte are then used to designate the device address. The comparable addresses for use of the subchannel as individual control unit and as shared control unit are shown in Figure 2-10.

In assigning device addresses, be careful that a single subchannel is not addressed by both its individual address and by its shared address. If this were to happen, the operation data in the UCW could be accessed by both device operations and result in transmission errors for both devices. In addition these addresses should not be assigned to any of the integrated I/O devices assigned to channel 0 in a manner that would prevent the use of a UCW as either individual or shared. An example of this lockout would be the addressing the 2540 Reader as 01 and the 2540 Punch as 9X. Any attempt to use either of these addresses for channel devices would result in operating either the reader or punch of the 2540. The channel UCW-1 could not be used for the channel because the 2540 is selected first. The integrated I/O devices have their own UCWs.

Individual C.U. Address				Shar		
UCW		ary	Hex	C.U. Address Binary		Hex
		<u>_</u>				
0	0000	0000	00	1000	XXXX	8X
1	0000	0001	01	1001	XXXX	9X
2	0000	0010	02	1010	XXXX	AX
3	0000	0011	03	1011	XXXX	ВX
4	0000	0100	04	1100	XXXX	СХ
5	0000	0101	05	1101	XXXX	DX
6	0000	0110	06	1110	XXXX	ΕX
7	0000	0 <u>111</u>	07	1111	XXXX	FΧ
	Ł			T		
Share Bit						
UCW Address Bits						
Device Address						

Figure 2-10. Subchannel Addresses Individual and Shared Control Unit

### 2.53 SELECTOR CHANNEL DEVICE ADDRESSING

The selector channel address (eight high-order bits of the 11-bit address) is 01 hex. Device addressing on the selector channel may in theory be any of the 256 possible bit combinations. The addressing is limited at two points by the integrated disk storage devices that are also assigned to channel 1 and addresses 9X (Hex). The value of X ranges from 0 to 3 for the four possible disk drives. The remaining addresses have no special significance in the processing unit, and may be assigned as required by the program for the selector channel devices.

### 2.54 CHANNEL AND UNIT ADDRESSING RESTRICTIONS

No more than one addressing bit structure can be assigned to a specific I/O unit. Also, the same unit address may not be assigned to two or more devices.

### 2.54.1 CHANNEL 1

When the BURSTCH (selector channel) core load is loaded, device addresses 00 through FF are valid. Integrated 2311 units however, can be 0x-Fx and consume sixteen of these 256 possible address combinations.

2.54.2 CHANNEL 0 (EXCEPT 16K AND 24K SYSTEMS WITH BCTH THE MPX CHANNEL AND ICA FFATURES)

When the standard interface channel feature is installed and the BYTECH (multiplexer) ccre load is contained in control storage on 32K and 48K systems, the following device addresses may be used.

#### Device

Address	Usage
00-1F	MPX Channel single-unit adapter
	(SUA) addresses
20-3F	Communications attachment
	addresses*
40-7F	Invalid (condition code 3)
80-FF	MPX channel multiple-unit adapter
	(MUA) addresses
00-FF	Integrated 1052, 1403, and 2540**

- \* If the Integrated Communications Attachment (ICA) feature is nct installed, use of these addresses results in condition code 3.
- \*\* Although these integrated attachment features can use any address (00-FF), they should be assigned an address outside the ranges allocated for the MPX addressing capabilities of these facilities are not decreased.

	0 7	8 F
0	SUA 00 or MUA 8x	SUA 10
1	SUA 01 or MUA 9x	SUA 11
2	SUA 02 or MUA Ax	SUA 12
3	SUA 03 or MUA Bx	SUA 13
4	SUA 04 or MUA Cx	SUA 14
5	SUA 05 or MUA Dx	SUA 15
6	SUA 06 or MUA Ex	SUA 16
7	SUA 07 or MUA Fx	SUA 17
8	SUA 08	SUA 18
9	SUA 09	SUA 19
A	SUA 0A	SUA 1A
В	SUA 0B	SUA 1B
С	SUA OC	SUA 1C
D	SUA 0D	SUA 1D
Ε	SUA 0E	SUA 1E
F	SUA 0F	SUA 1F

\*(Except 16K and 24K Systems having both MPX and ICA features)

Figure 2-11. \*Auxiliary Storage Mcdule 2 (Channel)

Figure 2-11 is a map of auxiliary storage module 2 showing single-unit addresses and multiple-unit addresses (inside the figure), and the corresponding UCW addresses (figure cccrdinates), for systems <u>except</u> 16K and 24K systems having both the MPX channel and ICA features.

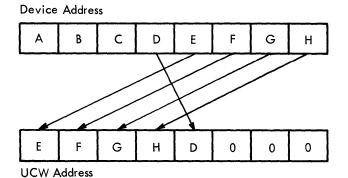
Eight UCWs (00-07) can be used either by SUA or MUA device addresses. Thirty-two subchannels are available (Figure 2-12).

MUA Device Addrs	SUA Device Addrs	Corresponding UCW Address	
8x	00	00	
••	10	00	
9x	01	10	
9X	11	18	
Ax	02	20	
AX	12	20	
Bx	03	30	
DX	13	38	
Cx	04	40	
	14	40	
Dx	05	50	
	15	58	
Ex	06	60	
EX	16	68	
 Fx	07	70	
FX	17	70	
	08	80	
-	18		
-	09	88	
	19	90 98	
		98 A0	
	0A	1	
-	1A	A8	
	OB	BO	
	1B	B8	
-	00	C0	
	1C	C8	
	0D	DO	
	1D	D8	
	0E	EO	
	1E	E8	
	OF	FO	
	1F	F8	

\*For all versions except the Combinational Versions of ICA and MPX Channel and 16K or 24K Program Storage

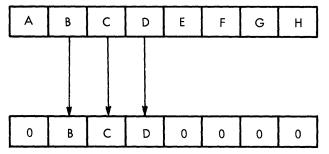
Figure 2-12. \*UCW Allocations (Channel)

The device address is used to develop the UCW address (except for 16K and 24K systems having both the multiplexer channel and ICA features) as shown in Figure 2-13. For <u>single-unit</u> addresses (SUA), A=0, B=0, C=0 for MPX, and C=1 for ICA:



For <u>multiple-unit</u> addresses (MUA), A=1, and E, F, G. and H are ignored:

Device Address



UCW Address

 \* Except for 16K and 24K systems having both the multiplexer channels and ICA features.

Figure 2-13. \*UCW Formulation (Channel)

2.54.3 CHANNEL 0 (16K AND 24K SYSTEMS WITH BOTH THE MPX CHANNEL AND ICA FEATURES)

When the standard interface is cperated on 16K and 24K system as a multiplexer channel (BYTECH loaded), the following device addresses are used.

Device	
Address	Usage
00-07	Invalid*
08-0F	MPX channel SUA UCWs
10-17	Invalid
18-1F	MPX channel SUA UCWs
20-27	Communications UCWs/LCWs**
28-7F	Invalid
80-FF	MPX channel MUA UCWs
00-FF	Integrated 1052, 1403, & 2540***

- Invalid addresses cause setting of condition code 3.
- \*\* If the ICA feature is not installed, these addresses are invalid.
- \*\*\* Unit addresses for these devices should not be assigned in the ranges reserved for the MPX channel cr ICA feature.

Figure 2-14 gives the UCW allocations for the multiplexer channel and integrated communications feature for 11K and 24K systems having both these features. Multiple-unit addresses (80-FF) and the corresponding single-unit addresses (18-1F) are mutually exclusive. Sixteen MPX subchannels are available with this system configuration.

MUA Device Addrs	SUA Device Addrs	Correspo UCW Ad		Feature
9x Cx 9X Dx Ax Ex Bx Fx    	18 19 1A 1B 1C 1D 1E 1F 08 09 0A 0B 0C 0D 0E	C0 C8 D0 D8 E0 E8 F0 F8 40 48 50 58 60 68		MPX Channei
	0F	78	<u>ا</u>	
		(UCW)	LCW	
     	20 21 22 23 24 25 26 27	80 88 90 98 A0 A8 B0 B8	00 08 10 18 20 28 30 38	Integr. Comm. Attach. (ICA)

Figure 2-14. MPX and ICA UCW Allocations for 16K and 24K Systems

Figure 2-15 represents a map of auxiliary storage module 2 for 16K and 24K systems having both the MPX and ICA features. It shows the SUA, MUA, and ICA device addresses and the corresponding UCW addresses.

	0 7	8 F
0	ICA	ICA
1	ICA	ICA
2	ICA	ICA
3	ICA	ICA
4	SUA 08	SUA 09
5	SUA 0A	SUA OB
6	SUA 0C	SUA 0D
7	SUA 0E	SUA OF
8	ICA	ICA
9	ICA	ICA
Α	ICA	ICA
В	ICA	ICA
С	SUA 18 or MUA 8x	SUA 19 or MUA 9x
D	SUA 1A or MUA 8x	SUA 1B or MUA Bx
E	SUA 1C or MUA Cx	SUA 1D or MUA Dx
F	SUA 1E or MUA Ex	SUA 1F or MUA Fx

\*Auxiliary storage module 2 for 16K and 24K systems with both the MPX and ICA features

Figure 2-15. \*Auxiliary Storage Mcdule 2 (Channel)

The algorithm used to build UCW addresses from device addresses for this system configuration differs from other versions, as shown in Figure 2-16.

2.54.4 ASSIGNING INTEGRATED 1052, 1403, 2311, AND 2540 DEVICE ADDRESSES

The microgrogram assembler system (MAS) assigns the device addresses shown in Figure 2-17. These standard addresses are placed in fixed auxiliary storage locations by the CSI deck.

The device addresses for the integrated attachments can be anywhere within the range of 00 through FF. The address to be used for any integrated attachment can be changed by changing the contents of the auxiliary storage location specified for that device in Figure 2-19.

MAS inserts FF in the auxiliary storage location for any of these optional attachment features <u>not selected</u> in the particular core load.

Putting FF in the auxiliary storage location for devices not included in the core load inhibits the use of FF as a device address for <u>any</u> device on the same channel.

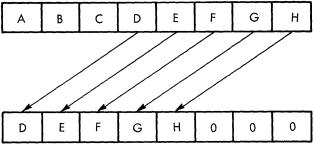
If FF is desired as a valid device address, the CE or SE must replace the FF, inserted by MAS for all attachment features

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not included, with any unused device address. This can be done by punching a card with the beginning data address, length of data field, and data to be loaded and by inserting the card in the MAS core load deck. The detailed instructions for preparing additional CSL cards are presented at the beginning of the BCPL microprogram routine.

For single-unit addresses (SUA), A=0, B=0, C=0 for MPX, and C=1 for ICA:





UCW Address

For <u>multiple-unit</u> addresses (MUA), A=1, and E, F, G, and H are ignored:

Device Address Δ В С D Ε F G Н C D В 0 0 0 1

UCW Address

\* For 16K and 24K systems having both the MPX and ICA features.

Figure 2-16. \*UCW Formulation (Channel)

		Standard Device Address	AS-Location of Device Address
Chni 0	1052 Printer- Keyboard 2540 Reader 2540 Punch 1403 Printer	1F 0C 0D 0E	00B4 00B5 00B6 00B7
Chnl 1	2311 Disk Storage Drive (con- trol unit address)	0090	0084

Figure 2-17. Standard Integrated Attachment Device Addresses and AS-Locations

### 2.55 MULTIPLEXER-CHANNEL UNIT CONTROL WORDS

A UCW (unit control word) contains the information necessary to sustain an I/O operation for a device. The UCW format for Channel-0 devices operated through the standard I/O interface is shown in Figure 2-18 and Figure 1-68.

		Byte			
0	1	2 and 3		4 and 5	6 and 7
Chnl	Flags	Data Address	1	ł	Next CCW
Status	and Op	Unit Status at Interrupt	Unit Addrs at Interrupt		Address

Note: Fields in this figure are defined in the associated text.

Figure 2-18. Channel-0 UCW Format (Standard I/C Interface)

The number of UCWs available for devices attached to channel 0 via the standard I/O interface depends upon:

- 1. the program-storage size, and
- the optional features installed on the system.

For 16K and 24K systems with both the multiplexer channel and integrated communications attachment features, 16 UCWs are available for the multiplexer channel. For all other systems, 32 UCWs are available for the multiplexer channel.

These UCWs are <u>in addition</u> to the UCWs allocated for the integrated 1052, 1403 2540 reader, 2540 punch, and communications lines.

The following definitions apply to the most common usage of the UCW bits (Figure 2-18). Refer to the microprogram listings

for exceptions during execution of various channel microprogram routine. Unless otherwise noted, the bit value is 1.

- 2.55.1 CHANNEL STATUS (EYTE 0)
- Bit Meaning
- 0 \*Secondary
- 1 Incorrect length
- 2 Program check
- 3 Protection Check
- 4 \*\*Channel data check
- 5 Channel control check
- 6 Interface control check
- 7 \*Interrupt in interrupt buffer
- \*Bits 0 and 7 indicate the following.
- 0 7 Indicate
- 0 0 Handling data, excepting data
- 0 1 Handling data, exception status
- 1 0 Status queued at I/O device
- 1 1 Status in IB (Interrupt Buffer)
- \*\* Channel data check can be set on only during input operations. The parity check is detected in the CPU A-register, and no machine check occurs.

### 2.55.2 OP-FLAG (BYTE 1)

- <u>Bit</u> <u>Meaning</u>
- 0 CDA (data chain in progress)
- 1 CC (command chain in progress)
- 2 SLI (Suppress Length Indication)
- 3 SKIP
- 4 PCI (Program Controlled Interruption)
- 5 \*Active
- 6 **\*\***Op 1
- 7 \*\*0p 2
- \* The active bit is on from the time that an operation is initiated at the device associated with the UCW until channel-send of the operation (i.e., such as for the last command of a command chain) has been stored in the CSW.
- <u>67</u> Indicate
- 0 0 Count zero (expecting channel-end)
- 0 1 Output command (write or control)
- 1 0 Read forward command (read or sense)
- 1 1 Read backward command (read backward)

#### 2.55.3 DATA ADDRESS (BYTES 2 AND 3)

Two bytes are used to maintain the current data address for the command operation; any System/360 Model 25 program-storage location can be specified with a two-byte address.

When status (channel-end) is presented by the device for the operation, the unit status byte is placed in the high-order address byte location. The device address is placed in the low-order address byte location. (The data address is no longer needed at that time.)

### 2.55.4 COUNT (BYTES 4 AND 5)

These two bytes contain the current count for the operation.

2.55.5 NEXT CCW ADDRESS (BYTE 6 AND 7)

These two bytes contain the address of the next CCW.

### 2.56 SELECTCR CHANNEL CONTROL INFORMATION

The information necessary to sustain an I/O operation on the selector channel is kept either in the IS-register reserved for the channel (U, V, G, and D in zone 7) or in K-addressable auxiliary storage locations.

The channel status, op-flag byte, count, and data address are kept in the and data address are kept in the channel LS-registers.

The next CCW address is kept in K-addressable auxiliary storage because this information is needed only if command chaining cr data chaining is performed.

2.56.1 CHANNEL STATUS (LS ZCNE 7 REGISTER G**0)** 

- <u>Bit</u> Meaning
- 0 Program-control interruption
- Incorrect length 1
- 2 Program check
- 3 Protection check
- Channel data check 4\*
- 5 Channel control check
- Interface control check 6
- 7\*\* Initial status received.
- This bit is meaningful only when the \* burst latch is on. When cff, this bit indicates that the channel is handling data, expecting data. When on, it indicates that data transfer is complete and channel-end has been presented by the I/C device.
- \*\* Channel data check can be set on only during input operations. The parity check is detected in the CPU A-register; no machine check occurs.

2.56.2 OP FLAG (LS ZONE 7 REGISTER G1)

Bit Meaning

- 0 CDA (chain data in progress)
- CC (command chain in progress) 1
  - SLI (suppress length indication)
  - Skip
- Ш PCI (program controlled interruption)
- 5\* General purpose
- 6\*\* Op 1

2

3

- Op 2 7\*\*
- This bit is used to store various indications and conditions at different points in the microprogram routines.
- \*\* When the burst latch is on, the Op-1 and Op-2 bits have the following significance.
- Meaning
- $\frac{6}{0}$   $\frac{7}{0}$ Count zero (excepting channel end)
- 0 1 Output command (write or control)
- Read forward command (read or sense) 1 0
- 1 1 Read backward command (read backward)

2.56.3 DATA ADDRESS (LS ZONE 7 REGISTER V)

Two bytes are used to maintain the correct data address for the command operation; any System/360 Model 25 program storage location can be specified with a 2-byte address.

When channel-end status is presented by the device for the operation, the unit status is placed in the high-order address-byte location (the data address is no longer needed at this time).

2.56.4 COUNT (LS ZONE 7 REGISTER U)

These two bytes contain the current data count for the operation.

2.56.5 NEXT CCW ADDRESS (AUXILIARY STCRAGE LOCATION 008A)

These two bytes contain the address of the next CCW.

2.57 CHANNEL ERROR-HANDLING PHILOSOPHY AND LOCOUT

Error conditions that can be detected by the Model 25 channel interface are:

Incorrect Length 1.

- Program Check 2.
- 3. Protection Check
- 4. Channel Data Check
- Channel Control Check 5.
- Interface Control Check. 6.

These error conditions are discussed in the System/360 Principles of Operation.

#### 2.57.1 CHANNEL STATUS BYTE

Channel status kits, stored in the CSW for Mcdel 25 channel operations, are defined as follows.

Incorrect Length (Bit 41): This condition is tested at channel-end time. The suppress incorrect length flag causes this indication to be suppressed.

<u>Program Check (Bit 42)</u>: All program checks (except when the data address used exceeds the installed program storage capacity) are detected by the microprogram.

Program checks caused by attempting to address a program storage location above the installed capacity are detected by circuitry.

<u>Protection Check (Bit 43)</u>: A circuitry test is made for this condition. In the Model 25, a protection check can occur only when data is being <u>stored</u> into core storage; that is, only when a read or sense is being executed.

<u>Channel Data Check (Bit 44)</u>: This condition is detected by setting a circuitry latch whenever the bus-in is being stored or gated into local storage or core storage. If incorrect parity exists during such an operation, the channel data check bit is set on.

If the latch is set when unit status cr unit address is being gated into local storage (because of incorrect parity), an interface control check is indicated. Also, see <u>Section 2.57.2.2</u> for errors that apply to the integrated attachments.

Channel control checks can occur only when the CPU check control switch is in the process position. When this switch is in the disable position, the check is ignored. When in stop, a hard stop occurs in the microprogram step in which the error occurred. The appropriate error lights are turned cn.

Channel Control Check (Bit 45): This error indicates that a machine check occurred during a channel-high or channel-low priority trap (MMSK bit 0 or 2 on).

Interface Control Check (Fit 46): Except as noted in the <u>Channel Data Check</u> section (unit status or address), this condition is detected by microprogramming.

Chaining Check (Bit 47): This indication is not used on the Model 25.

#### 2.57.2 LOGOUT

The channel performs a logout for two types of errors:

- 1. Channel Control Check (logged
- synchronously on the 1052), and 2. Interface Control Check (logged
- asynchronously in main storage).

### 2.57.2.1 Channel Control Check Logout

The channel microprogram initiates a logout on the 1052 <u>only</u> on channel control checks. A channel control check is a machine check while in a channel high or low priority trap.

The logout is as follows, When a channel control check trap occurs, this routine stores into the program storage starting at hex location 80 and prints out on the PR-KB (console printer-keyboard) through the ALDP routine, the following information.

- 80 Trap priority register (MMSK)
- 81 Branch condition register (BA)
- 82 Machine-check register (MC)
- 83 Error Count
- 84-85 Backup Address. Address of the microword where the machine check occurred.

Trap Priority (MMSK) Register

- Bit 0 Channel high pricrity trap
  - 1 2311 Disk Control trap
    - 2 Channel low pricrity trap
    - 3 2540 Reader trap
    - 4 2540 punch trap
    - 5 Communication bit service trap
    - 6 Communication character service trap
    - 7 Level-1 priority hold.

Branch Condition (BA) Register

- Bit 0 Channel-0 Interrupt Latch
  - 1 Mode Bit 0
  - 2 Mode Bit 1
  - 3 Mode Bit 2
  - 4 IPL Latch
  - 5 LS Zone Bit 0
  - 6 LS Zone Bit 1
  - 7 LS Zone Bit 2.

Machine Check (MC) Register

- Bit 0 File Control Check
  - 1 Storage Protect Parity Check
  - 2 Storage Address Parity Check
  - 3 Control Word Parity Check.
  - 4 Storage Data Parity Check
  - 5 ALU Error Check
  - 6 A-Register Parity Check7 B-Register Parity Check.

Machine-check trap occurs only if the M-bit (bit 13) of the PSW is on.

Because the logout latch is set here, no CPU instruction is executed before the printout of the logout area is completed.

Any previous PR-KB operation in process, such as alter/display display, instruction step address typeout, or normal 1052 functions, are terminated.

When a machine check or channel control check is detected, MMSK bit 9 is set and remains set until the check is subsequently logged out on the 1052. If a second machine check or channel control check occurs while MMSK-9 is still cn, the CPU clock is stopped with the appropriate error light on. The flowchart in Figure 2-19 shows the channel control check operation. This check can occur only when the check control switch is set to the process position.

### 2.57.2.2 Interface Control Check Logout

The channel performs an asynchronous logout in main storage when an interface control check is detected by the microprogram. The following information is logged.

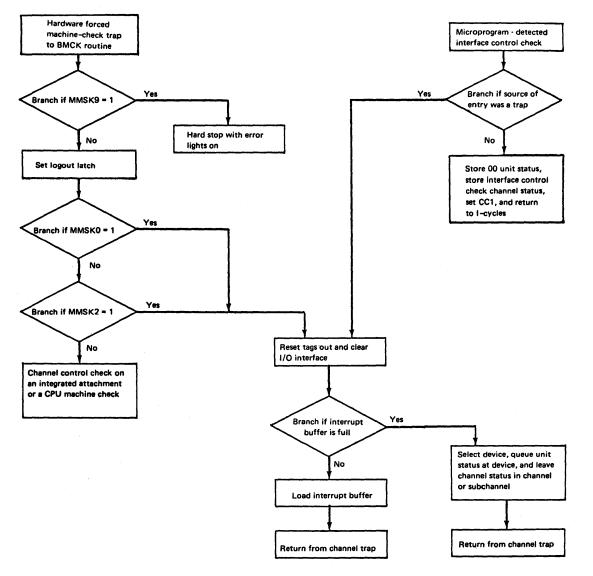


Figure 2-19. Channel Control Check Flowchart

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Stcrage	
Location	Contents
80	Trap priority register (MMSK)
81	Branch condition register (EA)
82	GS channel external conditions
83	Error count (6 Bits, 2-7; Bits 0,
	1=11)
84	GT channel external conditions
85	GD channel external conditions
86-87	Unit identification halfword.

Trap Priority (MMSK) Register

- Bit 0 Channel high priority trap
  - 1 2311 Disk Control trap
  - Channel low priority trap 2
  - Ш 2540 Punch trap
  - 5 Communication Bit service trap
  - 6 Communications character service trap
  - 7 Level-1 priority hold.

Branch Condition (BA) Register

- Bit 0 Channel-0 Interrupt Latch
  - 1 Mode Bit 0
  - 2 Mode Bit 1
  - 3 Mode Bit 2
  - 4 IPI Latch
  - 5 LS Zone Bit 0
  - 6 LS Zone Bit 1
  - IS Bit 2.

GS Channel External Conditions

Bit 0 Data chain request

- Buffered device latch 1
- 2 Channel-1 burst latch
- channel parity-error latch 3
- Initial selection latch Ц
- 5 Channel-1 interruption latch
- 6 Spare
- 7 Suppress control latch

GT Channel External Conditions

Bit 0 Address in

- 1 Not select-in 2\* Service-in
- 3\* Status-in
- 4 Operational-in
- 5 Not request-in
- Channel identification latch 6
- 7 Channel diagnostic latch
- \* Service-In and Status-In conditions from the interface are detectable in GT only if neither Command-Cut nor Service-Cut have yet been brought up in response to Service-In or Status-In.

- GD Channel External Conditions
- Operational-cut Bit 0
  - Service-out 1
  - 2 Address-out Command-out 3
  - μ. Spare
  - 5 Select-out
  - 6 Spare
  - 7 Suppress-out

Unit Identification Halfword

Byte 0

- Bits
- Meaning
- $\begin{array}{c|c} 0 & 1 & 2 \\ \hline 0 & 0 & 0 \end{array}$ Integrated 1052, 1403, or 2540
- 0 0 1 Multiplexer channel
- 0 1 X Selector channel
- 1 0 0 Integrated communications attachment

If bits 0-2 indicate the MPX channel feature, bits 3-6 are used for various functions under microprogram control.

If bits 0-1 indicate the selector channel feature, bits 2-6 are used as a timeout counter for interface sequences.

Bit 7 is used to indicate whether any unit or channel status may be stored directly in a CSW, or whether the interruption must be put in the interrupt huffer and subsequently cleared by an I/O instruction or an I/O interrupt.

Byte 1, for the selector channel or multiplexer feature, contains the current device address.

GA (Channel Conditions)

A set/reset word with CS-field=B is used to set or reset bits in GA. The set/reset bit in the set/reset word is ignored whether the bits are to be set or reset. The K-bit values determine which bits are set or reset. If a K bit=1, the corresponding bit in GA is set; if a K bit=0, the corresponding bit in GA is reset.

### <u>Bit</u> <u>Meaning</u>

- Selective reset. Drops 0
  - operational-out for 6 microseconds.
- Service-out 1
- Address-out 2
- 3 Command-out tı.
- Initial selection (Inhibits low-priority traps during an initial selection sequence. That is, data or chaining traps for channel 0, chaining or status traps for channel 1.)
- 5 Select-out
- Channel reset (diagnostic). Resets 6 channel latches.
- 7 Spare

#### 2.58 STANDARD INTERFACE HARDWARE

The standard interface hardware is identical for the multiplexer or selector versions of the channel. The function of the channel (multiplexer or selector) depends entirely upon the microprogram (EYTECH or BURSTCH).

Figure 2-20 is a summary of GA- and GB-register definitions.

		GA Register	GB Register
КН0	8	Not Op-Out (Set Only)	Data Chain Request Latch
KH1	4	Service-Out (Set/Rst)	Chnl ID Latch (Chnl 0 if 0; Chnl 1 if 1)
KH2	2	Address-Out (Set/Rst)	Burst Latch
кнз	1	Command-Out (Set/Rst)	Set Buffered Device Latch if 1; Reset Chnl Par-Error Latch if 0
KL0	8	Initial Selection (Set/Rst)	Channel Diagnostic Latch
KL1	4	Select-Out (Set/Rst)	Chnl 1 Interrupt Buffer
KL2	2	Diagnostic Chnl Reset	Not Used
KL3	1	Not Used	Suppress-Out Control

Figure 2-20. GA- and GB-Register Definitions

<u>Note:</u> <u>All</u> of the GA and GE latches may be displayed in one of the GS, GD, GT, cr GE/IN channel external displays (see Figure 2-21).

Display Bit	GS=C	GT=D	GD=E
0	Data Chain Reg Latch	Addrs-In	Op-out
1	Buffered Dev Lat	Not Sel In	Serv-Out
2	Burst Lat	Serv-In	Adrs-Out
3	Chnl Par Ck Lat	Stat-In	Cmd-Out
4	Initial Selection	Op-In	Spare
5	Chnl 1 IB	Not Reg In	Sel-Out
6	Spare	Chnl ID (Sel)	Spare
7	Supp Ctrl Latch	Channel Diag Lat	Suppress Out

Figure 2-21. Display of GA and GB External Facilities

2.59 EXTERNAL TO CPU FACILITIES (CHANNEL)

2.59.1 GS (CHANNEL BRANCH CONDITIONS)

A branch (on condition or mask) word with AS-decode=C can be used to test the following conditions. Unless otherwise ncted, a bit must be on (set to 1) for the meaning to be applicable.

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GS

<u>Bit</u>	<u>On If</u>	Meaning
0	GB0=1	Data chain request latch
1 2	GB3 <b>=1</b>	Buffered device latch
2	GB2=1	Burst latch (used only for
		channel 1; signifies that a
		burst operation is in
		progress).
3		Channel parity-error latch. A
		parity error has been detected
		on a byte received bus in.
4	GA4=1	
		Blocks channel-low priority
		traps.
5	GB5=1	-
Ŭ	0.00 1	(on to indicate that channel 1
		has status to present to the
		CPU).
6		STP trap inhibit latch.
7	GB <b>7=1</b>	
'	GD/-T	
		Indicates that a command chain
		is in progress and that a new
		CCW is being fetched by the

2.59.2 GT (CHANNEL BRANCH CONDITIONS)

channel.

A kranch (on condition or mask) word with AS-decode=D can be used to test the following conditions. These bits are in in-tags for the I/O interface.

GT

GD

- Bit Meaning 0 Address-in
- 1 Not select-in
- 2\* Service-in
- 3\* Status-in
- 4 Cperational-in
- 5 Not request-in
- 6 Channel identification latch
- 7 Channel diagnostic latch
- \* Service-in and Status-in conditions from the interface are detectable in GT only if neither command-out nor service-out has yet been brought up in response to service-in or status-in.

#### 2.59.3 GD (CHANNEL DIAGNOSTIC REGISTER)

A branch (on condition or on mask) word with AS-decode=E can be used to test these bits (from channel to interface).

GD		
<u>Bit</u>	<u>On If</u>	Meaning
0	GA0=0	Operational-Out
1	GA1=1	Service-Out
2	GA2=1	Address-Out
3	GA 3=1	Command-Out
4		Saved GB/IN Bit 1
5	GA 5=1	Select-Out
6		Not 1400 word separator
7	GB <b>7=1*</b>	Suppress-Out

\* Suppress-out is also testable if the interruption huffer latch is on.

2.59.4 GB/IN (CHANNEL BUS-IN)

A branch (on condition or on mask), storage, or move word with AS-deccde=F can be used tc access these bits. Eits 0 through 7 of GB/IN correspond tc bits 0 through 7 of the interface bus-in lines.

2.60 CPU TC EXTERNAL FACILITIES (CHANNEL)

#### 2.60.1 GB/OUT (CHANNEL BUS-OUT)

A storage or move word with AS-deccde=F can be used to set the bus-out register. This is the same decode used for the bus-in lines. The specific operation determines whether data is to be received into the bus-in (GB/IN) from the interface, or set into the bus-out (GE/OUT) from the CPU.

### 2.61 HANDICAD ROUTINE FOR CHANNEL

When the BCPL Routine has been altered or destroyed and a CSL from a card reader on the channel is not possible, the handload routine as shown in Figure 2-22 must be entered.

Addr	Word	Statement	Comment
0010	3210	SET MMSK K=81	Blcck traps
0012	2610	SET EC K=01	Set logout latch
0014	2C07	P0=0	Zerc cut switch
0016	2413	G0=0\$K01	Start setup of addr 0100
0018	51AF	TO=SWCD	SWCD equal device addr.
001A	802C	BR	Branch tc location 002C
002C	2486	SET MCDE K=38	Set channel mode, PCU zone
002E	2507	G0=0	Finish setup of addr 0100
0030	2B08	SET GA K=40	Set service out
0032	C9B3	BR IF GT4=1	Branch on OP-IN
0034	4FAF	GB/CUT=TO	Send device address out
0036	2B04	SET GA K=20	Raise address out
003,	2B44	SET GAK=24	and select out
003A	C9BA	BR IF GT4=0	Wait for OP IN
003C	2B40	SET GA K=04	Reset address out
003E	CDBE	BR IF GT0=0	Wait for address in
0040	2B23	T1=0\$K02	Build read command
0042	4FBF	GB/CUT=T1	Send cut read command
0044	2B42	SEI GA K=14	Raise command out
0046	FDC6	BR IF GT3=0	Wait here for status
004	5FBF	T1=GB/IN	Read status
004A	C4CA	BR IF ZNZ	Lccp here if invalid stat
004C	2B48	SET GA K=44	Set service out
004E	FDCF	BR IF GT3=1	Wait for
0050	EDCE	BR IF FT2=0	data
0052	5FFF	H1=GB/IN	Get data byte
0054	F05B	BR IF G07=1	ER if bcotstrap reading
0056	7F48	STE H1 AS, G+1	Uncenditional branch
0058	F05E	BR IF G07=0	
005A	6F48	STE H1 CS, G/1	
005C	055D	Z=G1 K50	Check if all data in,
005E	C4CC	BR IF ZNZ	if not, get more.
0060	8100	BR	Branch to bootstrap

Figure 2-22. Handload Routine for Channel

## Section 1F. ICA Procedures

### 2.62 NONOFERATIONAL LINES

All ICA lines are in a nonoperational state at shipment. If an I/O instruction is issued to a line, a condition code of 3 (nonoperational) is set. To make the lines operational, refer to microprogram routine GASN or the Model 25 Installation Instructions.

### 2.63 STATION SELECTION FEATURE

If the Station Selection feature is installed (check the front of the

microprogram listing for ADPREP), line addresses must be entered into storage via patch cards at ICPL time. Refer to microprogram routine GASN or the Model 25 Installation Instructions.

#### 2.64 JUMPER OPTIONS

Refer to logic pages HA000 for the jumpering options associated with the ICA and related data sets and/or modems.

## Section 2. Features

2.65 STORAGE PROTECT KEY--DISPLAY

Refer to <u>Section 2.1</u>.

#### 2.66 MULTIPLE CHARACTER SET

This feature allows the use of print chains or trains of other than 48-character size. The printer translate table must be loaded with utility program UT048 when the MCS feature is installed.

### 2.67 EXTERNAL INTERRUPTION

This feature allows the Model 25 to respond to signals from an external device or another CPU. An external interruption also can occur from the interrupt key on the system control panel (standard on the Model 25) or from the interval timer (special feature). An external interruption can occur only when PSW bit 7 (system mask) is set to 1. The specific interruption sources identified by PSW bits 24-31 are as follows.

Interruption	
Code Bit	External Interruption Cause
24	Interval timer
25	Interrupt key
26	External signal 2
27	External signal 3
28	External signal 4
29	External signal 5
30	External signal 6
31	External signal 7

The interval-timer and interruption-key lines are available from within the CPU.

#### 2.68 2560 PROCEDURES

2.68.1 HANDLCAD ROUTINE FOR 2560

When the BCPL routine has been altered or destroyed and a CSL from the 2540 is not possible, the handload routine as shown in Figure 2-23 must be entered manually. For bootstrap information, refer to the AKXXX logic pages.

Addr	Word	Statement	Comment		
0010	3210	SET MMSK K=81	Elcck all traps		
0012	2610	SET BC K=01	Set logout latch		
0014	2C07	P0=0	Zerc handload flag register		
0016	2413	G0=0\$K01	Euild high half CS addr 0100		
0018	80AC	ER	BR to 00AC		
00AC	240E	SET MCDE K=70	Put in mod/20, 2560 mode		
00 AE	2F04	SET MFA K=20	Select sec. feed (Note 1)		
00B0	2507	G1=0	Lcw half CS addr G=0100		
00B4	DAB8	BR IF MFT5=0	ER to 00E8 if NPRO req.		
00 B6	FD33	ER IF P12=1	BR if not ready		
00B8	2F10	SET MFA K=01	Set read ex.		
00 BA	DAC6	BR IF MFT5=0	Check NPRO		
00 BC	CAB9	BR IF MFT4=1	BR on no data available		
00BE	58FF	H1=MFR1	Read 1/2 byte		
00 C	5AEF	HO=MFR2	Read the other 1/2		
00C2	4EF3	H1=H0XH-H1L	Put two 1/2 bytes together		
00C4	6F48	STB H1 CS, G+1	Store them		
00 C6	2B14	SET MFC K=21	Rst NPRO, and rd. ex.		
00C8	055D	Z=G1 K50	Check fcr 80 bytes		
00CA	C4B4	BR IF ZNZ	If not 80, go to 00B4		
00 CC	8100	BR	BR to bootstrap addr 0100		
Note 1: To use the primary feed, replace this word with 2F80. The start key must be pressed at the end to complete the CSL (last card).					

Figure 2-23. Handload Routine for 2560

# Chapter 3. Preventive Maintenance

## Section 1. Basic Unit

- a. Perform the following maintenance every 26 weeks:
  - Test lamps using the lamp test key on the console. Replace lamps as necessary.
  - 2. Check blowers and replace filters every 26 weeks. Filters may require more frequent replacement depending on cleanliness of environment.
- B. Replace coil protect relay, part 2532227, under the following conditions.
   <u>1403 Model 2 or 7</u>
   Every 18 months based on average usage

of 2 to 2.5 million lines per month. <u>1403 Model N1</u> Every 12 months based on average usage of 5 to 5.5 million lines per month.

This schedule should be adjusted proportionally for any deviation from average usage.

- c. Run usage meter test every 6 months.
- d. 1052-7: Refer to the <u>Selectric I/O</u> <u>Keyboardless Printer FE Maintenance</u> <u>Manual</u>, Form 225-3207; <u>1052-1053</u> <u>Keyboard Printer FE</u> <u>Instruction-Maintenance Manual</u>, Form 225-3179.

# Section 2. Features

I/O DEVICE MAINTENANCE

Scheduled maintenance for I/O devices is included in the maintenance manual for the particular device.

## Section 1. Basic Unit

### 4.1 CPU TIMING

Timing for the CPU is developed from a crystal controlled oscillator. The CPU clock is located in board position B2-C4 and D4 on the A-gate.

### 4.1.1 SPECIFICATIONS

- 1. Oscillator frequency: 5.56 MHz ± .03%.
- 2. T-Pulses (Figure 4-1 and 4-2):
  - a. Width--180 ns +25/-10 ns, measured from the 1.2V level of the leading or rising edge to the 1.9V level of the trailing, or falling edge.
  - b. Level--each pulse has a down level of 0.49V to 1.06V, and an up level of 2.68V to 3.33V.
  - Overlap--adjacent T-pulses are C. overlapped by 90 ns  $\div$ 25/-10 ns as measured from the 1.2V level of the rising pulse to the 1.9V level of the falling pulse.
  - đ. Skew--the skew between TO pulse and T2 pulse (and subsequent alternate pulses) on the transmission line is +30/-25 ns, as measured from the 1.9V level of the falling pulse to the 1.2V level of the rising pulse.
- Clock Pulses On the Boards: (applies 3. to nets driven by line receiver-power driver):
  - T-pulses--(180 ns) have +20/-40 ns а. tolerance as measured from the 0.3 volt level of the rising pulse to the 1.8 volt level of the falling pulse.
  - P-pulses--(90 ns) have +20/40 ns b. control tolerance as measured from the 0.3 volt level of the rising pulse to the 1.8 volt level of the falling pulse.

### 4.2 CORE STORAGE ARRAY TEMPERATURE CONTROL

#### 4.2.1 COOLING

The BSM (Basic Storage Module) provides the SLT cards with forced air cooling with fans operating at 208-volts ac 60-cycle single phase, or 220-volts ac 50-cycle single phase.

### 4.2.1.1 Specification

The maximum temperature anywhere within the BSM must not exceed 133F(55C).

### 4.2.2 HEATING

A heater, fan, and associated control circuitry provide a wide temperature range by maintaining the core array at a fixed elevated temperature. The heater element, control circuits, temperature adjustment, and temperature sensing devices are packaged in a complete heater subassembly that is part of the BSM.

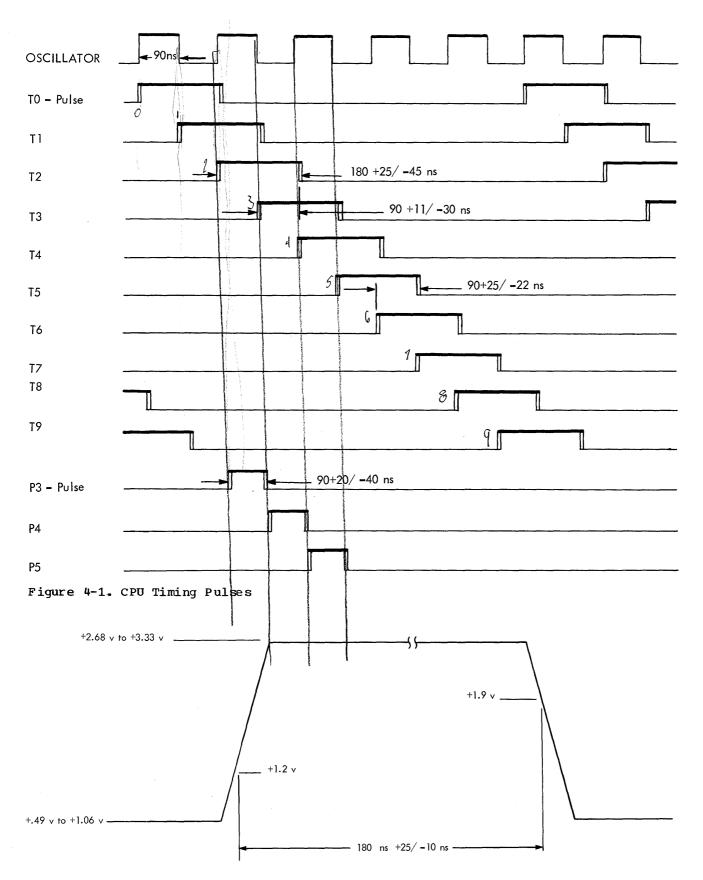
### 4.2.2.1 Specifications

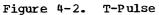
- The array inlet temperature must be 1. maintained at 105±3F(40.4±1.7C).
- 2. The low temperature light on the console must go off when the array inlet temperature exceeds 96±5F(35.6±2.8C).
- 3. The thermal trip mechanism (normally closed switches) operates at over and under temperatures of 120±3F and 96±5F(49±1.7C and 35.6±2.8C).

### 4.2.2.2 Heater Adjustment

Do not attempt to adjust the array inlet temperature if the machine ambient temperature is greater than 95F(35C).

- With power on, allow five minutes for 1. warm-up.
- 2. Carefully insert a nonmetallic thermometer (part 5392366 or equivalent) through the array cover access hole and into the rear of the heater plenum. The thermometer should extend about 3.25 in. (82,6 mm) into the unit and the tip should be slightly downward.
- The heater adjustment potentiometer is 3. adjusted from the front of the heater box. Turn the potentiometer clockwise to decrease the temperature or counterclockwise to increase the temperature until a stabilized temperature of  $105\pm3F(40.4\pm1.7C)$  is indicated. Allow about three minutes for the thermometer to record properly. 4. Remove thermometer.





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#### 4.3 SCHMOO CURVE (MAIN STORAGE)

#### 4.3.1. EXAMPLE OF SCHMOO CURVE PROCEDURE

Figure 4-3 shows an example of a typical four-point schmoo procedure. It is used for plotting the optimum storage strobe and voltage operating point. A no-failure voltage and strobe setting is selected as a starting point. The voltage is varied over its range up and down to a point of failure, and varied from that failing point into the no-failure range (1 in Figure 4-3). The no-failure points are determined at four different strobe settings by running the worst-case patterns (Section 4.3.4.1) with the diagnostic control switch set at TEST PATTERN. Switches A, B, C, D must equal FF00, 00FF, 01FE, or, FE01.

Once the no-failure voltages have been plotted, the optimum strobe setting for a

single BSM is a point where the difference between the upper and lower BSM limits is greater than 5.0 volts (2 in Figure 4-3). At a strobe setting  $\pm$  10 ns from optimum, the difference between the high and low voltage setting must be greater than 3.0 volts (3 in Figure 4-3).

For a double BSM, the difference between the upper and lower BSM limits at optimum strobe must be greater than 3.6 volts. At a strobe setting ±10 ns from optimum, the worst-case diagnostic must still run successfully. In both cases the strobe setting must be between 35 ns and 55 ns. It should be the earliest setting that will meet requirements, and 35 ns should be used if possible.

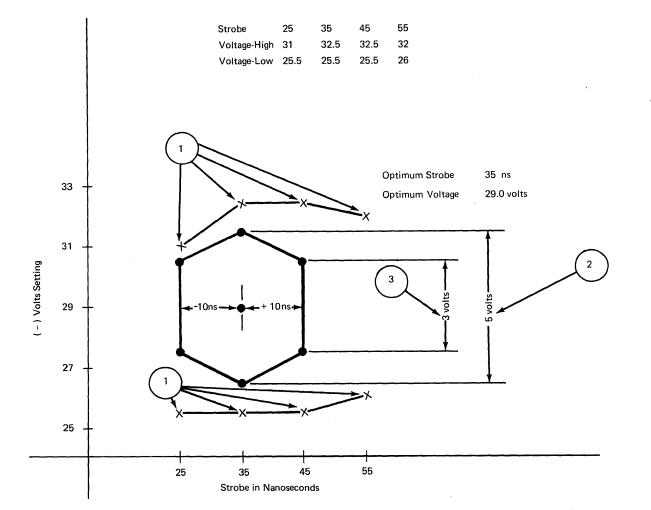


Figure 4-3. Schmoo Curve Example (Single BSM)

### 4.3.2 WHEN TO SCHMOO

A four-point strobe and a two-point strobe schmop procedure are given. The four-point strobe schmop procedure should be used only when an array is replaced. The two-point strobe schmop procedure should be used only under the following conditions.

- When any one of the following cards is replaced or identified as a trouble area.
  - a. Sense amp, part 58004648
  - b. Source driver, part 58004649
  - c. Strobe, part 58007237
  - d. Clock, part 58001762
- 2. An intermittent problem exists and it is desired to increase the failure rate to isolate the trouble within the memory area.
- 3. On a new memory installation.

#### 4.3.3 SERVICE CHECKS

### Refer to <u>Section 4.3.6</u>, <u>Checkout</u> <u>Procedures</u>.

#### 4.3.4 WORST-CASE PATTERNS

The worst-case test patterns are run from the console by the customer engineer as a diagnostic to test the storage unit for a failing condition. The test is done with the diagnostic control switch set to TEST PATTERN, and the check control switch set to STOP.

### 4.3.4.1 Worst-Case Test

Each test should be run for approximately fifteen seconds with switches A, B, C, and D set as follows.

		Α	В	С	D	Test Description
1st	Test	0	0	F	F	Checks worst-case zeros
						(adds noise to cores)
2nd	Test	F	F	0	0	Checks worst-case one's
						(subtracts noise from
						cores)
3rd	Test	0	1	F	Е	Checks parity bits
4th	Test	F	Е	0	1	Checks parity bits

4.3.5 FOUR-POINT STROBE SCHMOO PROCEDURE

Note: For measuring critical voltages, use Weston\* 901 (or equivalent)

- Set the -30 voltage (XYZ) to -29 volts ±0.5 volts.
- 2. The schmoo timing points are taken at 25 ns, 35 ns, 45 ns, and 55 ns.

\*Trademark of Sangamo Electric Co., U.S.A.

- 3. Refer to logic MD008 for instruction on how to set the strobe card. The strobe card is part 5807237 and is plugged in B1E3.
- 4. Start the schmoo at a setting of 35 ns.
- 5. Run worst-case patterns (Section 4.3.4.1) at -29 volts. If failures are noted (stor data light turns on), lower the voltage until a running point can be found. To restart the test after failure, press CHECK RESET then START. If no running point can be found, consult memory strategy diagrams in the 2025 Maintenance Diagram Manual (MDM).
- Increase voltage in one volt increments and run the worst-case patterns until a failure occurs.
- Decrease the voltage in one-half volt increments and run the worst-case patterns until no failure occurs. Record this voltage as the upper voltage limit for this particular strobe setting. Figure 4-3 shows an example that can be used as reference for this procedure.
- Start at running point found in step 5, repeat steps 6 and 7 <u>in the opposite</u> <u>direction</u>, and record the setting found in step 7 as the lower voltage limit for this strobe setting.
- Repeat this procedure, beginning at step 5, using strobe settings of 25 ns, 40 ns, and 55 ns, and plot these values on a graph (Figure 4-3).
- 10. The optimum strobe setting for a single BSM is at a point where the difference between the upper and lower BSM limits (on the graph) is greater than 5.0 volts. At a strobe setting ± 10 ns from optimum, the difference between the upper and lower BSM limits must be greater than 3.0 volts.

For a double BSM, the difference between the upper and lower BSM limits at optimum strobe must be greater than 3.6 volts. At a strobe setting ±10 ns from optimum, the worst-case diagnostic must still run successfully. In both cases the strobe setting must be between 35 ns and 55 ns. It should be the earliest setting that will meet requirements, and 35 ns should be used if possible.

 Set the voltage midway between the upper and lower limits (steps 7 and 8) for the optimum strobe setting.

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### 4.3.6 CHECKOUT PROCEDURES

- Check to see if all logic voltages are within tolerances, that the array heater is operating, and that the array temperature is properly adjusted (Section 4.2).
- 2. Measure the voltage on B1U2D07 (referenced to B1U2D08) using a Weston 901 meter (or equivalent). The sense-amplifier voltage is set to -18 volts ± 0.1 volt accuracy (see decal) by means of the potentiometer on the card located in B1U2.

At EC 799307, 16K and 32K BSM sizes have the -18V set at -17.6V. The 32K BSM remains at -18V.

### CAUTION

This is a critical, highly regulated voltage that is set under controlled conditions at the factory before shipment. The voltage setting should be changed <u>only</u> when the card that generates it is replaced. It should then be set using a Weston 901 meter (or equivalent). In case of array replacement, this voltage should <u>not</u> be touched.

- 3. Changing any memory card should not change the timing more than 5 ns.
- The optimum strobe setting of the System/360 Model 25 memory should fall between 35 to 55 ns.

### 4.3.6.1 Scoping Main Storage

Refer to Section 1.31 for main storage diagnostic information and scope waveforms.

4.3.7 TWO-POINT SCHMOO PROCEDURE

<u>Note</u>: Use a Weston 901 meter (or equivalent) when measuring the -18 voltage. The -18 volt supply should not be changed, and should measure as follows.

- 8K (16K bytes) -17.6 volts 12K (24K bytes) -17.6 volts
- 16K (32K bytes) -18.0 volts
- Record the voltage at which memories are set.
- 2. Vary the voltage 2 volts above that voltage.
- 3. Run the worst-case patterns (Section 4.3.4).
- 4. Vary the voltage 2 volts below value recorded in step 1.
- Run the worst-case patterns. If machine does not fail at this voltage setting, restore the voltage to that recorded in step 1. (This indicates that memory is within operating schmoo tolerance; return to routine in )MDM.)
- 6. If machine fails during steps 3 or 5

(indicated when STOR DATA lights on console), measure the -18 volt supply between, B1U2D07 and B1U2D08 (MD999) to ensure it is not grossly in error. If the spread from high to low operating limits is still below 4 volts, a memory component failure is indicated. Set the voltage and strobe as recorded in step 1, indentify the circuit failure, and re-schmoo the memory (starting at step 2).

- Vary the -30 volt supply 0.2 volts toward the voltage recorded in step 1.
- 8. Repeat the worst-case pattern that failed in step 6.
- 9. If failures continue, repeat step 7 and step 8 until no failure is detected and record the voltage setting used in this step.

CAUTION

Do not exceed -35 volts.

- Set the voltage 4 volts from the limit recorded in step 9 toward the original setting (step 1).
- 11. If the worst-case patterns run at voltage setting in step 10, set the voltage midway between the high and low operating limits.
- 12. If the worst-case patterns do not run at the voltage setting in step 10, increase the strobe timing on the failing BSM, 5 ns.

Note: The failing BSM can be identified by the higher address-bit of the failing address. 0=lower BSM, which is adjacent to power supply; 1=higher BSM, which is adjacent to console.

13. Repeat procedures starting at step 1 and attempt to establish a 4-volt spread from the high to low operating limits.

#### 4.4 MAIN STORAGE REPLACEMENT

- 4.4.1 REMOVING THE 0-32K UNIT
- Ensure that power to the system is off.
   Disconnect the wires from terminal blocks TB12-L and U. These are the terminal blocks at the heater box. Label the wires if necessary.
- 3. Remove the power-input cable from LBC-1 (mounted on top of CSU frame). Number the wires if necessary.
- 4. Remove the ribbon cable connectors from B1A3, B1A2, and B2A2. Remove the cable clamp and cables.
- 5. Lift the storage unit free of its hinges and remove.
- 6. Replace in the reverse order.

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#### 4.4.2 REMOVING THE 32-64K UNIT

- 1. Ensure that power to the system is off.
- Disconnect the wires from terminal blocks TB12-L and U. These are the terminal blocks at the heater box. Label the wires if necessary.
- Remove the power-input cable from LBC-1 and 2 (mounted on top of the BSM frame). Number the wires if necessary.
- Remove the ribbon cable connectors from B1A2, B1A3 and B2B2. (These are cables from the adjacent 32K unit.) Remove the cable clamp and cables.
- 5. Lift the storage unit free of its hinges and remove.
- 6. Replace in the reverse order.

#### 4.4.3 ARRAY CHANGING

To remove the array from either storage unit:

- 1. Ensure that power to the system is off.
- 2. Viewing the core storage unit from the card side, remove the outrigger by loosening the screws on the BSM frame and array. Lift the outrigger up to remove.
- Open the two side doors (right and left side of array).
- Disengage the four locking screws in the array cover and remove the cover.
- Loosen the two screws on the underside of the cross member that separates the B1 and B2 card areas. These screws hold the sense cable clamp and the array to the frame.
- Remove the top cover (B1 board card area) and unplug the sense cables.
- 7. Remove the two screws holding the heater plenum to the array.
- Remove the six screws (four on card side, two on opposite side) in the bracket holding the heater plenum to the BSM frame.
- 9. Viewing the BSM from the front, place one hand beneath the heater plenum to the BSM frame (located immediately above the terminal blocks). The heater can now be lowered down away from the array.
- 10. Using the diode board stiffeners and/or the U-shaped bracket (not diode boards), pull the array out by rocking it up and down slightly until it comes free from the large board. Cover the top of the array (C-side) and carefully feed the sense cables down through the card area as the array is removed.
- 11. Replace in the reverse order.

#### 4.4.4 CHANGING DIODES

If diode or drive-line trouble is suspected in storage, follow the storage address lines in storage logic through the read/write drivers and eventually to the pin numbers on the array diode cards.

The logic shows the layout of the array diode cards and diode pack. The removal procedure is:

- Extract the array from the logic boards.
- Place the array carefully on a flat work area.
- 3. Unsolder the four diode-pack pin connections, taking care not to apply excessive heat or to damage any land pattern.
- 4. Extract the defective diode-pack and replace it with a tested spare.
- 5. Inspect the card for damage.
- 5. Inspect the card for damage.
- 6. Replace the array.

Note: Diode card location on array ALD page MD007. Diode-pack location on diode card ALD page MD007. Diode-pack pin location on ALD page MD007, Note 2. Diode cards land patterns on ALD pages MD860-MD890.

### 4.5 LOCAL STORAGE

Two delay lines are used in the local storage (B150 stack) circuit (01A-B1E2). The tolerance on the delay lines is  $\pm$  4.5 for the 90 ns delay line and + 3.0/-2.0 for the 30 ns delay line. The 30 ns delay line controls the sense amplifier gate pulse (LS Read Line), and the 90 ns delay line controls the bit timing pulse (LS Write Line) and the width of the X- and Y-address lines.

#### 4.5.1 SCOPING LOCAL STORAGE

Refer to Section 1.32 for local storage waveforms.

#### 4.5.2 INITIAL DELAY LINE SETTINGS

The initial settings for the two delay lines are: LS Read Line -- 30 ns LS Write Line -- 90 ns.

### 4.5.3 DELAY LINES (LOCAL STORAGE) ADJUSTMENT

 Store the following arithmetic into an unused portion of control storage (FE trap area). U0=U0 + U1 (hexword 6013) followed by an unconditional branch back to this word.

Example:	:
Hexword	
Address	Hexword
0 280	6013
0282	8270

- Sync the scope on word type 3 (01A-B1G7B05).
- Scope and record the duration from the 10% fall -LS ADDR X0 to the 10% fall -LS READ LINE (ALD-CC131). Refer to Figure 4-4.

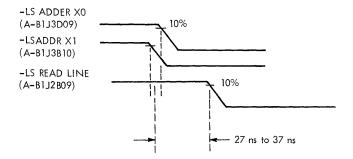


Figure 4-4. LS Address Lines and Read Line

- 4. Scope and record the duration from the 10% fall of -LS ADDR X1 to the 10% fall of -LS READ LINE. Refer to Figure 4-4.
- 5. Take the average of the durations recorded in steps 3 and 4. The average of these two durations must fall between 27 ns to 37 ns. If the average does not meet this requirement, plug the appropriate jumpers to increase or decrease the delay.
- Scope -LS ADDR X0 and +IS WRITE LINE using the same sync as in step 2. These two signals must be coincident for a minimum of 70 ns from the 10% point of the rising edge to the 10% point of the falling edge (Figure 4-5).
- 7. Scope +LS ADDR Y0 to ensure that the

same coincidence holds true as in step 6 (Figure 4-5). If not, the delay line value must be increased to satisfy this requirement.

Note: In Figure 4-5, points E and F must fall inside points A and B, and C and D, for a minimum of 70 ns. The +LS WRITE LINE may fall outside address pulses if there is no second address selected.

### 4.5.4 LOCAL STORAGE/STORAGE PROTECT CARDS

Machines with the storage protect feature use a local storage card in the storage protect circuits (the cards are identical). If the local storage card is suspected to be failing, it can be swapped with the storage protect card.

Refer to <u>Appendix A</u> for detailed operation and circuit specifications.

### 4.6 SCR CIRCUITS

There are three spare indicator SCR circuits for use as replacements for defective SCR light drivers. The load input pins, wire number and cable position on the SCR boards in cable part 2532050 are as follows.

Location	Wire No.	Cable Position
A2A2B10	19	20
D1N7B10	39	20
C2N7D09	57	9

The wires 19, 39, and 57 are connected to the SCR in the respective paddle card. The console-end of these spare wires are taped back in a group. Figure 4-6 shows the point from which continuity can be checked to find the correct spare wire at the console-end of the cable.

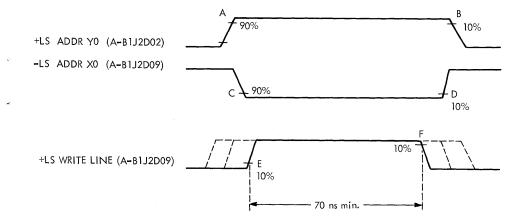


Figure 4-5. Local Storage Address Lines and Write Line

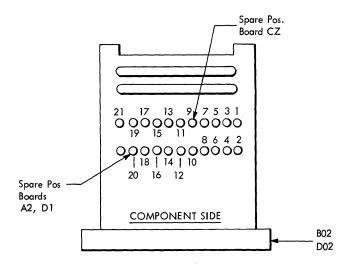


Figure 4-6. SCR Card Cable-Connecting Terminals

### 4.6.1 REPLACEMENT

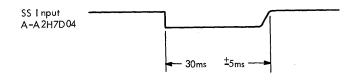
Connect the signal to the input pin of the spare circuit to be used. Replace the wire to the indicator lamp with the spare cable lead to be used.

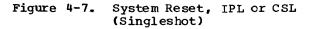
### 4.7 SYSTEM RESET, IPL, OR CSL--SINGLESHOT

The CPU contains a singleshot that is activated when the system reset, IPL, or ICPL switches are pressed. Its purpose is to prevent switch bounce noise from stopping the CPU clock.

#### 4.7.1 ADJUSTMENT

- Turn the process switch to single cycle and press the system reset key.
- Adjust the singleshot (logic PF 251) to 30 ms ±5 ms, using the upper potentiometer (Figure 4-7).





### 4.8 OPERATIONAL OUT--SINGLESHOT

The System/360 standard interface contains a singleshot (A-E1G7) with an adjustable potentiometer on it to adjust the operational-out signal.

### 4.8.1 ADJUSTMENT

Scope A-E1G7D12 and adjust the lower potentiometer on A-E1G7, while pressing the system reset key, to obtain a negative pulse of  $8.0 \text{ us } \pm 1/-0 \text{ us.}$ 

#### 4.8.2 CHECKOUT PROCEDURE

Operational-out singleshot is checked in routine 3 (YMO3) in the channel microdiagnostic \*600. See instructions in routine YMO3 for adjustments.

### 4.9 2540 ATTACHMENT

The optional 2540 attachment consists of two SLT boards located in the A-gate, E2, and E3. Three leading-edge time delay cards are located at A-E3D5, A-E3E5, and A-E3E4.

### 4.9.1 SPECIFICATIONS

The 2540 attachment clock is driven from a 1.667 megahertz oscillator located in the A-E3 board. This provides a 4.8 us clock cycle for communication with the 2540 and the attachment in the CPU.

The timing for the three leading-edge time delay cards are as follows.

Location	Timing	
A-E3D5	150 us,	+20/-0 us
A-E3 E5	2.2 ms,	+50/-50 us
A-E3E4	5.5 ms,	+0/-100 us

### 4.9.2 ADJUSTMENTS

The adjustments for the three leading-edge time delay cards are made using the following routines in the nonresident microdiagnostics.

Card Location	<u>Microdiagnostic</u>		Logic
A-E3D5	VM07	(Reader-Punch)	RT015
A-E3E5	VM08	(Reader-Punch)	RT021
A-E3E4	VM20	(Reader-Punch)	RT041

### 4.10 PR-KB (1052-7) -- SINGLESHOTS

The PR-KB attachment circuitry is located on the A-gate, A2 board. The circuitry contains two singleshot cards having two adjustable singleshots per card.

### 4.10.1 SPECIFICATIONS

The singleshots must be adjusted so that when the input signal goes from its negative level to its positive level, the output of the singleshots will go to a <u>negative level</u> for the following durations.

Number: SS1 Duration: 28.0 ms (+15.0 ms/-1.0 ms) Location: A-A2G7D04 (PF021) Upper Pot.

Number: SS2 Duration: 500 ns (+100 ns/-100 ns) Location: A-A2G7D06 (PF021) Lower Pot.

<u>Number</u>: SS3 <u>Duration</u>: 40.0 ms (±15%) Location: A-A2H7D06 (PF021) Lower Pot.

### 4.10.2 ADJUSTMENT

Refer to TYDD diagnostic routine \*110. This describes the procedure to adjust and check the PR-KB singleshots.

### 4.11 2311 READ CLOCK ADJUSTMENT

The 2311 read clock card is located in the B-gate in E3-board, J5-socket. This adjustment procedure makes use of the write clock signal as an input to the read clock to allow the adjustment to be made without using a disk drive.

Note: Use a Tektronix\* 453 oscilloscope or equivalent.

SCOPE SETUP Chan 1: B-E3J5J10 (FA 111) Chan 2: B-E3J5G02 (FA 111) Sync: Minus Internal Chan 1

- Jumper B-D3M5D05 to ground (D08 pin). This resets the chain-end and NTO-OP latches (FA 651).
- Jumper B-E3J3B04 (FA 109) to B-E3K6B09 (FA 111). This feeds write pulses into the read clock.
- 3. Jumper B-E3J5G04 (FA 111) to ground (D08). This forces the read clock to use the long time constant.
- SYNC minus (-) on Channel 1. This is the 800 ns write pulse (Figure 4-8). Make certain that points A and B are exactly 8 divisions apart. If they are not, adjust the scope until they are.
- 5. Display Channel 2 and adjust potentiometer on B-E3J5 (FA 111) until

-----

\*Trademark of Tektronix, Incorporated

the 10% level of the rising clock pulse is 640(+0,-5) ns from point A.

6. Remove all jumpers.

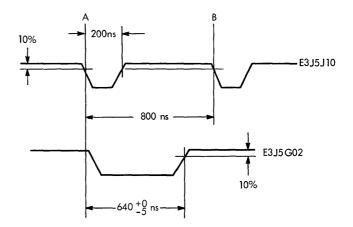


Figure 4-8. Read Clock Traces

#### 4.12 DAC--SINGLESHOTS

4.12.1 SPECIFICATIONS

Recalibrate Time Out S	551 16 ms (± 5%)
Recalibrate Time Out S	5S2 16 ms (± 5%)
Head Conditioning SS	60 us (± 5%)
Index SS (2)	400 ns (± 5%)
Control Tag SS	1.0 us (minimum)

### 4.12.2 ADJUSTMENTS

All singleshot adjustments for the DAC are made while using microdiagnostic \*300, routine 6. First, load \*300, set switches ABCD to 0106, press and release SET IC, and press and release START. This forces a loop on routine 6. For the adjustment to be performed, the sense switch specified in the adjustment must be on. Only one section sense switch can be on at any one time.

4.12.2.1 Head Conditioning Singleshot (FA131)

- 1. Turn section sense switch 2 on.
- 2. Sync the scope on 01B-E3G7D12 (negative).
- Look at the output on E3G7D04 and adjust to 60 us ± 5%.

4.12.2.2 Index and Delta Index Singleshots (FA131)

- 1. Turn section sense switch 3 on.
- 2. Sync the scope on O1B-E3G3D12 (neg).
- Look at the output on E3F2D13 and adjust to 400 ns ± 5% by varying the

bottom potentiometer.

 Look at the output on E3F2B13 and adjust to 400 ns ±5% by varying the bottom potentiometer.

4.12.2.3 Control Tag Singleshot (FA225)

- 1. Turn section sense switch 4 on.
- 2. Sync the scope on 01B-E3F2D02 (negative).
- 3. Look at the output on E3F2D12 and adjust to one microsecond (minimum) by adjusting the upper potentiometer.
- 4.12.2.4 Recalibrate Singleshots (FA611)
- 1. Turn section sense switch 5 on.
- 2. Sync the scope on 01B-C3C2B10 (negative).
- Look at the output on C3C2D11 and adjust to 16 ms ± 5% by varying the upper potentiometer.
- 4. Sync the scope on 01B-C3C2D13 (negative).
- 5. Look at the output on C3C2D12 and adjust to 16 ms  $\pm$  5% by varying the lower potentiometer.

#### 4.13 DAC--TIME DELAY CIRCUITS

#### 4.13.1 SPECIFICATIONS

The DAC contains two time-delay cards that have two delay circuits on each card. These delay circuits are pluggable in increments of 5 ns with a maximum of 125 ns delay per circuit.

These circuits are plugged at 75 ns and 125 ns in the 2025 DAC.

### 4.13.2 CHECK

- 1. Loop \*300 routine 05.
- 2. Scope delays as indicated in Figure 4-9.
- 3. Refer to ALD ZZ016 for card plugging if necessary.

### 4.14 1403 ATTACHMENT (FIGURE 4-10)

An optional integrated printer attachment may be provided in the CPU. This attachment is capable of operating either a

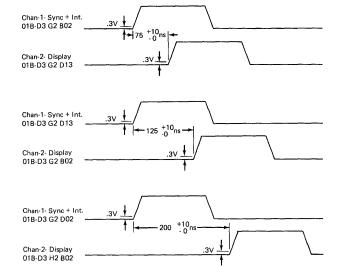


Figure 4-9. DAC Time Delay

1403-2, 1403-7, or 1403-N1 printer. The attachment is housed in the CPU frame on the A-gate. Three boards, B3, C3, and D3, contain the control logic. A fourth board, H-P1, contains hammer, magnet, and indicator drivers, including associated interface circuitry for the printer. The H-P1 board is located in the power tower.

The integrated printer attachment uses SLT circuits of the 30 nanosecond group for all areas except for the hammer and magnet drivers, and interface to the printer. The hammer and magnet drivers are mounted on SLT cards and use discrete transistors capable of providing the current necessary to operate the printer. The hammer driver and the switch level set cards contain SLD modules of the 100-nanosecond group.

The print buffer consists of 168 positions of 13 bits. Of the 13 bits, nine are used for data and parity. The remaining four bits are used for checking purposes.

#### 4.14.1 TIMING (FIGURE 4-11)

The attachment clock for the 1403 Model 2 or 7 is an eight-point clock controlled by a 720-KHz oscillator having a  $\pm 0.1\%$ stability. The clock runs only during printing and produces 11.1-microsecond pulses.

The attachment clock for the 1403 Model N1 is an eight-point clock controlled by a 1667-KHz oscillator having a ±0.03% stability. The clock runs only during

4-10 (7/69)

printing and produces 4.8-microsecond pulses.

The timing pulses necessary during loading of the buffer from the CPU are provided by the microprogram. 4.14.2.1 PSS (B3E3D04) PR262

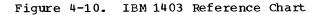
Adjust to 15 us +5 us/-0 us, with the printer idling and T-casting closed.

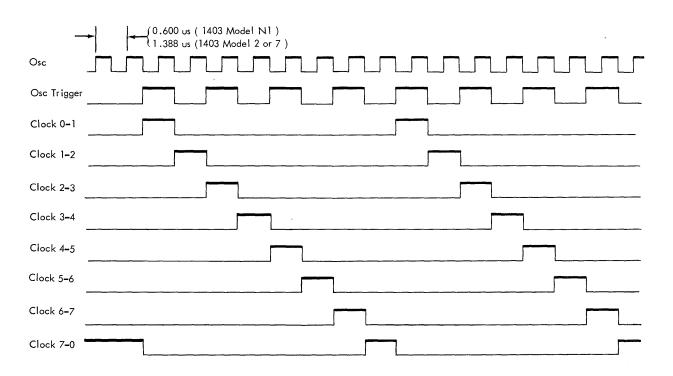
### 4.14.2 SINGLESHOT ADJUSTMENTS (FIGURE 4-12)

Refer to Section 4.18 for MCS feature.

Name of Unit or Item	Model 2	Model 7	Model N1
Cartridge Type	Chain	Chain	Train
Number of Print Positions	132	120	132
Max. Printing Speed (LPM)	610*	610*	1127**
Chain Motor Speed (RPM)	3600	3600	3600
Chain Velocity (IPS)	90.3	90.3	206.0
Time Required for Type to move .001"	)		
(Microseconds)	11.1	11.1	4.8
Settling for Calibration of Print-Timing			
Dial with Print Density Lever set at C	20	20	
Timing Disk Speed (RPM)	750	750	1714
Time Required to Print One Line with	ł		
Single Space (Milliseconds)	98.3	98.3	53.2
Carriage Interlock Time	21.4	21.4	20.7
Carriage Type (Speed)	Dual 33 in./sec	Single 33 in./sec	Dual 33 in./sec
	75 in./sec		75 in./sec

\*750 (LPM) with MCS feature \*\*1419 (LPM) with MCS feature







Name	Location	Length	Tolerance
PSS	B3 E3D04	15us.	+5, -0
Strobe Delay	B3 M2D04	250 ns.	Note 1
Home Gate	B3 F3B03	340 us.	± 20us.
(Model 2, 7)	(Upper)		]
Home Gate	B3 F3B03	160us.	± 15us.
(Model N1)	(Upper)		
Coil Protect	B3 D3B03	3.5 ms	± 350us.
	(Upper)		
Coil Protect	B3 C4B03	1.5 ms	± 150us.
	(Upper)		1
Coil Protect	B3 D3D10	2.0ms	±200us.
	(Lower)		
Coil Protect	B3 C4D10	5.0ms	±500us.
1	(Lower)		
Single Space	B3 L6B03	5.5ms	Note 2
Double Space	B3 F3B07	9.8ms	Note 2
Triple Space	B3 L6D10	13.8ms	Note 2
Note 1: This value is given as a starting point - see			
Buffer Adjustment			

Note 2: These values are given as a starting point. The exact value varies with each printer and must be obtained by using the procedure outlined in Diagnostic Section \*420, Routine WESS.

Figure 4-12. 1403 Singleshots

#### 4.14.2.2 Home Gate (B3F3B03)-(Upper) PR252

<u>Model 2 or 7</u>: Adjust using diagnostic routine WE06 in Section \*400. This provides a range of 320 to 360 microseconds.

<u>Model N1</u>: Adjust using diagnostic routine WE06 in Section \*400. This provides a range of 145 to 175 microseconds.

### 4.14.2.3 Coil Protect PR691

Adjust using diagnostic routine WE26 in Section \*400. The diagnostic fires the singleshots, and the resulting waveforms can be observed on the oscilloscope.

4.14.3 Delays (Figure 4-13)

Name	Input	Output	Length
Carriage Settling Delay	B3 H7D02	B3 H7D13	See 4.14.3.2
Speed Limit	B3 J2D05	B3 J2D13	See 4.14.3.1

### Figure 4-13. 1403 Delays

### 4.14.3.1 Speed Limit Delay PR262

Adjust using diagnostic routine WE29 in Section \*400.

<u>1403-2 or 1403-7 without MCS</u>: A minimum of 46 print scans must be taken before the last scan is allowed. This gives a maximum speed of 610 lines per minute. <u>1403-2 or 1403-7 with MCS</u>: A minimum of 35 print scans are taken before the last scan is allowed. This gives a maximum speed of 750 lines per minute.

<u>1403-N1 without MCS</u>: A minimum of 45 print scans must be taken before the last scan is allowed. This gives a maximum speed of 1127 lines per minute.

<u>1403-N1 with MCS</u>: A minimum of 30 print scans must be taken before the last scan is allowed. This gives a maximum speed of 1419 lines per minute.

### 4.14.3.2 Carriage Settling Delay (PR742)

Adjust using diagnostic routine WE51 in Section \*420 after setting the single-space singleshot. For the 1403-2 or 1403-7, this will give a combined single space and carriage settling range of 20.4 to 21.4 ms. For the 1403N1 this gives a combined single space and carriage settling range of 20.6 to 20.9 ms.

### 4.14.4 BUFFER SERVICE CHECKS

Refer to Section 4.14.6.

#### 4.14.5 BUFFER ADJUSTMENT

- 1. Set all voltages are specified in Chapter 5.
- Initially set Vsl to +3V with respect to ground (PR551) using the upper potentiometer.

#### 4.14.5.1 Vxy Adjustment

- 1. Estimate the temperature of the room. Measure Vxy (01A-C3L2D11) with respect to ground.
- 2. Set Vxy using the lower potentiometer ofC3L2 to the appropriate value with respect to the room temperature:

60F	(15.6C)	+1.6V
70F	(21.1C)	+1.5V
80F	(26.7C)	+1.4V
005	(32, 2C)	1.3V

Note: If air conditioning ducts or floor cutouts allow air colder than room temperature at the input to Gate-A in the C-board area, use the Vxy setting for the next lower temperature. If such cooling conditions are present, check Vxy after the gates have been closed to verify that the Voltage is at the desired value. It may be necessary to readjust for the proper setting.

### 4.14.5.2 Strobe Adjustment

- Attempt to write all bits in the buffer (<u>Diagnostic Routine WE15</u>, Section \*400): disregard any errors.
- \*400); disregard any errors.
  2. Sync the scope on '-0 x+4x Strobe SA'
  (PR551) (01A-C3L2B04).
- Observe the output of the PLB1 sense amplifier, '-0 PLB sense 1' (PR561) (01A-C3K2B02).
- 4. Adjust the strobe delay singleshot in 01A-B3M2 until the sense amplifier output appears. Adjust the singleshot potentiometer to obtain an output pulse of maximum width. If the maximum width occurs over a range, adjust the potentiometer to the center of the range.

### 4.14.5.3 Vsl Adjustment

- Loop on the 1403 buffer voltage routine (WE16 in Section \*400), set sense switches to continue after errors, and print an asterisk (\*) only on errors.
- 2. Adjust the upper potentiometer on C3L2 clockwise until an error message prints (or until a print check occurs).
- 3. Adjust the potentiometer clockwise until the error conditions show up and set the Vsl .1 volt more negative than the high failure level of Vsl.

Note: The range between the failure points should be at least .3V. A range of less than .3V may indicate a bad component such as a sense amplifier.

4. The buffer should now be adjusted properly to track effectively over its specified operating temperature range. If any of the buffer components (sense amplifier, driver, etc.) are replaced, the <u>Buffer Adjustments</u> procedure (Section 4.14.5) must be repeated to obtain optimum operation.

### 4.14.6 BUFFER CHECKOUT PROCEDURES

Loop the ripple print routine to test accuracy of buffer adjustments.

#### 4.15 2560 ATTACHMENT

### 4.15.1 BLOCK FEED CHECK JUMPER

When the block feed check jumper is installed, all 2560 feed checks are prevented. To scope the feed and feed check circuitry:

- Set up a short instruction loop according to the type of feed check, using MFT 72.
- Connect the block feed check jumper (MF 506), and load blank cards in the selected hoppers.

Control and check circuitry can then be scoped as desired. Sync signals are FCB 1 to 6, trailing edge, or those signals that initiate a feed cycle.

### 4.15.2 ADJUSTMENTS

### 4.15.2.1 Singleshots

The monitor-controlled 2560 diagnostic coreload \*820, routines UM35 and UM36, describes the adjustment of all singleshots in the 2560 attachment feature for both print and nonprint 2560s.

### 4.15.2.2 Feed Cells

Refer to the publication, <u>Model 25</u> <u>Pluggable Display and External Field</u> <u>Definitions</u>, and plug the display cable in the location that brings the signal, 'any feed cell dark,' to the indicator lights. Adjust the feed cells as described in the 2560 FEMM.

### 4.16 INTEGRATED COMMUNICATIONS ATTACHMENT

#### 4.16.1 TIMEOUT OSCILLATOR

The timeout oscillator contains two 115-ms singleshots. The singleshots are running continuously: adjust each one to 115 ±5ms while scoping the output pin. See ALD page HA064.

### 4.16.2 TIMEOUT CLOCK SINGLESHOT

The 350-ns timeout clock singleshot is started every 460 ns, and should be adjusted to 350 ±35ns while scoping the output pin. See ALD page HA064.

#### 4.16.3 SYSTEM RESET SINGLESHOTS

There are two 5-microsecond system reset singleshots. One is started by the system reset switch on the console (Note 4 on ALD HA064). The second is used by the ICA microdiagnostics and can be scoped by looping the entire section or any routine in \*700 (Note 5 on ALD HA064).

### 4.16.4 A-CLOCK SINGLESHOT

There is one 2.5-microsecond A-clock singleshot per start/stop base board. The singleshot runs continuously and can be adjusted while the output pin is being scoped. See ALD HA137 for EIA boards (B-X1). See ALD HA337 for TLG boards (B-Y1).

## Section 2. Features

### 4.17 EXTERNAL INTERRUPTION AND DIRECT CONTROL FEATURES

The external interruption and direct control features are combined here because installation of the direct control feature requires that the external interruption feature also be installed. The external interruption feature, however, can be installed without the direct control feature.

Both features are plugged on board A1-A3.

### 4.17.1 SPECIFICATIONS

Signals on the direct control interface are of three types:

- The direct-control bus-out and the direct-control bus-in lines carry static levels that remain on the lines until changed by the CPU program or by the external equipment.
- The timing-out, read-out, write-out, and external bus-in lines carry pulses.
- 3. The hold-in line may carry either a pulse or a static signal.

These signals are shown in Figures 4-14 and 4-15. In these figures, all pulses are considered positive and the up-level is considered a logical one.

When the CPU power is off, all outputs to the outbound busses or tag lines must be at a logical zero.

### 4.17.2 ADJUSTMENTS

Although circuit adjustments cannot be made to these features, the circuit cards of any given type <u>must</u> operate satisfactorily in any socket location specifying that type. Selection or interchange of cards to obtain satisfactory performance is unnecessary and should not be done.

### 4.18 INTERVAL-TIMER ADJUSTMENT

The singleshot located at A-A3J7 must be adjusted as follows. Scope the signal at A-A3H3D05 (CT011). Adjust the singleshot to give a 10-millisecond ± 10% positive going pulse at this point for 60-cycle machines, or an 11-millisecond ± 10% positive going pulse for 50-cycle machines. It is not necessary to have the CPU clock running to make this adjustment. The singleshot must be functioning all the time power is on.

### 4.18.1 SERVICE CHECK AND CHECKOUT PROCEDURE

To test the interval-timer feature, first run microdiagnostic \*200. Timer switch must be on to run this test. Next place the machine in single-cycle mode and press system reset. Display the interval-timer register; it must be zero. Now alternately press start and then display the interval-timer register. Each time this is done, there is a 50% chance that the register will be advanced. Each time it does advance, it is increased by only one count. When a count of one has been reached, turn the interval-timer switch off. The interval-timer register should continue to advance. When all bits of the C-register are on (interval-timer register equals 15), press the start button ten more The value in the interval timer times. must not change.

Leaving the interval-timer switch off and the machine in single-cycle mode, press system reset. Display the interval-timer register; it must be zero. Press start ten times. The interval-timer register must still be zero.

### 4.19 STORAGE PROTECTION FEATURE ADJUSTMENT

Figure 4-16 shows the time relationship of the STP1 local storage compared to the CPU word type 2. A delay line is used to adjust the STP local storage read line. This delay line has a tolerance of +3 to -2 nanoseconds and can be adjusted by using the following procedure.

1. Store the storage word 5210, followed by an unconditional branch back to this word, into an unused portion of control storage.

Example: Address Contents

4

- 0280 5210 (FE Trap Area) 0282 8280
- Sync on word type 2 (location 01A -B1C7B03).
- Scope and record the duration from the 10% rise of 'YO ADDR LINES STP1' to the 10% fall of 'STP1 READ LINE' (ALD -XQ007).
- 4. The duration (Figure 4-17) must be between 27 ns and 37 ns. If this requirement is not met, the delay line must be plugged to satisfy this condition.

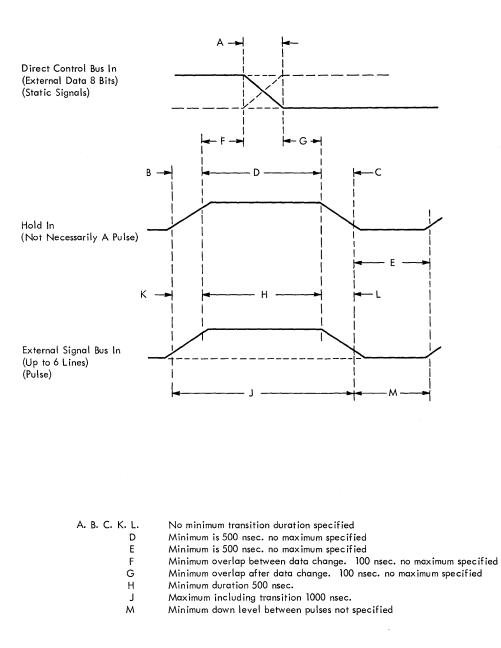
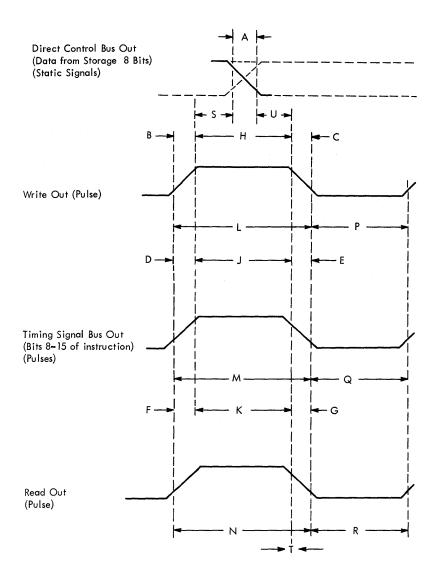


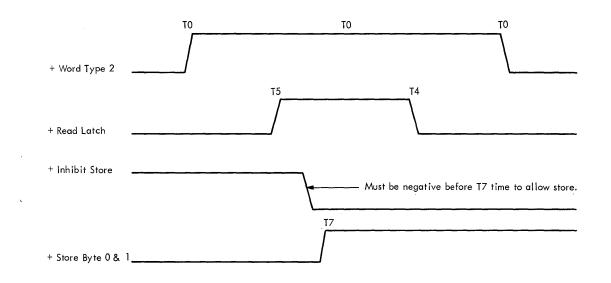
Figure 4-14. Direct Control Signals Originating Outside the CPU

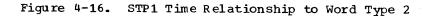


A. B. C. D. E. F. G Maximum transition time is 200 nsec.
H. J. K Minimum duration is 500 nsec.
L. M. N Maximum including transition. 100 ns.
B. D Leading edges coincidental within skew tolerances
F. D Leading edges coincidental within skew tolerances
S Overlap start Write Out to change D. C. P. O. 100 nsec. (MIN)
U Overlap change of D. C. P. O to finish of Write Out 100 nsec. (MIN)
T Earliest time to sample hold line during read direct.

P. Q. R Minimum down time between pulses is 500 nsec.







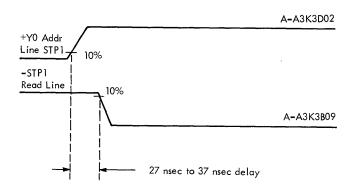


Figure 4-17. STP1 Read Line Delay

#### 5.1 GENERAL INFORMATION

Electrical power requirements for the 2025 processing unit and integrated input/output attachment features, including the associated I/O devices, are supplied through the 2025 processing unit.

The ac service into the 2025 processing unit is 208/230V, 60 amps, 3-phase, 60 Hz ac for domestic machines. For World Trade machines, provision is made for 50 Hz, 195/220/235V, delta input, or 50 Hz, 380/408V, Y-input.

The dc supplies are ferroresonant for all levels.

The dc supplies are sequenced. The ac power to the 2311 disk drives and the 2560 MFCM is also sequenced.

Some of the power supplies and associated components are used only with certain integrated I/O attachments. Where possible, these components are specified in feature groups, and are installed only when the associated features are installed.

The following is a listing of the power supplies by group.

Basic Power Group: +3 50A -3 0 30A +6 0 40A +12 0 13A -12 0 13A -30 0 8A Core storage 7.25V ac 0 2Console indicators 41V ac 0 --- Meter power pack 115V ac 0 15A Convenience outlets and 1052 motor +24 0 4.5A Sequence circuitry

Ferrotransformer T1 Supplies: +48 @ 3A Console typewriter, communications

Power requirements supplied from the processing unit for integrated I/O attachment devices are as follows.

#### 1403/2540 Power Group:

-6 a 4A -20 a 4A

#### 1403 Power Group:

+6 a 16A Hammer drivers +60 a 20A Hammer drivers 2311 Power Group:

-36 @ 2A

#### 2560/Communications Power Group:

+3 a 45A +6 a 32A

2560 Power Group:

+20 @ 1A

#### 5.2 INPUT POWER

Input power for domestic installations is 208 volts  $\pm 10\%$  or 230 volts  $\pm 10\%$ , 60  $\pm .5$ hertz, 60-amperes three-phase four-wire (the fourth wire is equipment ground) shielded cable. The shield and ground wire are bonded to the input line filter case at the cable entry point.

Input power for World Trade installations is 200, 220, 235/380, or 408 volts ±10%, 50 ±.5 hertz, 60-amperes three-phase five-wire shielded cable (the fourth wire is neutral for a WYE system and not used on DELTA, and the fifth wire is equipment ground. The shield and ground wire are bonded to the input line filter case at the cable entry point. An autotransformer is provided for 200 volts, 235 volts, or 408 volts, 50 hertz inputs.

Power supply logics YA 011, YA 092, and YA 101 show input connections to voltage sensitive units and YA 031 shows the power on/off sequence. The 2025 power supply is described in detail under <u>Power Supply</u> in the <u>IBM 2025 FE Theory of Operations</u> <u>Manual</u>, Form Y24-3527.

# 5.3 POWER CONVERSION

Ferroresonant regulators feeding full wave bridge rectifiers are used to transform the systems ac input voltage to the dc voltage required by the series regulators and the special power requirements. The special power requirements do not require close regulation.

#### 5.4 AC OUTPUTS

5.4.1 CONVENIENCE OUTLETS

For domestic machines, two convenience outlets provide 115 volts, 60 hertz, single phase, at a maximum of 15 amperes for the CPU. For World Trade, two convenience outlets provide 200, 220, or 235 volts at 8 amperes for the CPU. Integrated units can draw up to 8 amperes per unit. The convenience outlets for the CPU and the integrated attachments cannot exceed a total of 15 amperes.

# 5.4.2 BLOWERS

The CPU has three blowers in the power supply tower, three blowers per SLT gate, and three blowers in each M2-I unit. These blowers require 208 or 230 volts, 60 hertz, or 220 volts at 50 hertz, single phase.

## 5.5 DC OUTPUTS

The power system of the 2025 supplies dc outputs as shown in Figure 5-1.

All dc voltages must be within the tolerances indicated in Figure 5-1 (excluding transient noise) at any card socket in the CPU. Therefore, each power supply must maintain its output voltage in accordance with its individual performance specification. The distribution tolerance must not exceed  $\pm 2\%$  within the CPU and devices with reference established at the point of the external entry into the device.

5.5.1 MARGINAL CHECKING JACK RECEPTACLE (P1)

A jack receptacle (P1) located on the 2025 relay panel provides +12 volts for marginal checking the 2540 (logic YA 241).

#### 5.6 POWER ON/OFF SEQUENCING

See timing power supply logic YA 031.

5.6.1 POWER ON/OFF OF CPU AND INTEGRATED I/O UNITS

5.6.1.1 +6, -3, +3, and -30 Voltages

The +6, -3, and +3 voltages must be within a sensed percentage of their rated level prior to bringing up the -30 volts used by storage. The -30 volt supply must be down to or below a sensed level before removing +6, +3, or -3. Whenever the +6 volt supply is between +5.4 volts and +2.0 volts for more than 100 ms, -30 volts should be dropped to less than -10 volts. Any loss of the +6 volts should result in the removal of -30 volts from the BSM (basic storage modules).

# 5.6.1.2 +6, +3, -3, and +60 Voltages

The +6, +3, -3, and +60 volts direct must be up within a sensed percentage of their rated level prior to applying the +60 volts

Supply Rating	Maximum Current Permitted (Avg.)	Power Supply Location No.	Tolerance at Circuits	Setting ±0.5%	Position	Feature
+12V 13A	11.7 A	8	±4%	12.24	PS-TB1-2, TB1-5	Basic
-12V 13A	13.0 A	3		12.24	PS-TB1-2, TB1-5	Basic
– 3V 30A	30.0 A	6		3.01	*A-LBA1	Basic
-6V 4A	4-0 A	1		6.24	PS-TB1-5, TB1-2	1403, 2540
+ 3V 45A	42.0 A	2		3.12	PS-TB1-2, TB1-5	2560, Comm
-30V 8A	8.0 A	12	1	(Per Mem Spec)	**M21LB	Basic
•	(9.0A at 34.5V)					
***+ 6V 40A	47.0 A	10	±4%	6.02	*A-LBA1	Basic
+60 V 20A	20.0 A	14	±10%	N/A	N/A	1403
+6V16A	15.5 A	11	+4%			
			-7%	6.02	TB25-15, 13	1403
-30V 2A	2.0 A	4	±4%	36.72	PS-TB1-2, TB1-5	2311
-20 V 4A	4.0 A	Developed from T1	±10%	N/A	N/A	Basic
+24∨ 4.2A	4.2 A	Developed from T3	±15%	N/A	N/A	Basic
+48V 3A	3.0 A	Developed from T1	±10%	N/A	N/A	Basic
+ 6 V 32A	30.0 A	5	±4%	6.24	PS-TB1-2, TB1-5	2560, Comm
+ 3V 50A	50.0 A	9	±4%	.3.01	*A-LBA1	Basic
+20V 1.0A	1.0 A	Developed from T7	±10%	N/A	N/A	2560

\*See logic page YA251 \*\* See logic page YA271 \*\*\* +6V @ 50A on machines with EC133539

Figure 5-1. DC Outputs

5-2 (7/69)

controlled output to the 1403. This makes the three-phase ac power available for the motors. The +60 volts controlled must be down to or below a sensed level before removing other dc voltages used by the 1403.

# 5.6.1.3 2311 DC Power

The first dc power on the 2311 is the +6, +3, and -3 volts; then the ac power-on control line is activated. The first step in power-off is to deactivate the 'power-on control' line, remove ac power, and finally remove dc voltages. The 2311 heads extended prohibit sequence down until the heads retract or an EPO occurs.

## 5.6.1.4 2540 DC Power

The -20 volt dc power to the 2540 is applied at the same time as the -30 volts is supplied to main storage.

# 5.6.1.5 2560 AC Power

The ac to the 2560 is applied after the dc voltages and removed before the dc voltages.

5.6.2 POWER ON/OFF TO CHANNEL CONTROLLED I/O UNITS

A maximum of eight I/O control units can be controlled by the CPU channels. These units are powered up after all CPU and integrated I/O units have been sequenced on. The channel controlled I/O units step their power on one at a time. When the last I/O unit has completed its power-on sequence under remote control and the memory temperature is above the low limit, the system power-on reset line is deactivated and the system power-on light is turned on.

Power off occurs in the same sequence as power on, with the following exception: if the 2311 heads are extended at the time of power off, the power-down sequence is prohibited until the heads retract or an EPO occurs.

#### 5.7 EMERGENCY POWER-OFF (EPO)

Operation of the emergency-pull switch removes primary power within two seconds from the CPU and every I/O control unit attached to a channel simultaneously, and without stepping down. An emergency power-off can cause the data in main storage to be lost. Operation of the emergency-pull switch sets a mechanical latch within the switch mechanism that must be manually reset before power can be restored.

# 5.8 OVERCURRENT, UNDERVOLTAGE, AND OVERVOLTAGE SENSE

When an overcurrent or an overvoltage condition occurs on <u>dc power supplies with</u> <u>an overcurrent CB</u>, the following events take place.

- A circuit breaker is tripped and the CB trip light is on.
- A normal power-off sequence is initiated.
- 3. A power-check light is energized on the console.

The dc power supplies <u>not provided with</u> <u>an overcurrent CB</u> are fused for overcurrent protection. Loss of the supply outputs when system power is on initializes a normal power-off sequence and turns on the power-check light on the console panel. Loss of the +24 volt supply causes a <u>random</u> <u>power off</u> and does not light the power check light.

Loss of any dc supply (except the +24 volt) below its sensed rating initiates a normal power-off sequence and lights the power-check light on the console panel.

The 20-volt, 24-volt, 36-volt, 48-volt, and 60-volt dc supplies do not require overvoltage circuits.

# 5.8.1 SYSTEM-RESTART/POWER-CHECK LIGHT RESET

System restart can not be accomplished without first pressing the power-off button to reset the power-check light. Inability to reset the power-check light indicates the power failure is caused by an overcurrent, overvoltage, or thermal-trip condition. The system power-off button must be pressed after resetting the condition at the power tower.

### 5.9 THERMAL SENSING

Thermal sensing switches are provided on logic gates, main storage, and power supply areas. Whenever any of these thermal switches senses a temperature in excess of their specified limit, the following occurs.

- A normal power-off sequence is initiated.
- 2. The thermal-trip light on the power tower is turned on and remains on until the condition is corrected and the thermal reset switch is actuated.
- 3. The power-check light on the console is turned on.

5.10 SERVICE CHECKS AND CHECKOUT PROCEDURES (FIGURE 5-2)

Continued problems with the 2025 power supplies could be an indication that:

- Line in use is out of specification. The voltage must be within ±10% of rated input line voltage. (See <u>Physical Planning Manual</u>, Form C22-6820, for complete requirements.)
- 2. Transformer taps set for wrong line voltage. If the voltage is ever changed, the correct Feature Bill of

Material should be ordered through Plant Field Engineering. These B/Ms contain complete instructions for the 2025 conversion as well as the correct voltage nameplate tags. The voltage nameplate must always reflect the voltage for which the machine is wired. When the B/M is ordered and installed, Machine Level Control Department is advised of the change in the machine voltage wiring.

3. On thermal failures, check blowers and filters for sufficient air flow. Room temperature can also be a factor.

			· · · · · · · · · · · · · · · · · · ·		
Logic Page	Descripton	Part Number	EC133201	EC133323	EC133539
YA011	Switching Instruction for Input Voltage	2542161			
YA021	Machine Layout Data (Door Side)	2542162	2543021	2470741	
YA022	Machine Layout Data (Gate Side)	2542163		2470739	
YA031	Power "On" - "Off" Sequence	2542164			
YA041	Component Data Location Chart	2542165	2543022		
YA042	Component Data Location Chart	2542166			2470747
YA043	Terminal Location Chart	2542167			
YA061	Connector Reference Chart	2542168			
YA071	External Cable Connections	2542169		2470740	
YA072	External Cable Connections	2542170			
YA091	AC Power Control	2542171	2543023		
YA092	Control Transformer and Conv. Outlet Power Dist.	2542172			
YA101	AC Distribution	2542173			
YA111	AC - Distribution to 1052 and Blower Circuits	2542174			]
YA131	1403 AC - Control and Distribution	2542175	1	2470732	
YA132	Solid State Switch and 1403 Motors	2542191			
YA141	1403 +60 V Control and Disteibution	2542176		2470733	
YA151	System Power Control	2542177			
YA161	System Power Control	2542178			
YA171	EPO and PWR "On" Control for I/O Control Units	2542179		· .	
YA181	Voltage Sense Circuits CB Trip Sense Circuits, Over Temperature Circuits	2542180			
YA185	Lamp Supply and Time Meter Circuit	2542181			
YA191	Ferro Mid Pack T1, T2, and Power Supplies PS1, PS4	2542182		A second second	
YA201	Ferro Mid Pack T6, T7, and Power Supplies PS2, PS5, PS11, PS12	2542183			
YA211	-3V - Power Supply and Distribution	2542184			
YA221	+3 V - Power Supply and Distribution	2542185			
YA231	+6 V - Power Supply and Distribution	2542186			
YA241	+12V, -12V - Power Supply and Distribution	2542187			
YA251	DC Distribution to Gate "A"	2542188			· ·
YA261	DC Distribution to Gate "B"	2542189			
YA271	DC Distribution to Gate "C1", Gate "C2" and Gate 01H01-A (Hammer Driver Board)	2542190			
YA112		2539396			
YA182		2470789			

Figure 5-2. Power Supply Logic Pages

#### 5.11 MID-PAC POWER SUPPLY

5.10.1 MID-PAC TROUBLESHOOTING PROCEDURES

The following procedure is recommended for troubleshooting the Mid-Pac power supply. Only the most probable conditions are indicated.

# 5.11.1.1 High Voltage

Either a defective amplifier card or a shorted series regulator power transistor. To determine which of these is causing the high voltage, remove the amplifier card and press the power-on key just long enough to determine whether voltage is present. Voltage being present indicates that one or more of the power transistors (normally clamped to 0-volts with the amplifier removed) is shorted. If no output voltage is present, the amplifier card is probably defective. It may be necessary to disconnect the output cable and remove the overvoltage card. Never remove the overvoltage card with the dc output cable connected to the module if power is to be applied to the machine.

#### 5.11.1.2 Low Output Voltage

Low output voltage usually is caused by a defective amplifier card.

#### 5.11.1.3 DC Module Circuit Breakers (Individual Tripping)

Either a shorted series regulator power transistor, or a short in the logic wiring (load). To determine which condition is causing the circuit breaker to trip, remove the amplifier card. If the circuit breaker trips with the card removed, the power transistor is shorted. If the circuit breaker does not trip with the card removed, the short is probably somewhere in the load circuits.

#### CAUTION

The CPU should not be running when tools or scopes are plugged into the convenience outlet.

If necessary, normal processor operation may be interrupted to utilize the convenience outlet by:

- 1. pressing STOP.
- 2. connecting tools.
- 3. pressing START.

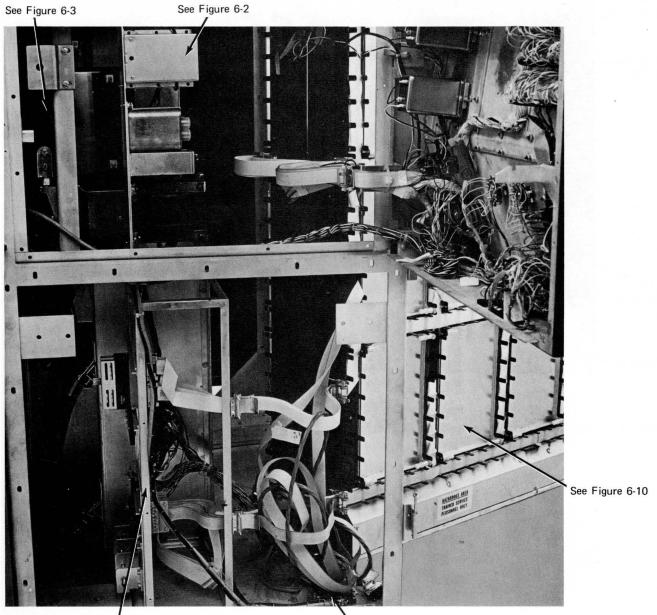
5.11.2 SERVICE CHECKS AND CHECKOUT PROCEDURES

# 5.11.2.1 Mid-Pac DC Outputs

All dc voltages must be within rated tolerances when measured anywhere in the CPU Logic area such as memory units and logic gates. Refer to Figures 5-1 and 5-2 for a chart and reference of the Mid-Pac power system.

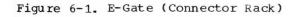
Measure and monitor the output voltage at the designated test point for the applicable power supply. Vary the red knurled knob of the potentiometer on the SMS card until the meter reads the specified voltage. Use a Weston 901 meter or equivalent.

# Chapter 6. Locations



See Figure 6-3





# Chapter 6. Locations

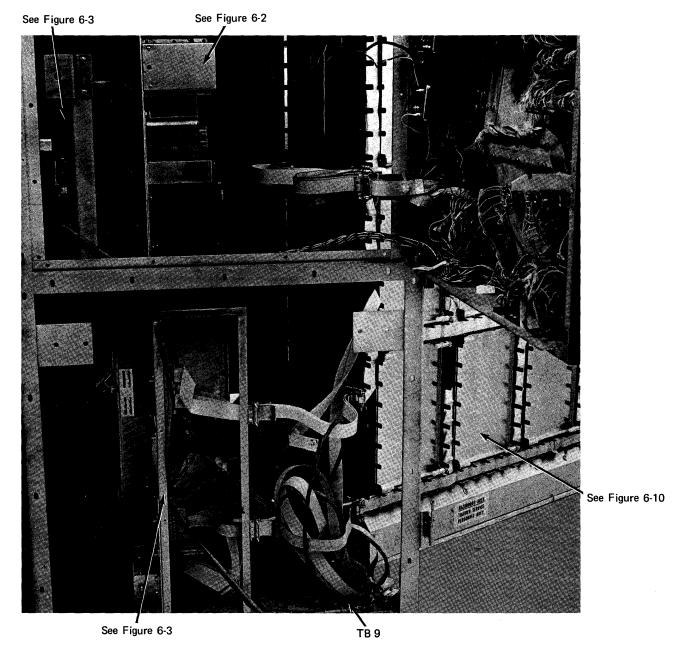


Figure 6-1. E-Gate (Connector Rack)

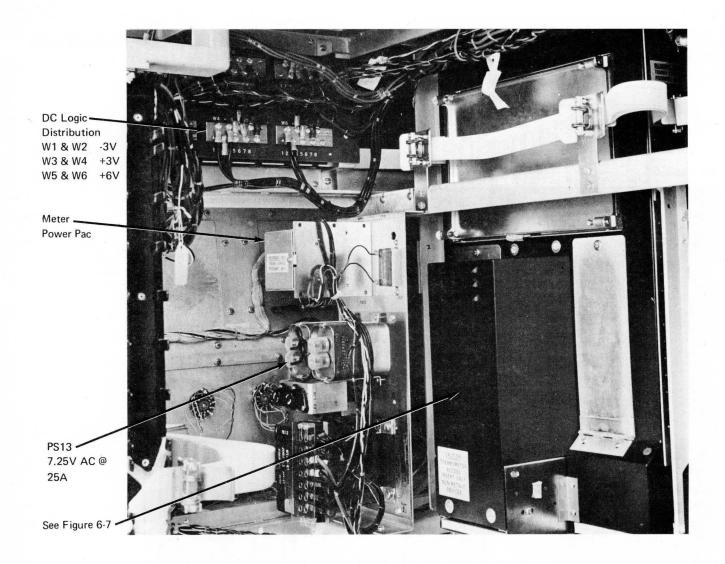


Figure 6-2. DC Distribution and Power Supplies

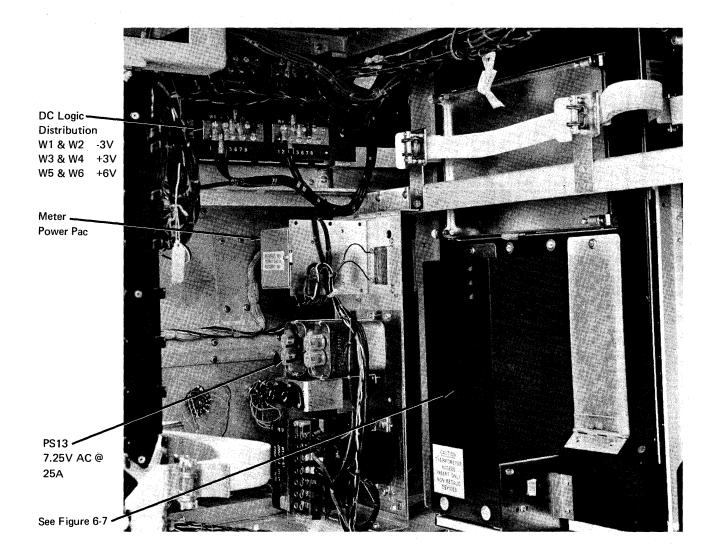


Figure 6-2. DC Distribution and Power Supplies

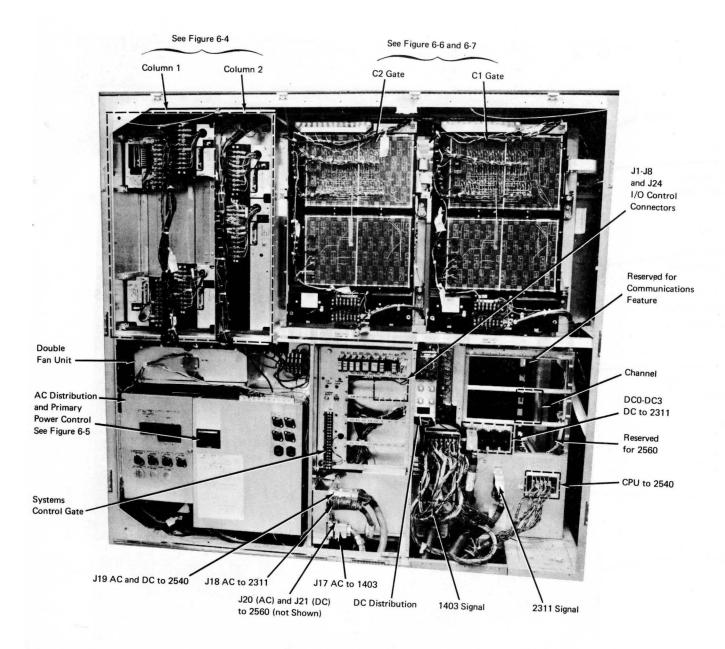
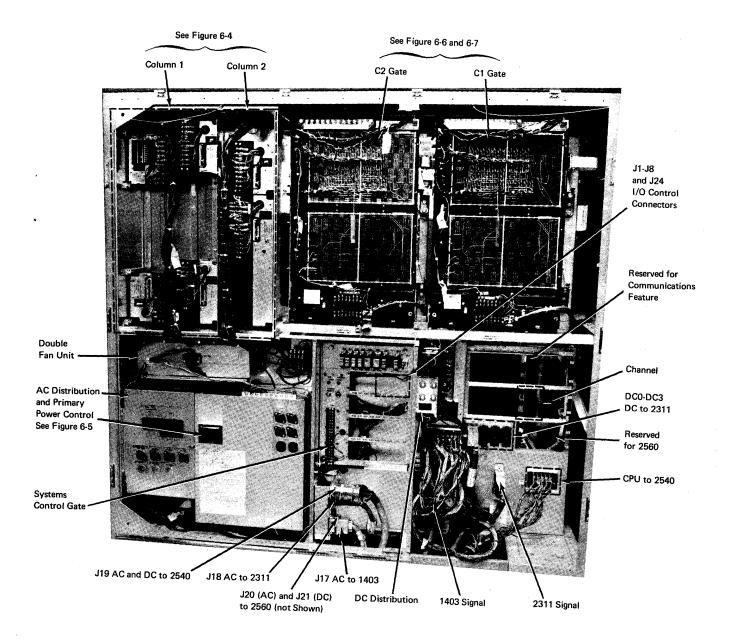
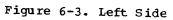
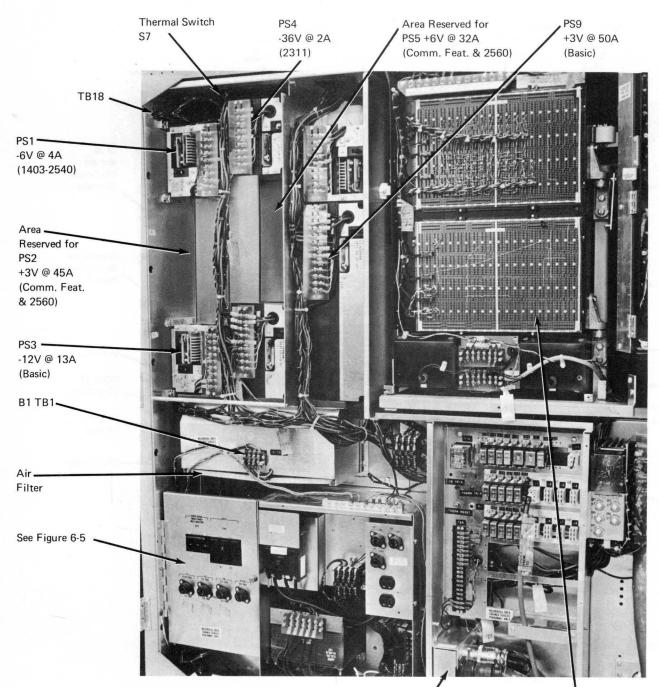


Figure 6-3. Left Side



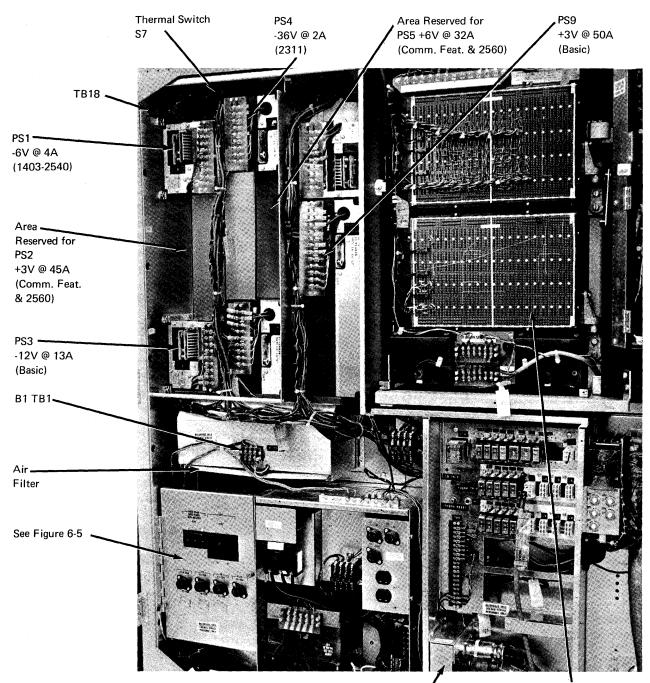




See Figure 6-3

See Figure 6-6 and 6-7

Figure 6-4. Power Supplies (Left Side)



See Figure 6-3

See Figure 6-6 and 6-7

Figure 6-4. Power Supplies (Left Side)

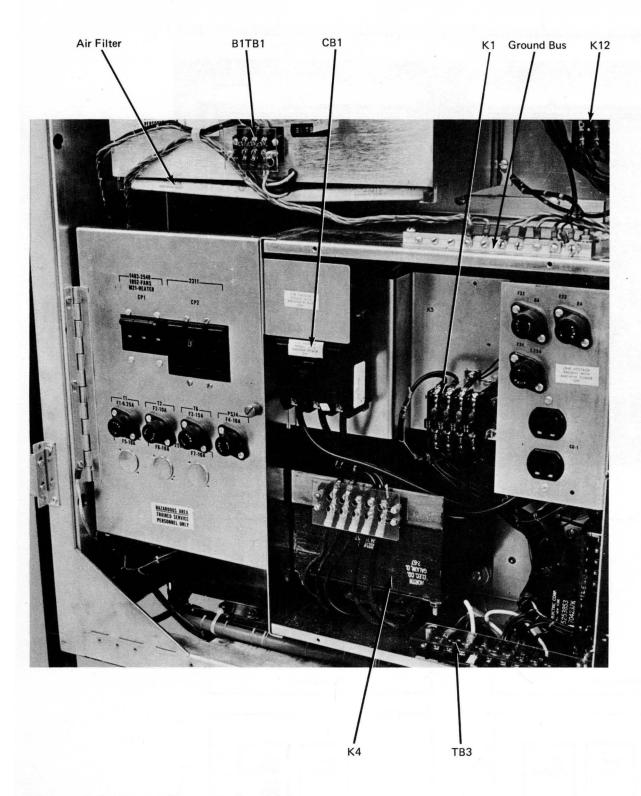


Figure 6-5. Fuses (Lower Left Side)

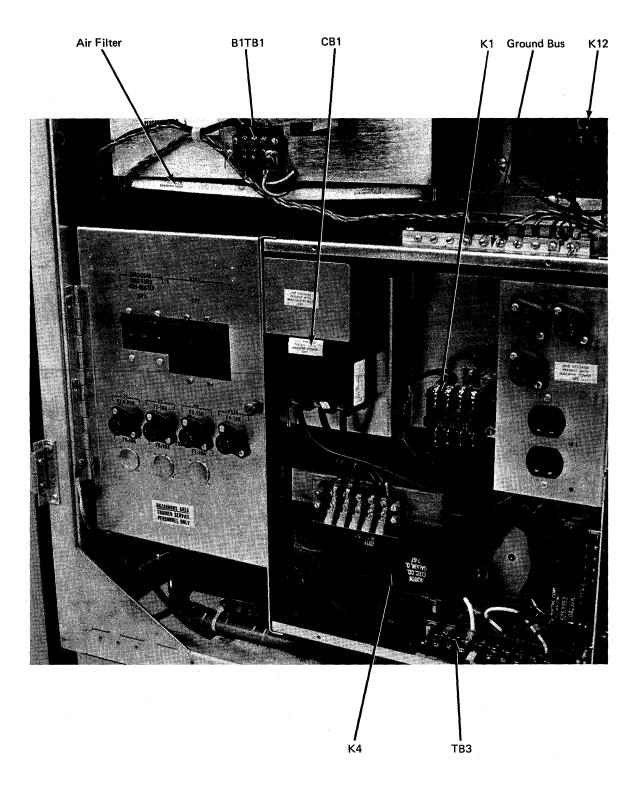


Figure 6-5. Fuses (Lower Left Side)

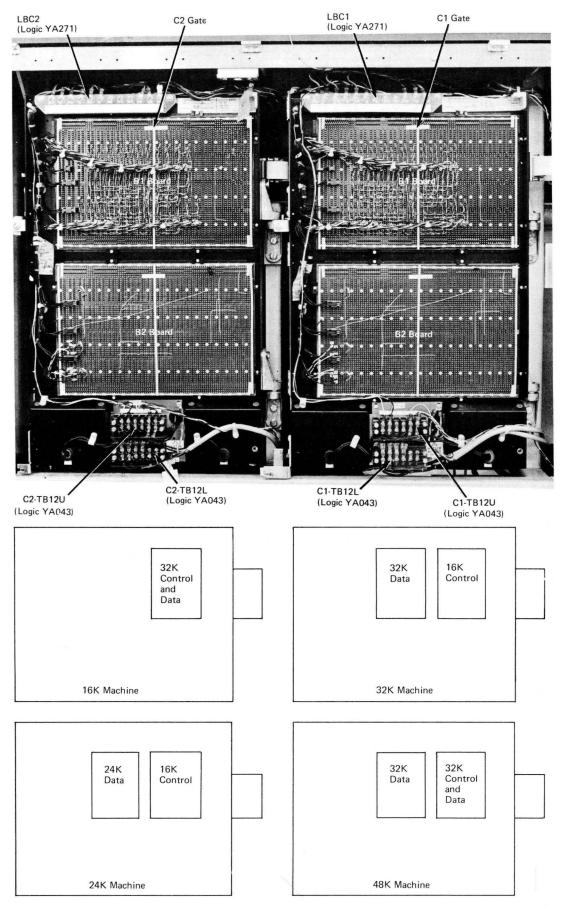


Figure 6-6. Main Storage Units (Pin Side)

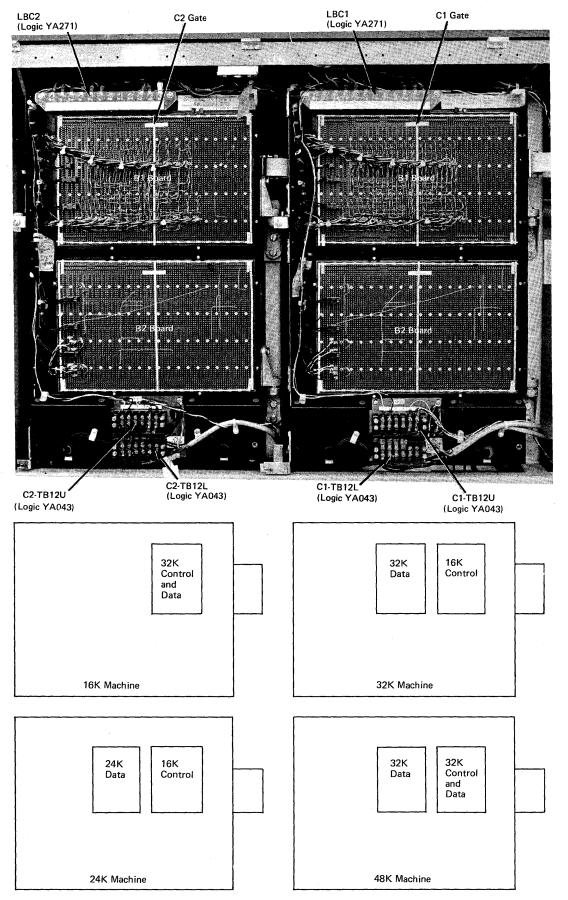
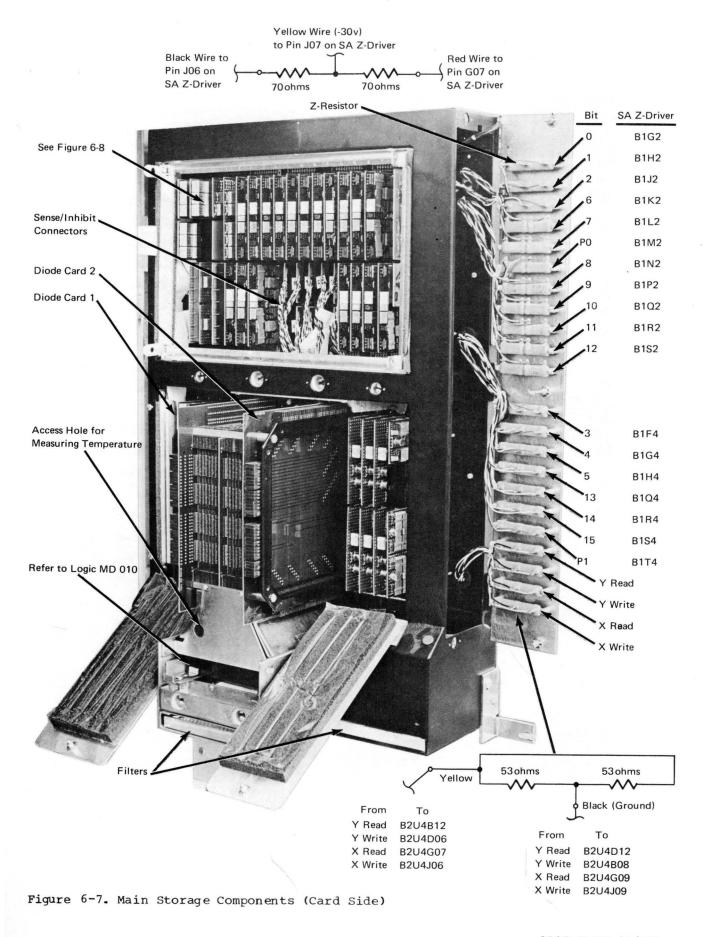
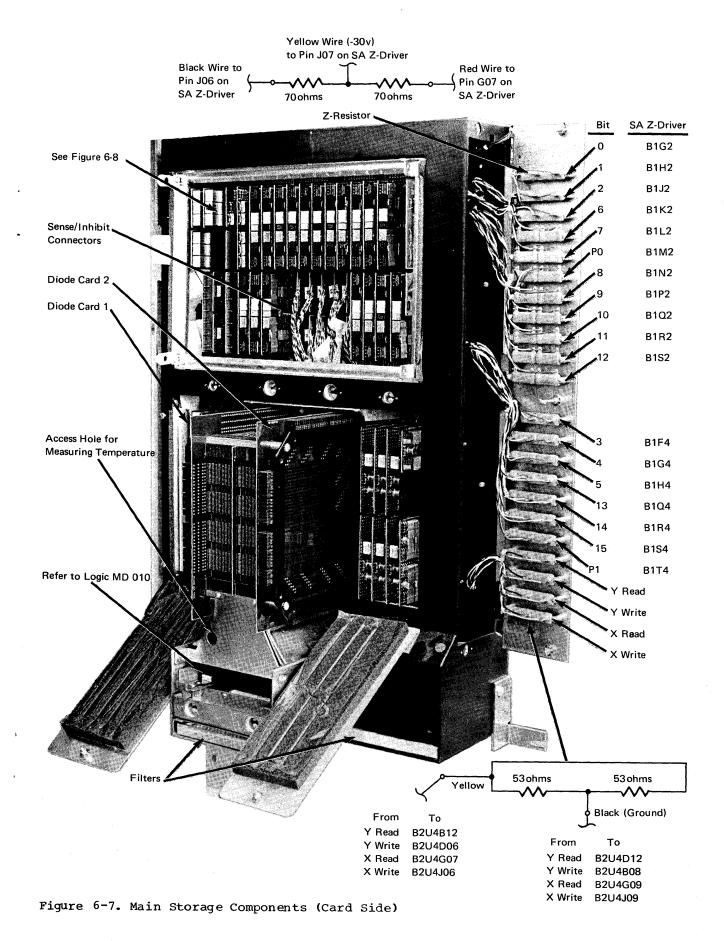


Figure 6-6. Main Storage Units (Pin Side)





2025 FEMM (7/69) 6-7

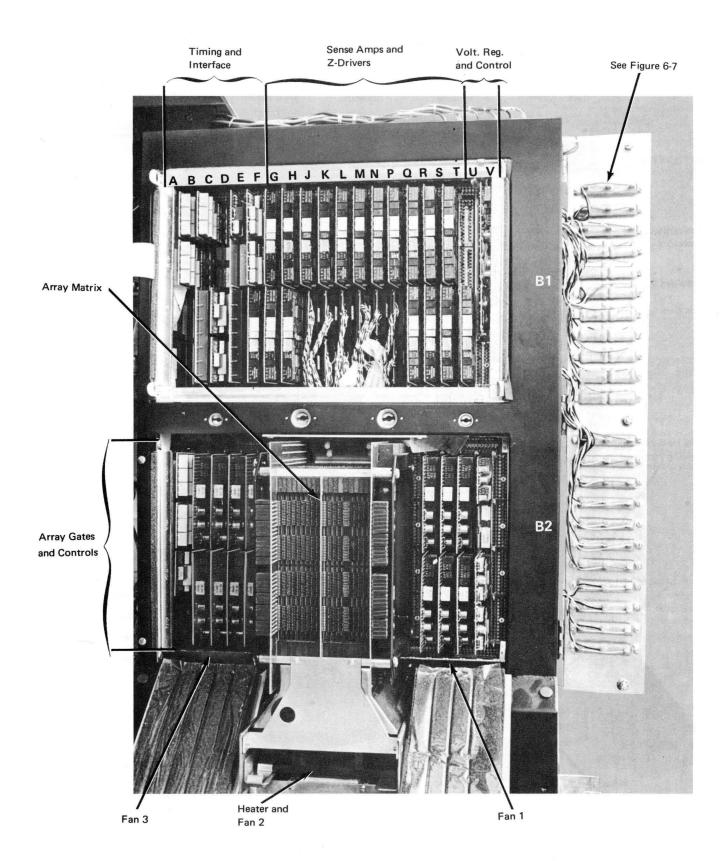


Figure 6-8. Main Storage Components (Card Side)

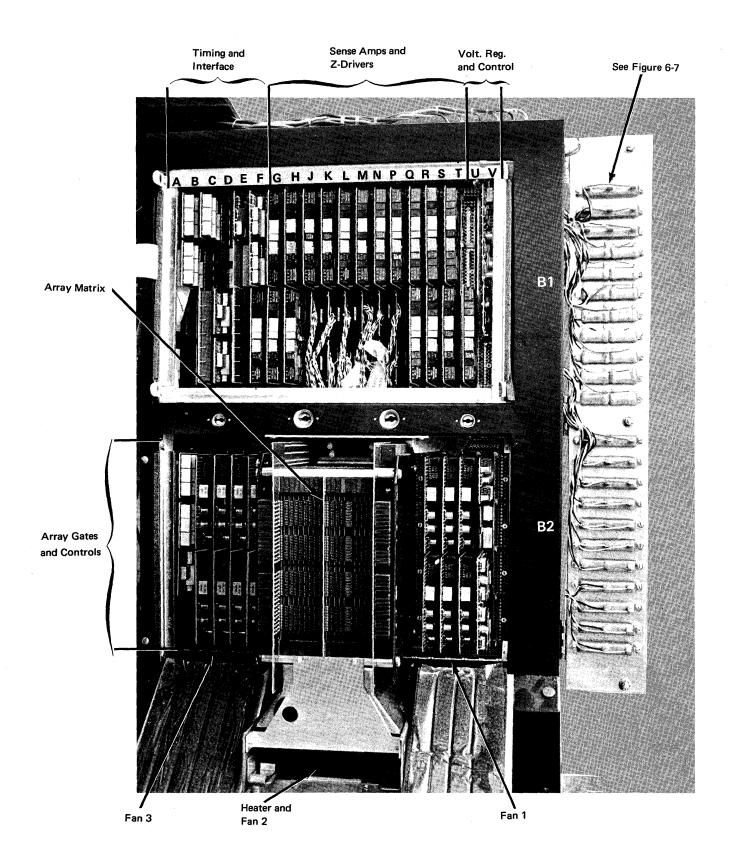


Figure 6-8. Main Storage Components (Card Side)

6-8 (7/69)

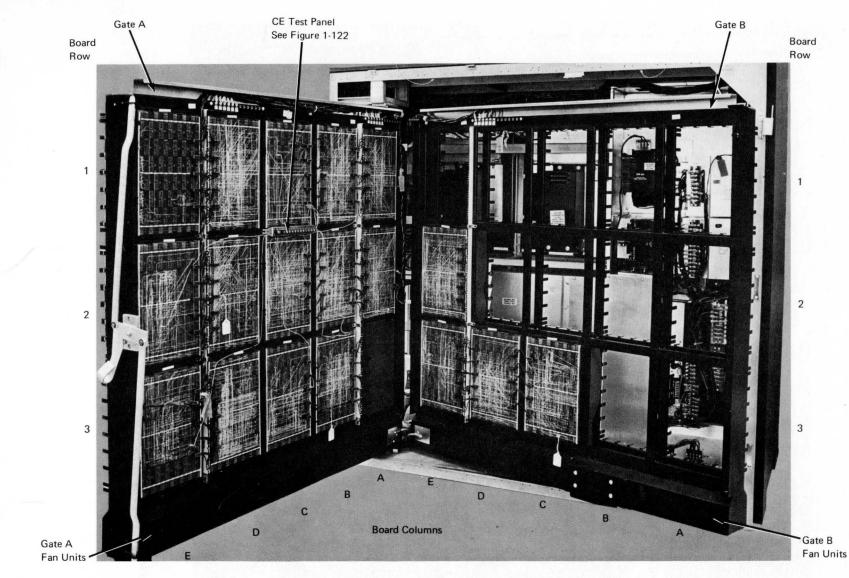


Figure 6-9. Logic Gates A and B (Open)

2025 FEMM (7/69) 6-9

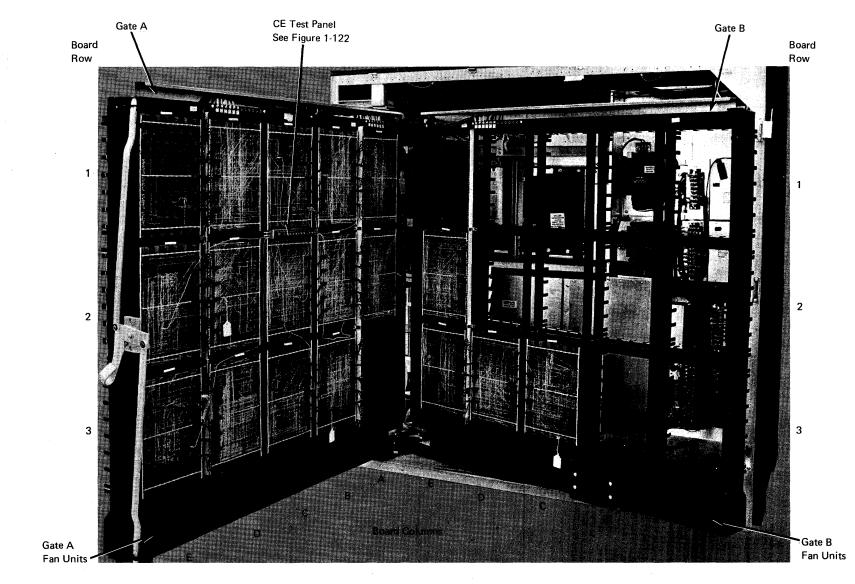


Figure 6-9. Logic Gates A and B (Open)

2025 FEMM (7/69) 6-9

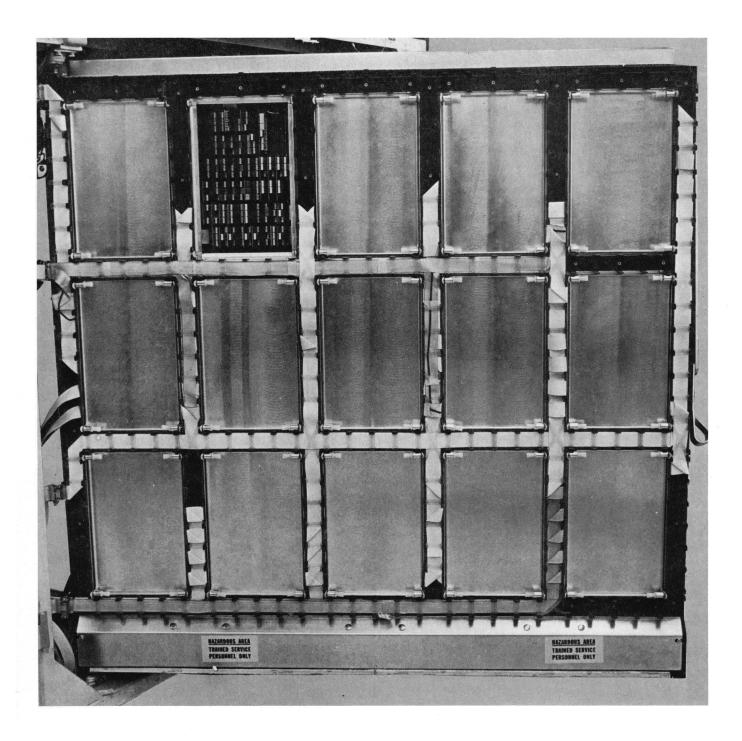


Figure 6-10. Logic Gate A (Card Side)

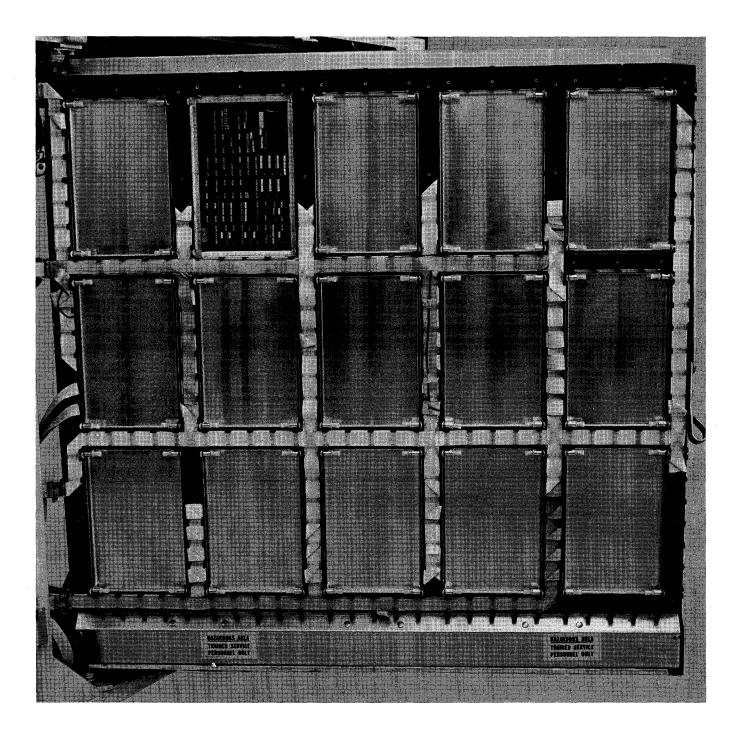


Figure 6-10. Logic Gate A (Card Side)

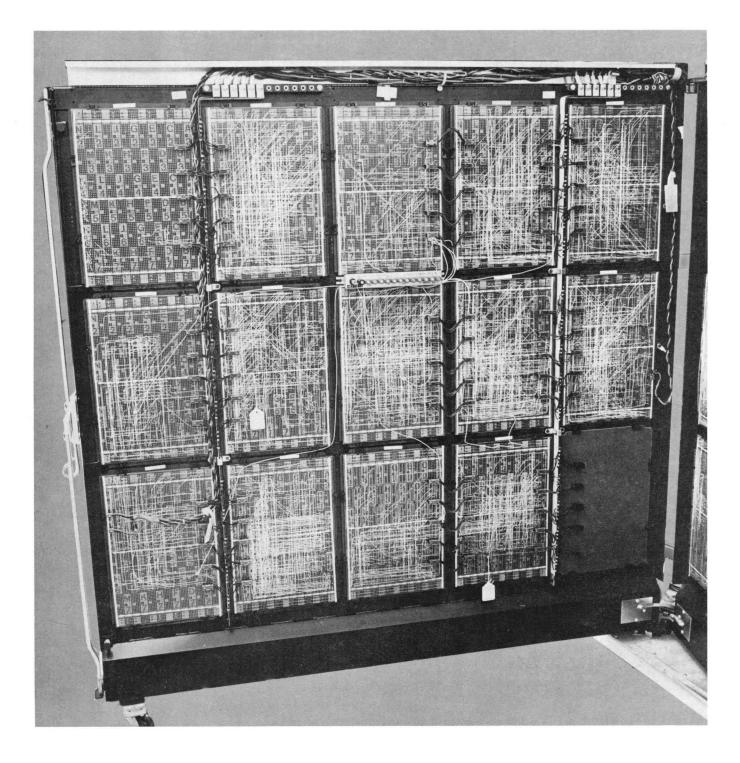


Figure 6-11. Logic Gate A (Pin Side)

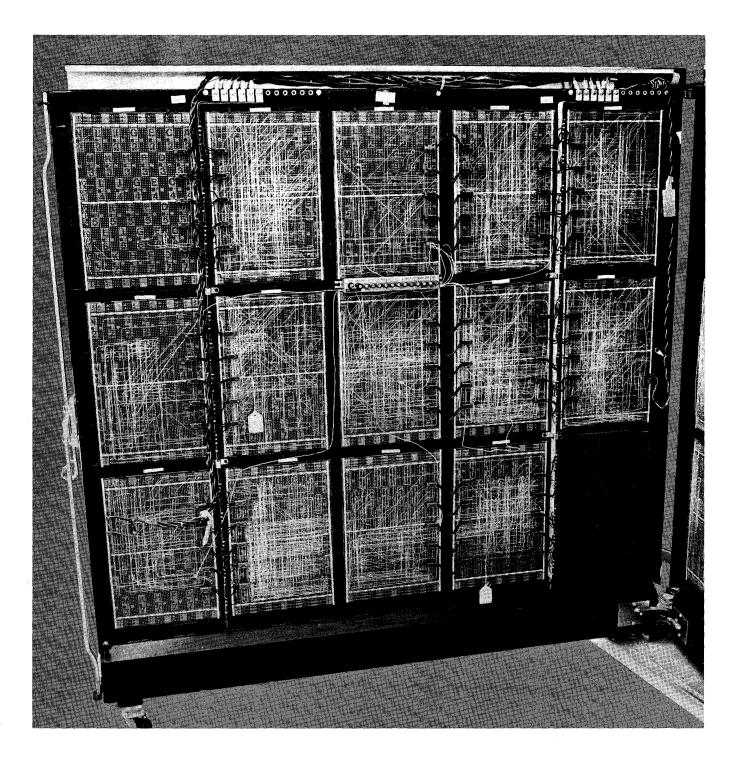


Figure 6-11. Logic Gate A (Pin Side)

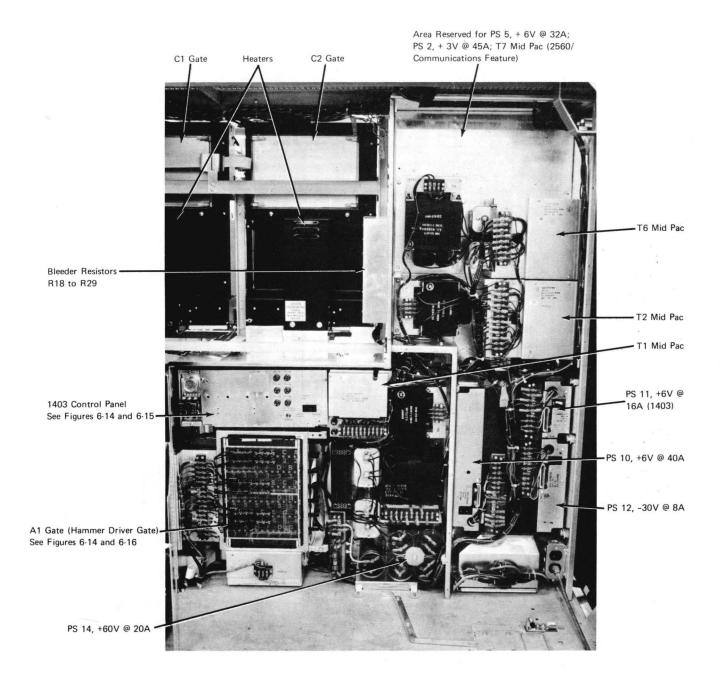
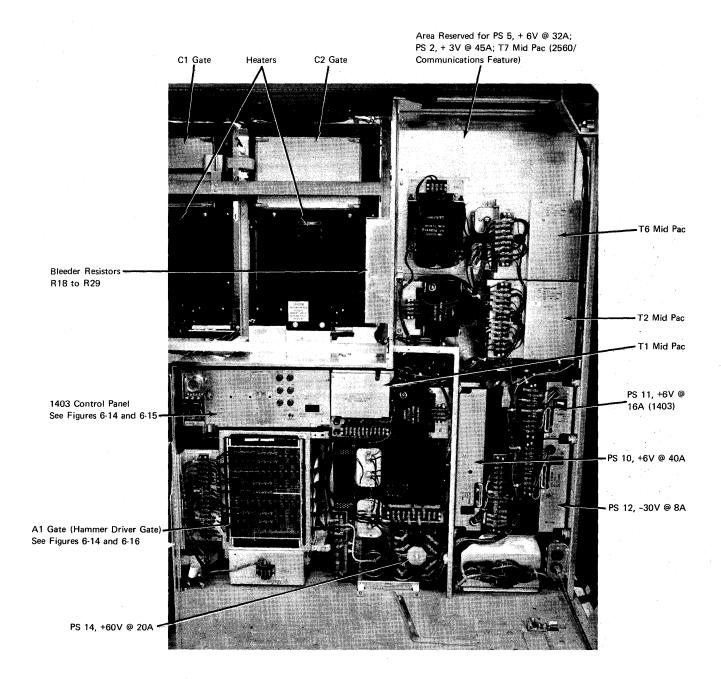


Figure 6-12. Right Side (Behind Logic Gates)



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Figure 6-12. Right Side (Behind Logic Gates)

6-12 (7/69)

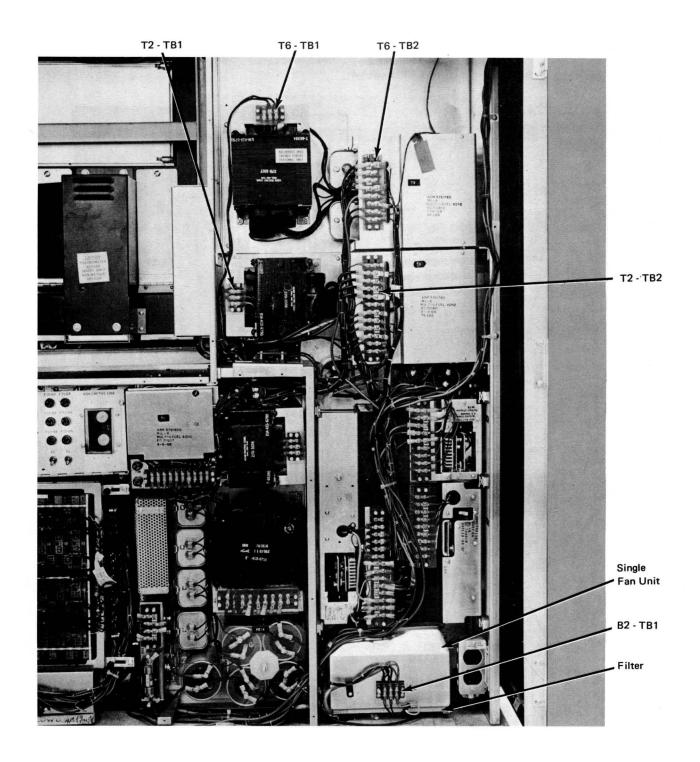


Figure 6-13. Power Supplies (Right Side)

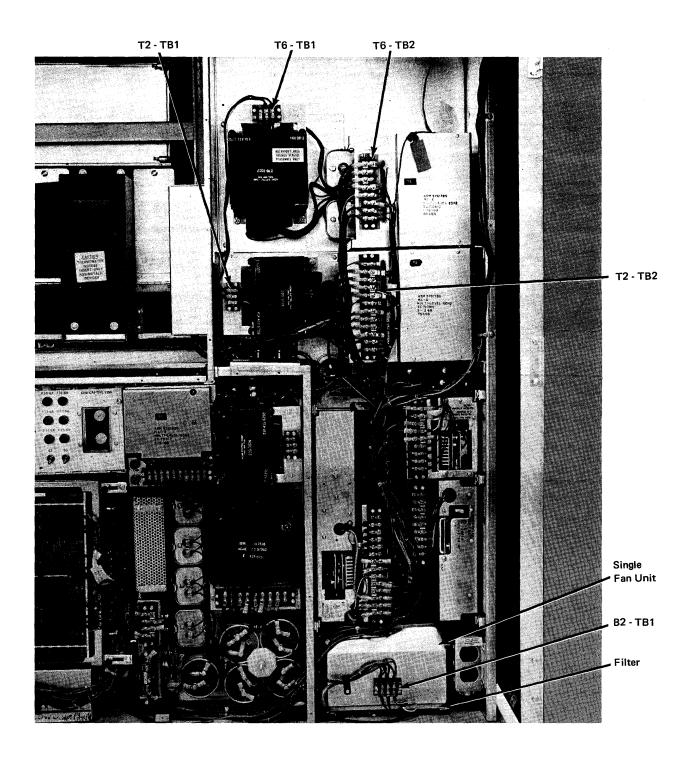


Figure 6-13. Power Supplies (Right Side)

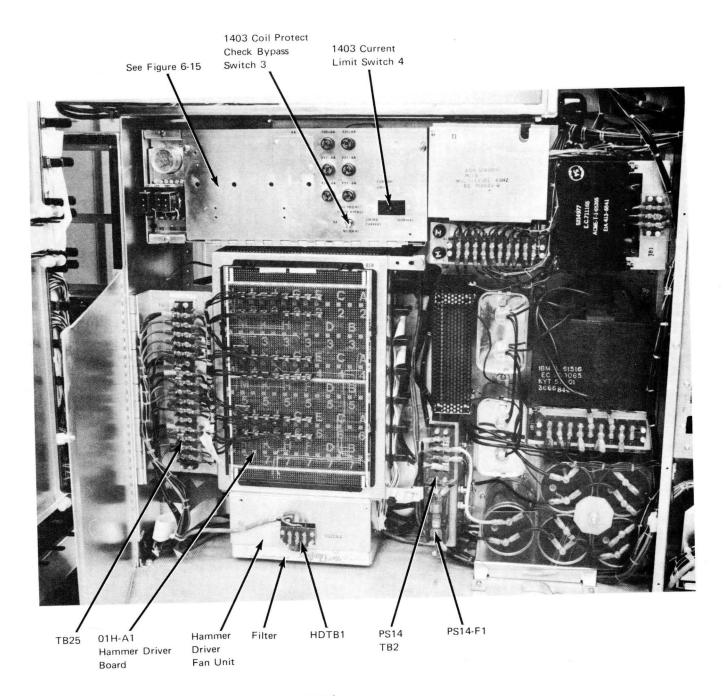


Figure 6-14. 1403 Controls (Right Side)

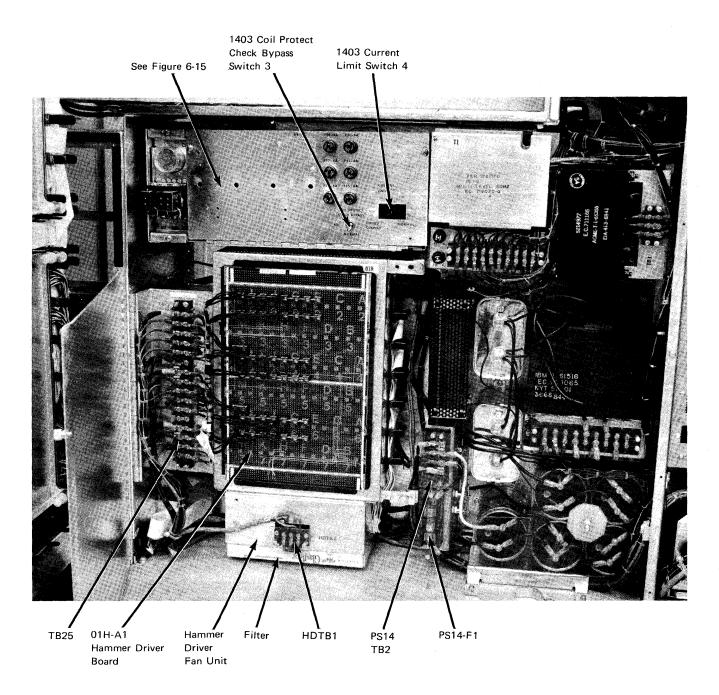


Figure 6-14. 1403 Controls (Right Side)

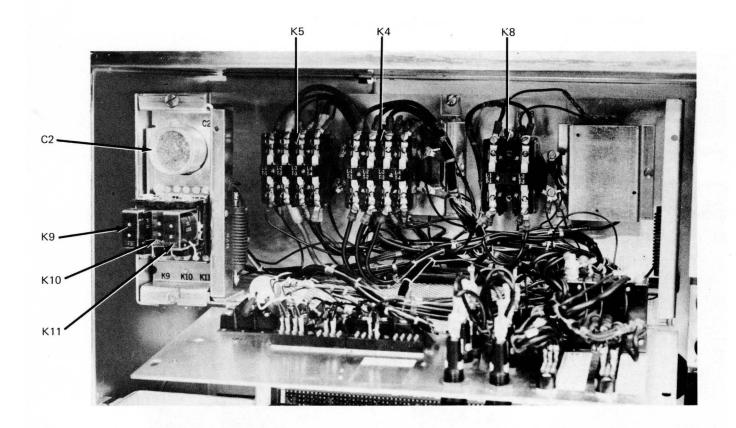


Figure 6-15. 1403 Control Panel (Open)

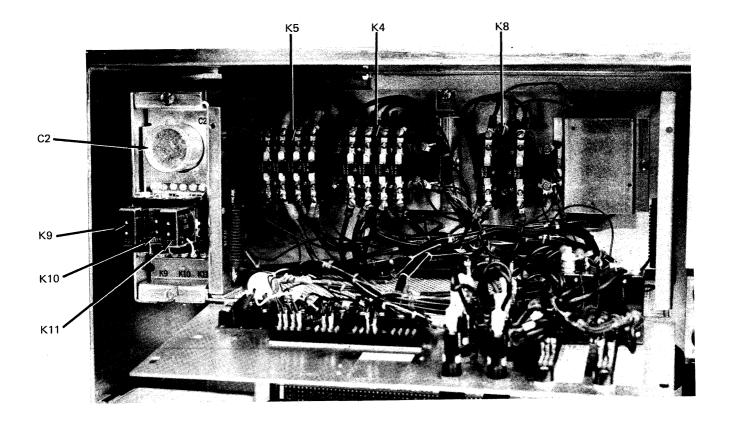


Figure 6-15. 1403 Control Panel (Open)

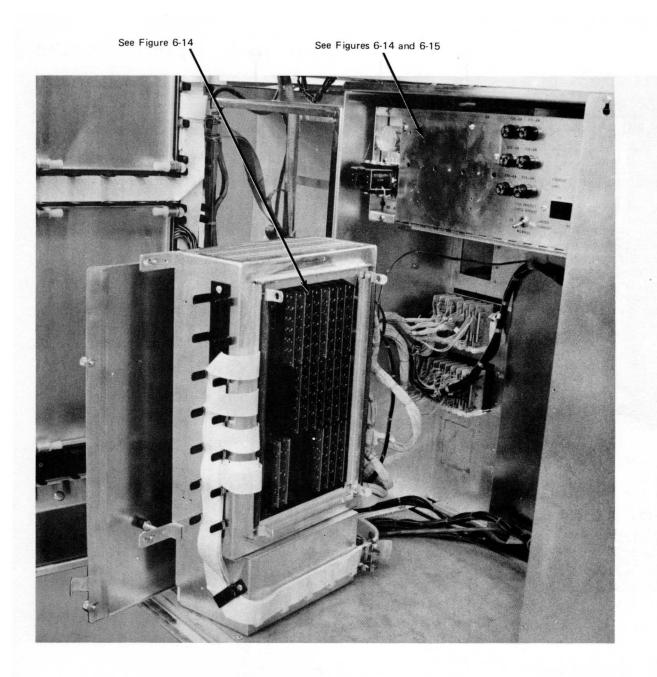


Figure 6-16. Hammer Driver Gate (Open)

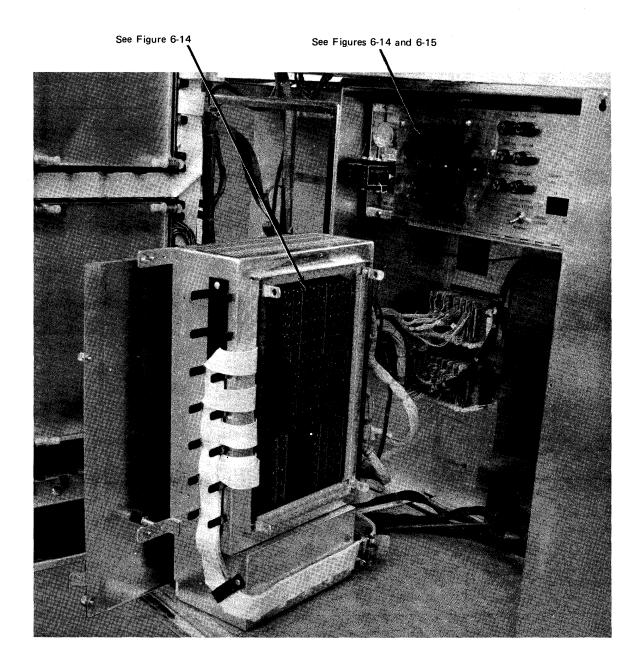


Figure 6-16. Hammer Driver Gate (Open)

#### A.1 LOCAL STORAGE CARD AND STORAGE PROTECTION CARD

#### A.1.1 FUNCTIONAL DESCRIPTION

A 64 X 10 self-contained functional three-dimensional storage-array card (including word drivers, storage elements, bit drivers, sense amplifiers and a voltage regulator) is used for local storage and storage protection. When the storage protection feature is present, the two cards (Figure A-1) can be swapped for diagnostic purposes. The inputs to the storage unit are an 8X by 8Y matrix. Two modes of operation are possible: 1. A write operation, or 2. A nondestructive read operation (NDR).

The NDR operation is accomplished by supplying a valid address (one X- and one Y-line selected), and sampling the output by conditioning the sense amplifier gate on. (If minimum access time is not needed, the sense amplifier gate can be left on at all times.) The write operation requires a valid address input, 10 data inputs, and a bit driver timing pulse (timed write instruction), all of which must be coincident. All signal input and output lines are compatible with SLD/SLT circuits.

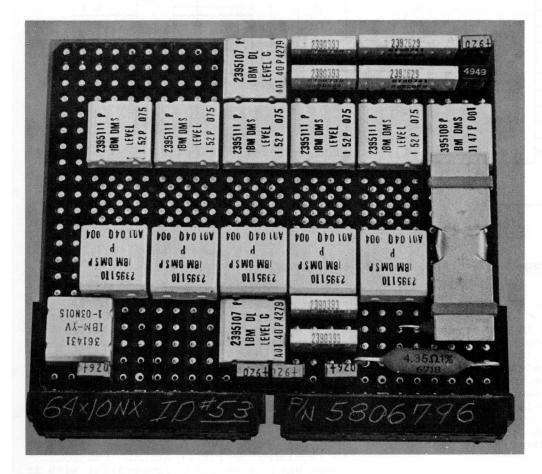


Figure A-1. Local Storage and Storage Protection Card

### Appendix A. Special Circuits

#### A.1 LOCAL STORAGE CARD AND STORAGE PROTECTION CARD

#### A.1.1 FUNCTIONAL DESCRIPTION

A 64 X 10 self-contained functional three-dimensional storage-array card (including word drivers, storage elements, bit drivers, sense amplifiers and a voltage regulator) is used for local storage and storage protection. When the storage protection feature is present, the two cards (Figure A-1) can be swapped for diagnostic purposes. The inputs to the storage unit are an 8X by 8Y matrix. Two modes of operation are possible: 1. A write operation, or 2. A nondestructive read operation (NDR).

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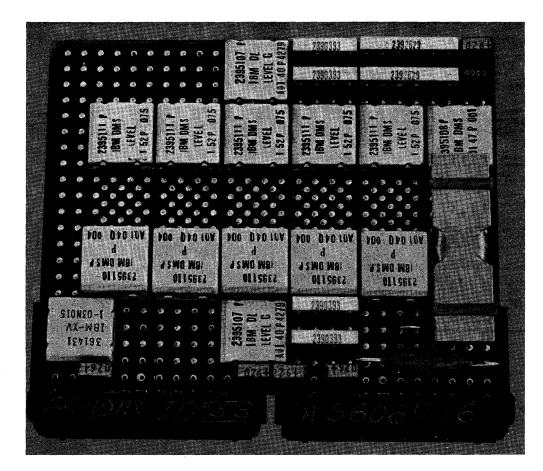
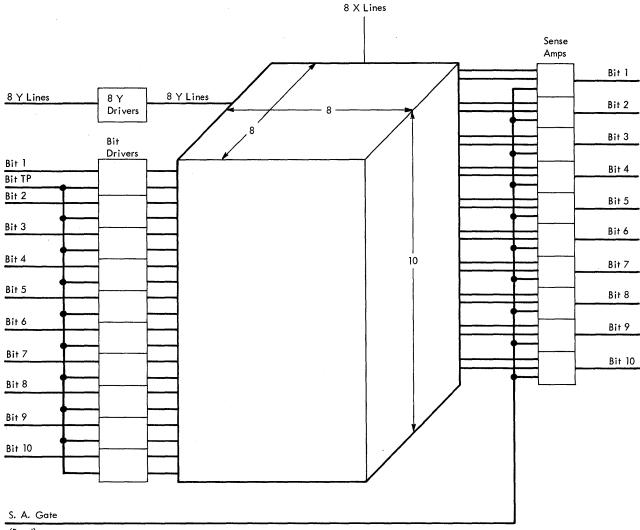


Figure A-1. Local Storage and Storage Protection Card



#### (Read)

Figure A-2. Local Storage and Storage Protection Addressing

#### A.1.2 CIRCUIT OPERATION (FIGURE A-2)

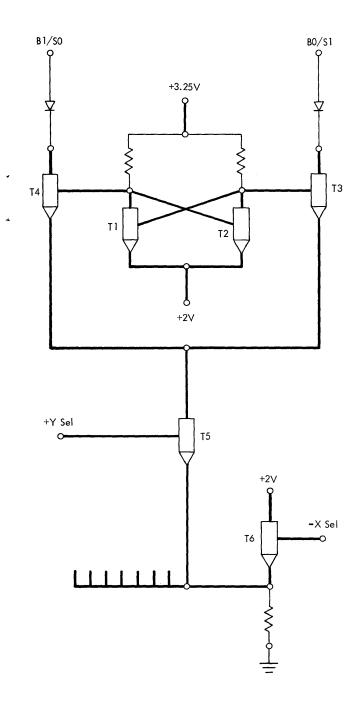
An address is selected in the array with the coincidence of a positive Y-line and a negative X-line. This condition selects 10 storage cells, one in each bit or plane. Selection of a cell causes current to flow in either the bit-one sense zero-line or the bit-zero sense-one line, depending on the state of the storage cell. The differential sense amplifier, when gated, provides an output indicative of the polarity of the input.

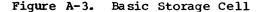
For the selected cell to be written into, the bit-one or bit-zero driver is turned on, depending on input data. The cell is left in the appropriate state when the bit driver is turned off. Because the array module cannot be powered directly from +6 volts, circuitry on the card provides the proper levels (+2 volts and approximately 3.25 volts).

There are two parts to the regulator circuitry: 1. a two-volt shunt regulator, and 2. a series-dropping resistor.

The regulator amplifier absorbs the load change while a resistor in parallel with it conducts the major portion of the current. The series-dropping resistor provides a voltage drop from +6 volts to approximately 3.25 volts. The storage latches are connected (all in parallel) between +2 volts and 3.25 volts.

A-2 (7/69)





#### A.1.2.1 Cell

A.1.2.1.1 Steady-State Operation: In Figure A-3, the inboard transistors T1 and T2 form a direct-coupled saturating flip-flop. Under steady-state conditions, one transistor is saturated with a collector voltage of approximately 2.2 volts while the other is cut off with a collector voltage of approximately 2.8 volts. Assuming a 1 is stored in the cell, transistor T1 is on and T2 off. The base of T1 and T3 is 2.8 volts while the base of T2 and T4 is 2.2 volts.

A.1.2.1.2 Read Operation: To read information from the cell requires the coincidence of X- and Y-voltage pulses. The X-voltage at the base of T6 is decreased from 2.6 volts to .7 volts while the Y-voltage at the base of T5 is increased from 0 volts to 1.7 volts. Thus, T6 is turned off and T5 is turned on. Due to the state of the flip-flop, T3 is enabled and the sense current, which is determined at the emitter of T5, flows to B0. In the case of a 0 being stored, the state of the flip-flop is reversed and T4 is enabled.

A.1.2.1.3 Write Operation: To write into the cell requires the coincidence of X, Y, and either BO or B1. Assuming a 1 is stored in the cell and a 0 is to be written, transistor T1 is on and transistor T2 off. The base of T1 and T3 is at 2.8volts. The X- and Y-lines are pulsed as previously indicated for a read cycle. B0 is decreased from 5 volts to approximately 1.5 volts. With the collector voltage of T3 reduced to saturation level, the enabled transistor T3 conducts all of its emitter current through the base and pulls down the collector voltage of transistor T2, which in turn tends to turn off transistor T1. As T1 turns off, its collector voltage rises and turns on T2. At the completion of this process a steady-state condition is reached with T1 off and T2 on. Thus, the saturating flip-flop is in its opposite condition and the 0 is stored in the cell.

#### A.1.3 STORAGE MODULE

The storage module is a one-half inch by one-half inch module consisting of a single substrate with twenty-three SLT input/output pins and eleven interstitial (feed through) pins.

Two 64-bit chips arranged in an 8Y by 8X by 1-bit configuration are mounted on the substrate making the module organization 64 by 2 bits. Nominal power dissipation per module is approximately 275 mw.

#### A.1.4 PERIPHERAL CIRCUITS (FIGURE A4)

<u>X-Drivers</u>: The X-driver is similar in configuration to the SLD100 A0I circuit except that it is clamped out of saturation. The driver input is a two-way AND circuit. There are four drivers per module and four load resistors per R-pack.

<u>Y-Drivers</u>: The Y-driver is a saturating emitter follower. It has one input and cannot be used as an AND circuit. There

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are four complete circuits per module including load resistors.

<u>Bit Drivers</u>: A one and a zero driver is required for each bit. The bit-1 driver is identical to the X-driver. The bit-0 driver is slightly different in that an input diode is used to clamp the output down level to a higher voltage. The bit-one driver is used as an inverter for the data input to the zero driver.

Sense Amplifier: The first stage of the sense amplifier is a gated differential amplifier followed by a level translating PNP stage and a saturating inverter. There are four bit drivers and two sense amplifiers on a stacked module.

<u>Voltage Regulator</u>: Plus-two volts is defined by a shunt regulator consisting of a differential amplifier and an emitter follower that drives the common emitter output transistor. The larger versions have two emitter followers. The reference voltage is generated by a resistor divider.

<u>Cell and Drive Circuit</u>: See Figure A-4 for a representation of the drive circuits with a cell.

#### A. 1. 5 PIN ASSIGNMENTS

Card pin assignments for the communicating lines and power connections to and from the storage card are as follows.

Y-Inputs 0 D02 1 B03 2 B04 3 D04 4 B05 5 D05 6 D06 7 B07				<u>X-Inputs</u> 0 J09 1 G10 2 J10 3 J11 4 G12 5 J12 6 G13 7 J13
<u>In</u> D10 D07 D13 D11 G03 G02 J05 G05 G05 G08 J07	Data 1 2 3 4 5 6 7 8 9 10			Out B10 B08 B12 D12 G04 J02 G07 J04 G09 J06
Bit T. P. S. A. GATE +2.0 Test Pin +3.2 Test Pin	D09 B09 B02 B13	+6 GND Not	Used	B11,G11 D08,J08 D03,J03,B06,G06

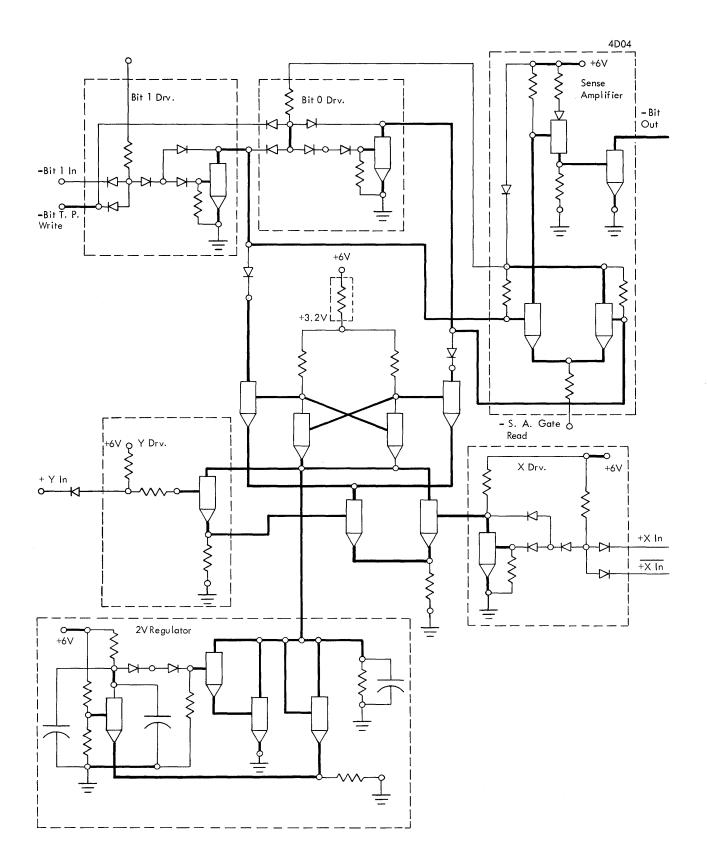


Figure A-4. Composite View of Circuits

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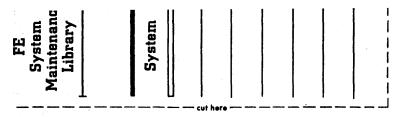
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